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June 2002

***Key Feature Analysis of the  
(Manufacturer) (Part #) (Part Description)***

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Report ID#: 0403-00000-S-5KF-11

04/29/03



***Key Feature Analysis of the  
(Manufacturer) (Part #) (Part Description)***

***By***

***Analyst's Name***

***June 2002***



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## Device Summary Table

<b>Package Type:</b>	100-pin TQFP
<b>Package Markings (Top):</b>	SI Example IC Kanata, Canada 0230
<b>Package Markings (Bottom):</b>	None
<b>Manufacturer:</b>	Semiconductor Insights
<b>Die Markings:</b>	SI © ® 2002 Example
<b>Speed</b>	166 Mhz
<b>Die Size:</b>	4.86 mm x 5.82 mm = 120 mm <sup>2</sup>
<b>Process:</b>	Double Metal, multipoly* CMOS Triple Well Technology
<b>Organization:</b>	Memory composed of 4 Banks Each Bank has 16 X 4 X 2 = 128 memory Blocks. Each memory block has 128C x 512R. Memory space of a Bank is thus given as 128 x 512 x 128 = 8M and Total space = 32M Horizontal Wordlines Vertical Bitlines.
<b>Redundancy:</b>	Each memory Block has four Redundant Wordline Drivers. And one Redundant Column Access Decoder.
<b>Minimum Observed Line Width/Pitch by optical Microscopy (+ 0.15 µm)</b>	
<b>Poly Gate Length:</b>	0.35 µm**
<b>Metal 1:</b>	0.6/1.2 µm
<b>Metal 2:</b>	0.8/1.6 µm

\* Indicates cross-section is required to identify the number of poly layers.

\*\* Indicates cross-section is required to confirm these statements.

## 1.0 Introduction

*The following report is an example report produced by Semiconductor Insights to illustrate the reports that the company produces. Examples of text, photographs and schematics have been taken from a variety of devices including a DRAM device, a Flash device, an A/D converter and a Frequency Synthesizer. The following introduction was taken from the analysis on the DRAM device.*

The following report is a design analysis of the Semiconductor Insights example report, which is a 16M Synchronous DRAM (SDRAM) organized in a  $512K \times 16 \text{ Bit} \times 2 \text{ Banks}$  arrangement. The device comes packaged in a 50-pin Thin Small Outline Package (TSOP II) measuring  $21.12 \text{ mm} \times 10.11 \text{ mm} = 213.50 \text{ mm}^2$ . The operating voltage is 3.3 V and the clock frequency range includes 83 MHz, 100 MHz, 111 MHz, 125 MHz and 143 MHz.

An interesting layout feature of the Semiconductor Insights example device is that the SN and SP generation circuits are located among the bitline sense amplifiers, thus requiring less layout space and increasing the die efficiency.

The Semiconductor Insights example device is fabricated using a double metal, double poly CMOS process on a  $3.22 \text{ mm} \times 5.73 \text{ mm}$  die.

This report includes the following sections:

- Architectural Overview (Section 2.0);
- Data Path - DRAM (Section 3.0);
- Address Path – Flash (Section 4.0);
- RX Prescaler – Frequency Synthesizer (Section 5.0);
- Phase Frequency Detector (Section 6.0);
- A/D Converter – A/D Converter (Section 7.0);
- SI Standard Cells (Section 8.0);
- Signal List.

Unless stated otherwise, the default transistor length is  $0.35 \mu\text{m}$ .



## 2.0 Architectural Overview

*The Architecture Overview is intended to provide an overview of the package and the die. The following section contains information about the device package, die structure and also information about transistor and device structure.*

### 2.1 Package Overview

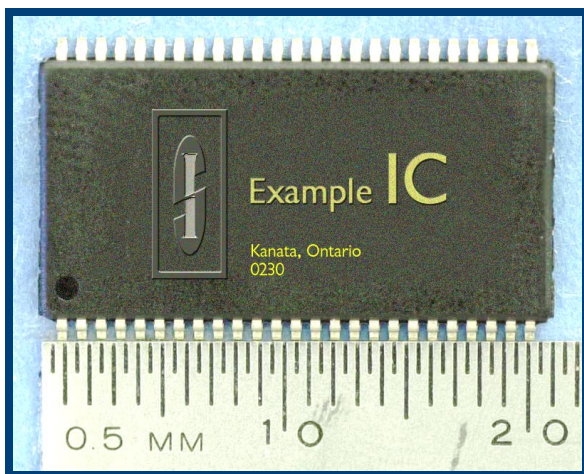
The SI Example IC is packaged inside a 50-pin TSOP II (Thin Small Outline Package) with dimensions of 21.12 mm × 10.11 mm = 213.50 mm<sup>2</sup>.

The package contains the following top markings:

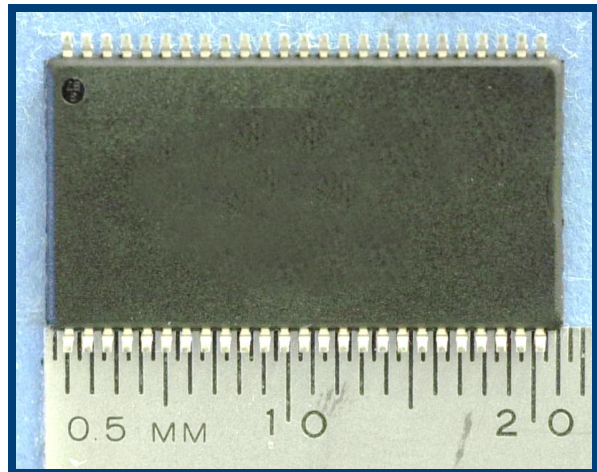
SI Example IC  
Kanata, Ontario  
0230

and there are no bottom markings:

The packages are presented as Photographs 2.1.1 and 2.1.2.

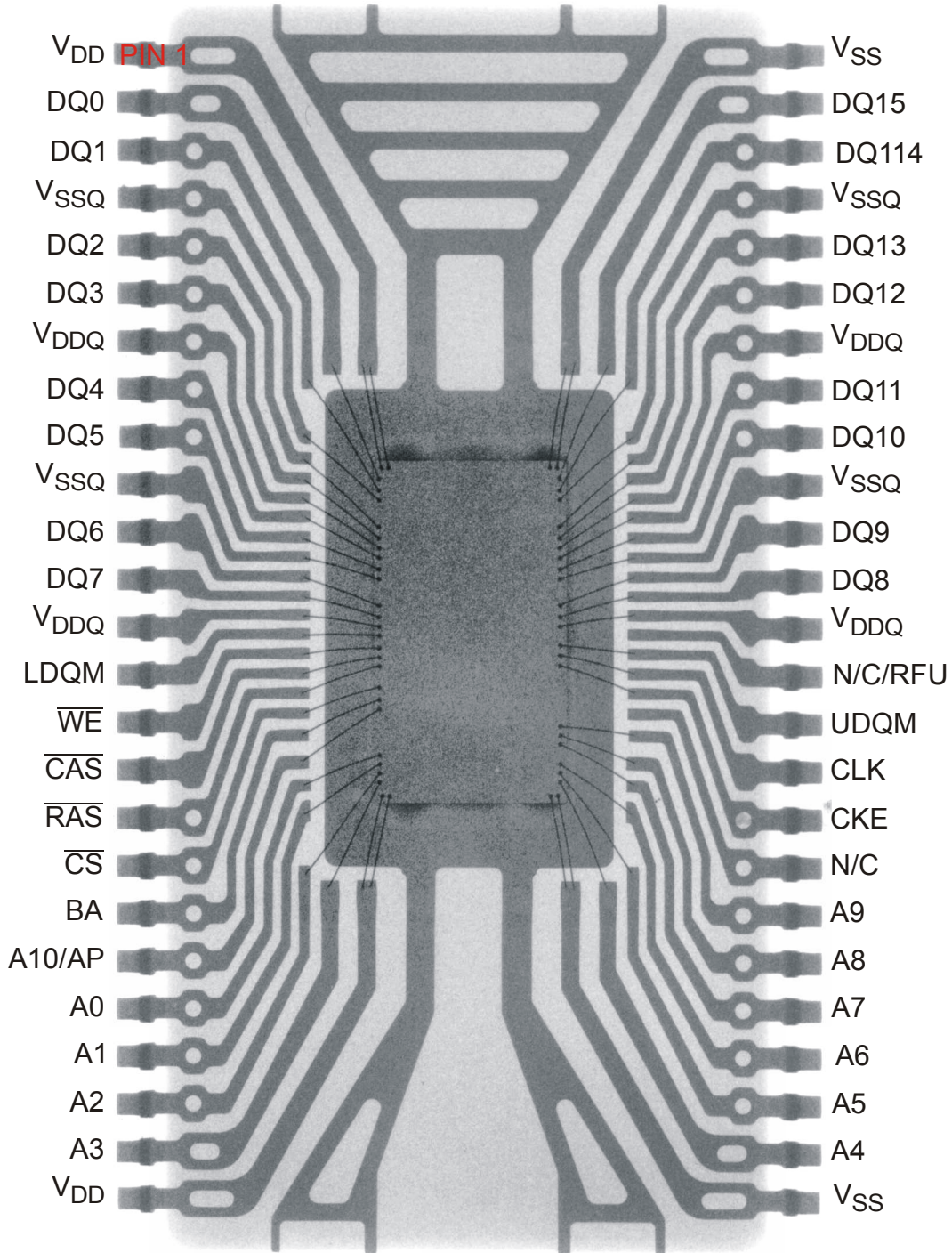


**Photograph 2.1.1: Package (top).**



**Photograph 2.1.2: Package (bottom).**

The pinout for the package and the package X-ray is presented as Photograph 2.1.3. For pad layout, refer to Photograph 2.2.1.

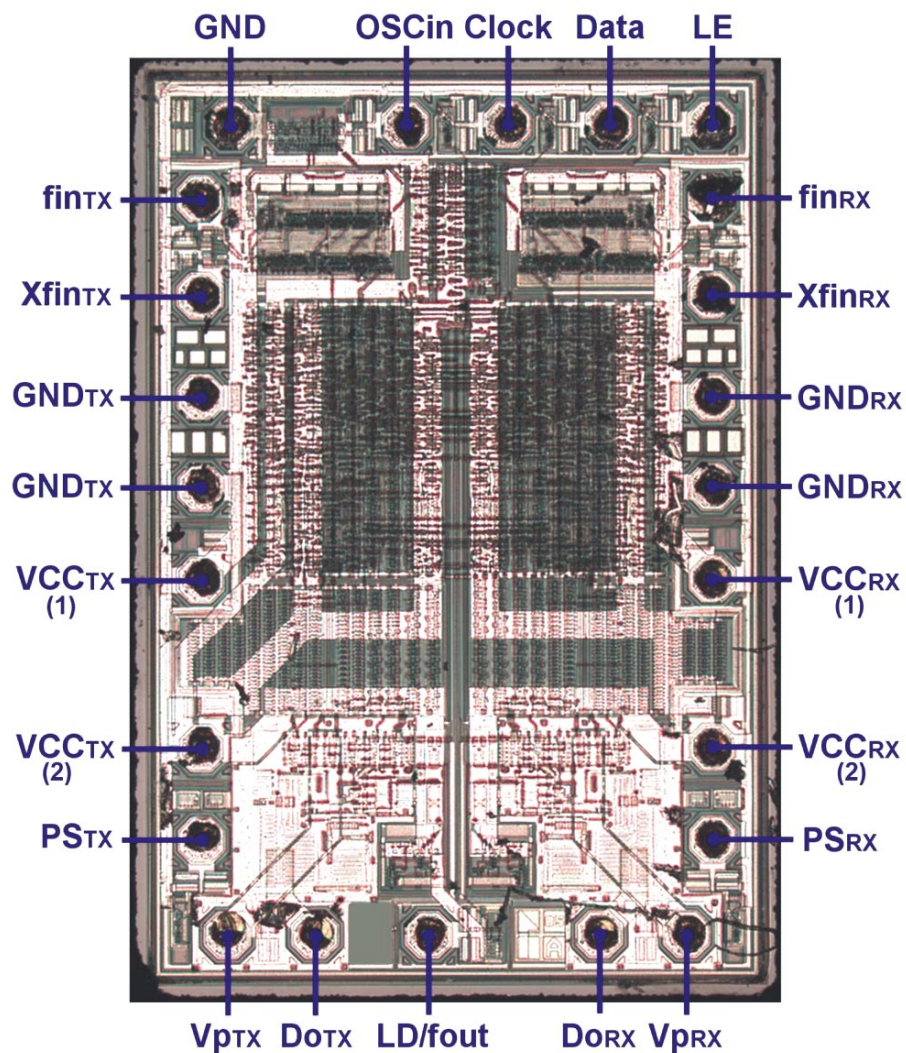


Photograph 2.1.3: Package X-ray.

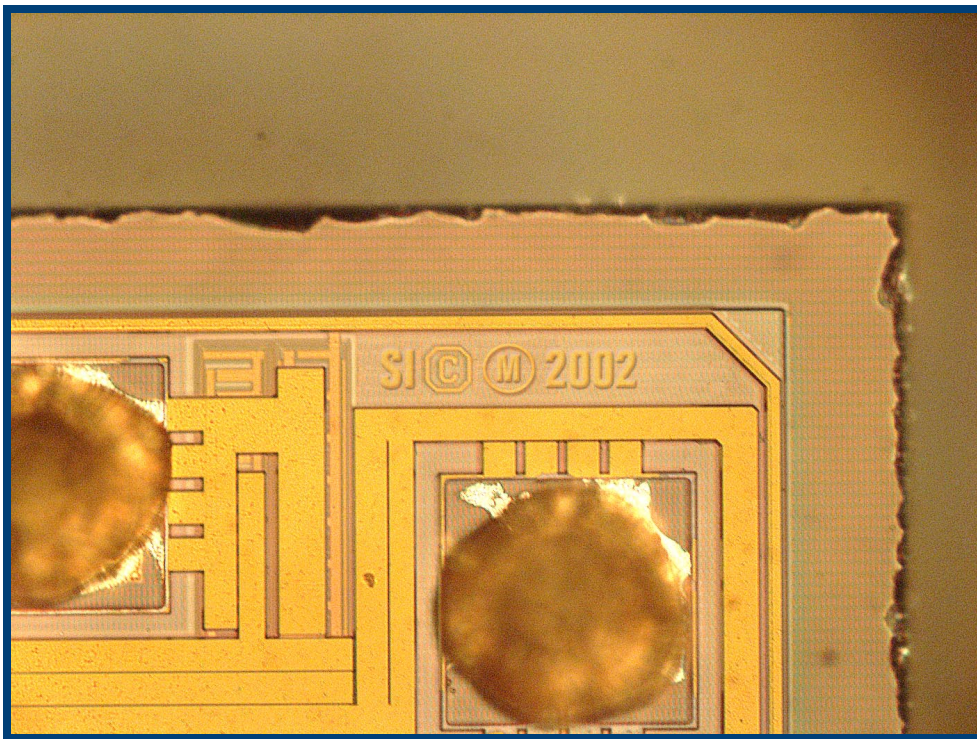
## 2.2 Physical Die Overview

The physical die overview contains photographs of the die and any markings found on the die. In this example the pins have been annotated on the die.

The SI Example IC is manufactured using a 0.35  $\mu\text{m}$  triple-metal double poly U-ESBIC4 BiCMOS process. However, the minimum feature size observed on the die was 0.5  $\mu\text{m}$ . Trace pitches are 1.0  $\mu\text{m}$  for polysilicon and 1.75  $\mu\text{m}$  for metals 1 and 2. The die is presented in Photograph 2.2.1 and Photograph 2.2.2 shows the die markings.



Photograph 2.2.1: Die with annotated bond pad names.



**Photograph 2.2.2: Die Markings.**

## 2.3 Functional Die Overview

### 2.3.1 Overview

*The following section contains information about the layout of the circuitry found on the device. The section contains a die map, power bussing and for memory devices a die structure and address bit maps. The following write up was taken from a memory report.*

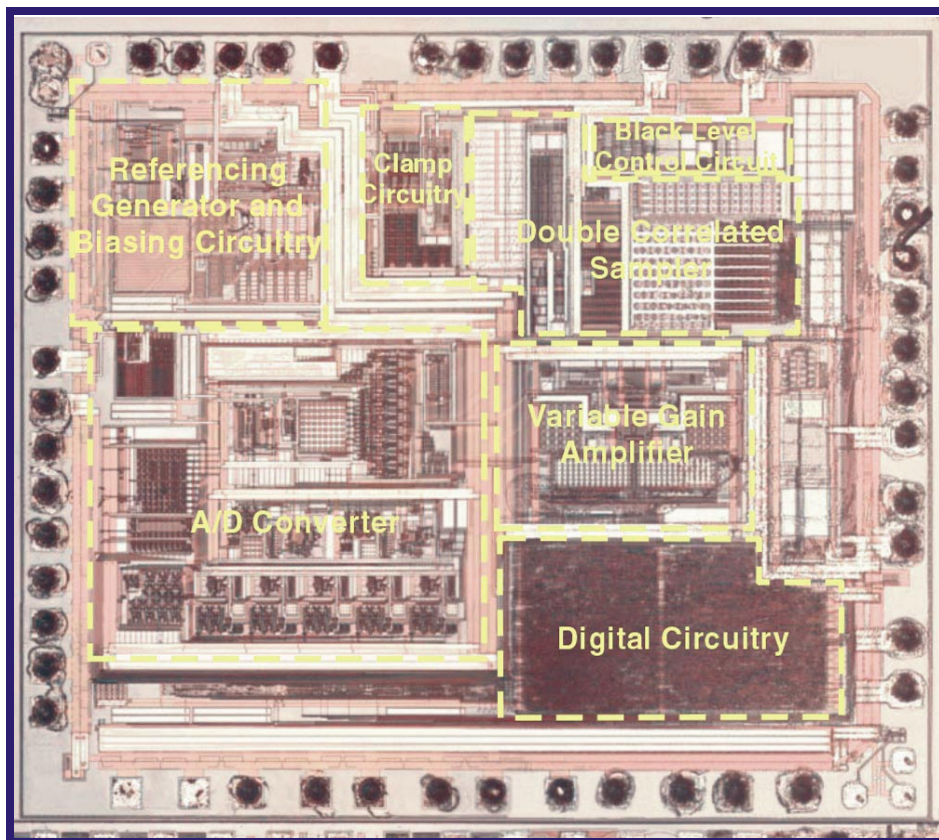
The die is functionally divided into two BANKS, then further into eight BLOCKS. Every Block contains eight 128 kb SUB-BLOCKS and two REDUNDANT 2 kb SUB-BLOCKS for redundant column accesses. There are 2 redundant wordlines for an additional 2 kb of redundant row access. For further explanation of the die structure refer to Figure 2.3.1.2.

A more specific breakdown of the die dimensions is found in Figure 2.2.1, from which we can estimate a die efficiency of 56%. The estimated die efficiency is within the expected range for SDRAM memories, but slightly higher due to the improved layout scheme of the SN and SP generator circuitry.

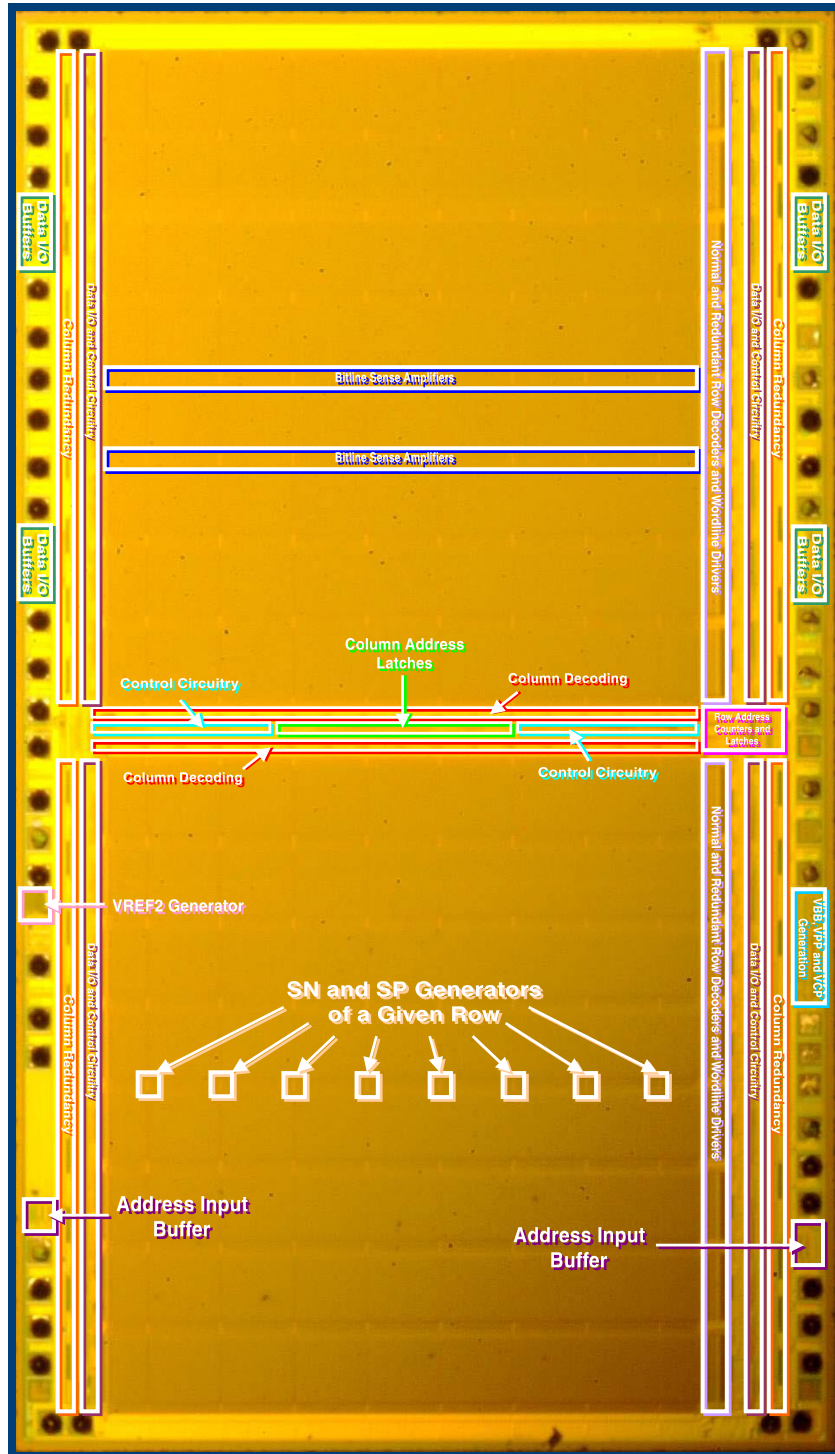
This section includes the following functional information about the die:

- Die Map (Photograph 2.3.1.1 and 2.3.1.2);
- Die Dimensions (Figure 2.3.1.1)
- Die Structure (Figure 2.3.1.2);
- Bitmap - Column Select (Figure 2.3.2.1);
- Address Bitmap - Row Select (Figure 2.3.2);
- Power Bussing (Photograph 2.3.3.1 and Figure 2.3.3.1);

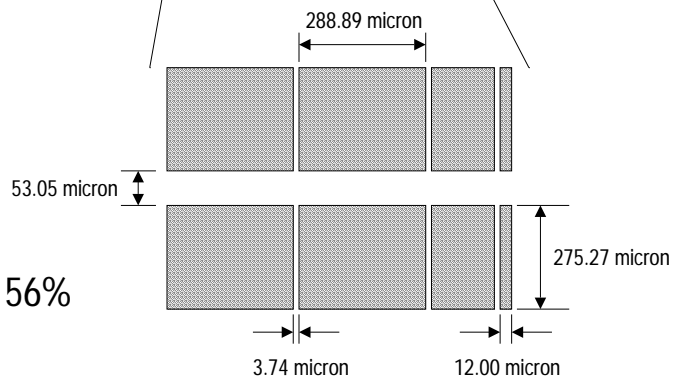
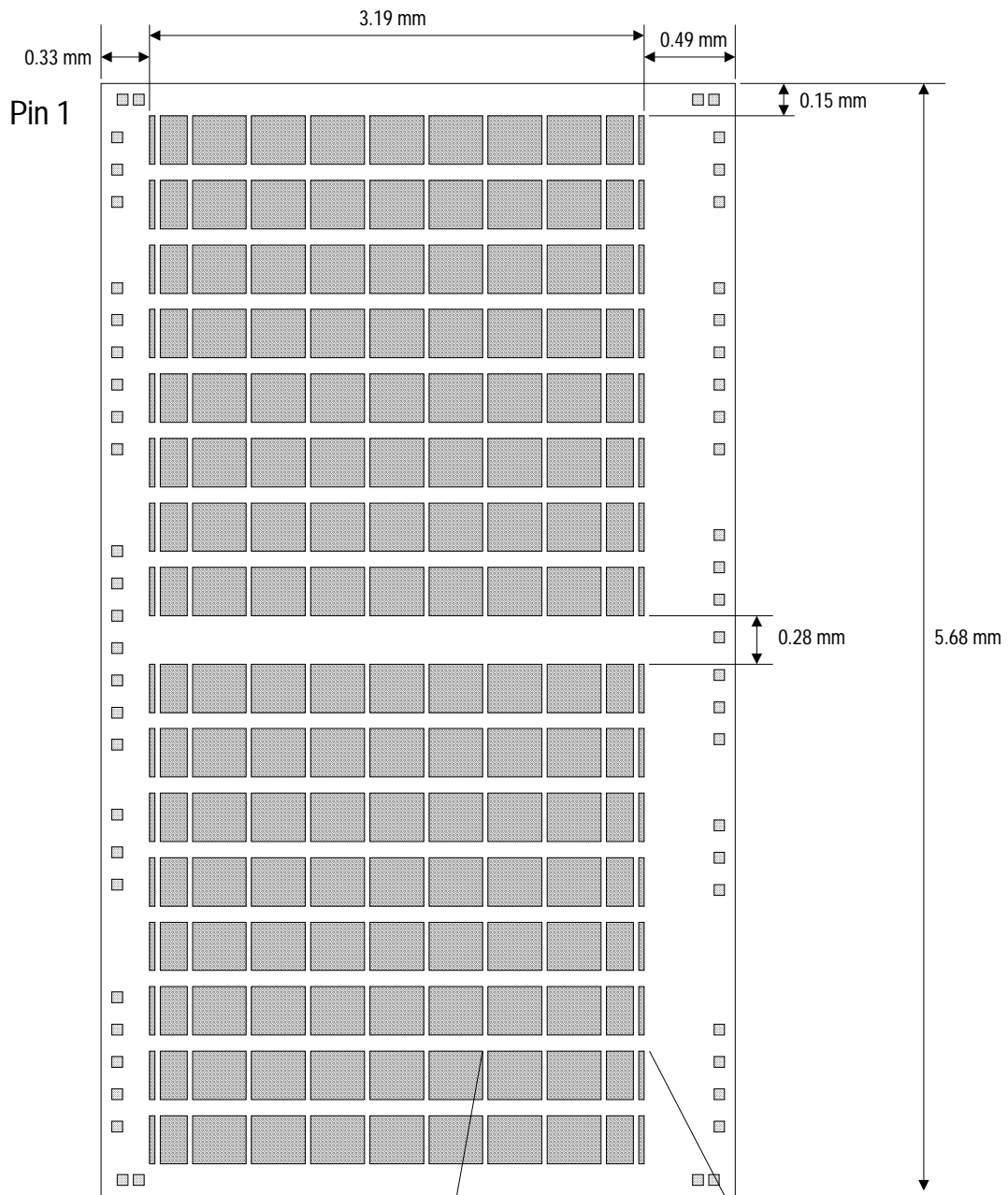




**Photograph 2.3.1.1 Die Map 1.**



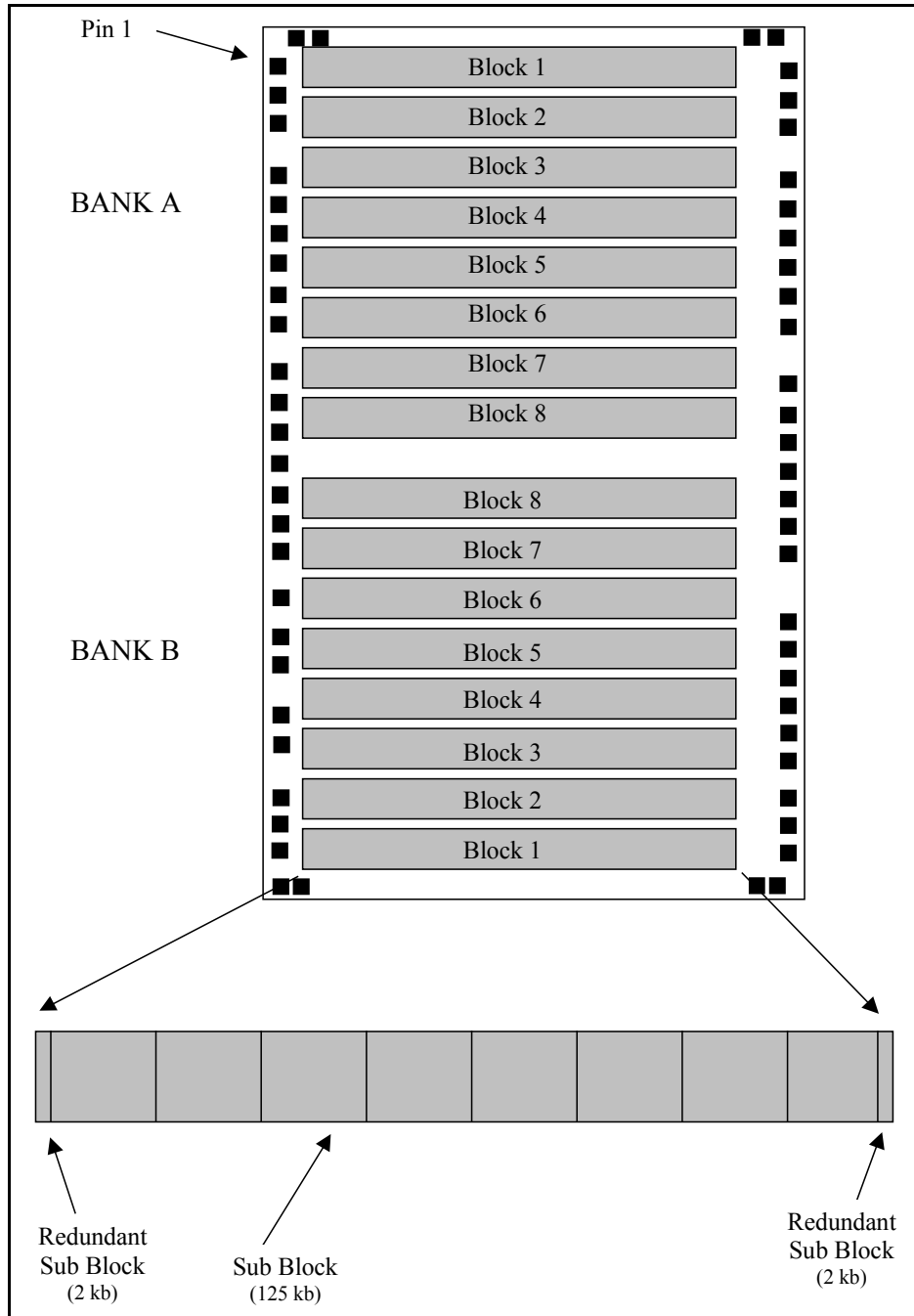
Photograph 2.3.1.2: Die map. 2



Estimated Die Efficiency = 56%

Part #:	SI EXAMPLE REPORT	
DATE CODE:	0230	
SCH_NAME:	DIEDIMEN	SI NUMBER: SI01
DATE_TIME:	6-17-2002_13:38	
LOCATION:	XXX	INITIALS: DM

Figure 2.3.1.1 DIE DIMENSIONS



**Figure 2.3.1.2: Die Structure.**

### 2.3.2 Address Bitmap

*For memory devices SI can include address bit maps which show the physical storage locations corresponding to logical address designations.*

#### **Bank Decoding**

A dedicated pin [BA] is used for Bank decoding. The [BA] pin is buffered in Figure 4.1 and the buffered signal  $\sim$ BA1 is then bussed to the control Section where it derives several signals.

In the Bank Address Control Block the  $\sim$ BA1 signal is used to produce the complementary signals BARAA and BARAB for row control and the complementary signals AYCK2A and AYCK2B for column control. The BARAA and BARAB signals are used in two instances of the Row Address Latches, one for each bank. Depending on the value of the complementary signals, it will choose Row circuitry for one bank, and deactivate the other one. The complementary signals AYCK2A and AYCK2B are used for two instances, one for each bank. The signal will select column circuitry for one bank, and deactivate the other bank.

In the Bank Selection Block, the complementary signals  $\sim$ BSB2 and  $\sim$ BSA2 are derived from  $\sim$ BA1. These signals are used to reset the line in the Row Address Latches for the bank that is deselected.

#### **Wordline Decoding**

Within each Bank, there are four levels of row decoding to select a wordline.

First in the Row Address Path schematic for 1 Bank, [A10] and [A9] are decoded to select two BLOCKS out of 8. Each Block contains 16 groups of 32 Wordlines. In the Row Predecoders 3, addresses [A8], [A7], [A6], and [A5] are decoded to select one of these groups.

The Row Predecoders 2 schematic decodes addresses [A4], [A3], and [A2] to choose, within one group of 32 Wordlines, a sub-group of 4 Wordlines.

The Row Predecoders 1 schematic decodes addresses [A1] and [A0] to choose one of these four wordlines.

### ***Bitline Control***

There are two levels of Column decoding besides the Bank decoding in order to activate a bitline.

First a sub-block needs to be selected. Each block contains 8 of these sub-blocks. The Column Address Decoders schematic selects two sub-blocks that shall remain active.

Afterwards addresses [A4], [A3], [A2], and [A1] will select a GSEL signal that will be activated in the two sub-blocks in the Column Address Decoder.

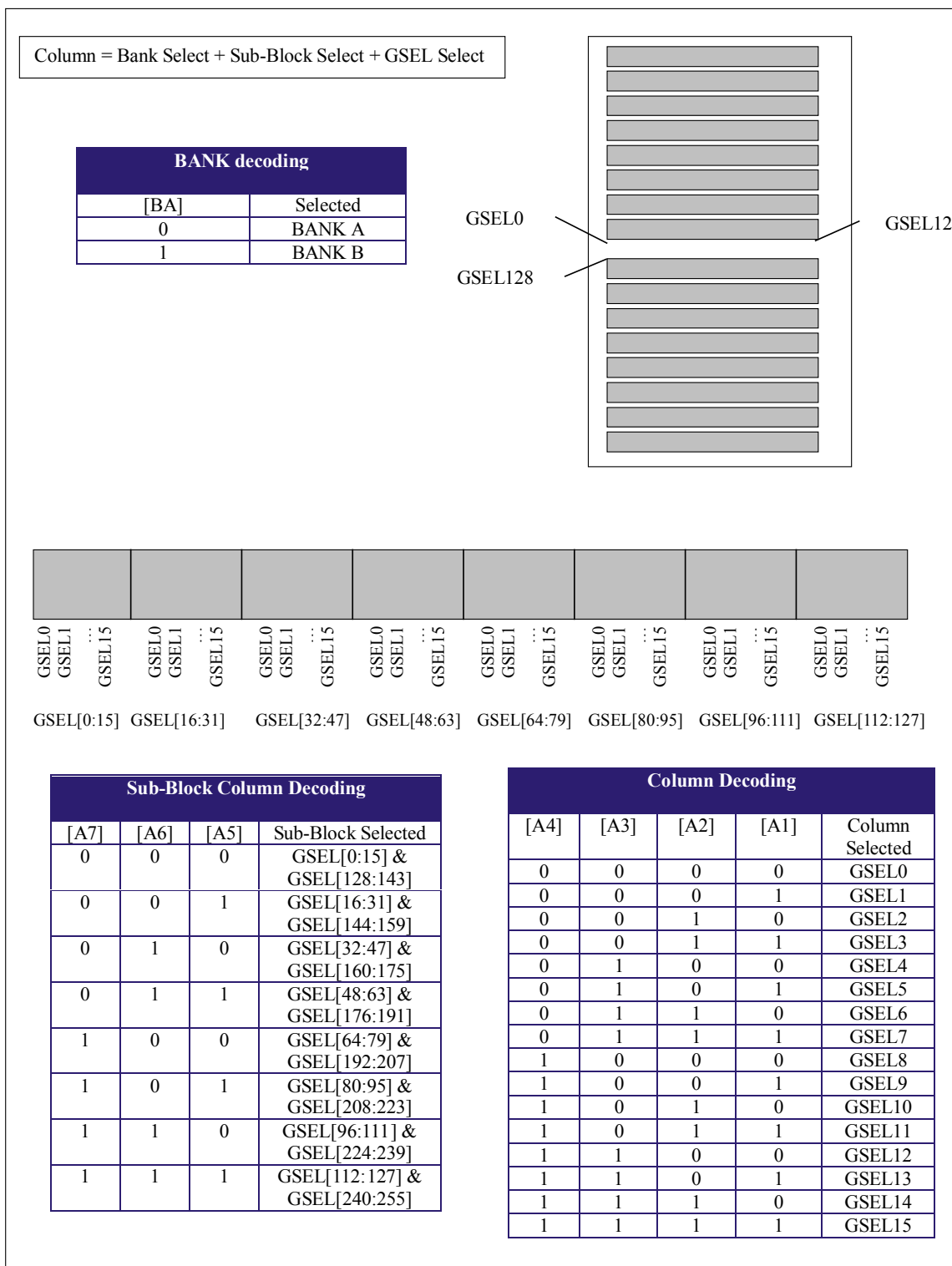
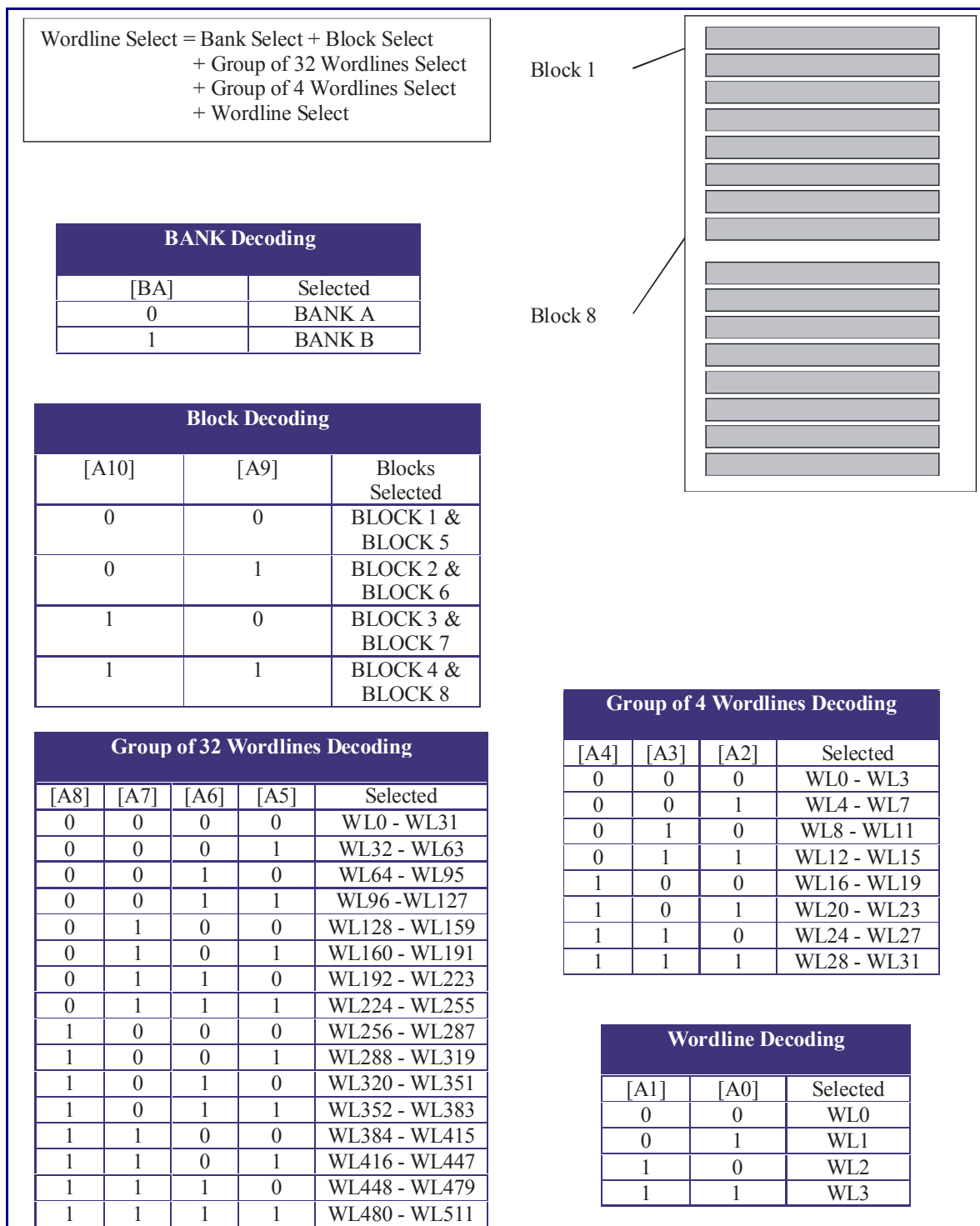


Figure 2.3.2.1: Address Bitmap - Column Select.



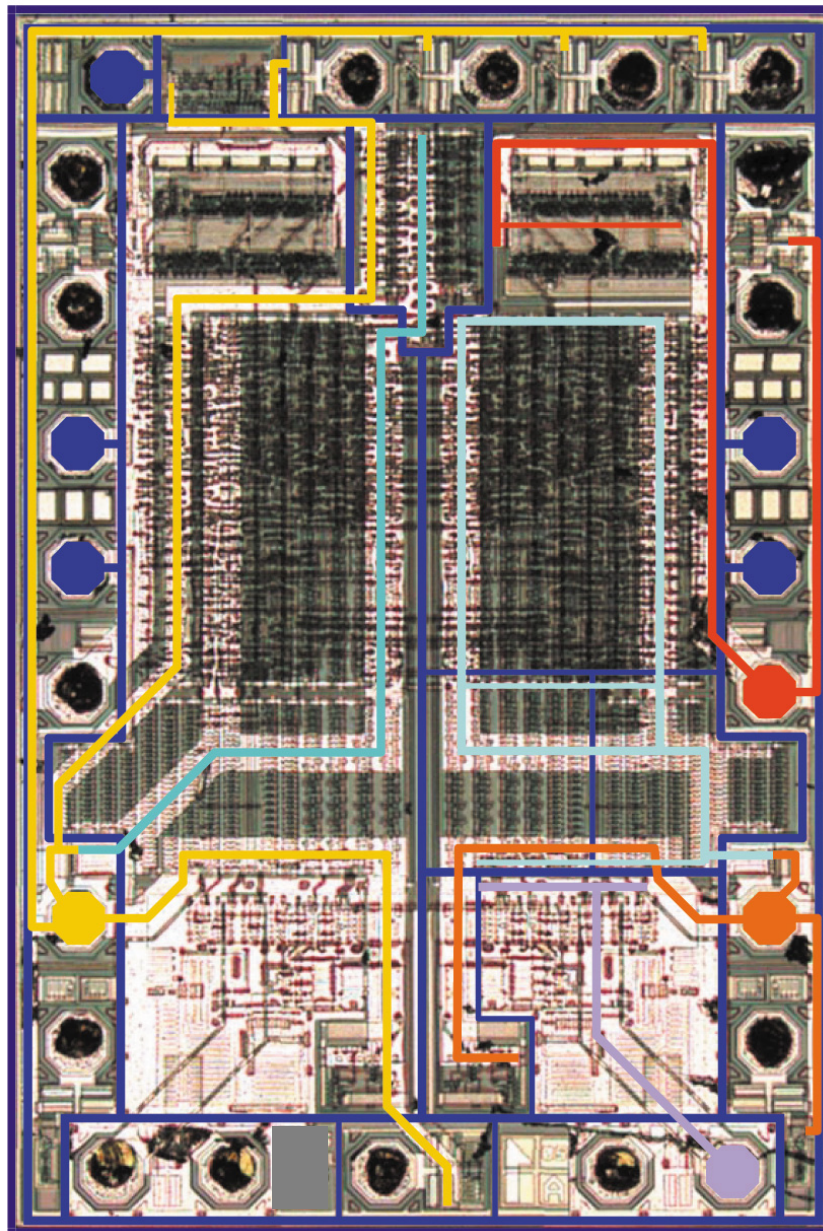
**Figure 2.3.2.2: Address Bitmap - Row Select.**



### 2.3.3 Power Bussing Map

*SI provides simplified diagrams showing the routing of power lines, namely power ground although other voltages are shown when appropriate. Examples of power bussing diagrams have been taken from both a mixed signal device and a memory device.*

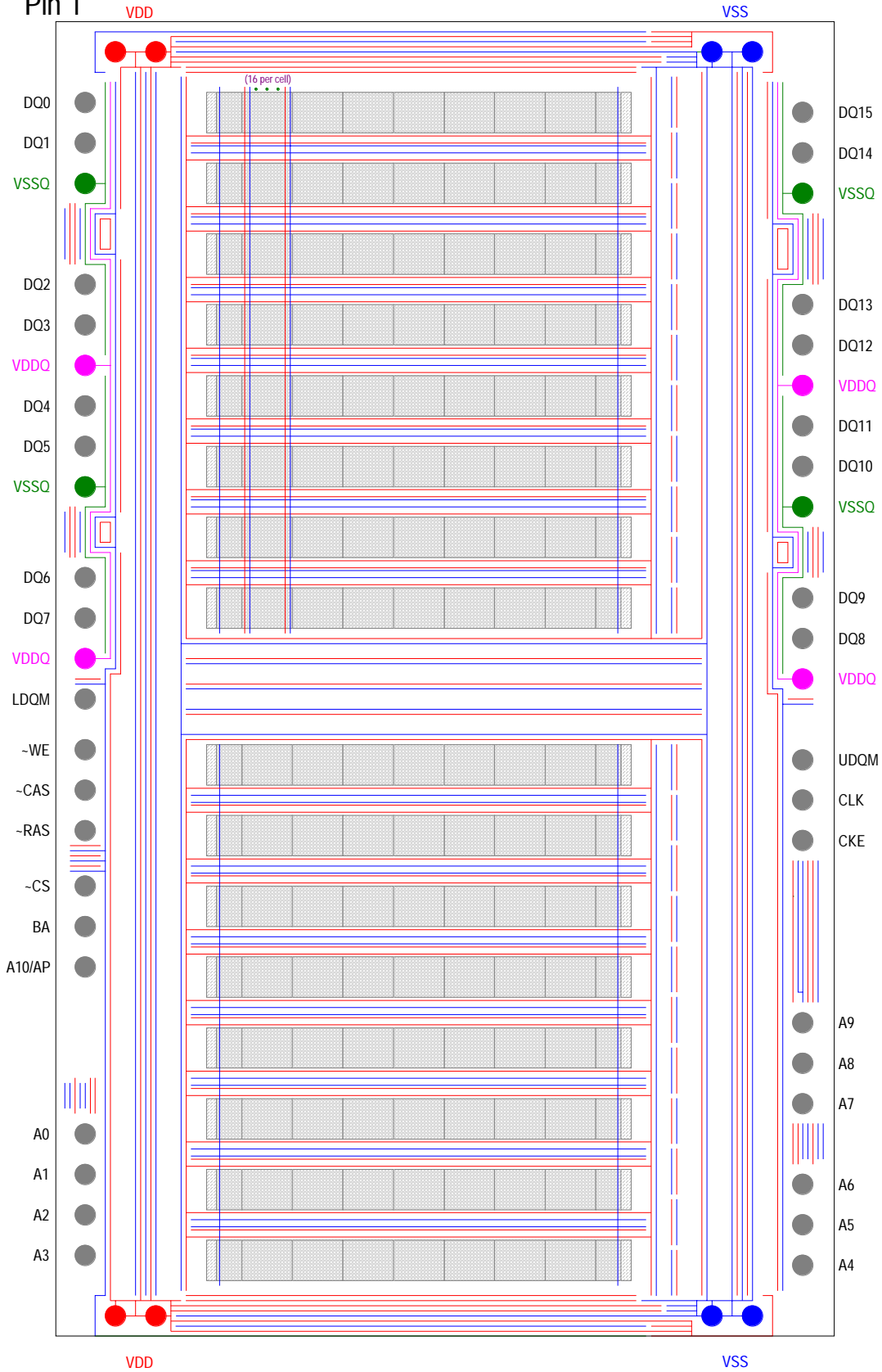
The SI Example IC die contains two pairs of GND<sub>TX</sub>, GND<sub>RX</sub>, Vcc<sub>TX</sub> and Vcc<sub>RX</sub> supply pads. Each pad pair has been bonded to a single package pin (i.e., a total of 4 package pins, each bonded to a pad pair as noted above). Internally, the GND<sub>RX</sub> and GND<sub>TX</sub> pads are shorted. The Vcc<sub>RX</sub> pads are not shorted internally and the upper pad Vcc<sub>RX</sub>(2) supplies only the BiPolar Prescaler, while the bottom pad supplies the remaining RX synthesizer logic. The RX Charge Pump is supplied from a separate Vp<sub>RX</sub> pad. There is a separate ground (GND) pad for the OSCin buffer and the Serial Interface logic. However GND, GND<sub>RX</sub> and GND<sub>TX</sub> pads are shorted internally. The OSCin buffer and Serial Interface is supplied from the Vcc<sub>TX</sub> bottom pad. Photograph 2.3.2.1 shows the Power Supply distribution throughout the die.



- |  |  |
|--|--|
|  Vcc <sub>RX_1</sub>  |  Vcc <sub>TX_2R</sub> |
|  Vcc <sub>RX_2</sub>  |  Vp <sub>RX</sub>     |
|  Vcc <sub>RX_2R</sub> |  GND                  |
|  Vcc <sub>TX_2</sub>  |  |

**Photograph 2.3.3.1: Power Bussing**

Pin 1



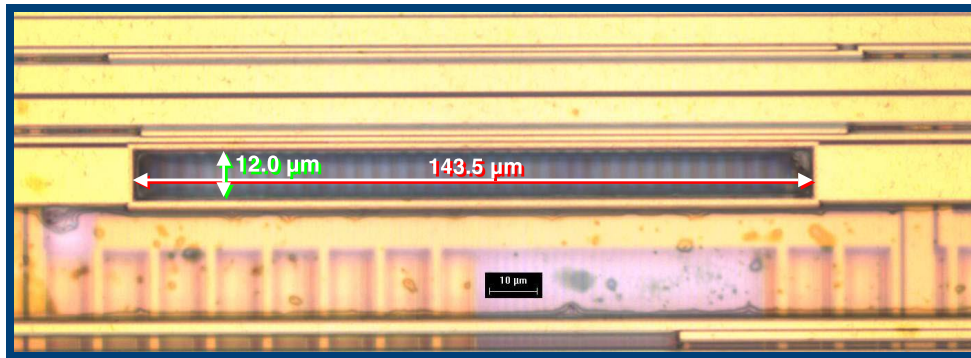
VDD —  
VSS —  
VDDQ —  
VSSQ —

Figure 2.3.3.1 POWER BUSSING DIAGRAM (NOT TO SCALE)

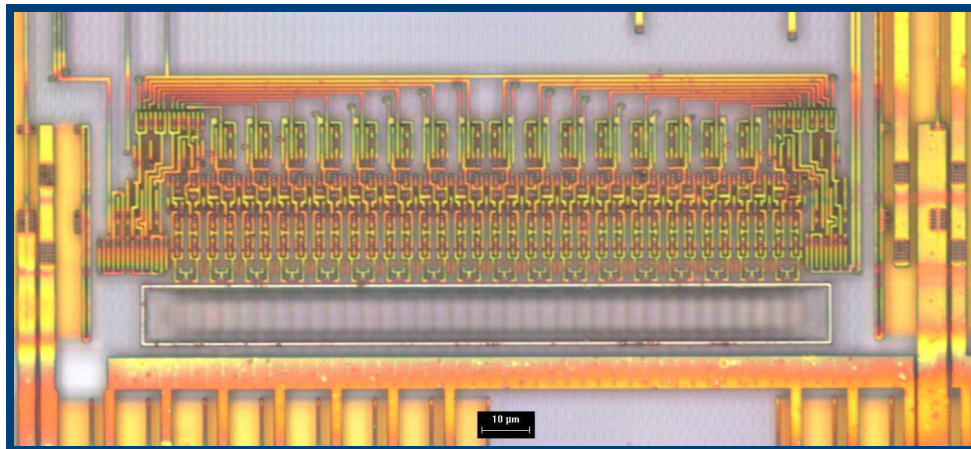
Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	POWERBUSSING
SCH_NAME:	POWERBUSSING	SI NUMBER:	SI01
DATE_TIME:	6-24-2002_10:40	LOCATION:	XXX
LOCATION:	XXX	INITIALS:	DM

### 2.3.4 Device Structures

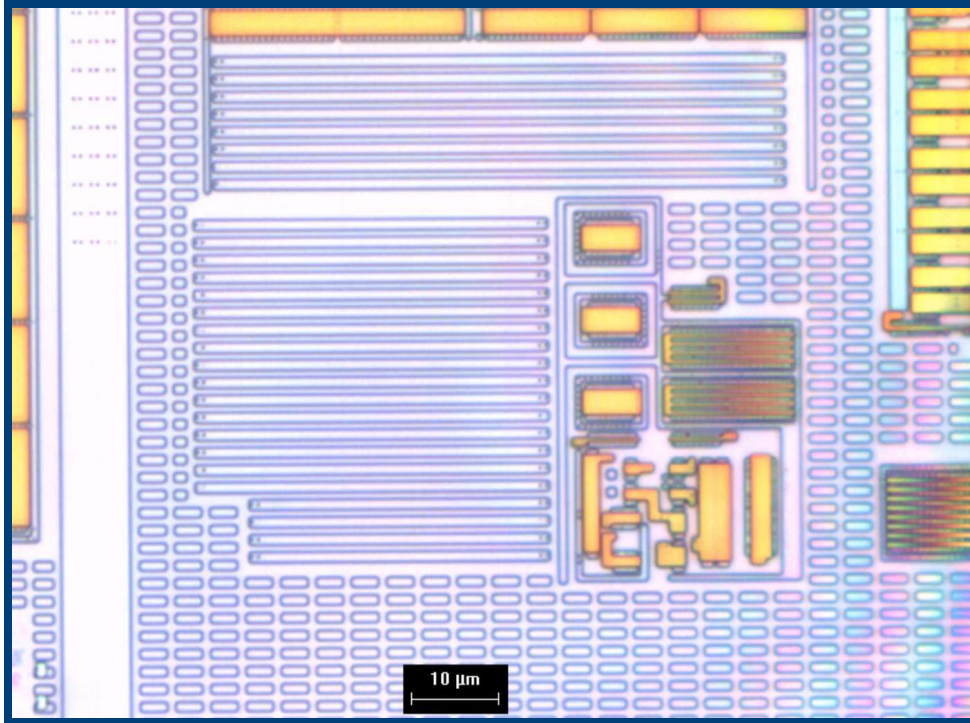
The following section contains select images from a variety of IC's intended to illustrate various structures found on analyzed IC's.



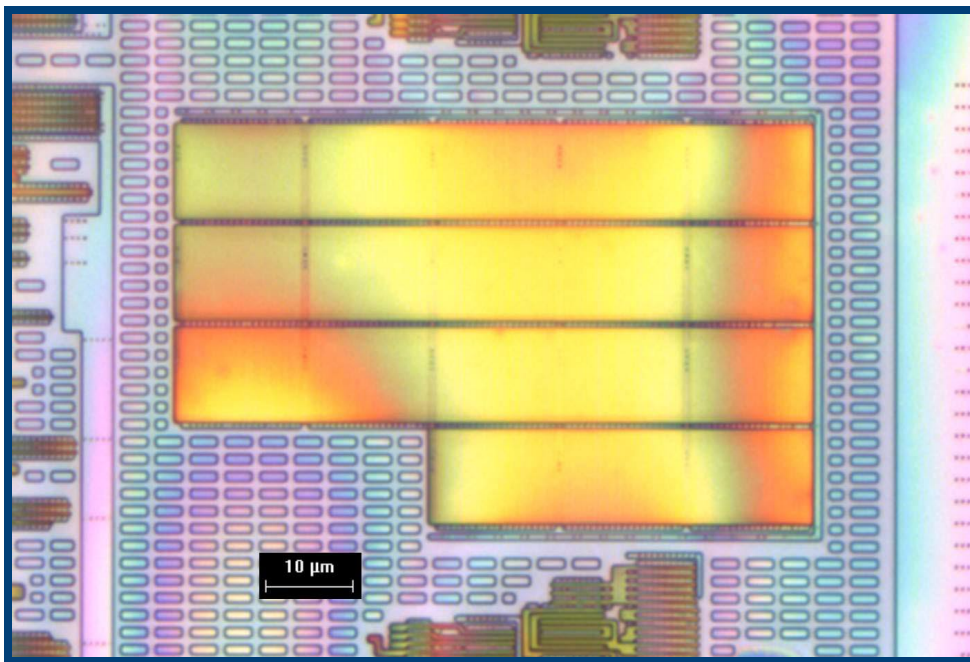
Photograph 2.3.4.1: Column fuses (metal 2).



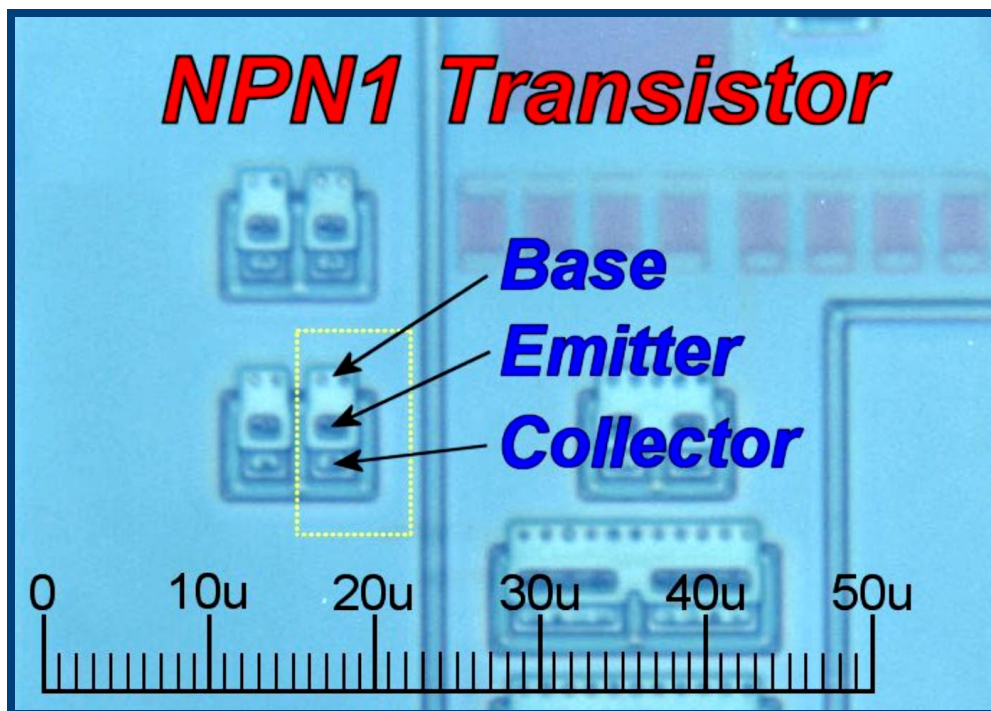
Photograph 2.3.4.2 Column fuses (metal 1).



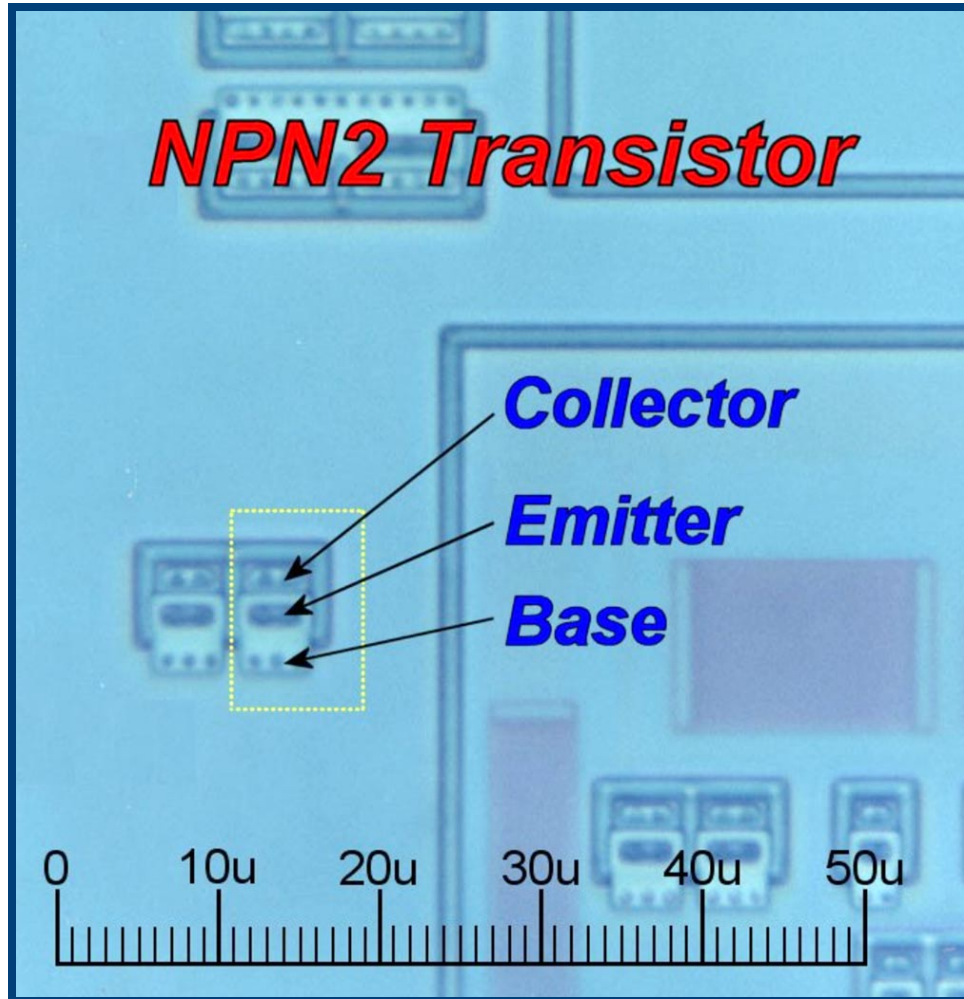
*Photograph 2.3.4.3: Diffusion resistor.*



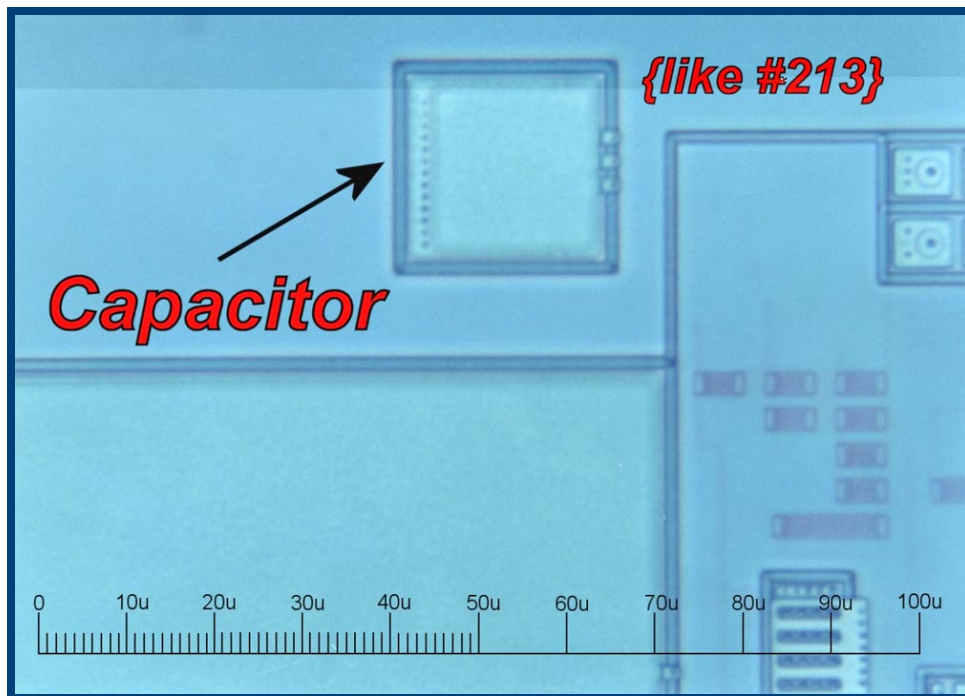
*Photograph 2.3.4.4: Poly-diffusion capacitor.*



Photograph 2.3.4.5 NPN HBT (NPN1).

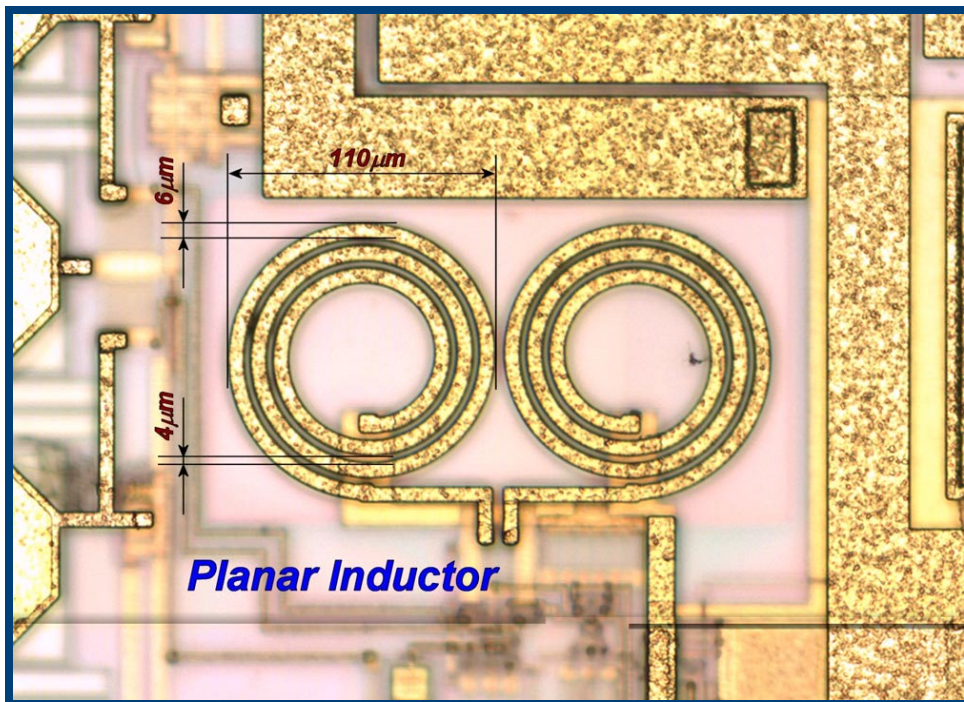


Photograph 2.3.4.6 NPN HBT (NPN2).



**Photograph 2.3.4.7 Capacitor (device #213).**





*Photograph 2.3.4.8 Planar Inductor.*

## 2.4 Design Overview

*The following section gives an overview of the structure of the device from a circuit standpoint and contains information about the overall structure of the device. The text was taken from a report on a frequency synthesizer. A top level diagram is included in Figure 2.4.1.*

*Note: The figure numbers found in this section refer to the original report, that the content was taken from.*

The SI Example IC is a double PLL integer frequency synthesizer. It contains two very similar synthesizers, the RX synthesizer (2.6 GHz) the TX synthesizer (1.2 GHz). This Key Feature Report covers only the RX synthesizer circuitry.

The RX synthesizer contains:

- dual modulus Prescaler (32/33 or 64/65)
- 7-bit programmable swallow counter with divide ratio from 0 to 127
- 11-bit programmable N divider with divide ratio from 3 to 2047
- 14-bit programmable reference divider with divide ratio from 3 to 16,383
- Phase Frequency Detector
- Charge Pump with Current Switch and Fast Lock circuitry
- Power saving mode control

Both the RX and TX synthesizers are programmed through a simple 3-wire Serial Interface. The Reference Frequency (OSCin) input buffer is common for both synthesizers. The LD/fout Output pad allows monitoring of the Lock condition for both synthesizers as well as the Reference and N Counter output frequencies.

The Synthesizer design is rather conventional and not altogether sophisticated. The main benefit from the innovative BiCMOS technology is high operation frequency and low power consumption. However, the Charge Pump circuitry implements some solutions that minimize power consumption.

It has been found that the Standard Cell block, where the Synthesizer Programmable Counters are implemented, does not contain any flip-flop Standard Cells. Flip-flops are built from transmission gate based multiplexers and NAND gates. Connections between flip-flop elements are made through routing channels. A lot of Standard Cell simple gates (inverters, NANDS, NORs) have been found in the design with equally dimensioned PMOS and NMOS transistors.

The extracted SI Example IC RX Synthesizer circuitry is presented through schematics organized in a fully hierarchical manner with a top level shown in Figure 2. The top-level schematics contain, apart from the RX synthesizer circuitry, the Serial Interface, the OSCin Buffer and the Lock Detect/Frequency Monitoring circuitry. Connections to and from the TX synthesizer are left unconnected in Figure 2.

The main functional blocks of the SI Example IC covered by this Key Feature Report are described below:

1. RX ECL Prescaler: This circuit receives the RX frequency from the  $fin_{RX}$  pad and divides it by 32/33 or 64/65 depending on the RXSW bit setting and SWEN (Swallow Enable) input state.
2. RX Programmable Counters: There are 3 programmable counters: the Reference Counter with divide ratio  $R = 3$  to 16,383, the N-Counter with ratio  $N = 3$  to 2,047 and the Swallow Counter which is programmable between 0 and 127. Each Counter has an associated latch, containing the actual divide ratio.
3. RX Intermittent Mode Control: This circuit controls the RX Synthesizer Power Down mode and recovery from Power Down to Operating Mode. It also controls the RX Charge Pump operation to lower the supply current in a Lock condition.
4. RX Phase Frequency Detector (PFD): This is a rather conventional solution of a PFD. The RX\_FC bit controls PFD operation depending on the VCO polarity type.
5. RX Charge Pump: The pump contains a current switch allowing the selection of a full scale output current between 1.5 mA and 6 mA. The RX Charge Pump also contains some interesting features like Fast Lock and Power Saving in Lock condition.
6. LD/fout Selector: This circuit drives the LD/fout PAD. Depending on signal LDS, T1 and T2 bit settings, it outputs Lock Detect information or one of TX/RX Reference or N-Counter output frequencies.
7. Serial Interface: This is a very simple 3-wire interface, based on a 23-bit serial register. The Serial Interface is used to program both TX and RX synthesizers.
8. OSCin Buffer: This circuit generates the internal Reference clocks for the TX and RX Reference Counters and Intermittent Control Circuits.

Input and Output Pad schematics and symbols can be found in Figures 11 through 11.5. Figures 12 through 12.12 contain symbols and schematics of Standard Cells and flip-flop macro-cells used in the CMOS logic portion of the design.

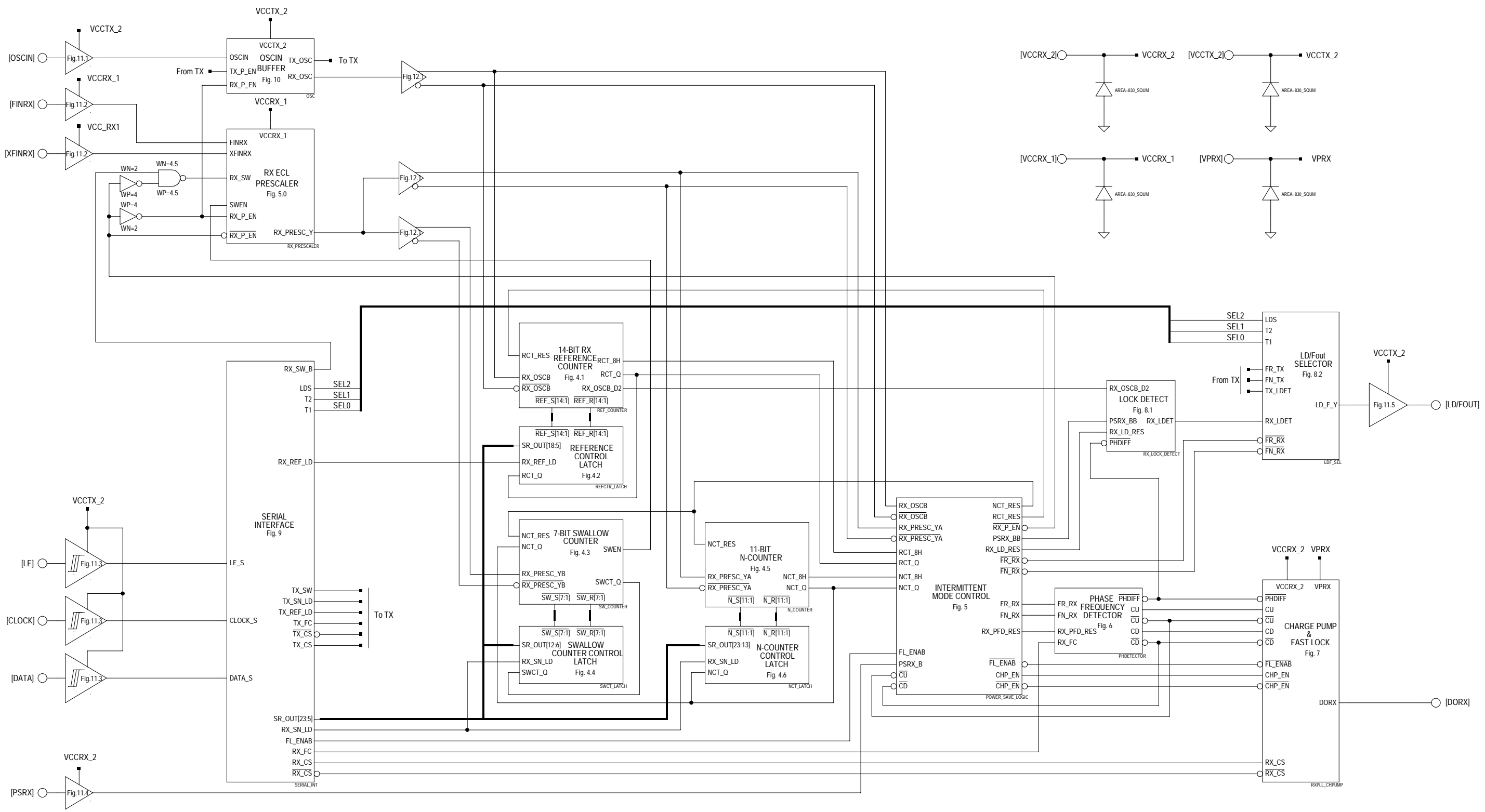


Figure 2.4.1 RX SYNTHESIZER BLOCK DIAGRAM



## 3.0 Data Path

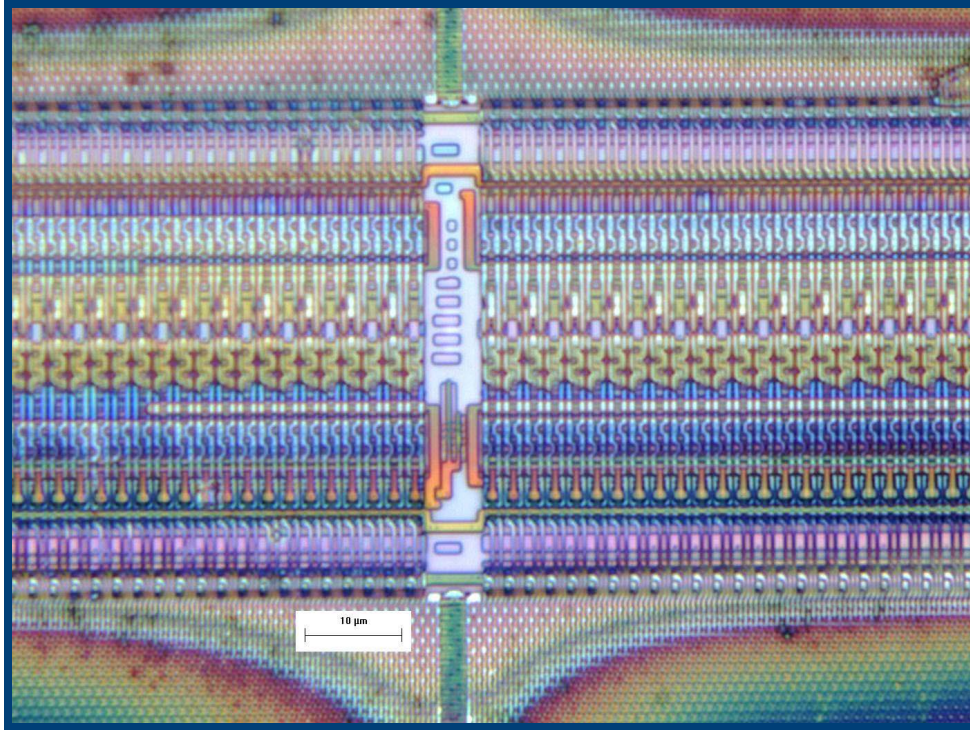
*The data path section was taken from a memory report. The section is complex so a simplified top-level diagram was included as Figure 3.0. The data path then was divided into three main parts, 3.1, 3.2 and 3.3. Each subsection is fully hierarchical and contains a page-by-page signal list. These page by page signal list, which are inserted to help navigate through the report.*

*Note: The page-by-page lists were taken directly from the original report and therefore the figure numbers are not valid for this document.*

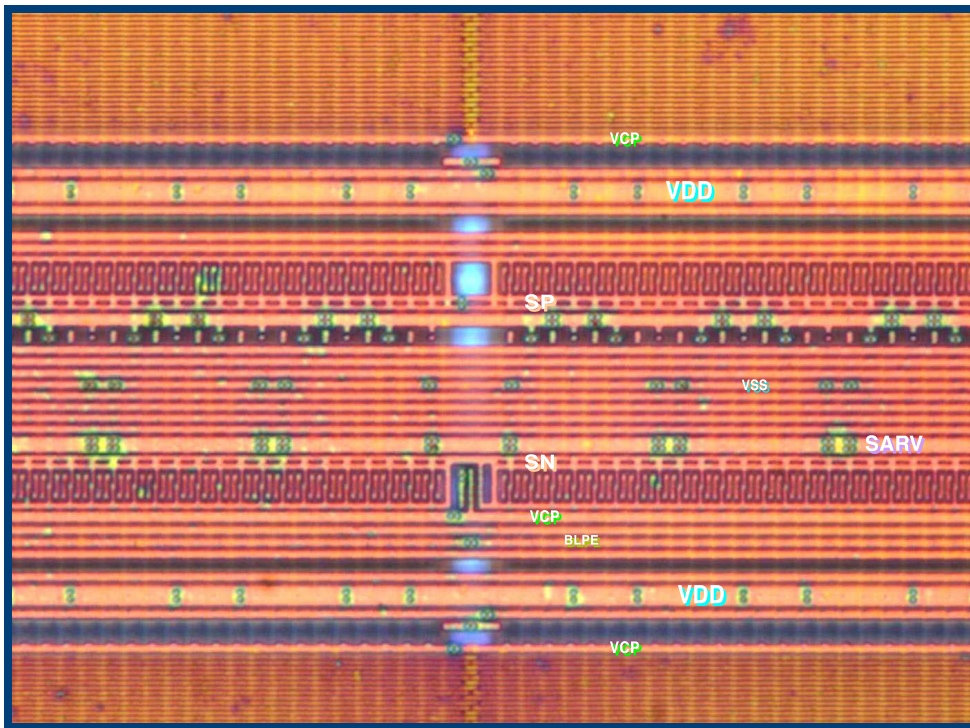
### 3.1 Read and Write Paths

A functional block diagram of the data path is shown in Figure 3.0. The lower byte of the data is stored/read by accessing the left quadrant of each bank and DQ\_[0:7] on the left side of the chip. The upper byte is stored/read by accessing the right quadrant of each bank and DQ\_[8:15] on the right side of the chip.

Data is transferred to the bi-directional Global Data Buses through the Data Input Buffer of Figure 3.1.1.1 and routed to the Local Data Buses through the Data Bus Sense Amplifiers of Figures 3.2.3.1, 3.2.4.1 and 3.2.5.1. These schematics also show the global data bus/local data line structure. Read data is placed on the normal data lines or the redundant data lines by the bitline sense amplifiers (shown in Figures 3.2.6.1 and 3.2.7.1). The redundant data lines are used to transfer read data between the data bus sense amplifiers and the normal data lines or the global data bus. Write data is transferred via pass gates to the normal data lines and/or the redundant data lines. Redundant memory access is controlled by normal column enable or redundant column enable signal. SN and SP generation circuitry is located between the bitline sense amplifier blocks of each memory array sub-block thus taking up virtually no real estate on the die.



**Photograph 3.1.1: SN-SP generator circuit (poly).**



**Photograph 3.1.2: SN-SP generator circuit (metal 1).**

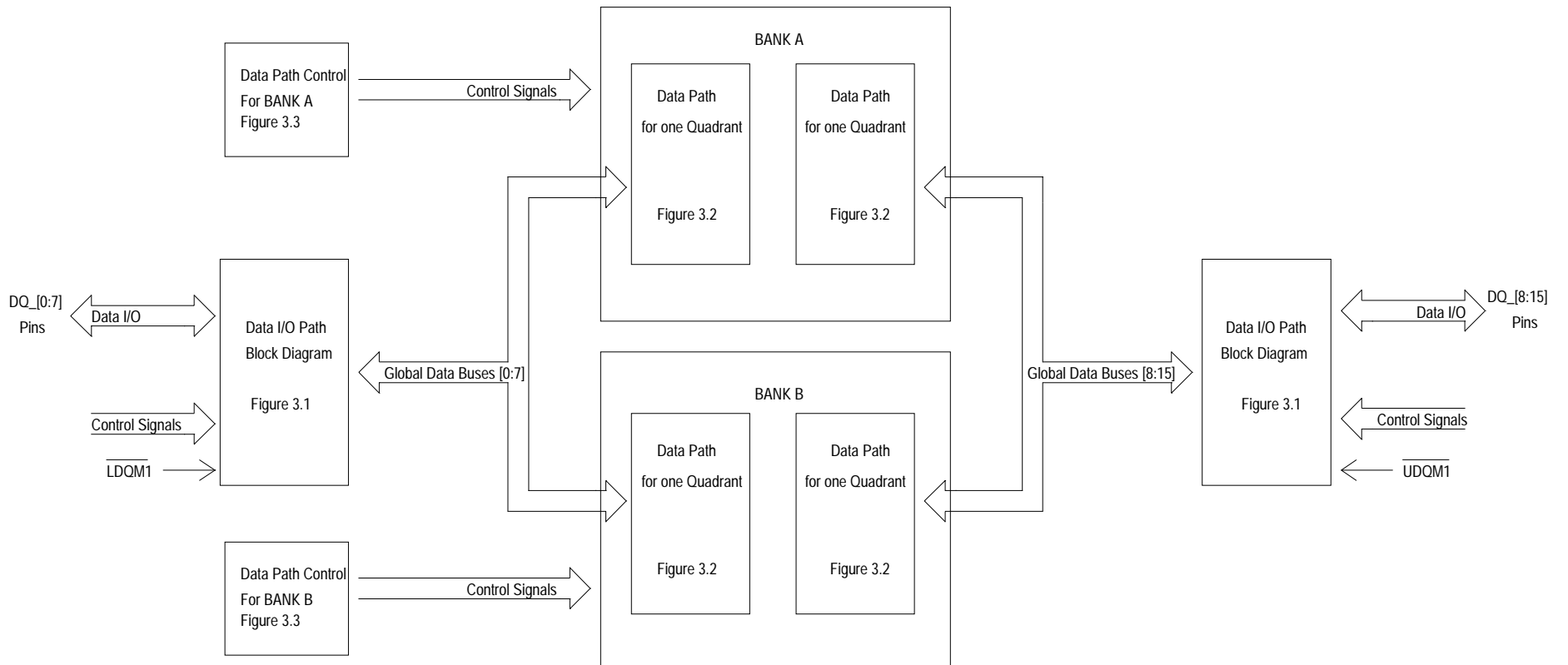


Figure 3.0 FUNCTIONAL BLOCK DIAGRAM DATA PATH

<b>Part #:</b>	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	FBDDATA
		SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:33	LOCATION:	A1
		INITIALS:	AZ, LW



**Figure 3.1 – Data I/O Path for Left Side of Die**

<b>Signal ID</b>	<b>Source</b>	<b>Destination</b>
CASLAT2		3.1
CASLAT3		3.1
CKE2	5.0	4.1, 3.1
CKPLSIL	5.0	3.2, 3.1
CLK2	5.0	4.1, 3.1
CLK2~	5.0	4.1, 3.1
DBPEL~	5.0	3.1
DQ0		3.1
DQ1		3.1
DQ2		3.1
DQ3		3.1
DQ4		3.1
DQ5		3.1
DQ6		3.1
DQ7		3.1
GDB0		3.1(BI)
GDB0~`		3.1(BI)
GDB1		3.1(BI)
GDB1~`		3.1(BI)
GDB2		3.1(BI)
GDB2~`		3.1(BI)
GDB3		3.1(BI)
GDB3~`		3.1(BI)
GDB4		3.1(BI)
GDB4~`		3.1(BI)
GDB5		3.1(BI)
GDB5~`		3.1(BI)
GDB6		3.1(BI)
GDB6~`		3.1(BI)
GDB7		3.1(BI)
GDB7~`		3.1(BI)
IO0CTRL[0:11]	3.1(BUS)	
IO1CTRL[0:11]	3.1(BUS)	
IO2CTRL[0:11]	3.1(BUS)	
IO3CTRL[0:11]	3.1(BUS)	
LDQM1~	5.0	3.2, 3.1
VREF2	7.4	5.0, 4.1, 3.1
WCAACK	5.0	3.2, 3.1

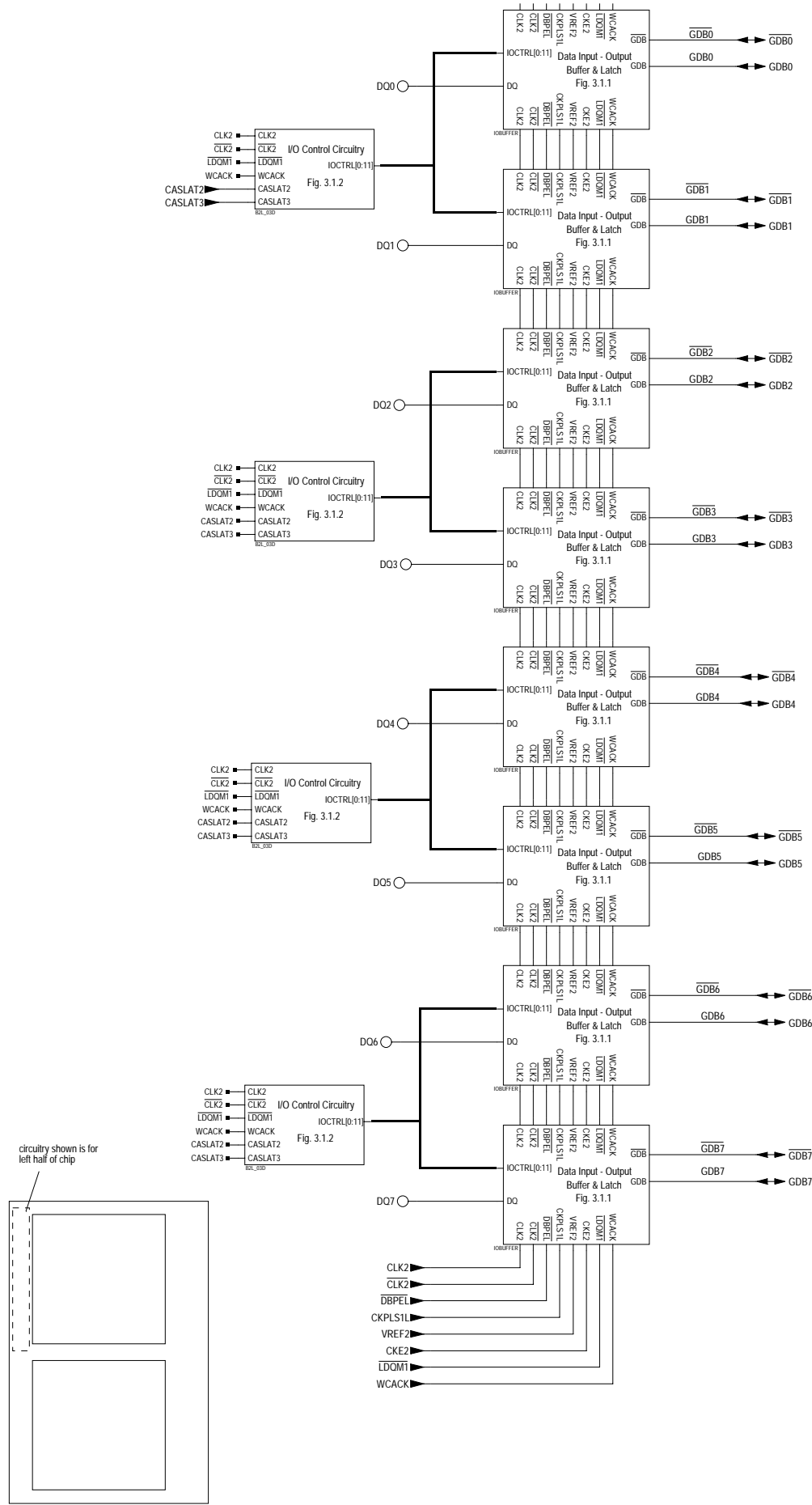


Figure 3.1 DATA I/O PATH FOR LEFT SIDE OF DIE

Part #:	SI EXAMPLE REPORT
DATE CODE:	FILE NAME OR DATE CODE
SCH. NAME:	SI NUMBER: SI01
DATE TIME:	
LOCATION: AREA B2	INITIALS: AZ, LW

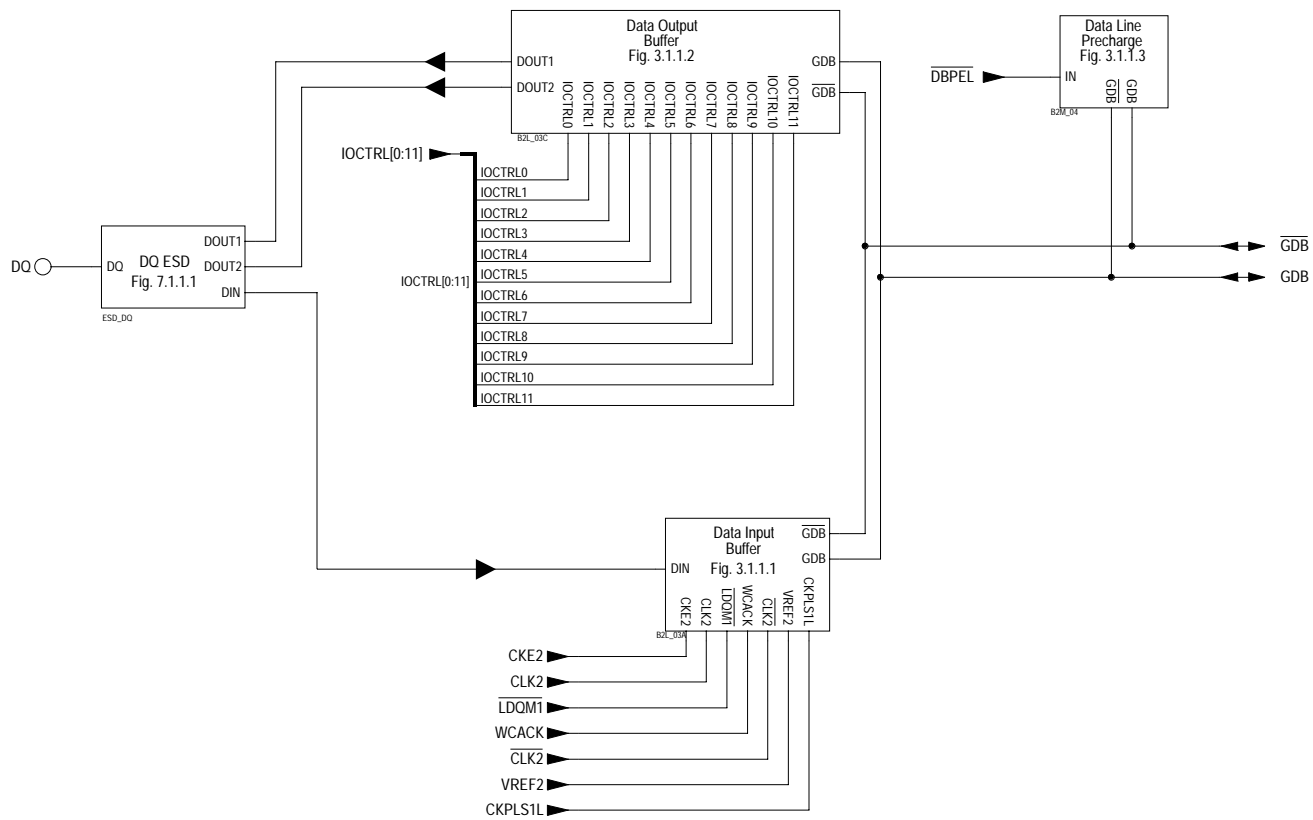


Figure 3.1.1 DATA INPUT/OUTPUT BUFFER AND LATCH

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	IOBUFFER
		SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:53	LOCATION:	XXX
		INITIALS:	AZ, LW

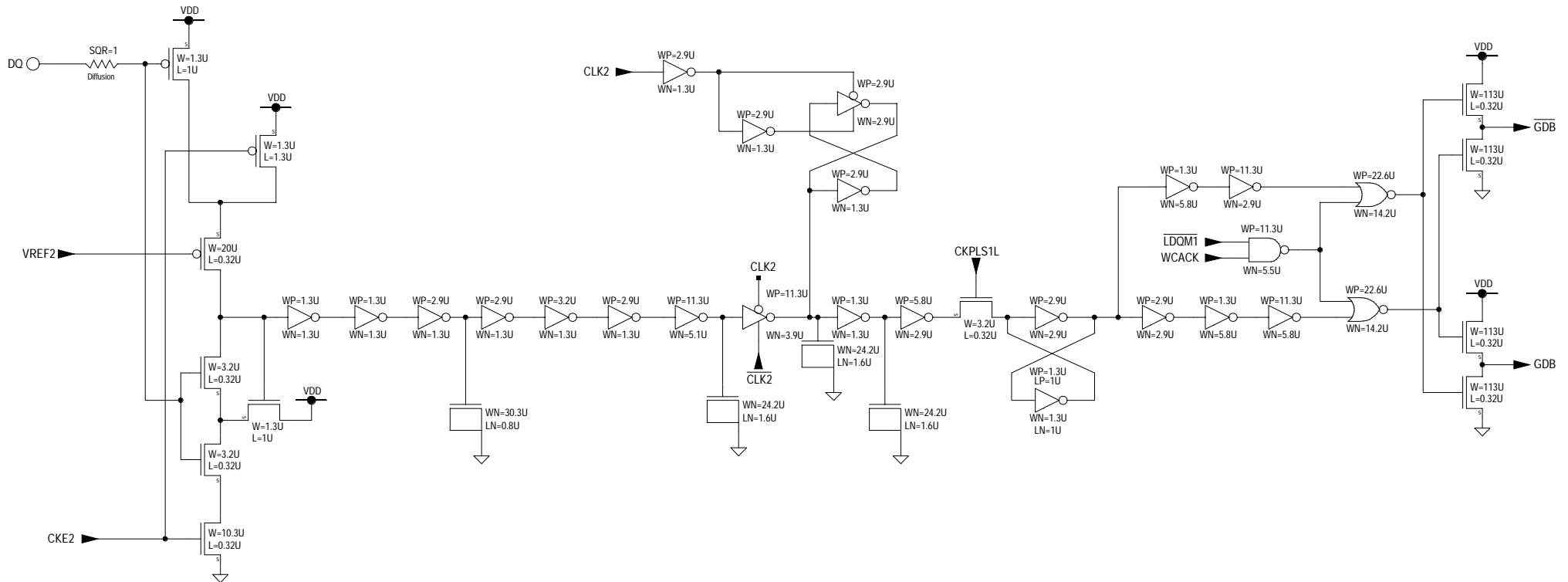


Figure 3.1.1.1 DATA INPUT BUFFER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B2L_03A
		SI NUMBER:	SI01
		DATE_TIME:	6-18-2002_8:53
LOCATION:	AREA C	INITIALS:	MW

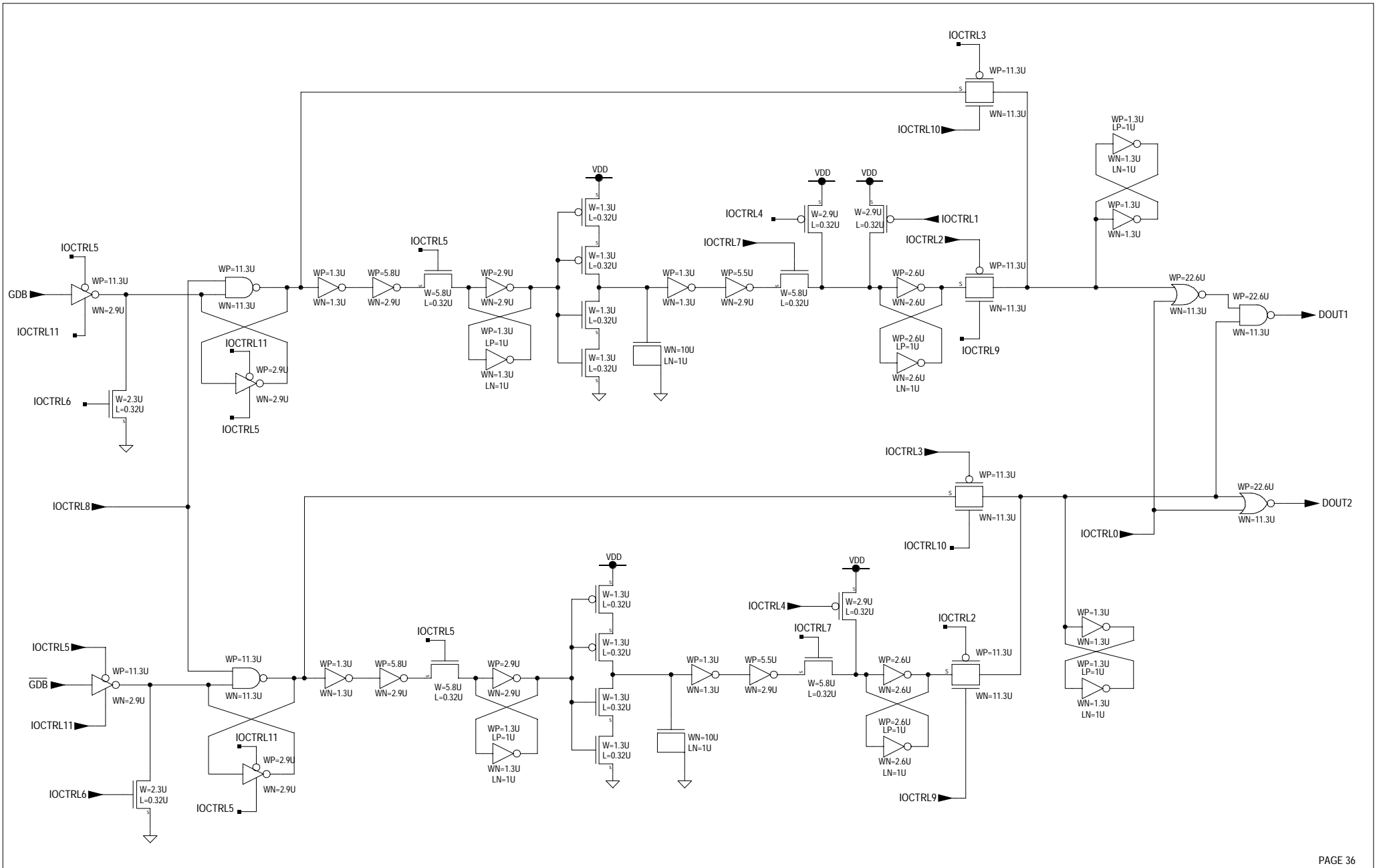
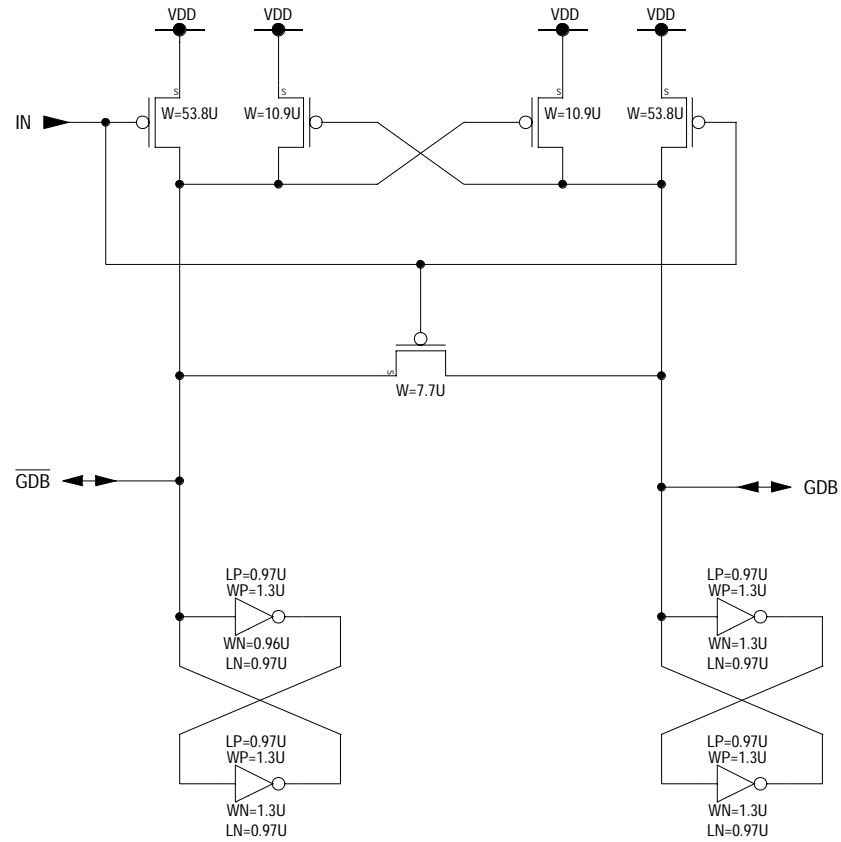


Figure 3.1.1.2 DATA OUTPUT BUFFER

<b>Part #:</b>	<b>SI EXAMPLE REPORT</b>		
<b>DATE CODE:</b>	0230	<b>SCH_NAME:</b>	B2L_03C
		<b>SI NUMBER:</b>	SI01
<b>DATE_TIME:</b>	6-18-2002_8:53	<b>LOCATION:</b>	XXX
		<b>INITIALS:</b>	AZ, LW



\*LP is assumed to be 0.32  $\mu\text{m}$  unless otherwise stated

Figure 3.1.1.3 DATA LINE PRECHARGE CIRCUITRY

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2M_04	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:53		
LOCATION:	AREA B2	INITIALS:	MW

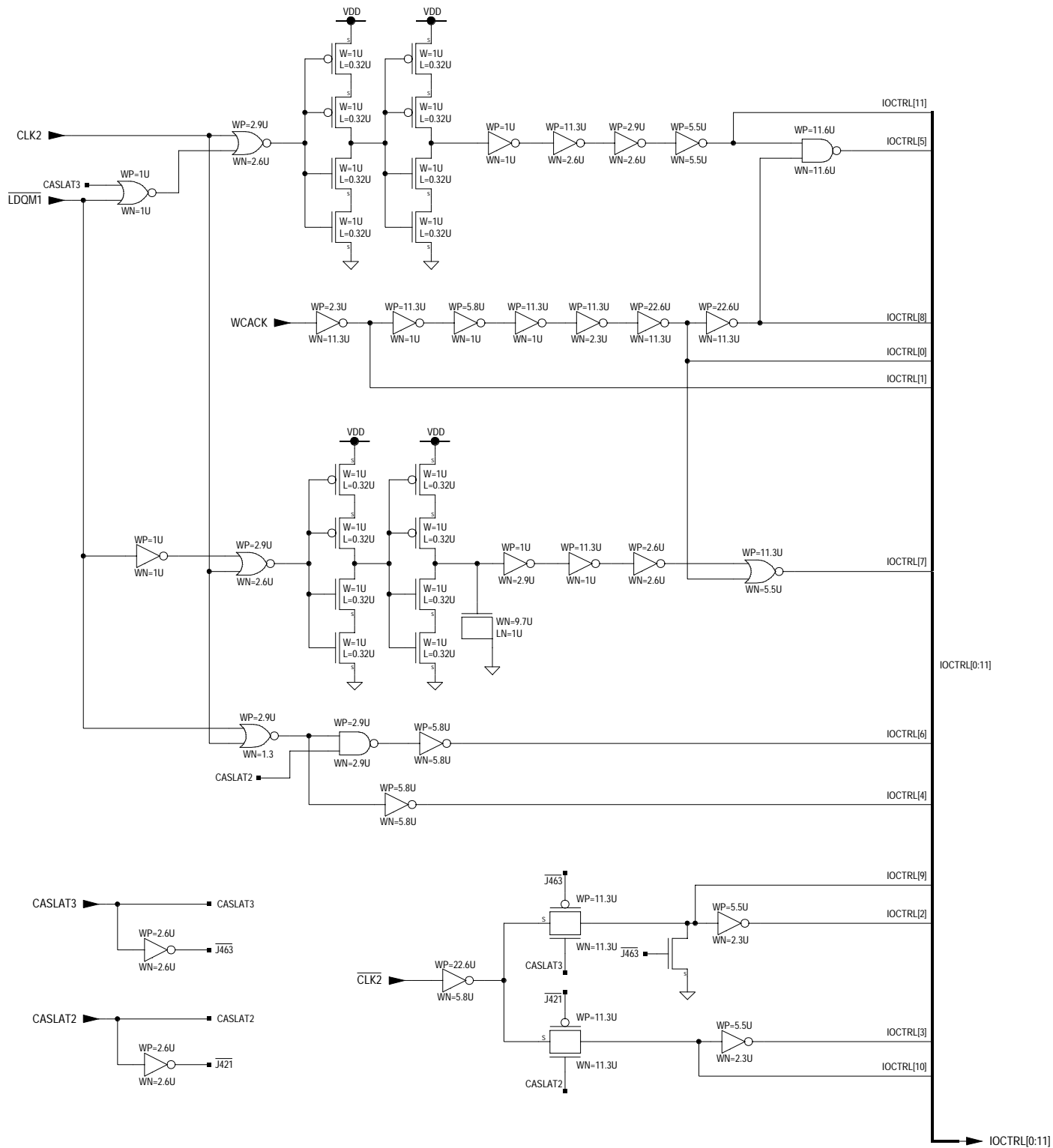


Figure 3.1.2 I/O CONTROL CIRCUITRY

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B2L_03D
SCH_NAME:	B2L_03D	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:53	LOCATION:	XXX
LOCATION:	XXX	INITIALS:	AZ, LW

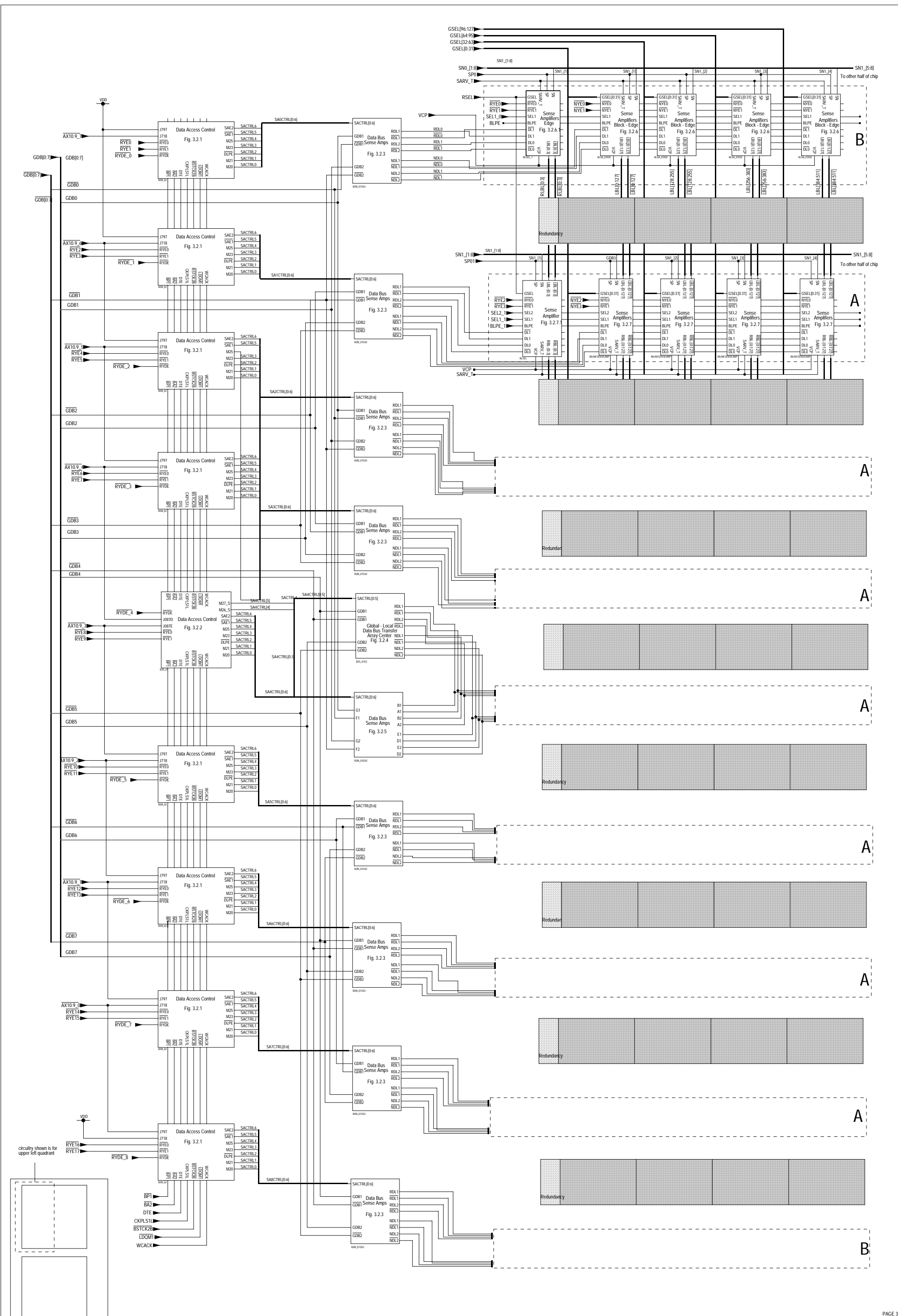


Figure 3.2 DATA PATH FOR ONE QUADRANT



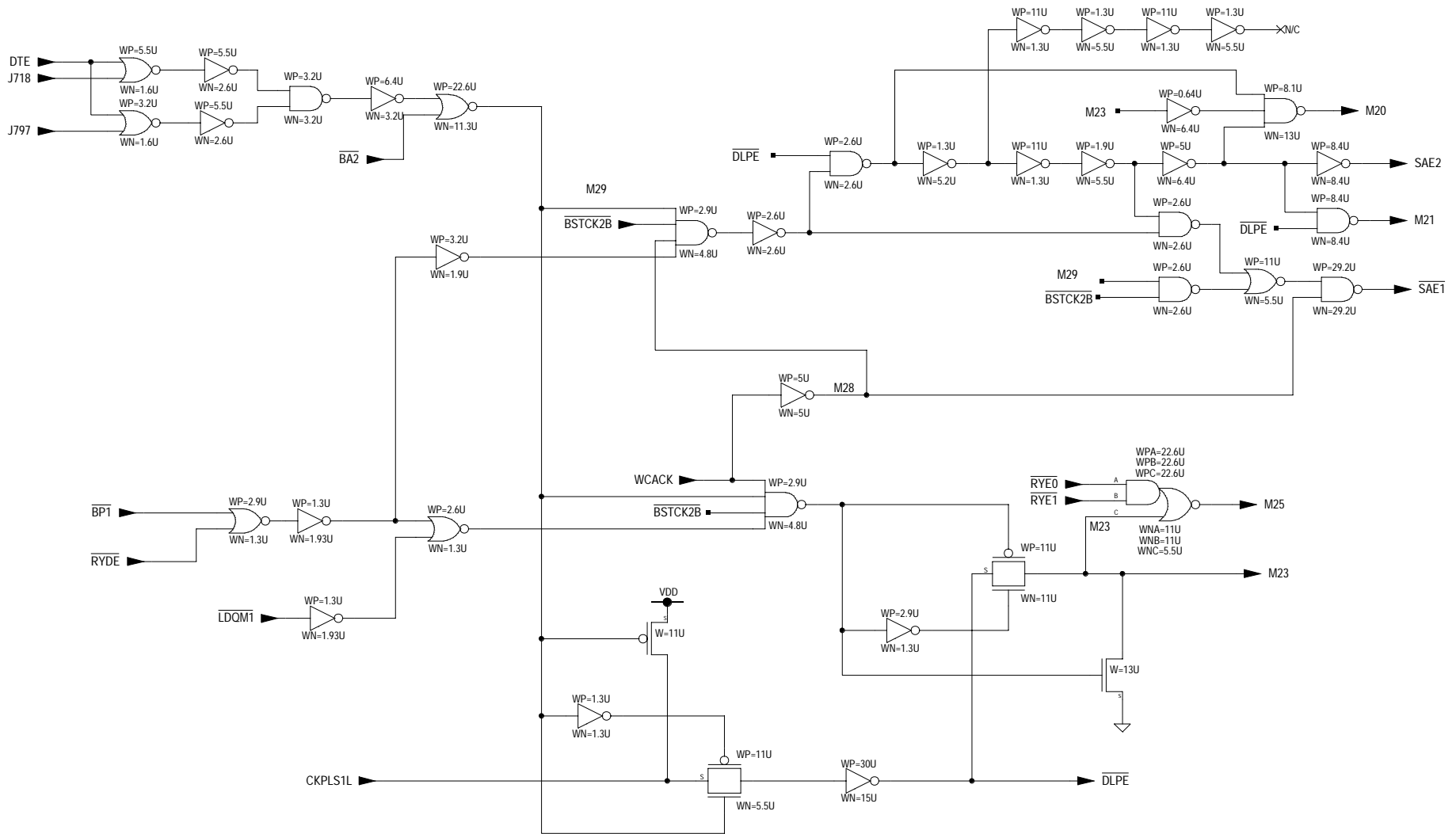


Figure 3.2.1 DATA ACCESS CONTROL

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B2M_02
		SI NUMBER:	SI01
		DATE_TIME:	6-18-2002_8:54
LOCATION:	XXX	INITIALS:	AZ, LW

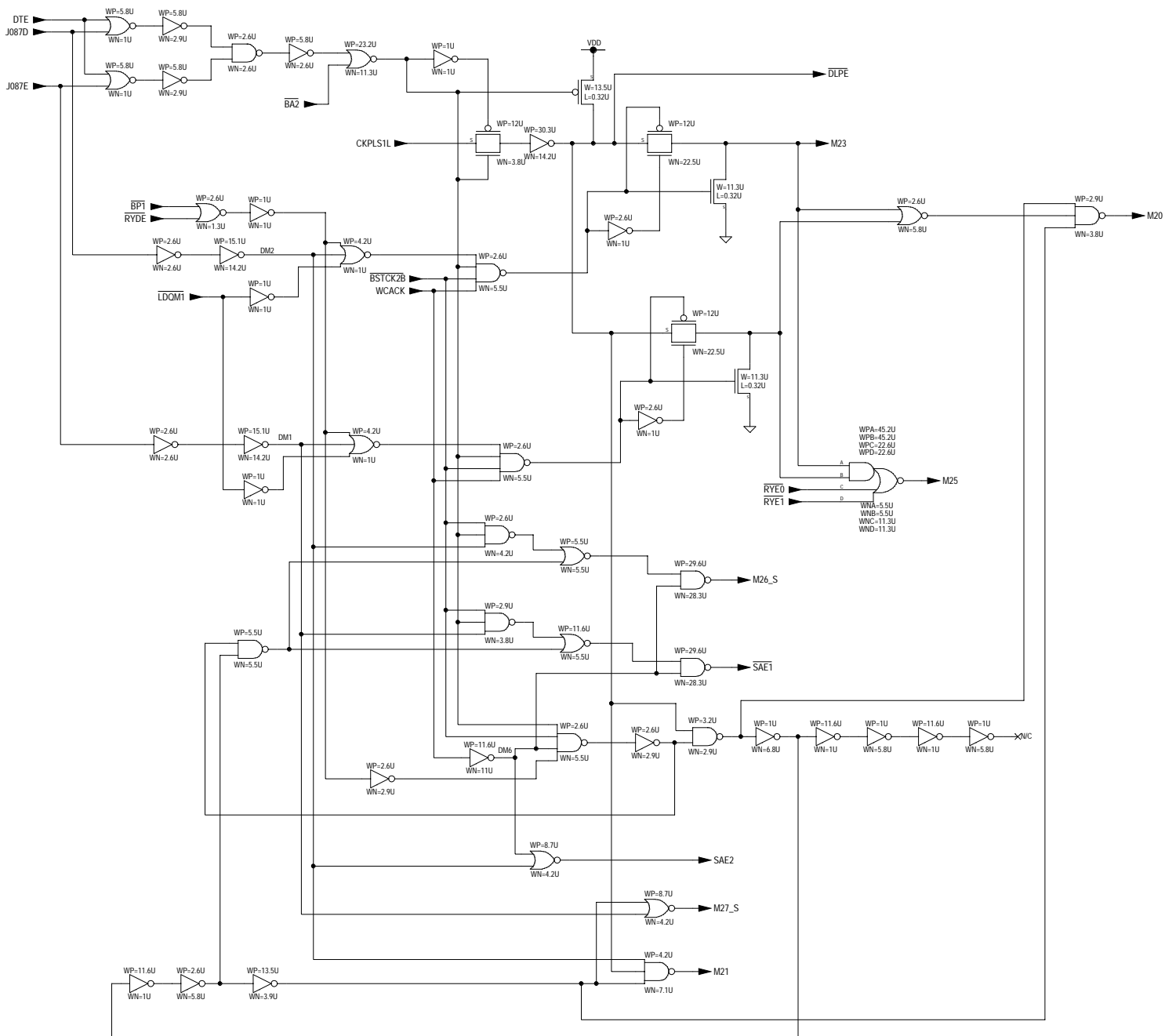


Figure 3.2.2 DATA ACCESS CONTROL

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	B2D_01
DATE_TIME:	6-18-2002_8:54
LOCATION:	XXX
SI NUMBER:	S101
INITIALS:	DM

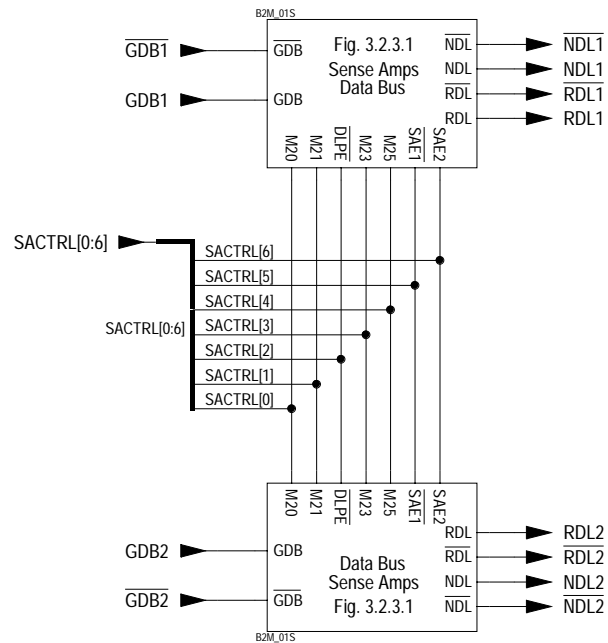


Figure 3.2.3 DATA BUS SENSE AMPLIFIERS TYPE 1

<b>Part #:</b>	<b>SI EXAMPLE REPORT</b>		
DATE CODE:	0230		
SCH_NAME:	B2M_01SX2	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55		
LOCATION:	AREA B2	INITIALS:	MW

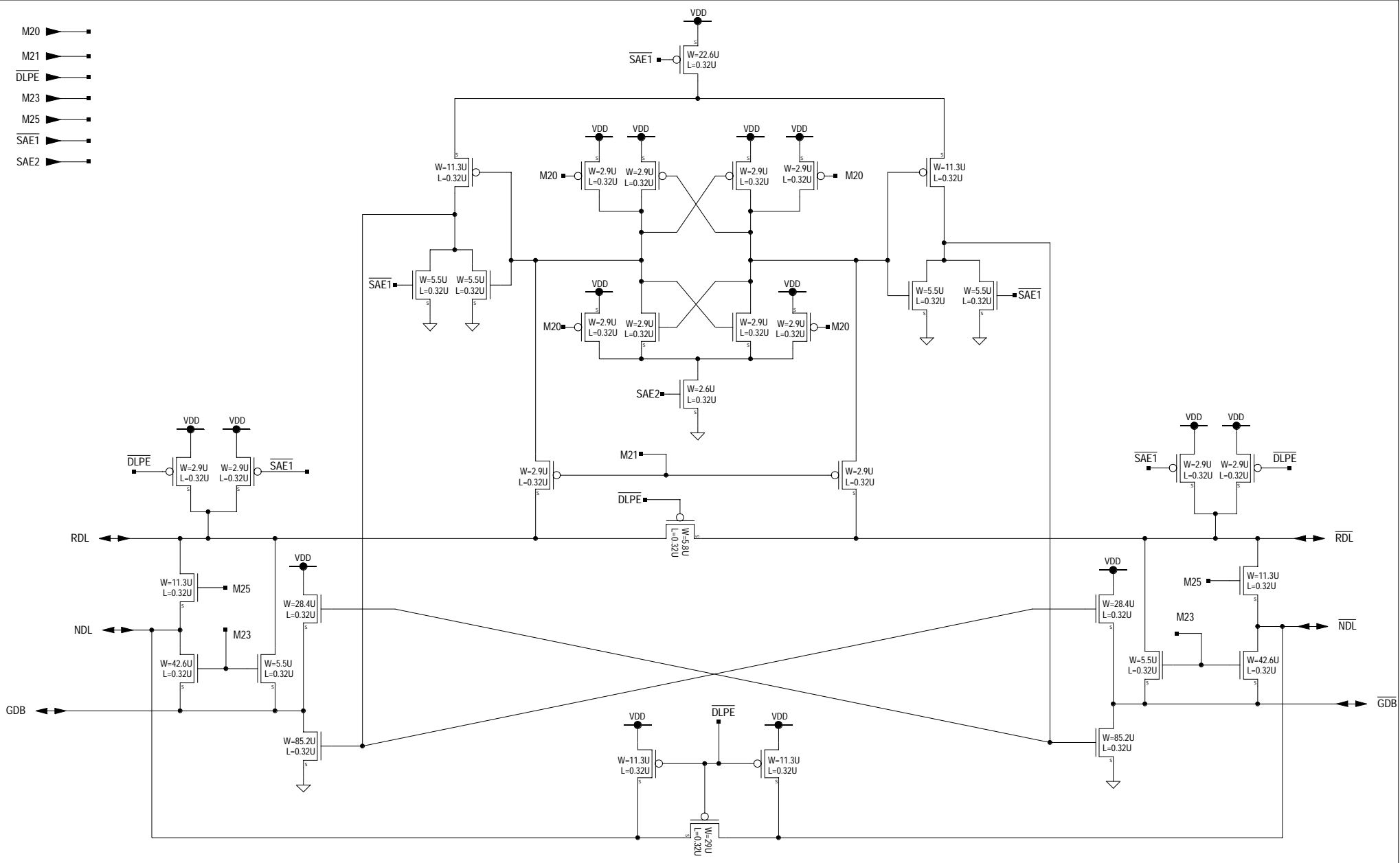


Figure 3.2.3.1 DATA BUS SENSE AMPLIFIERS

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	B2M_01S
SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55
LOCATION:	AREA B2
INITIALS:	MW

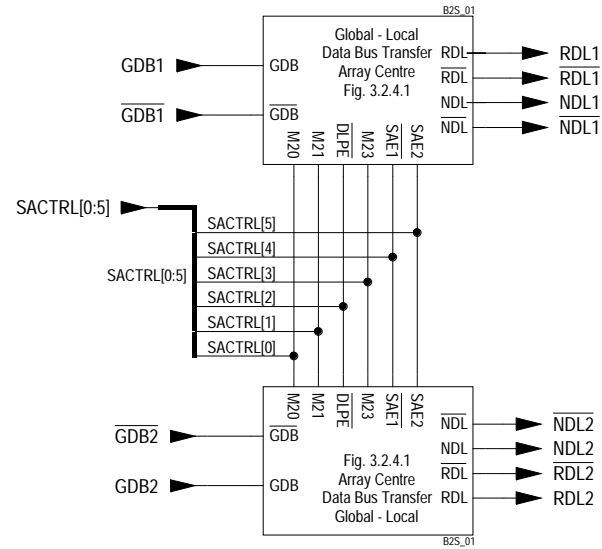


Figure 3.2.4 DATA BUS SENSE AMPLIFIERS TYPE 2

<b>Part #:</b>	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2S_01X2	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55		
LOCATION:	AREA B2	INITIALS:	MW

- M20
- M21
- DLPE
- M23
- SAE1
- SAE2

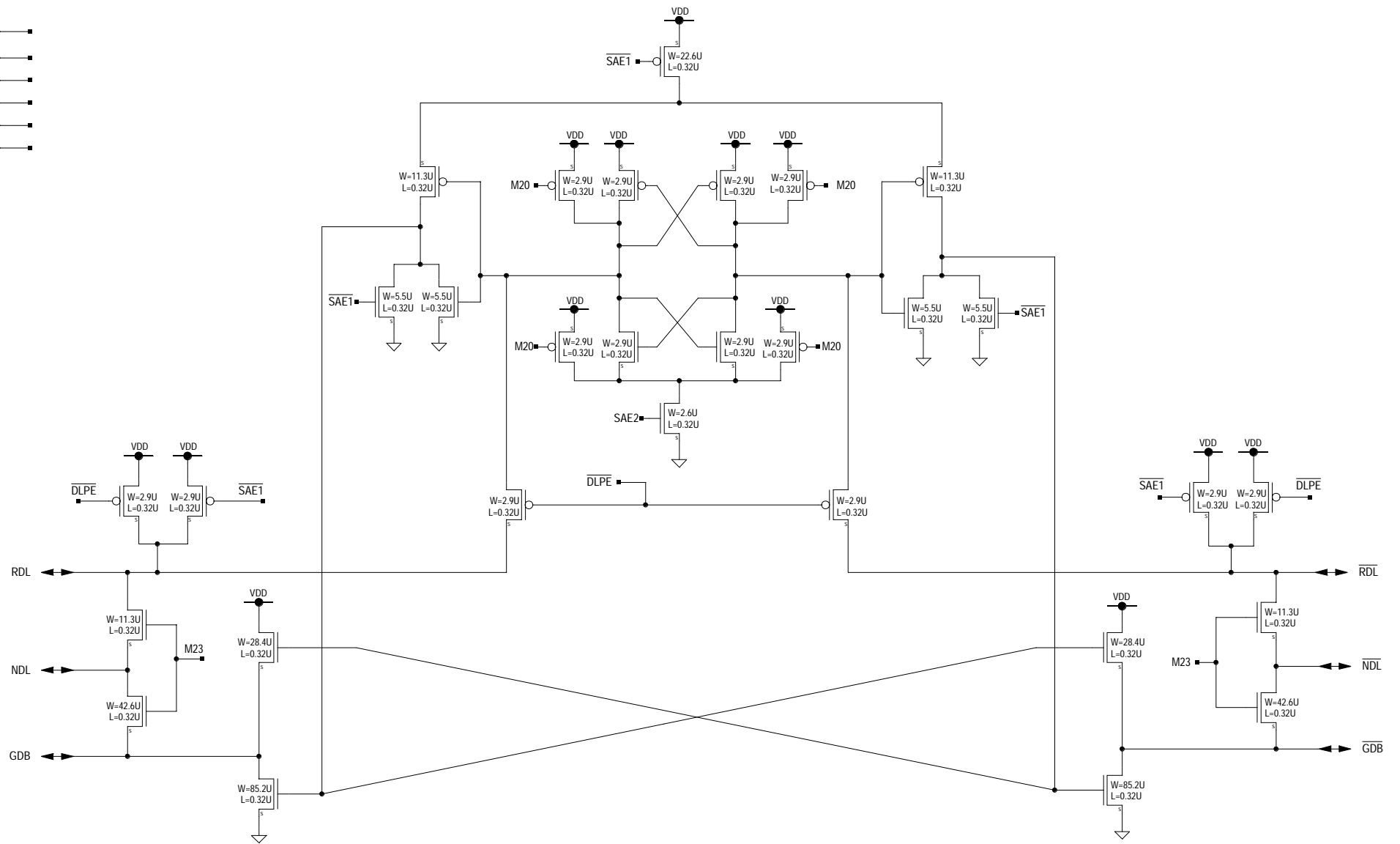


Figure 3.2.4.1 DATA BUS SENSE AMPLIFIERS

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	B2S_01
SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55
LOCATION:	AREA B2
INITIALS:	MW

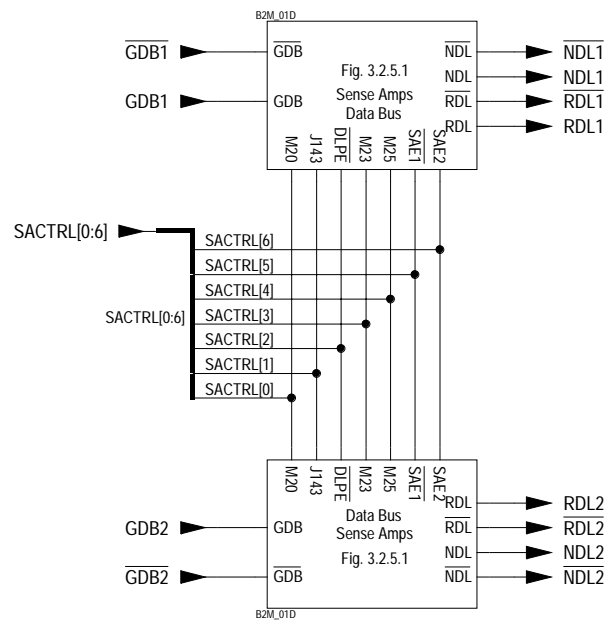


Figure 3.2.5 DATA BUS SENSE AMPLIFIERS TYPE 3

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2M_01DX2	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55		
LOCATION:	AREA B2	INITIALS:	MW

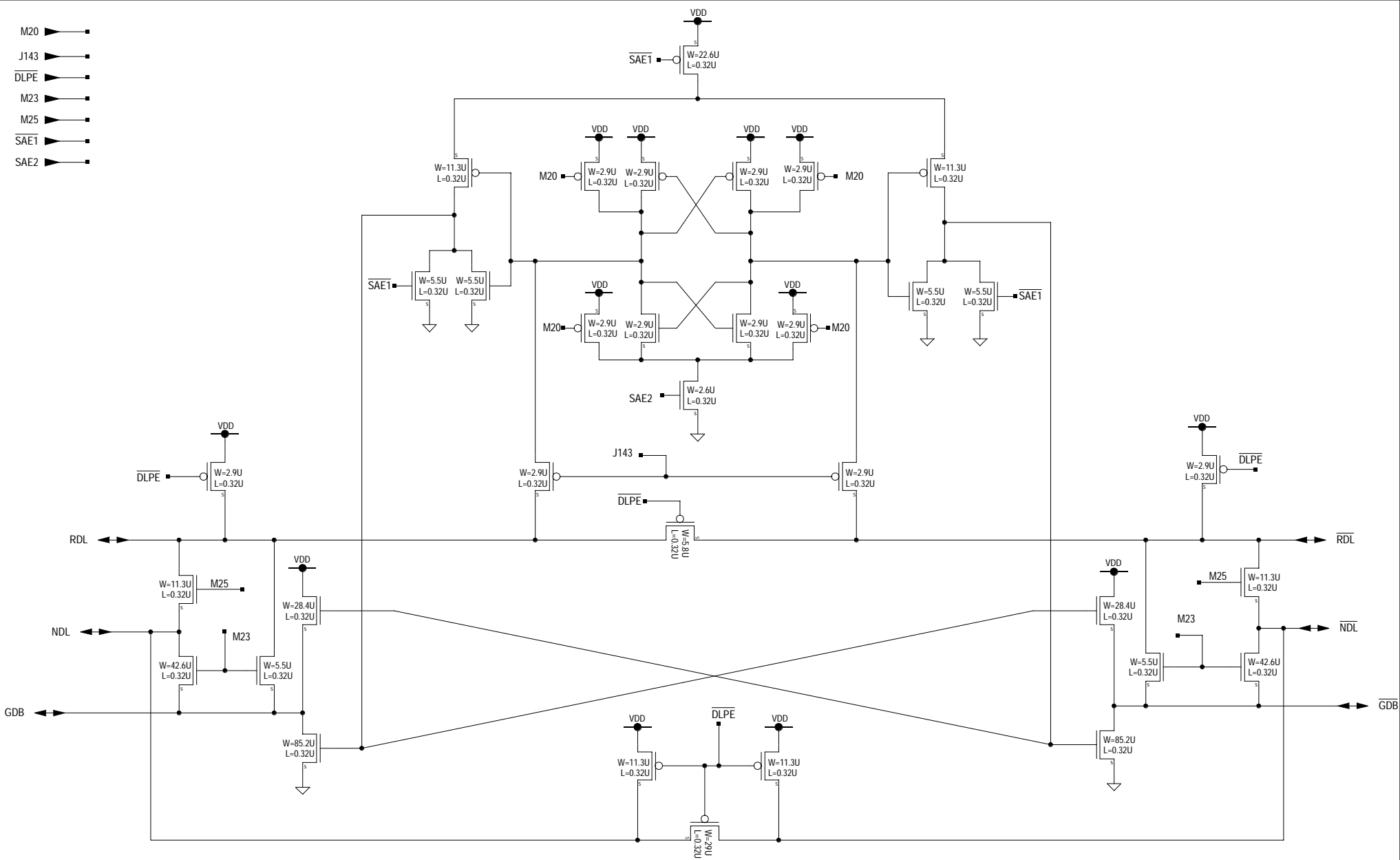


Figure 3.2.5.1 DATA BUS SENSE AMPLIFIERS

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	B2M_01D
SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55
LOCATION:	AREA B2
INITIALS:	MW



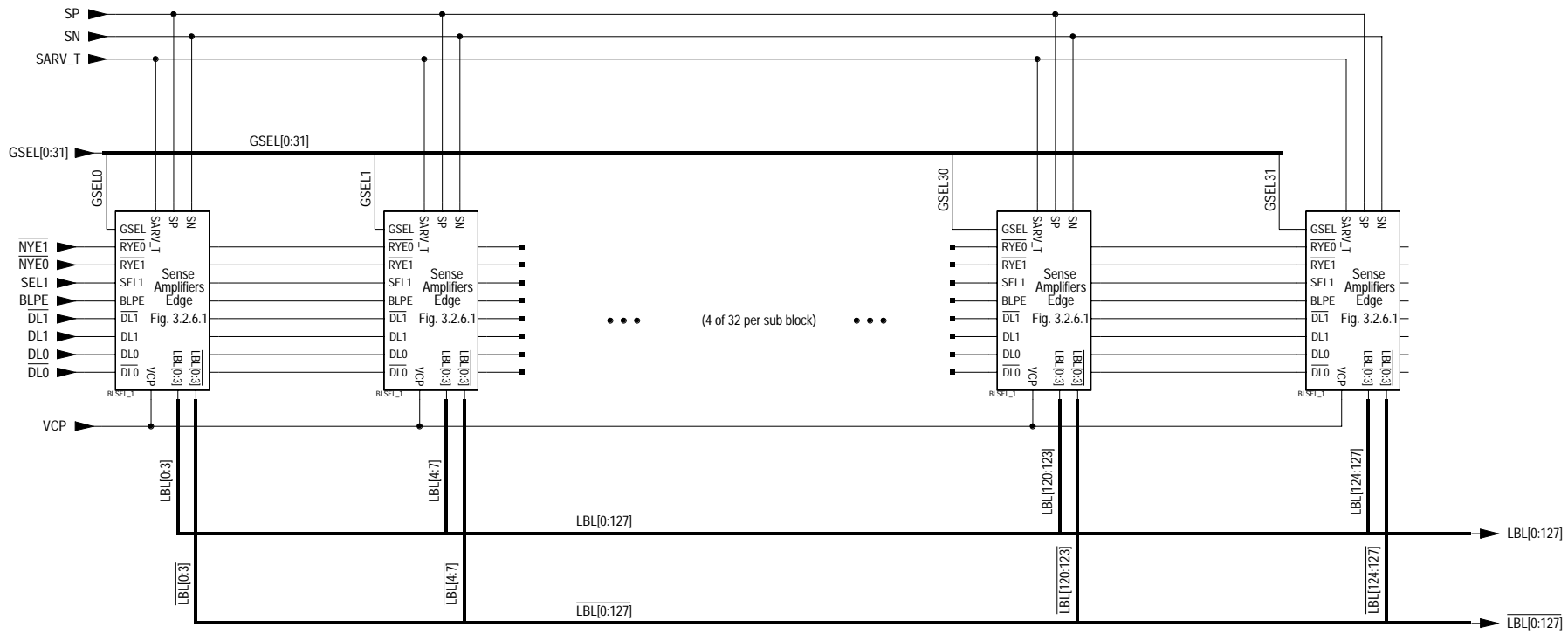


Figure 3.2.6 SENSE AMPLIFIER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	BLSA_EDGE	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55		
LOCATION:	XXX	INITIALS:	AZ, LW

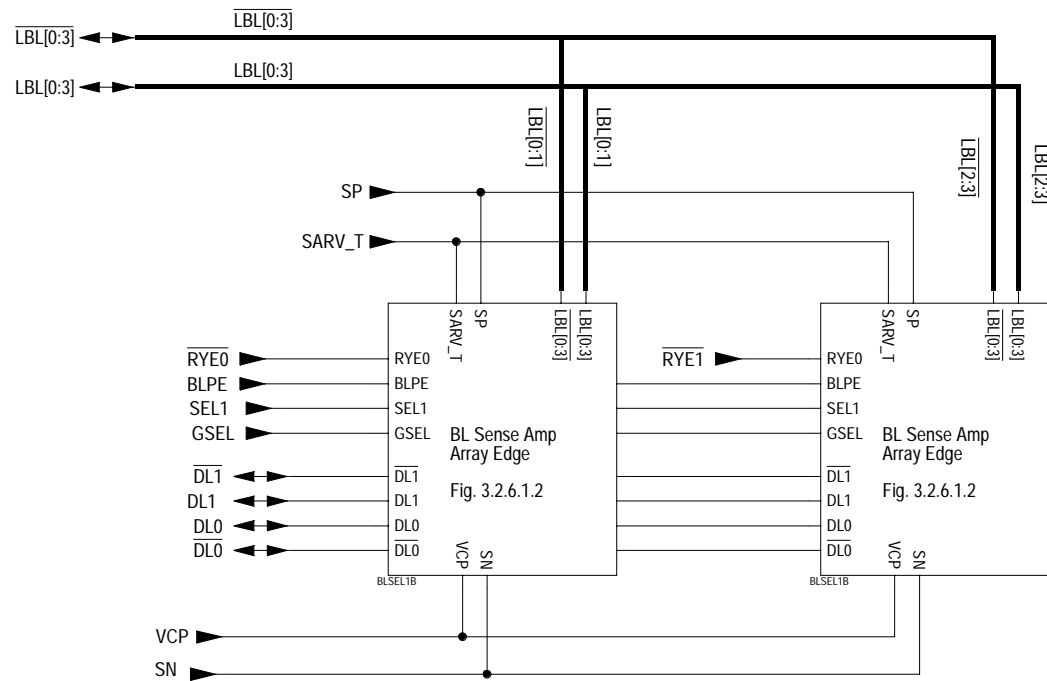
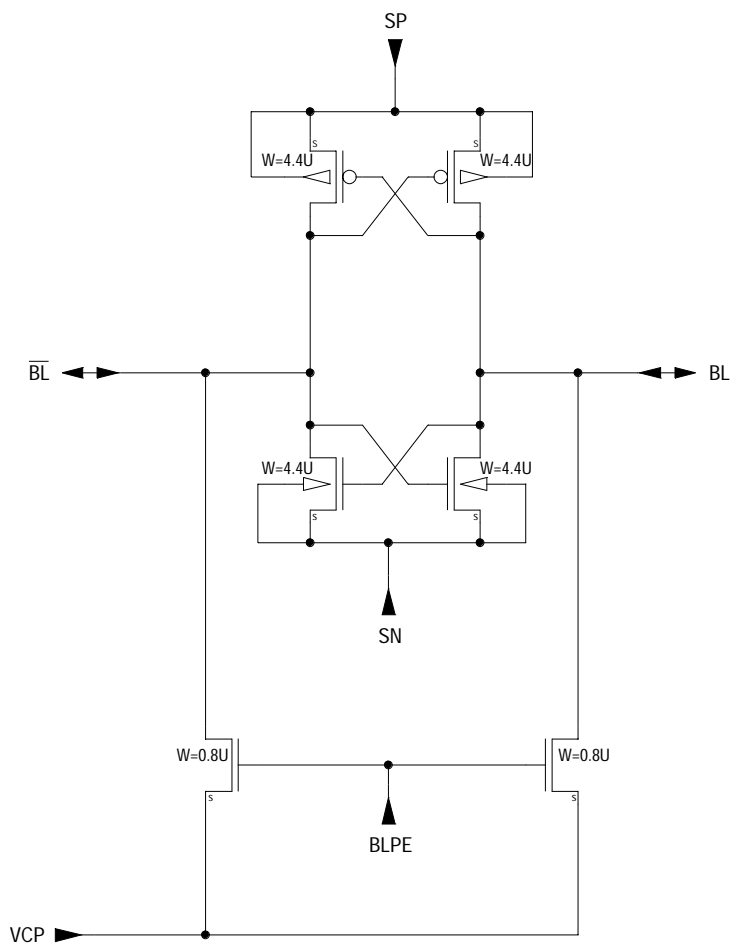


Figure 3.2.6.1 SENSE AMPLIFIERS/ BITLINE SELECTION EDGE OF MEMORY ARRAY

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	BLSEL_1	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:55		
LOCATION:	XXX	INITIALS:	XX



Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	BLEASEAMPS	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:56		
LOCATION:	XXX	INITIALS:	AZ, LW

Figure 3.2.6.1.1 SENSE AMPLIFIER

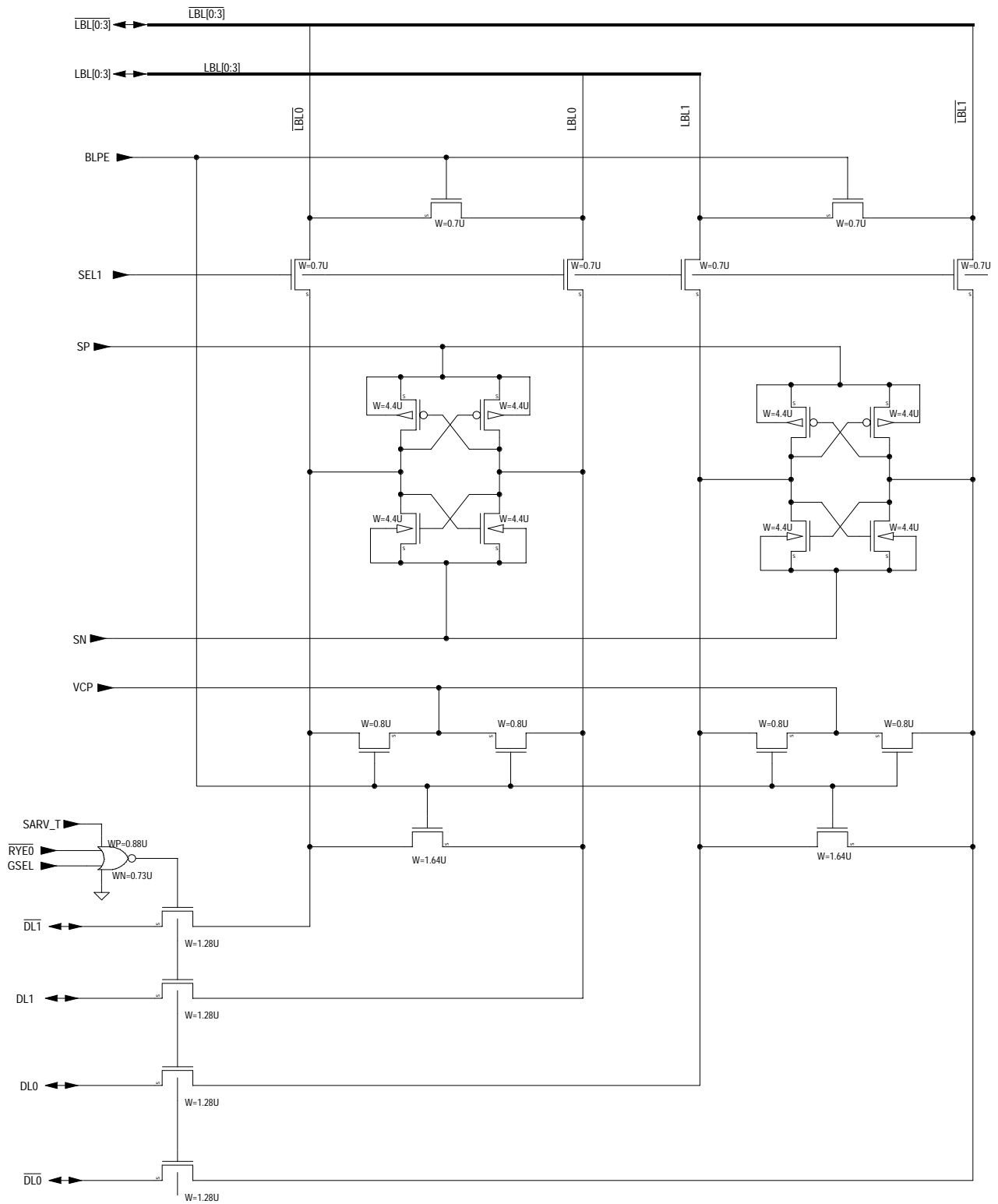


Figure 3.2.6.1.2 BIT LINE SENSE AMP ARRAY EDGE

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	BLSEL1B	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:56		
LOCATION:	XXX	INITIALS:	XX

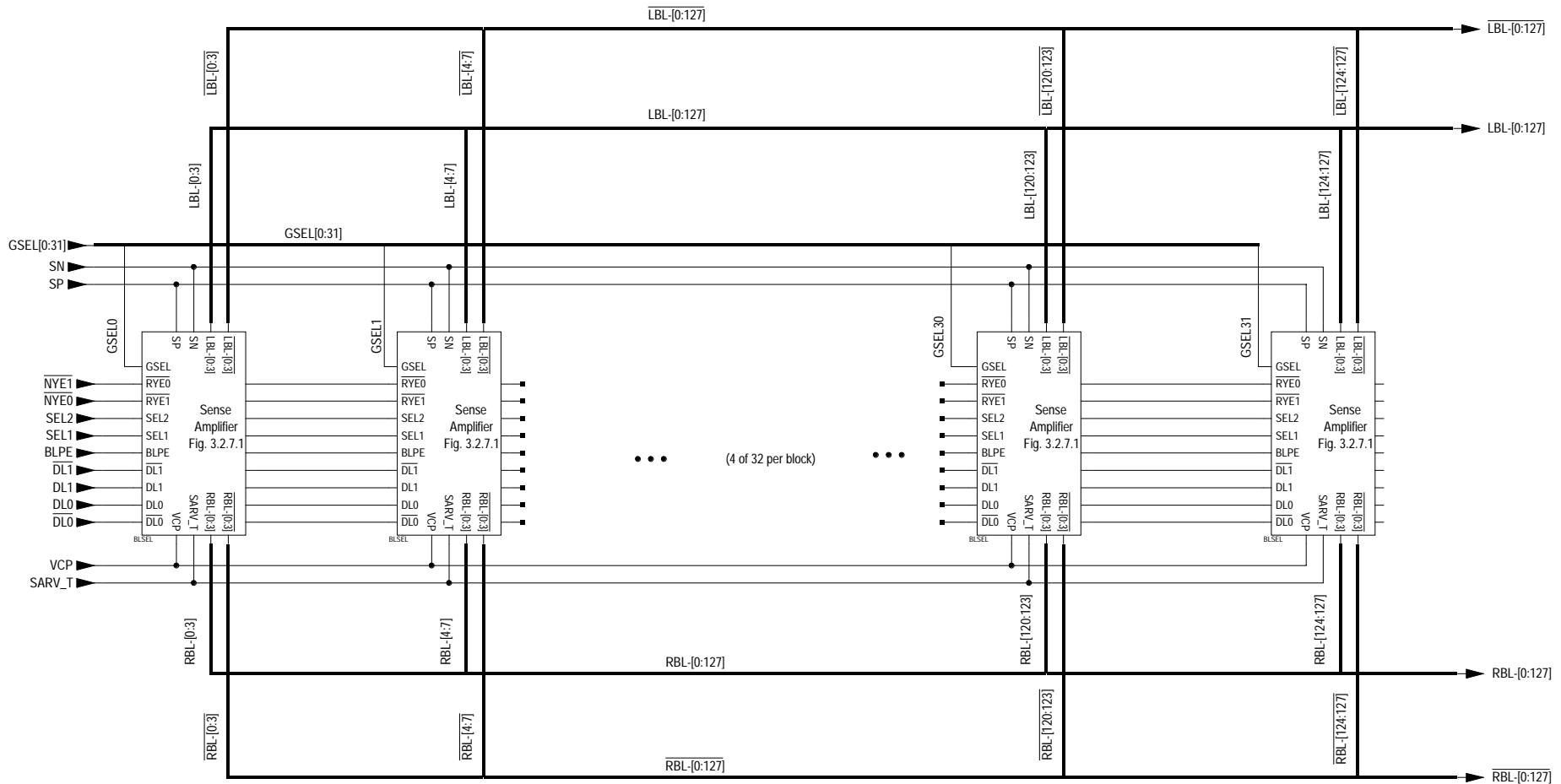


Figure 3.2.7 SENSE AMPLIFIER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	BILINESENSEAMP	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:56		
LOCATION:	XXX	INITIALS:	AZ, LW

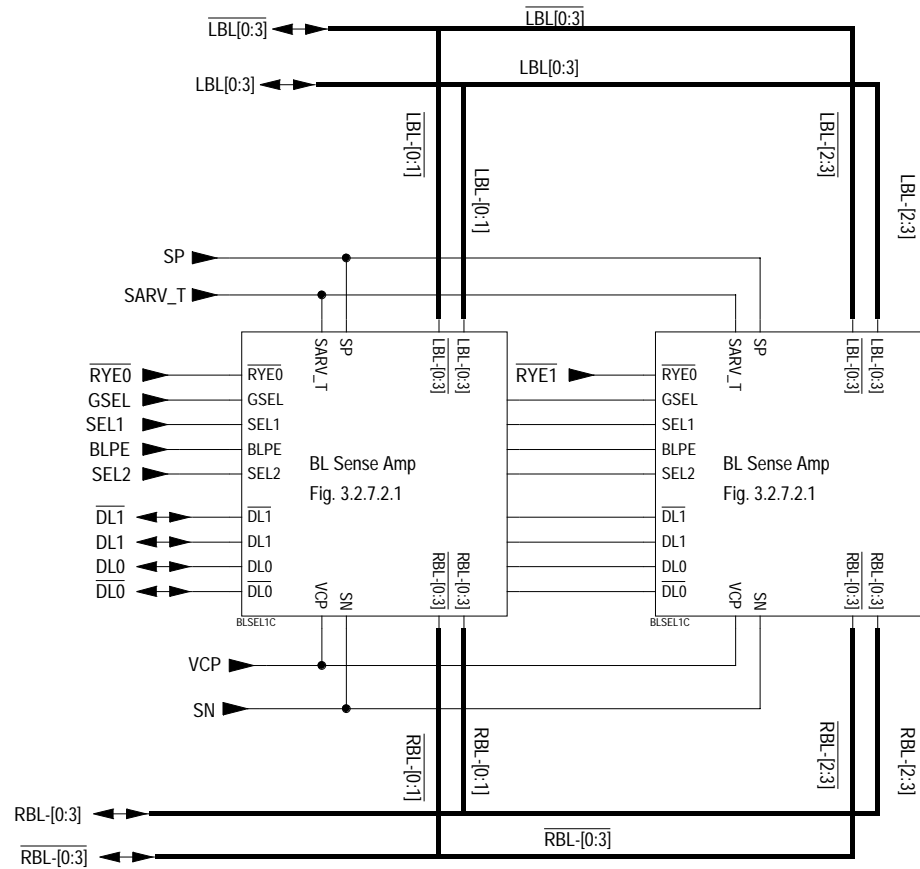


Figure 3.2.7.1 SENSE AMPLIFIERS/ BITLINE SELECTION

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	BLSEL
SCH_NAME:	BLSEL	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:56	LOCATION:	XXX
LOCATION:	XXX	INITIALS:	AZ, LW

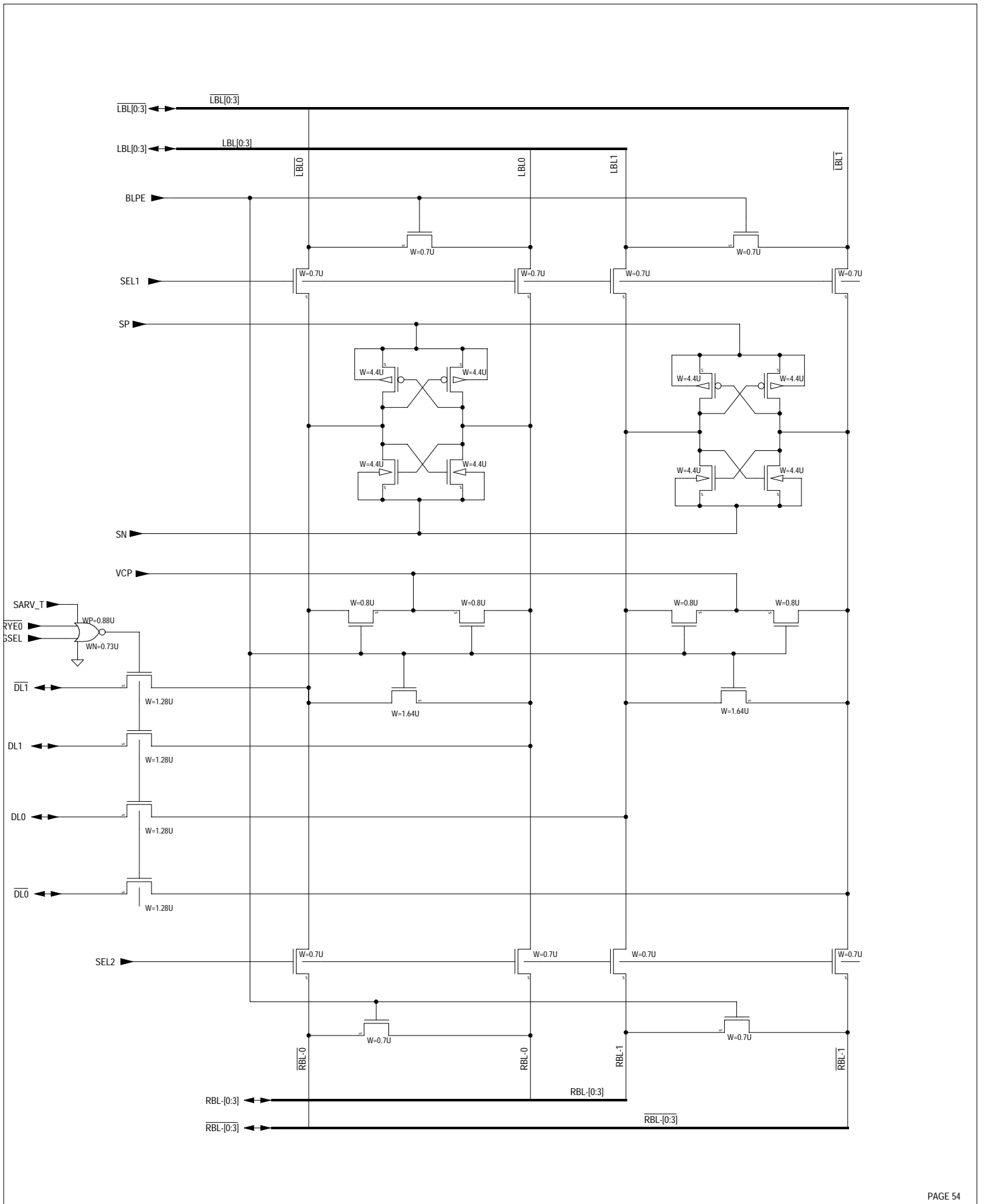


Figure 3.2.7.2 SENSE AMPLIFIERS/ BITLINE SELECTION

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	BILINSENSEAMP1	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:57		
LOCATION:	XXX	INITIALS:	AZ, LW

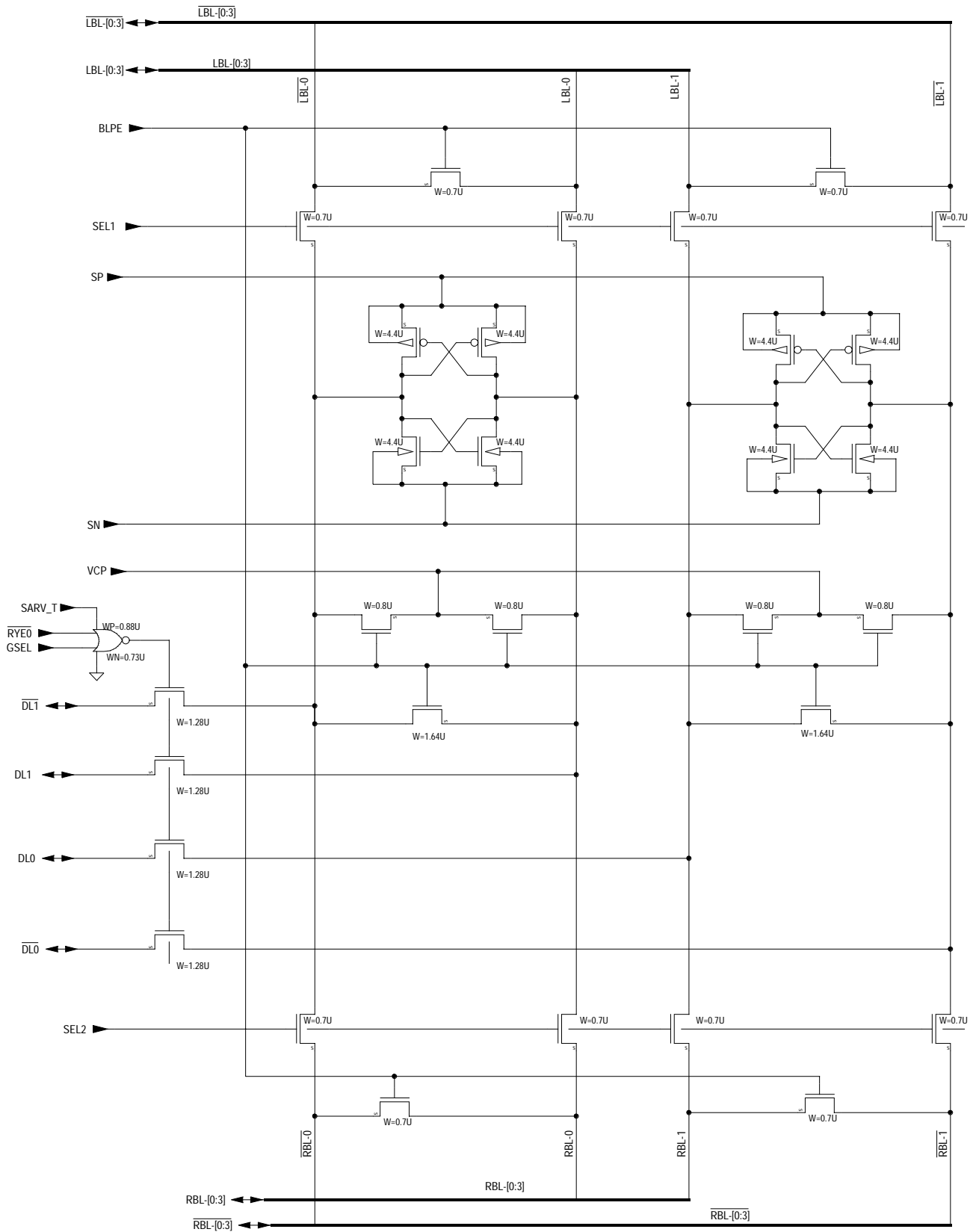
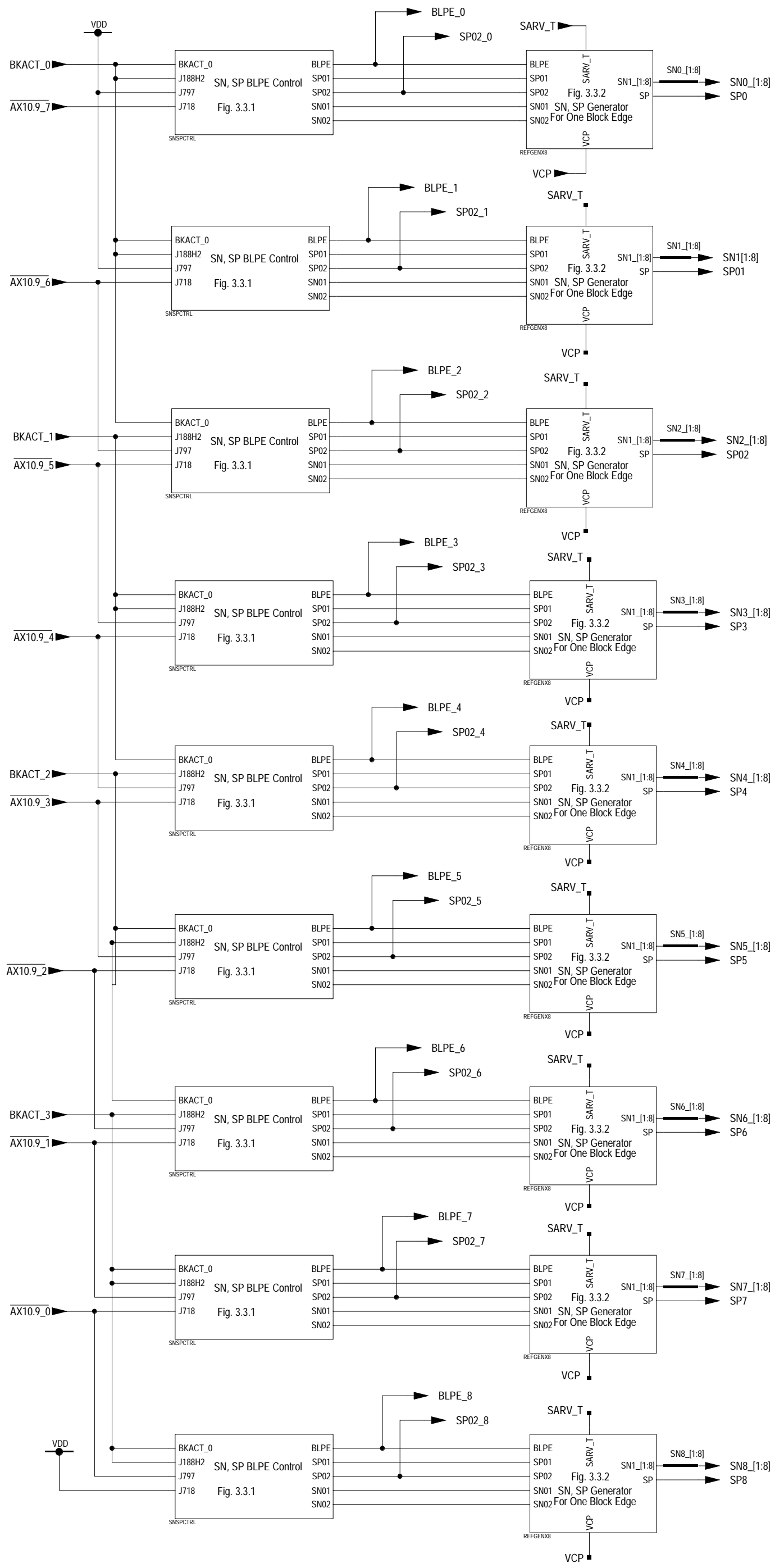


Figure 3.2.7.2.1 BIT LINE SENSE AMP

Part #:	SI EXAMPLE REPORT	
DATE CODE:	0230	
SCH_NAME:	BLSEL1C	SI NUMBER: SI01
DATE_TIME:	6-18-2002_8:57	
LOCATION:	XXX	INITIALS: AZ, LW





circuitry shown is for Bank A

Figure 3.3 DATA PATH CONTROL FOR BANK A

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	DATAPATHCTRL
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:21	LOCATION:	AREA B2
		INITIALS:	AZ, LW

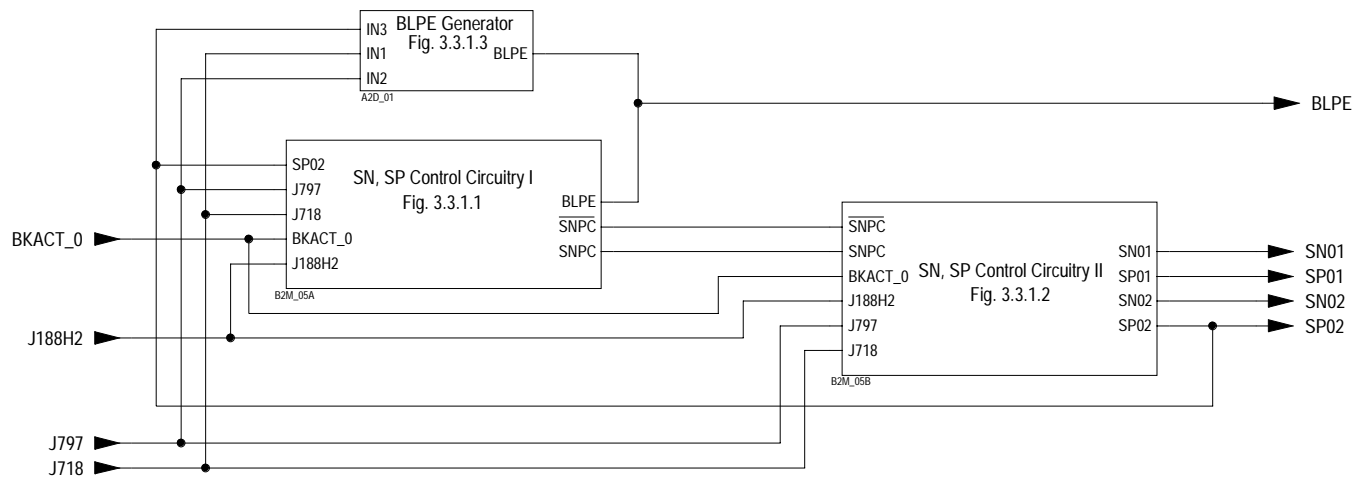


Figure 3.3.1 SN, SP CONTROL BLOCK

<b>Part #:</b>	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	SNSPCTRL	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:57		
LOCATION:	XXX	INITIALS:	AZ, LW

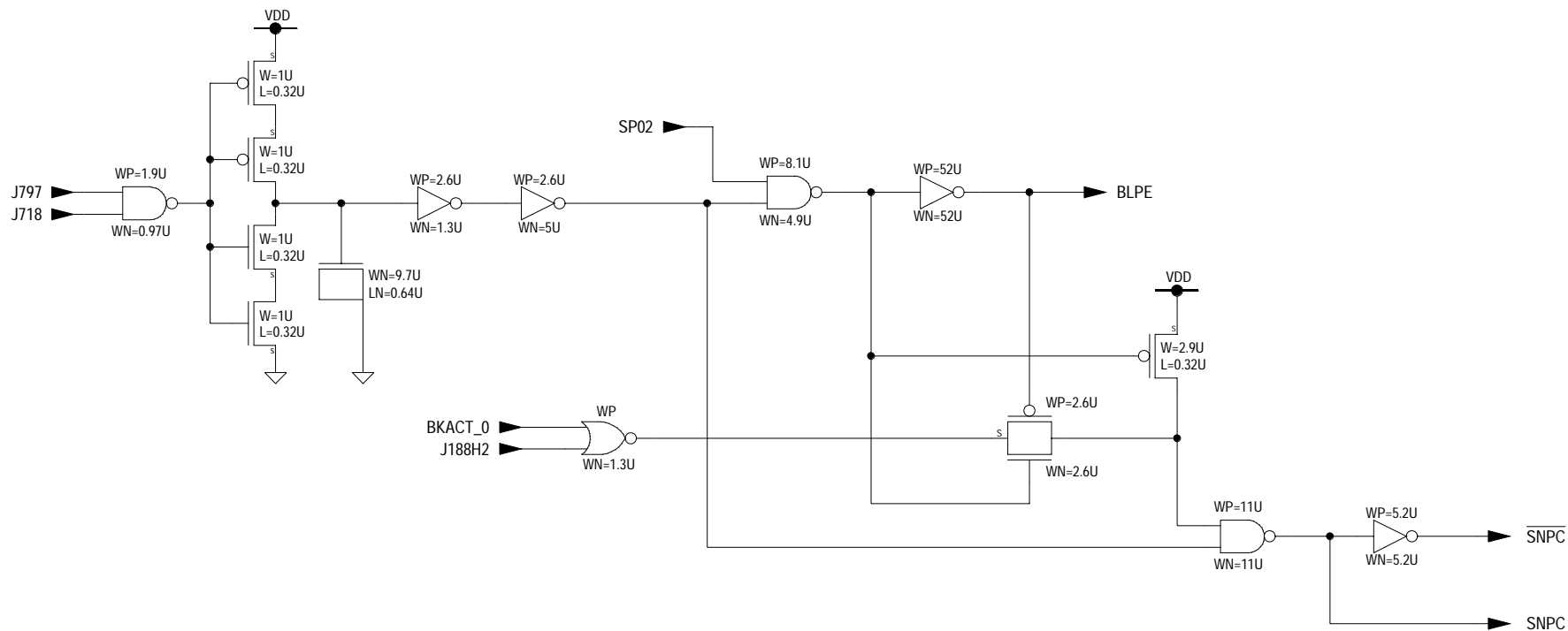


Figure 3.3.1.1 SN, SP CONTROL CIRCUITRY I

<b>Part #:</b>	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B2M_05A
		SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:58	LOCATION:	XXX
		INITIALS:	AZ, LW

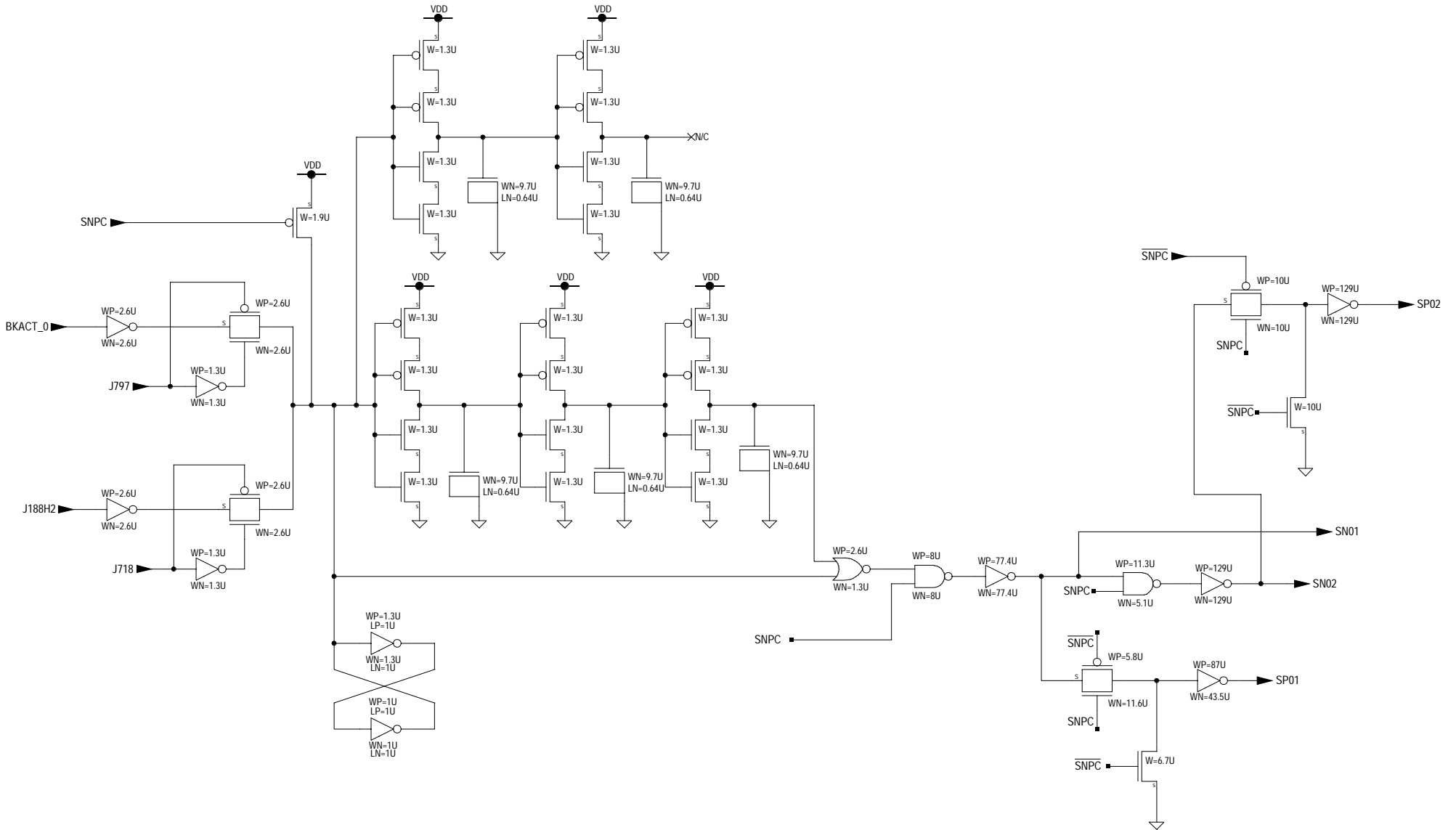


Figure 3.3.1.2 SN, SP CONTROL CIRCUITRY II

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2M_05B	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:58		
LOCATION:	XXX	INITIALS:	AZ, LW

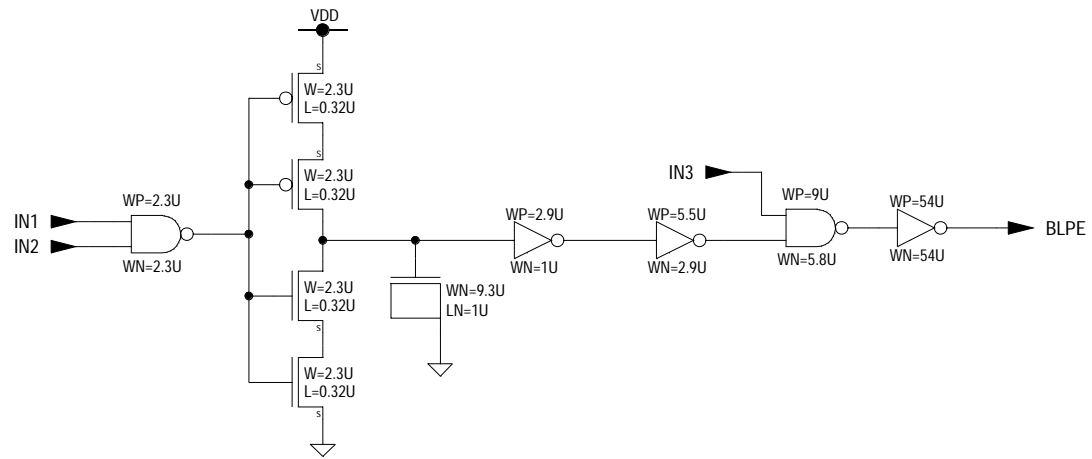


Figure 3.3.1.3 BLPE GENERATOR

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	A2D_01	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:58		
LOCATION:	XXX	INITIALS:	DM

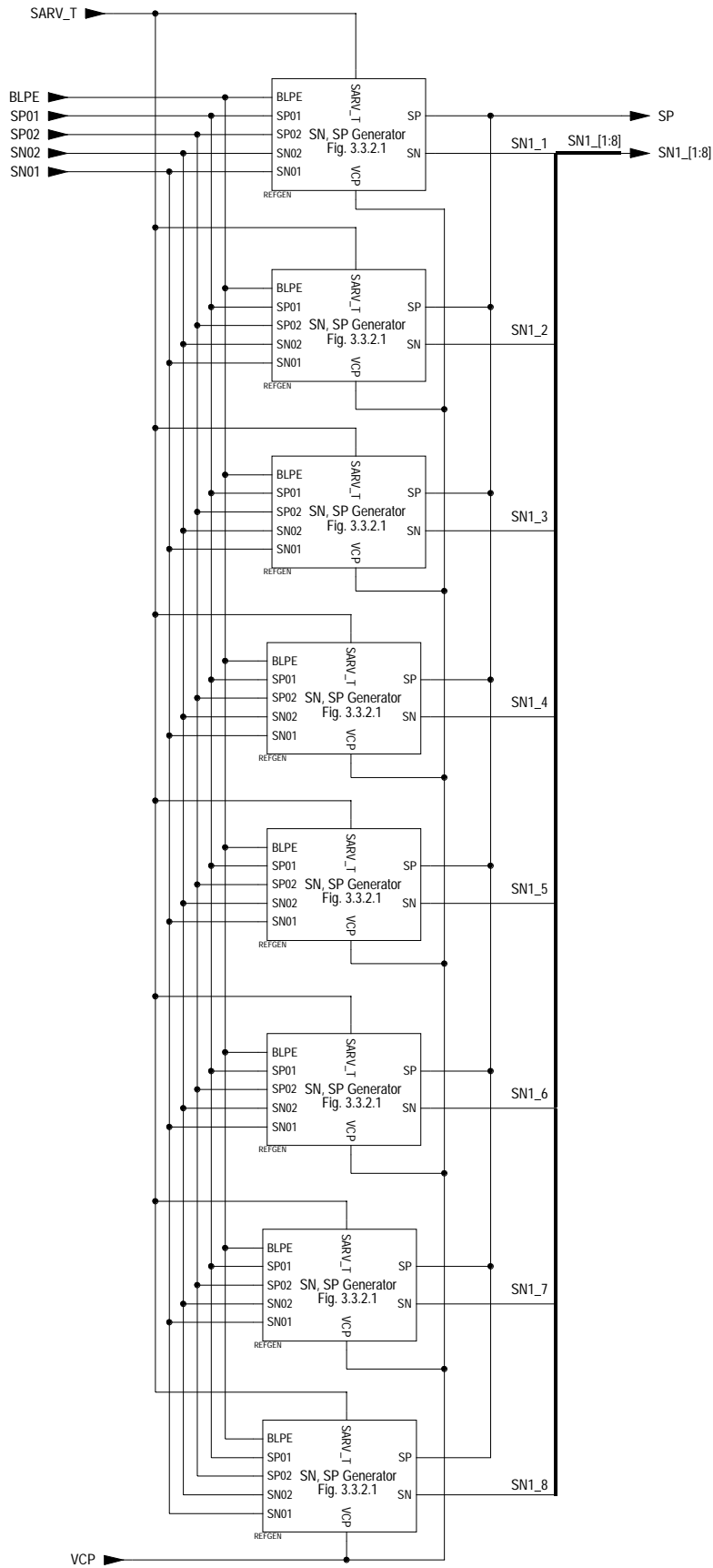


Figure 3.3.2 SN, SP GENERATION FOR ONE BLOCK EDGE

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	REFGENX8	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:58		
LOCATION:	XXX	INITIALS:	AZ, LW

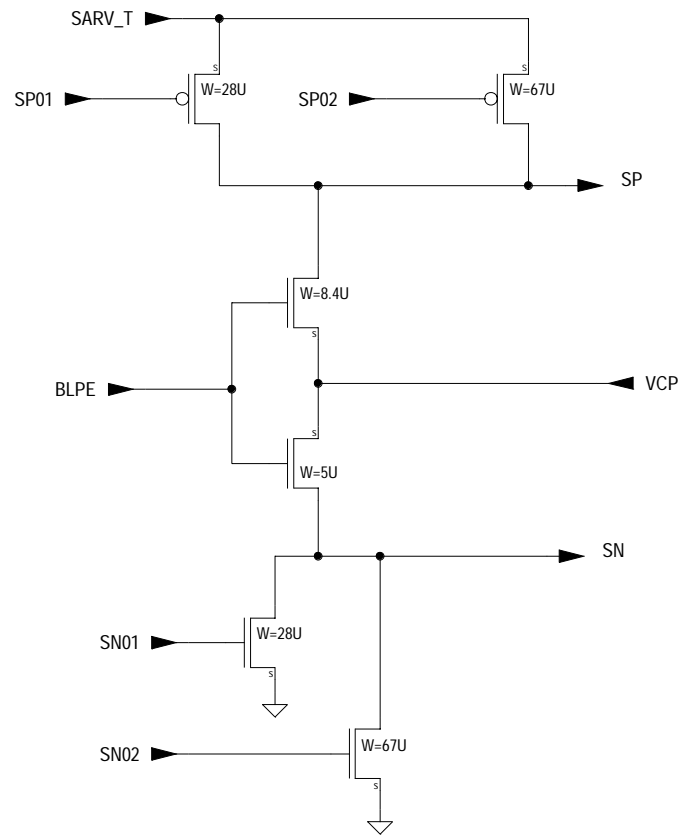


Figure 3.3.2.1 SN AND SP GENERATOR

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	REFGEN	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_8:58		
LOCATION:	XXX	INITIALS:	AZ, LW

## 4.0 Address Path

*The following section was taken from a report on a Flash device. This section is headed by a top-level diagram (Figure 4.0). The layout of this schematic has been constructed to illustrate the rough layout of the circuitry extracted. There is also a page-by-page signal list present in this section.*

*Note: The page-by-page signal list was taken directly from the original report and therefore the figure numbers are not valid for this document.*

### 4.1 Basic Operation

The two Flash banks found on the device are very similar and the address circuitry for one Flash bank is shown in Figure 4. The circuitry for this schematic is located on the left hand side of a bank of Flash cells. The address circuitry has a unique feature that may help in decreasing the access time for the memory. The feature involves the use of two wordline drivers and will be discussed in more detail below.

The address circuitry is controlled by two buses, a column address bus (AY[0:4]) and a row address bus (AX[0:10]). There may be other address signals but these were the only signals that could be identified with certainty based on the partial nature of the analysis. Both of these sets of address signals are buffered and driven into decoding circuitry. The decoding circuitry contains latches that are controlled by one of two address clocks. The latched decoded addresses are used to select one of thirty-two global bitlines or select one of 2 K wordlines in a normal read or program operation.

### 4.2 Two-Way Wordline Drivers

The unique feature of the address path is the presence of two wordline drivers. One wordline driver is used for normal read operations while the other is used for program/erase operations (Figure 4.13.7). The normal read address path uses the same addresses as the program path but the wordline driver is constructed of low voltage, high performance transistors. The low voltage wordline driver can be isolated from the wordline via a high voltage pass transistor. The isolation device is necessary because of the high voltages used during program and erase operations. Each wordline driver arrangement has some of its own address decoding circuitry. The address path for programming operations consists of a set of level shifters (Figure 4.11) and a tri-stateable wordline driver. The majority of transistors used in the programming path are high voltage low performance transistors. These transistors must be used in this path because of the high voltages used during program and erase. The two sets of wordline drivers improve the performance of the memory because the normal read operation uses high performance



transistors. Therefore the normal transistor wordline driver is faster than the high voltage wordline driver. However the high voltage wordline driver is necessary because the cell must still be programmed and erased using voltages that the normal transistor would not be able to stand.

The erase operation is accomplished with the aid of the erase block select (EBS[0:11]) signals. These signals select one of the blocks of Flash arrays described in Section 2 and in conjunction with some source line circuitry (not presented in this report) erase a block of cells. It appears that the wordline driver arrangement can also support a single wordline erase but more analysis is necessary to support this statement.

**Figure 4.0 – ADDRESS PATH**

Signal ID	Source	Destination
512EN		3
ADCK1		3; 6.1
ADCK2		3
ADLR1	3	6.1
ADLR2	3	
AX[0:10]	BUS	3; 3
AX[0:10]	BUS	3; 3
AY[0:4]	BUS	3; 3
AY[0:4]	BUS	3; 3
BAX[0:4]	BUS	3
BAX[0:4]~	BUS	3
BAX[6:10]	BUS	3
BAX[6:10]~	BUS	3
BAY[0:3]	BUS	3
BAY[0:3]~	BUS	3
BBES		3
BBLBLIO L	3	
BBLBLIOJ	3	
BBLBLI1 L	3	
BBLBLI1 U	3	
BBWL[0:15]	3	
BBWL[16:31]	3	
DAXO-4 [0:31]	BUS	3
DAXO-4 J0:31]~	BUS	3
DAX5	3	
DAX6-10 [0:31]	BUS	3
DAY[0:15]	BUS	3
EBS[0:11]	BUS	3; 3
EBS[0:11]	BUS	3; 3
ENVNPRO		3
OADRS1		3
OADRS2		3
ONRI		3
LAYO-	3	
LAYS	3	
LAYS-	3	
LAY4-	3	
LBLIO L	3	
LBLIO U	3	
MS		3
NF/BB		3
NSACS1		3
NSACS2		3

Signal ID	Source	Destination
NSAS1		3
NSAS2		3
NSEBS1		3
NSEBS2		3
NSLBLI1	3	4.6
NSLBLI2	3	4.6
NSWL1	3	4.6
NSWL2	3	4.6
NWLS[0:31] A~	BUS	3
NWLS[0:31] B~	BUS	3
NWLS[0:31] C~	BUS	3
NWLS[0:31] D~	BUS	3
P/EADS		3
P/EAEN1		3
P/EAEN2		3
P/ECSO		3
P/ECS1		3
P/ECS2		3
P/ECS3		3
P/ECS4		3
P/ECS5		3
P/EDIS	6.1	3
P/EWLSN[0:31]	BUS	3
P/EWLSP[0:31]	BUS	3
VNISO		3
VNPRO	3	
VPERS		3; 6.1
VPISO		3
VPNR		3; 4
VPNRI		3
VPPRO		3
VP VNPRO		3
WL[0:31]	3	
YADCK1		3
YADCK2		3
YADEN1		3
YADEN2		3
YADRS		3
Y[0:15]	BUS	3; 4; 4
Y[0:15]	BUS	3; 4; 4

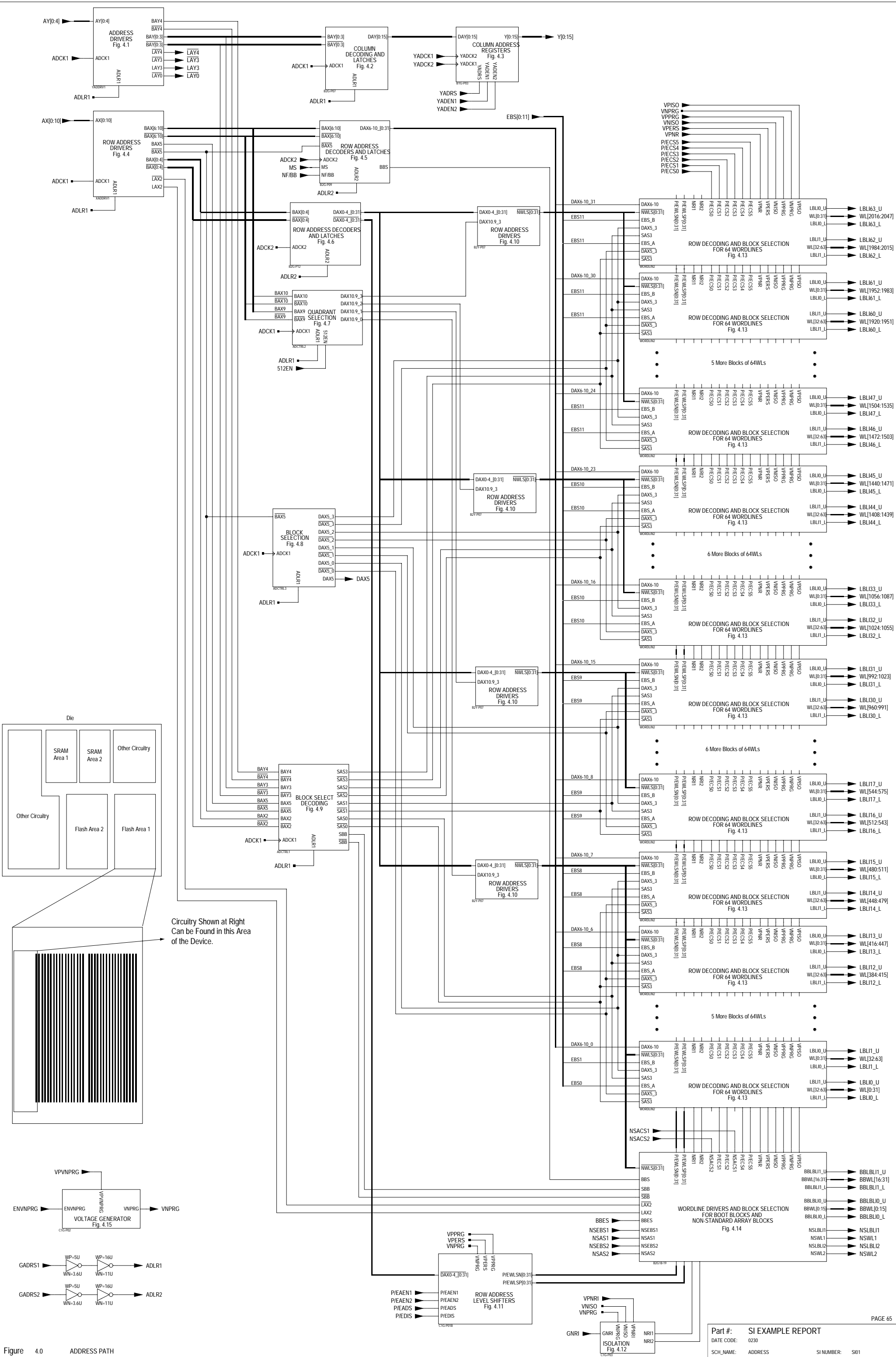


Figure 4.0 ADDRESS PATH

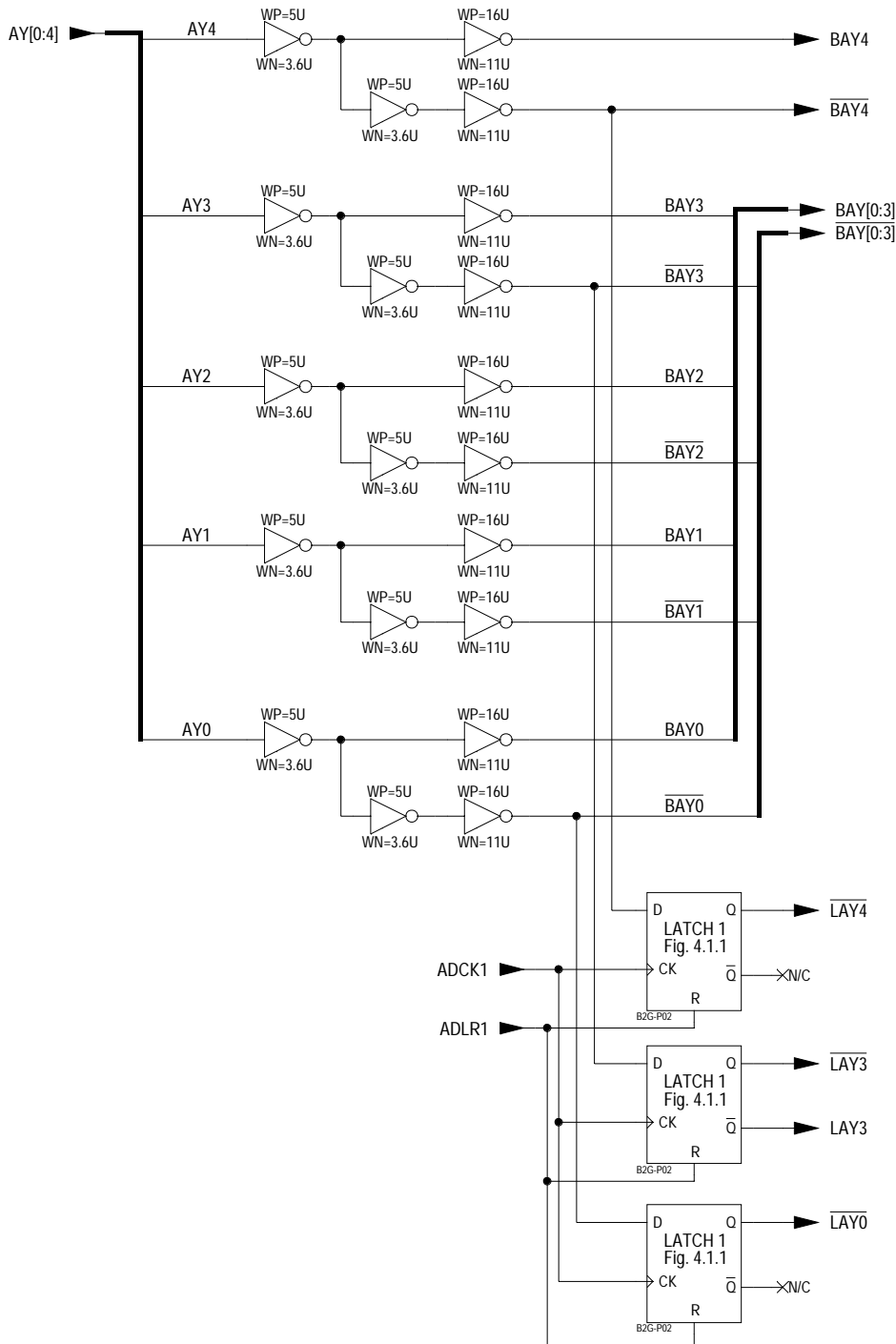


Figure 4.1 COLUMN ADDRESS DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	YADDRV1	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:51		
LOCATION:	BLOCK_NAME	INITIALS:	GM

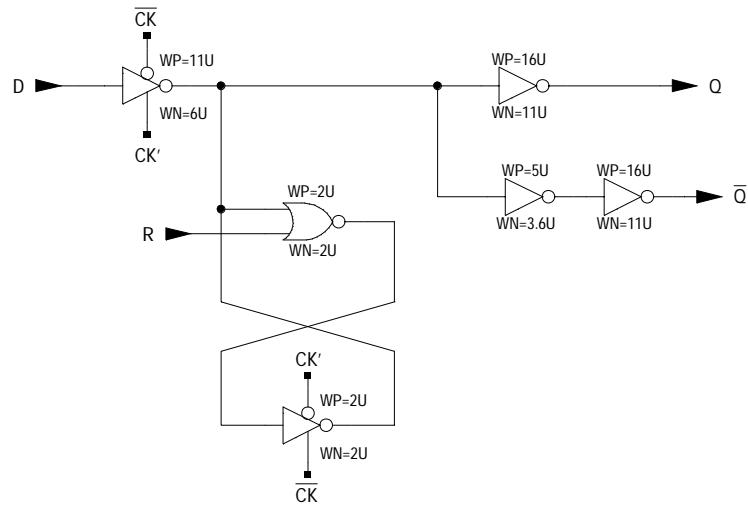
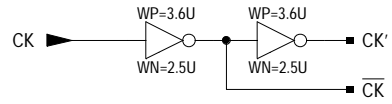


Figure 4.1.1 LATCH TYPE 1

Part #:	SI EXAMPLE REPORT		
DATE CODE:	EMBEDDED FLASH		
SCH_NAME:	B2G-P03	SI NUMBER:	3945
DATE_TIME:	6-20-2002_12:52		
LOCATION:	BLOCK_NAME	INITIALS:	GM

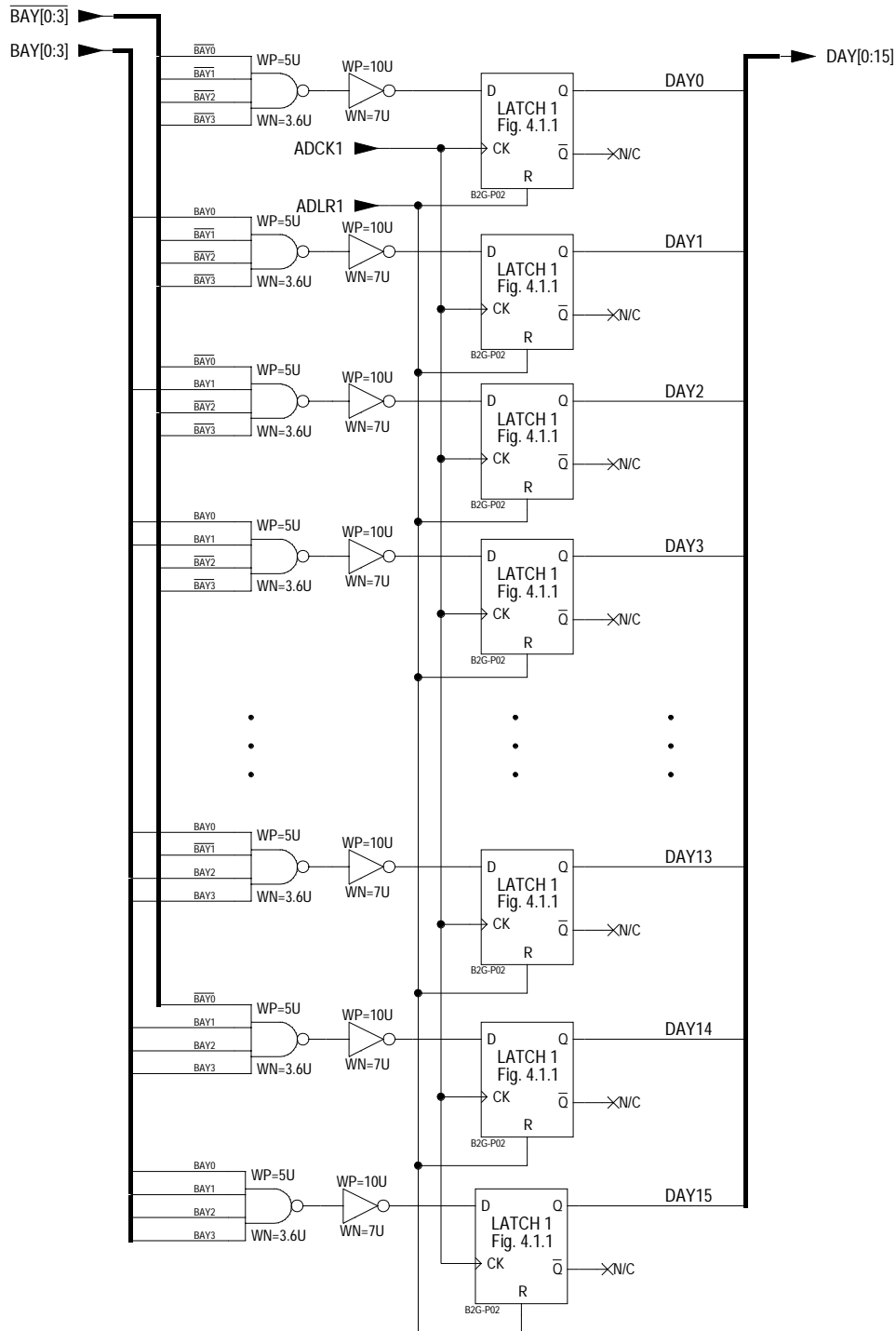


Figure 4.2 COLUMN DECODING AND LATCHES

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2G-P07	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:52		
LOCATION:	BLOCK_NAME	INITIALS:	GM

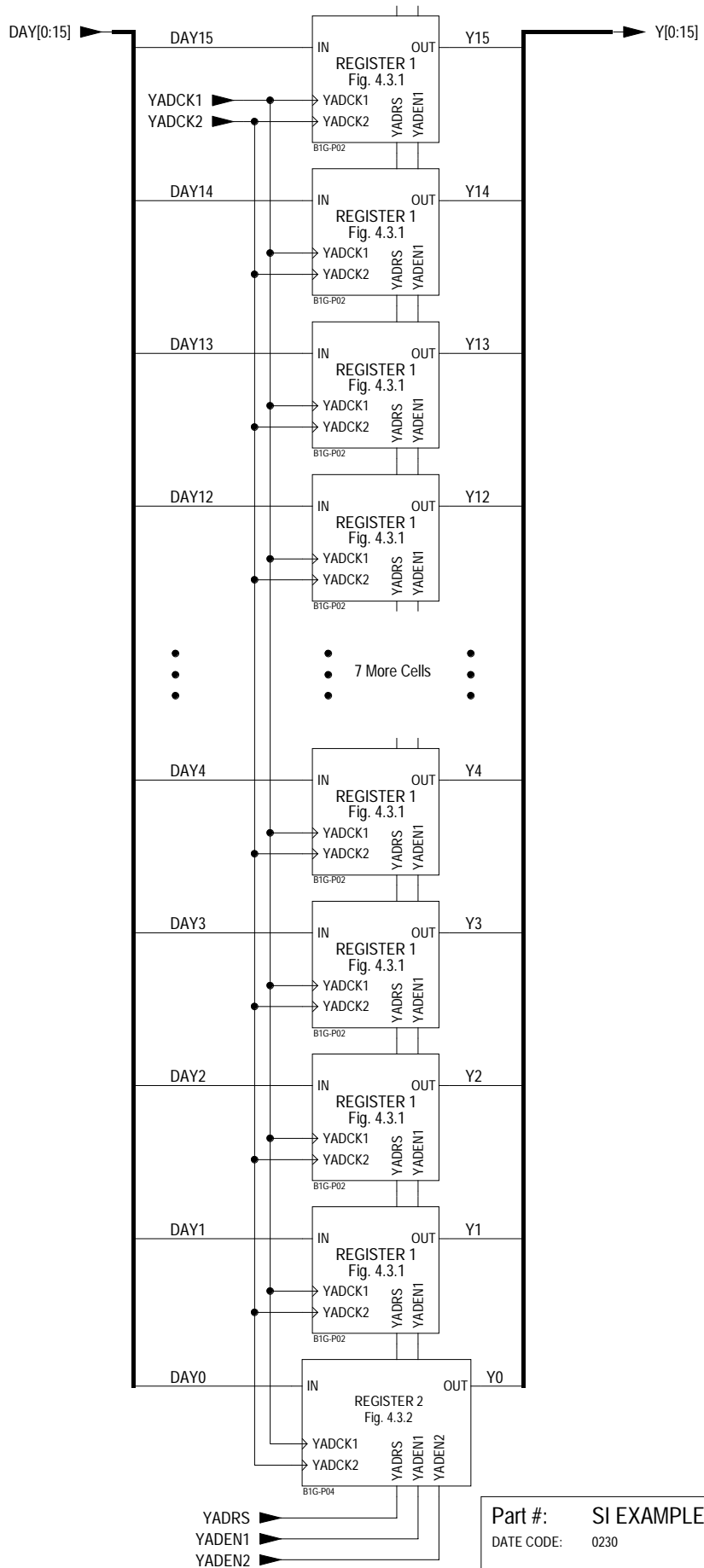


Figure 4.3 COLUMN ADDRESS REGISTERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B1G-P03	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:52		
LOCATION:	BLOCK_NAME	INITIALS:	GM

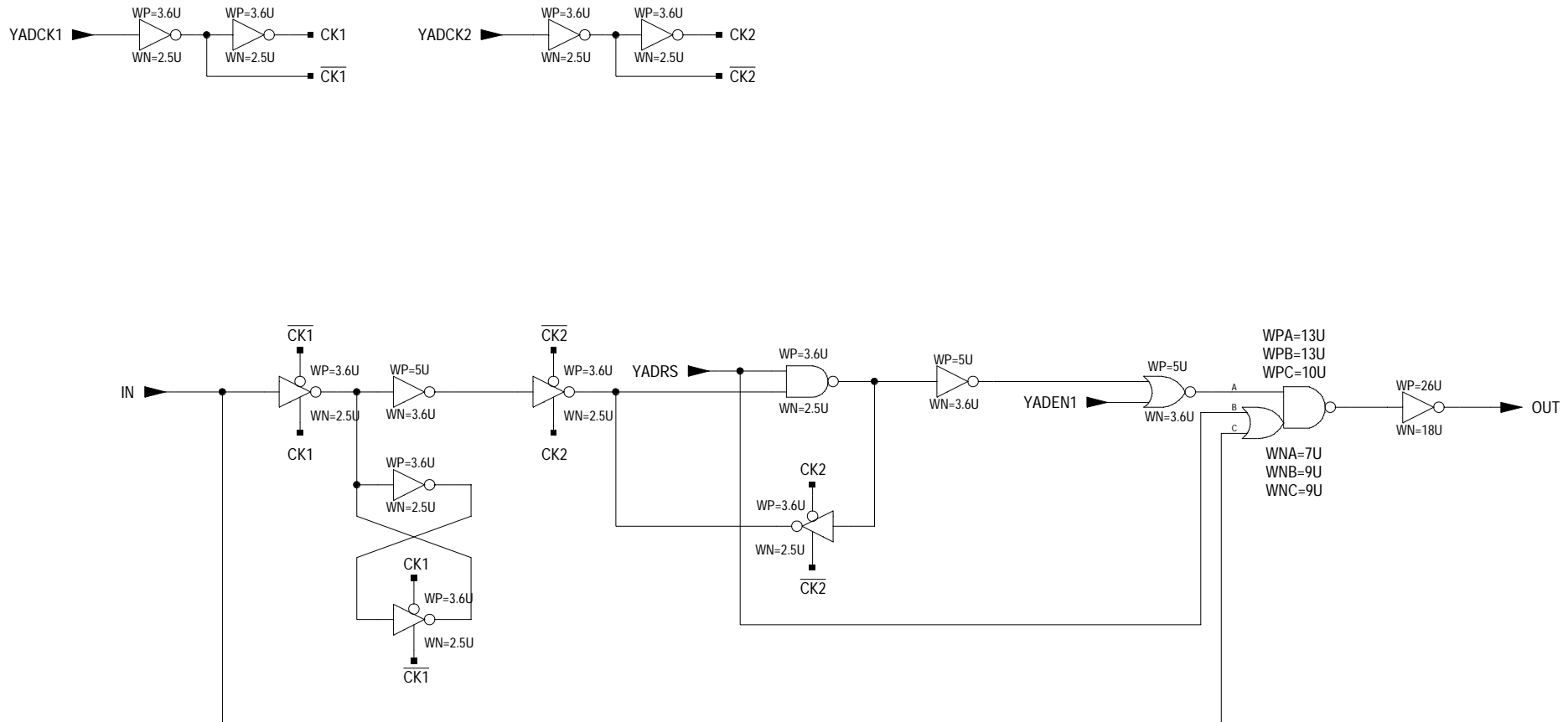


Figure 4.3.1 REGISTER 1 FOR DECODED COLUMN ADDRESSES

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B1G-P02	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:58		
LOCATION:	BLOCK_NAME	INITIALS:	GM

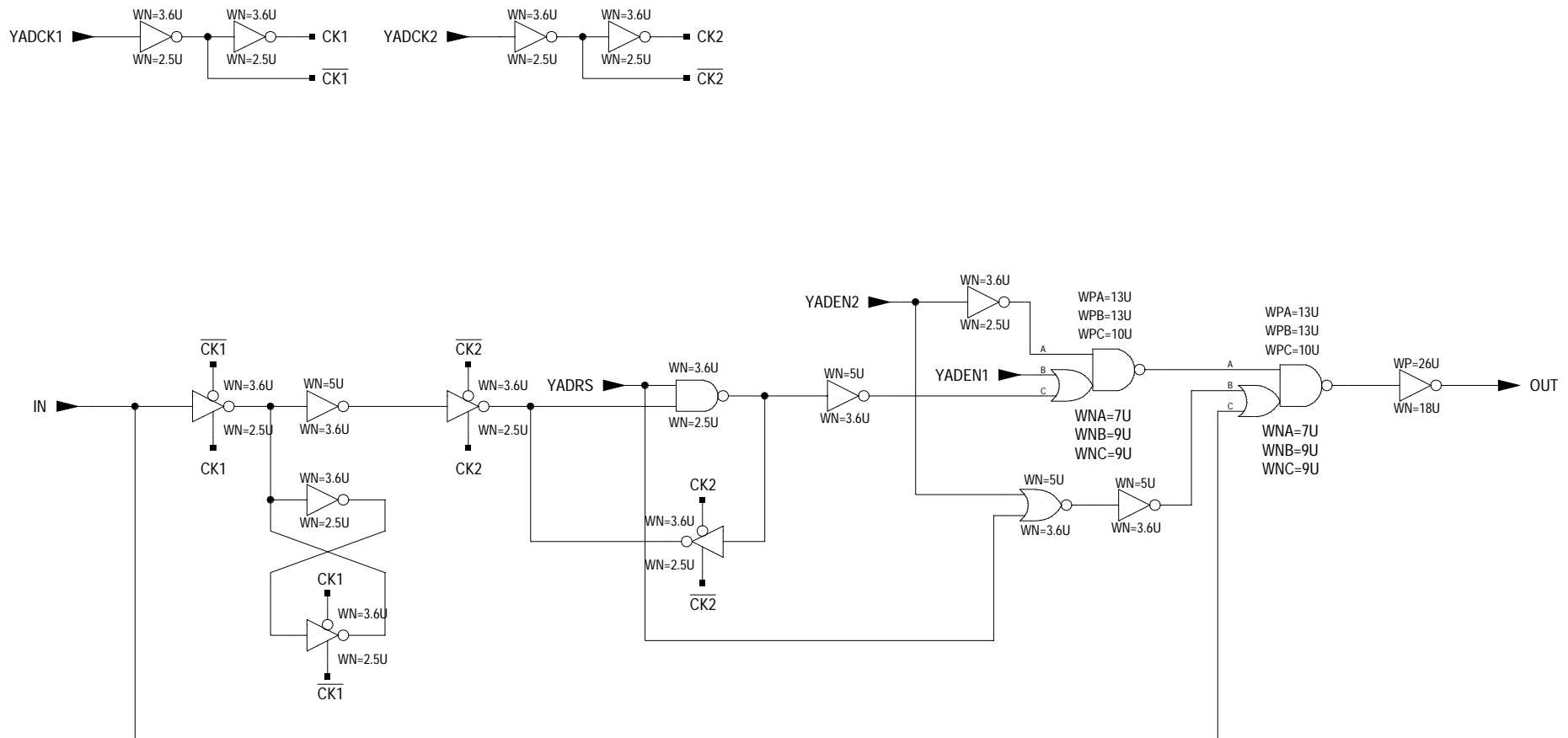


Figure 4.3.2 REGISTER 2 FOR DECODED COLUMN ADDRESSES

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B1G-P04
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:58	LOCATION:	BLOCK_NAME
		INITIALS:	GM



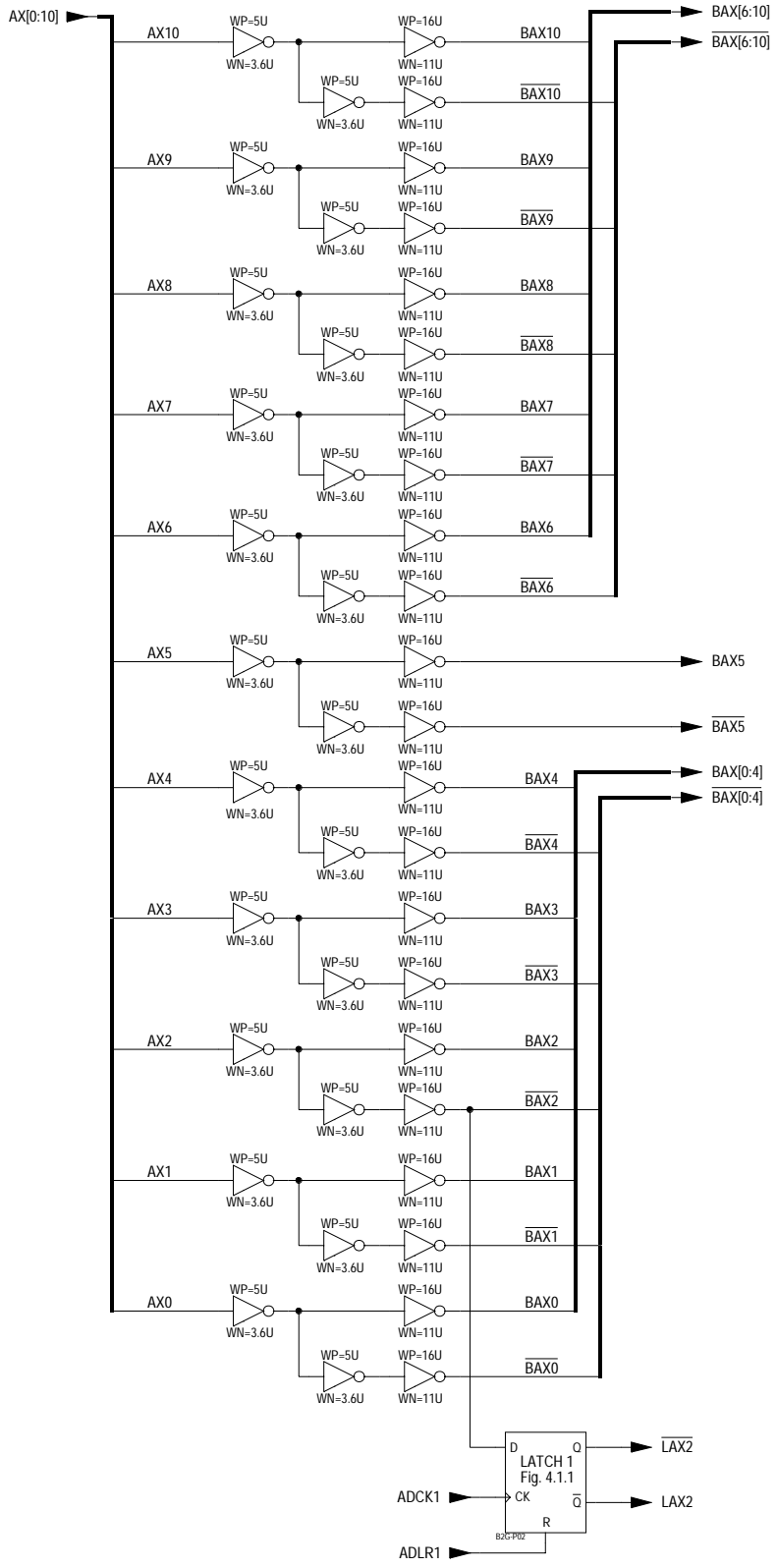


Figure 4.4 ROW ADDRESS DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	XADDRV1	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:58		
LOCATION:	BLOCK_NAME	INITIALS:	GM

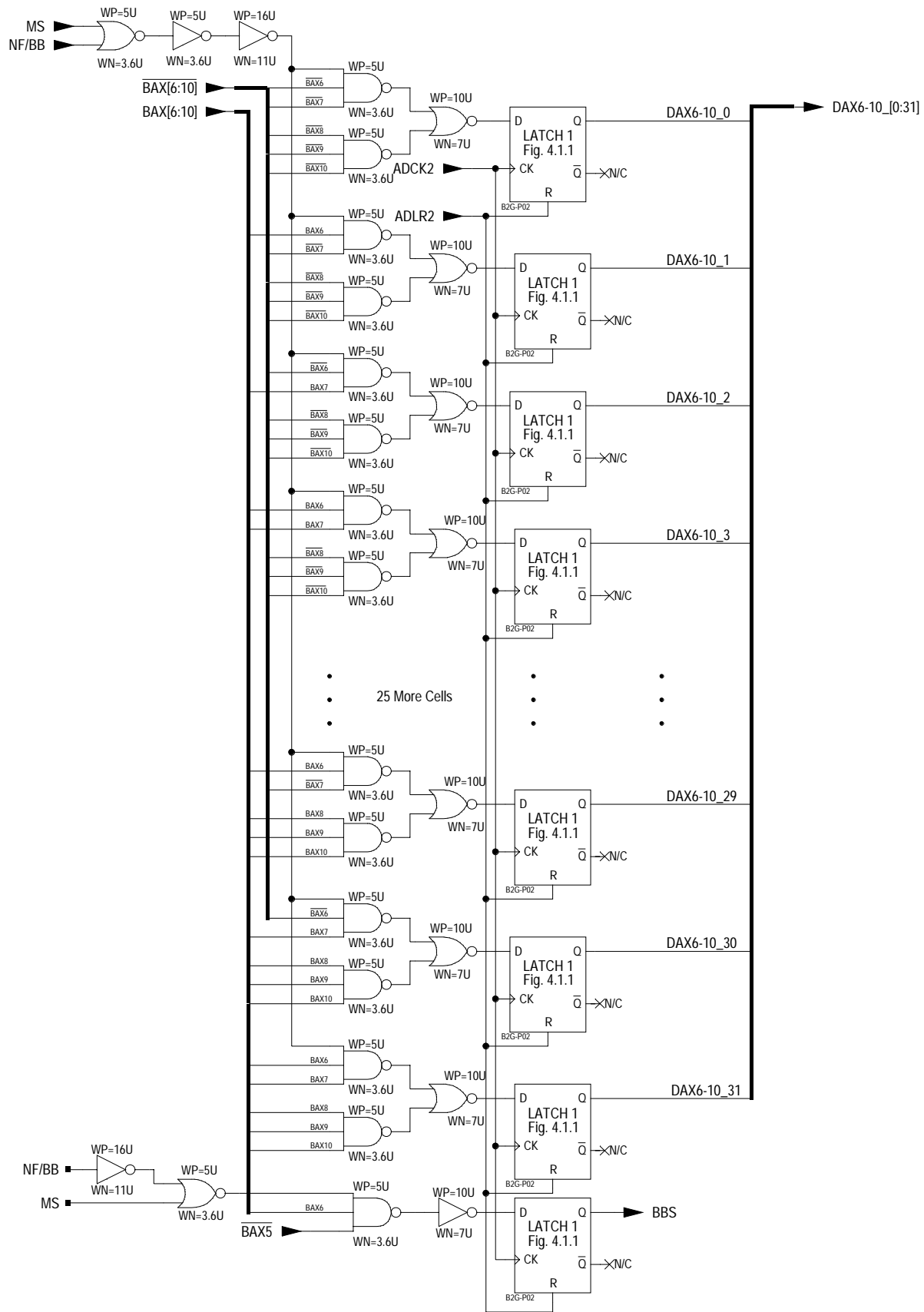


Figure 4.5 ROW ADDRESS DECODING AND LATCHES (UPPER BITS)

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2G-P09	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:58		
LOCATION:	BLOCK_NAME	INITIALS:	GM

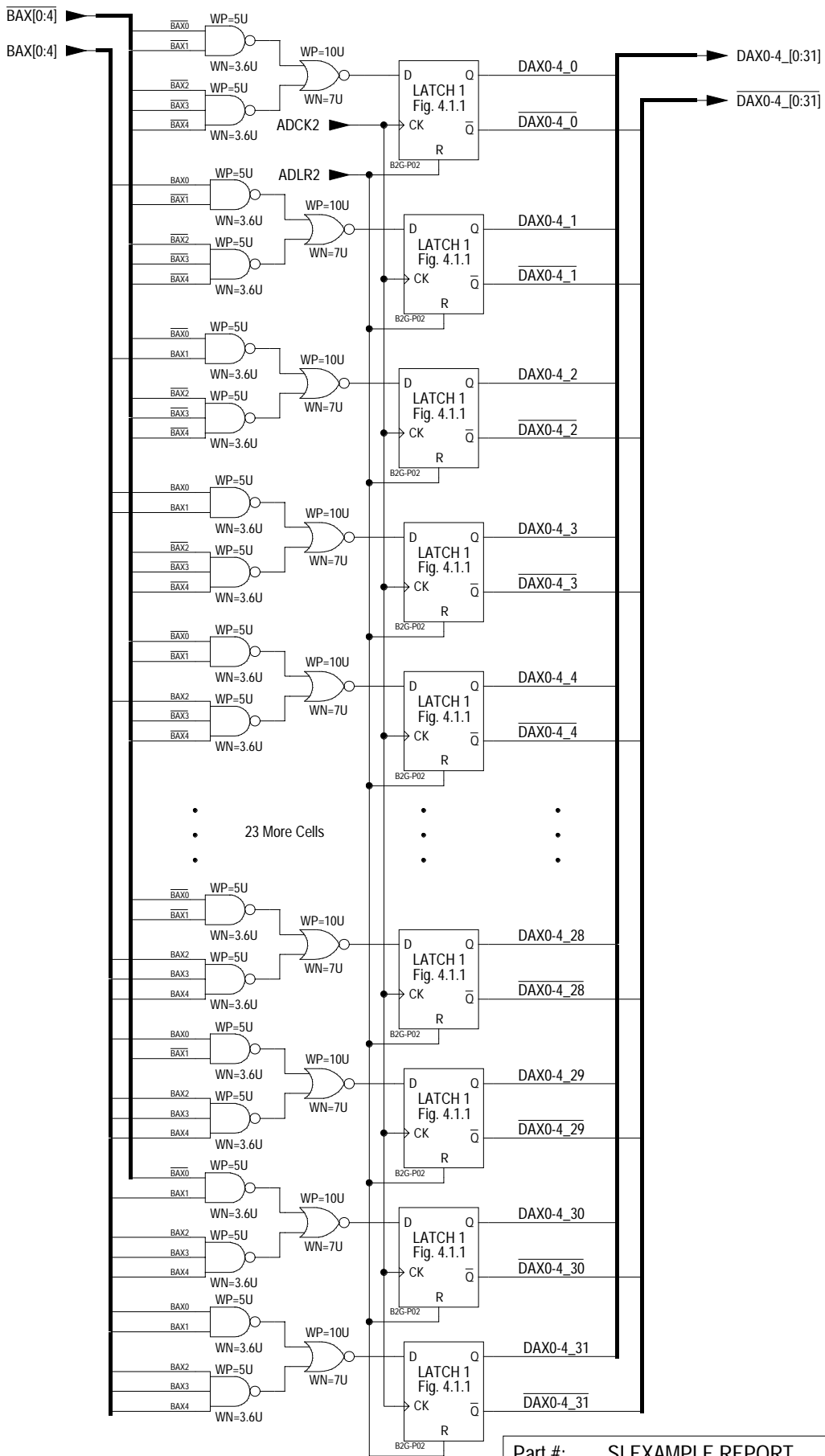


Figure 4.6 ROW ADDRESS DECODING AND LATCHES (LOWER BITS)

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B2G-P12
SCH_NAME:	B2G-P12	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:58	LOCATION:	BLOCK_NAME
LOCATION:	BLOCK_NAME	INITIALS:	GM

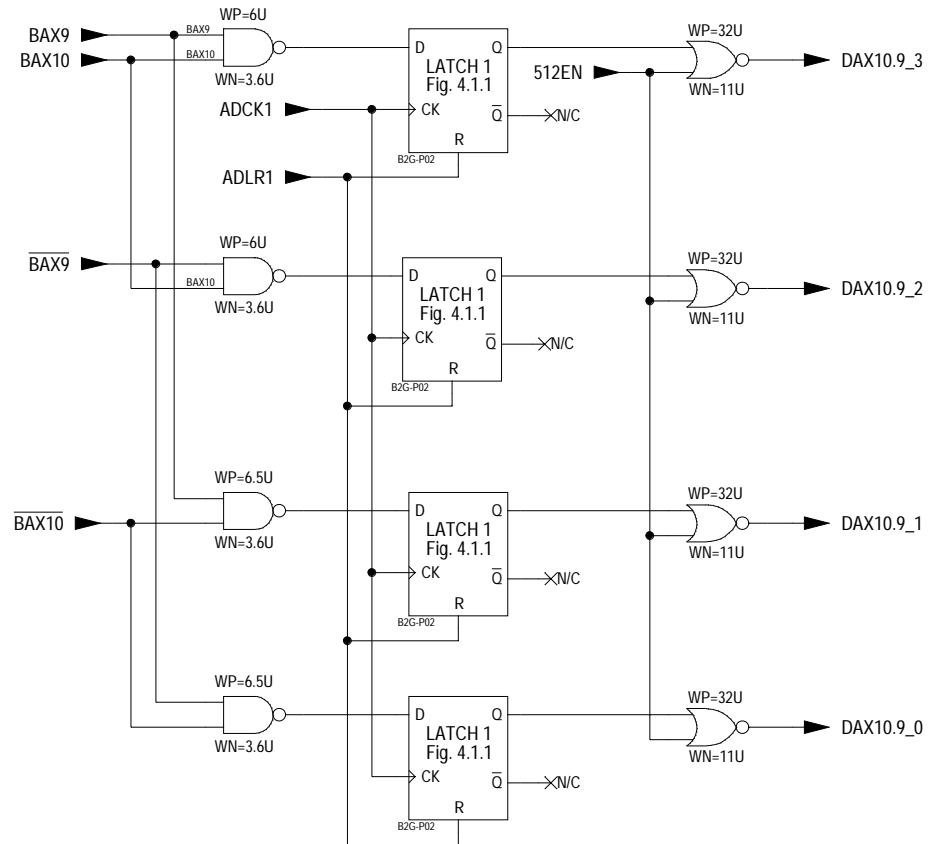


Figure 4.7 ROW ADDRESS DECODING QUADRANT SELECTION

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ADCTRL2	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:59		
LOCATION:	BLOCK_NAME	INITIALS:	GM

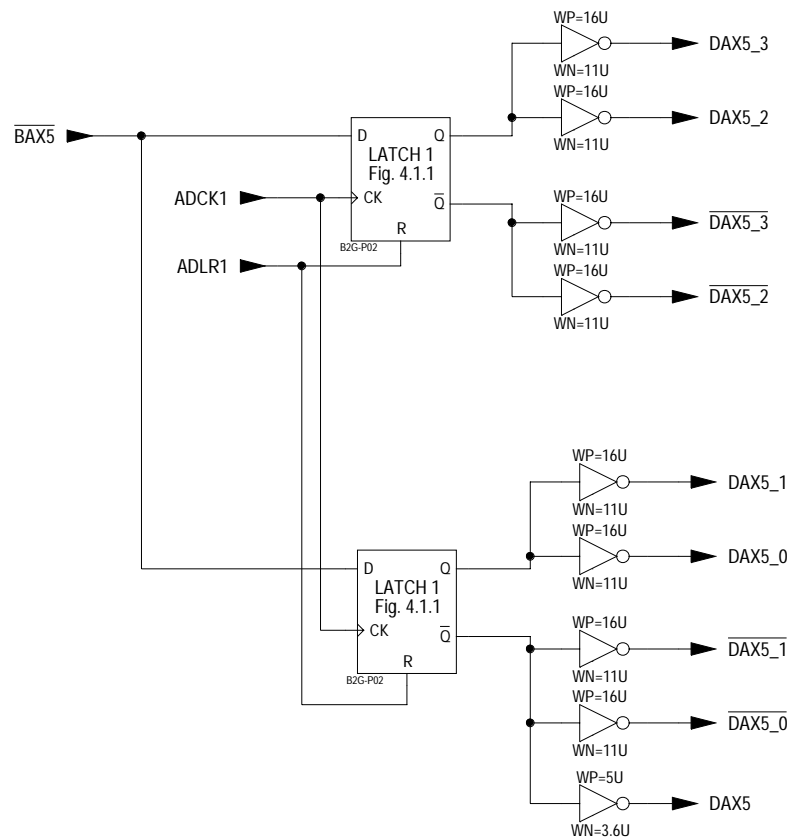


Figure 4.8 ROW ADDRESS LATCH AND DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ADCTRL3	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:59		
LOCATION:	BLOCK_NAME	INITIALS:	GM

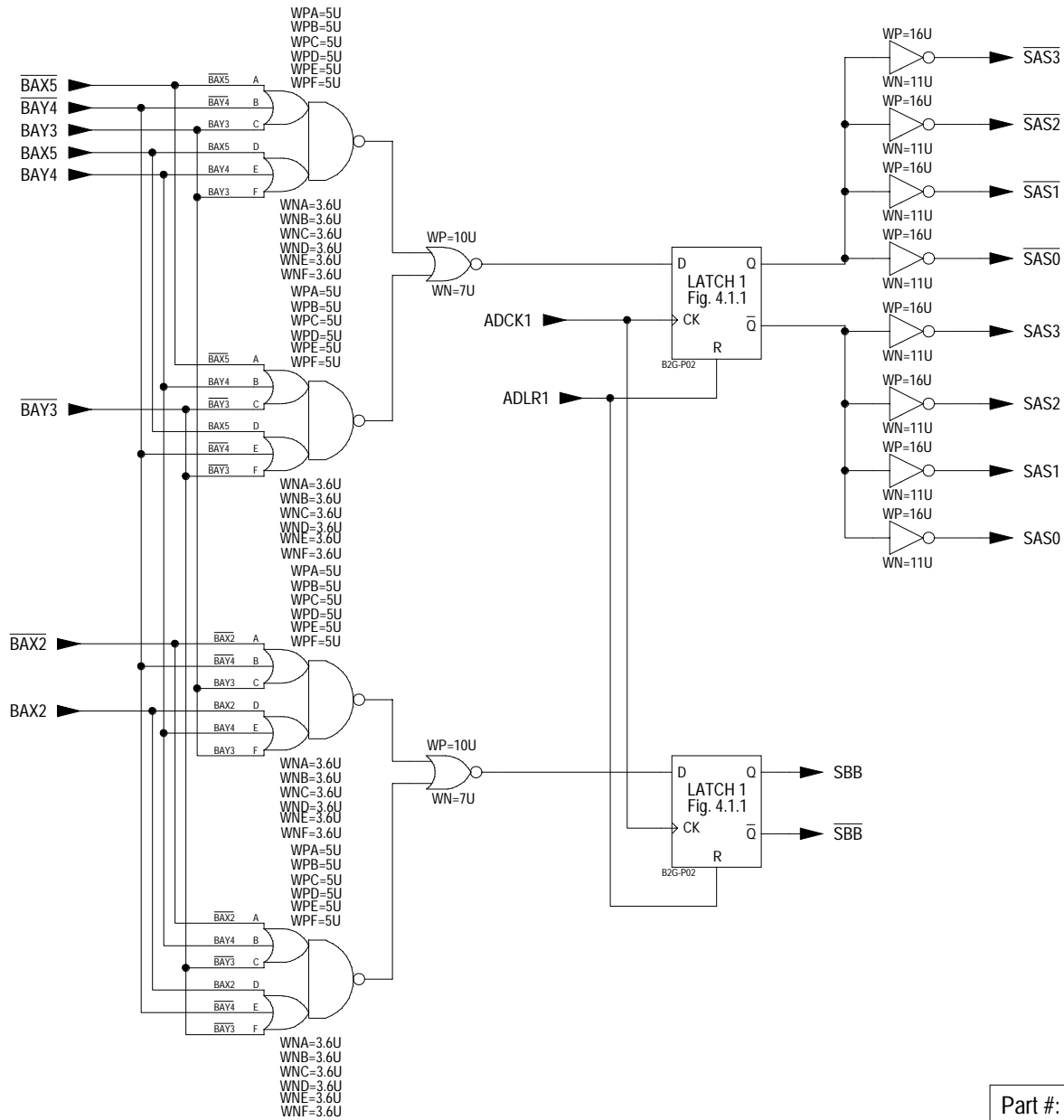


Figure 4.9 BLOCK SELECTION DECODING

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	ADCTRL1
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:59	LOCATION:	BLOCK_NAME
		INITIALS:	GM

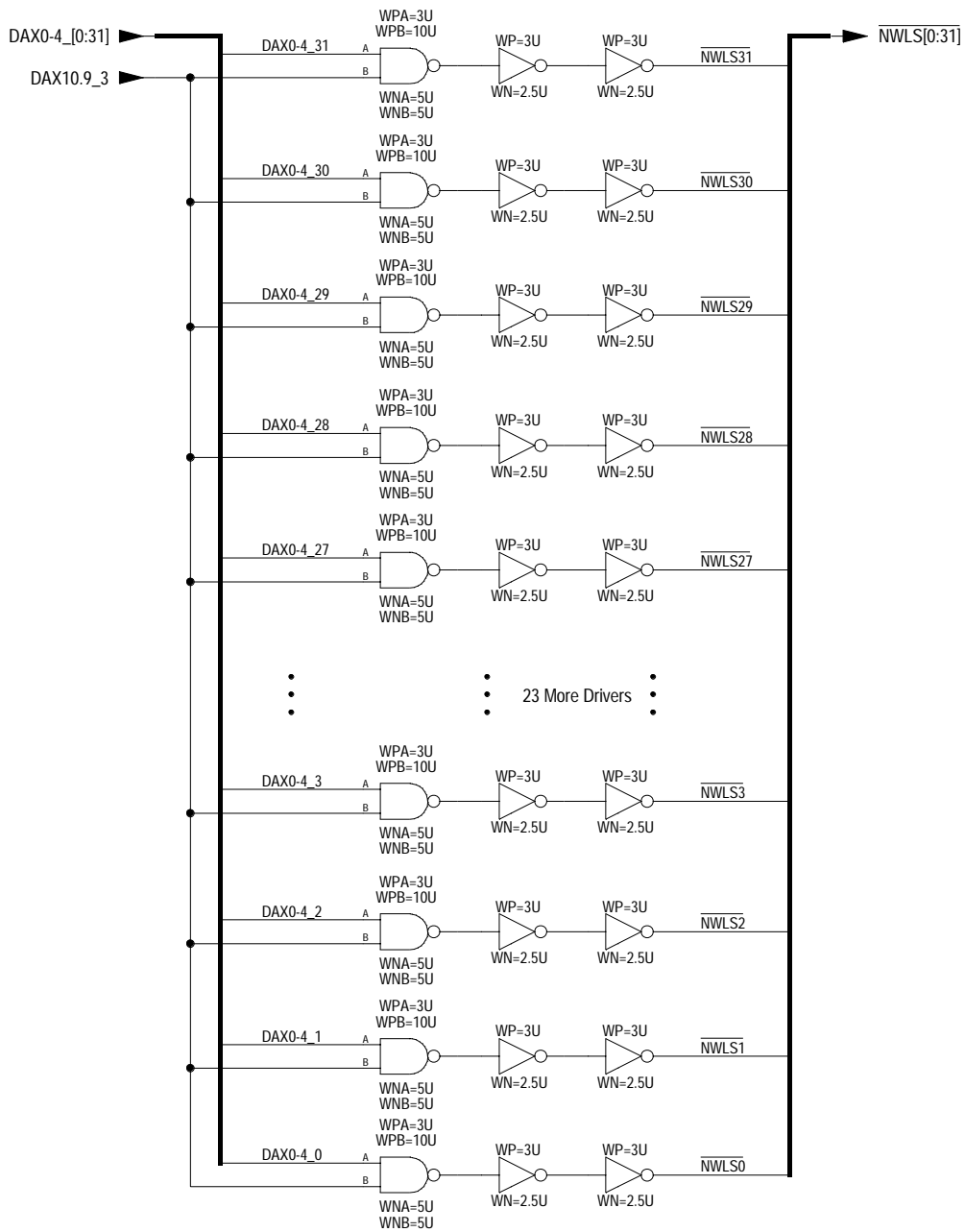


Figure 4.10 DECODED ROW ADDRESS DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2Y-P07	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:59		
LOCATION:	BLOCK_NAME	INITIALS:	GM

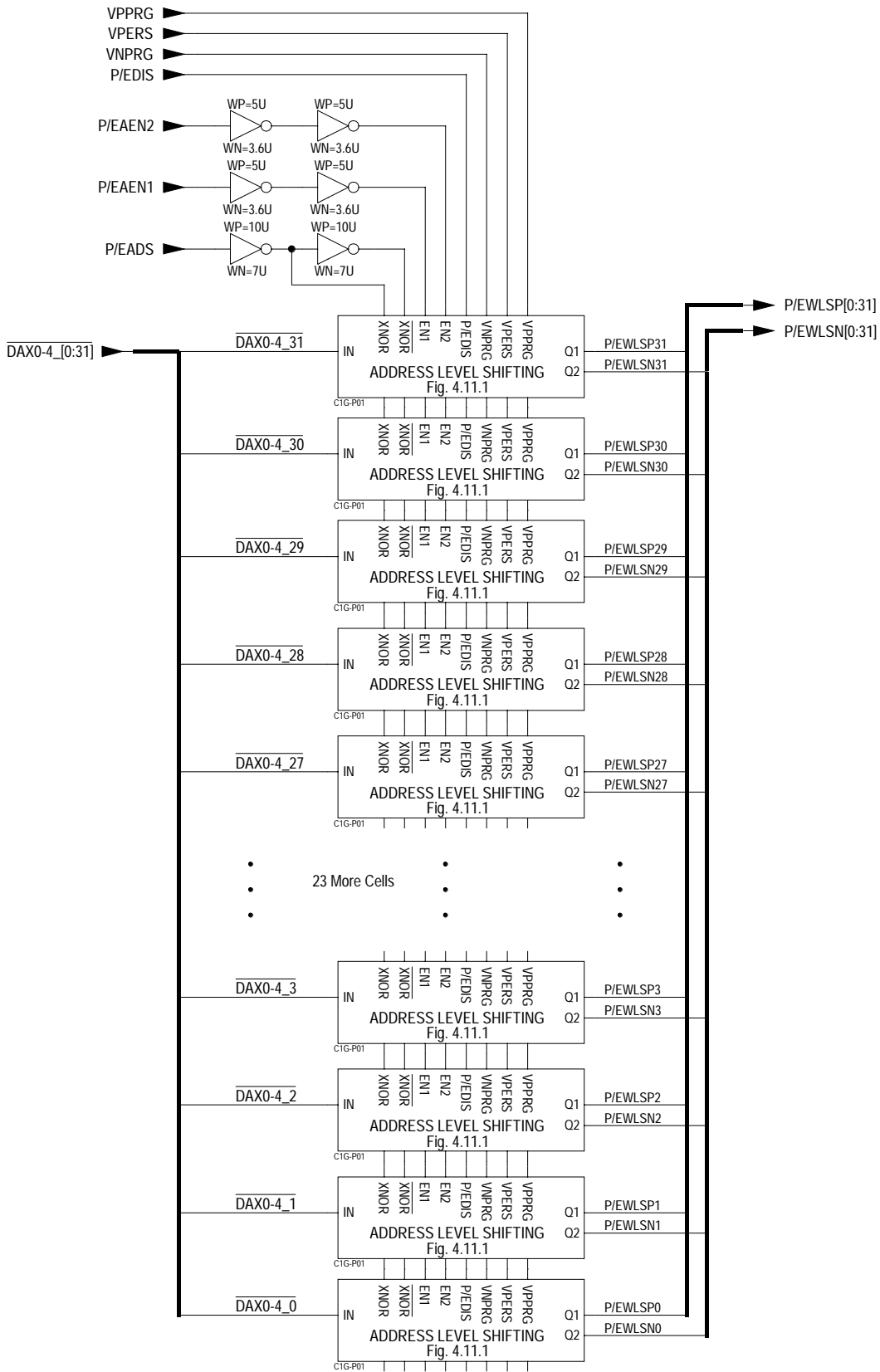
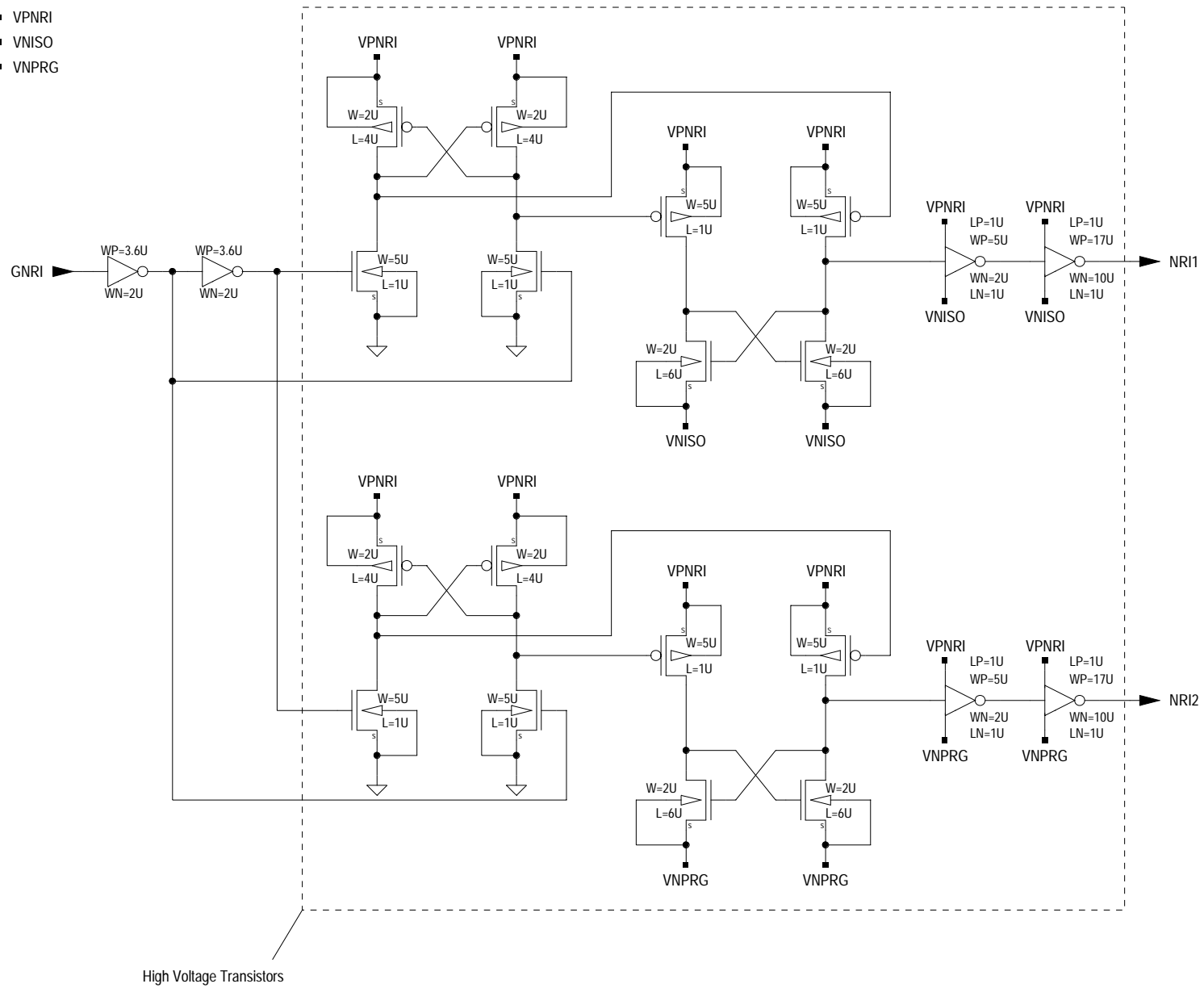


Figure 4.11 DECODED ROW ADDRESS LEVEL SHIFTERS FOR PROGRAM/ERASE

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	C1G-P01B
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_12:59	LOCATION:	BLOCK_NAME
		INITIALS:	GM



VPNRI  $\blacktriangleright$   $\square$  VPNRI  
 VNISO  $\blacktriangleright$   $\square$  VNISO  
 VNPRG  $\blacktriangleright$   $\square$  VNPRG



High Voltage Transistors

Figure 4.12 ROW ADDRESS ENABLE SIGNAL DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	C1G-P03	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:00		
LOCATION:	BLOCK_NAME	INITIALS:	GM

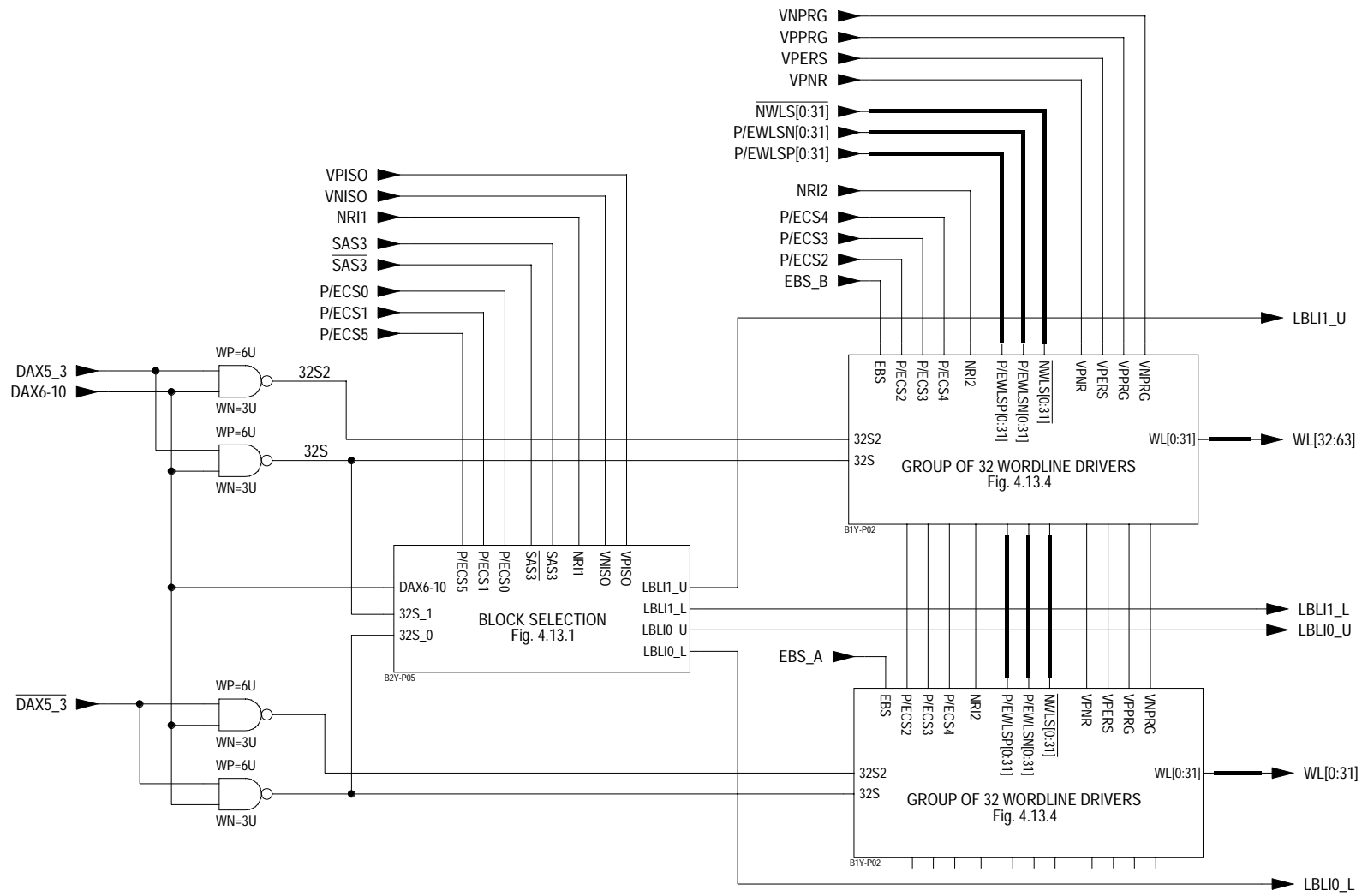


Figure 4.13 GROUP OF 32 WORDLINE DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	WORDLIN2	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:00		
LOCATION:	BLOCK_NAME	INITIALS:	GM

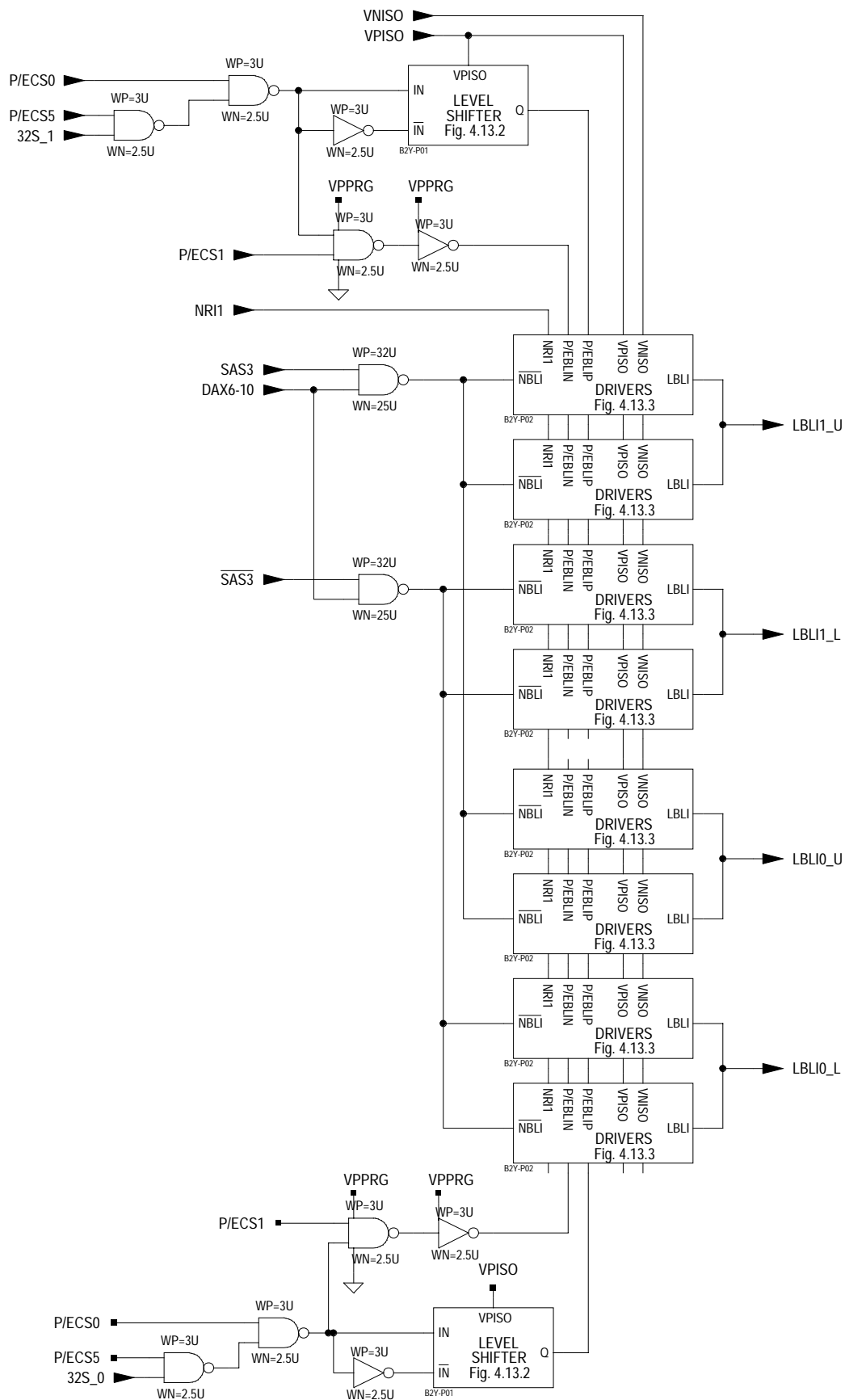


Figure 4.13.1 BLOCK SELECT SIGNAL GENERATORS FOR 64 WORDLINES

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	B2Y-P05
SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:01
LOCATION:	BLOCK_NAME
INITIALS:	GM

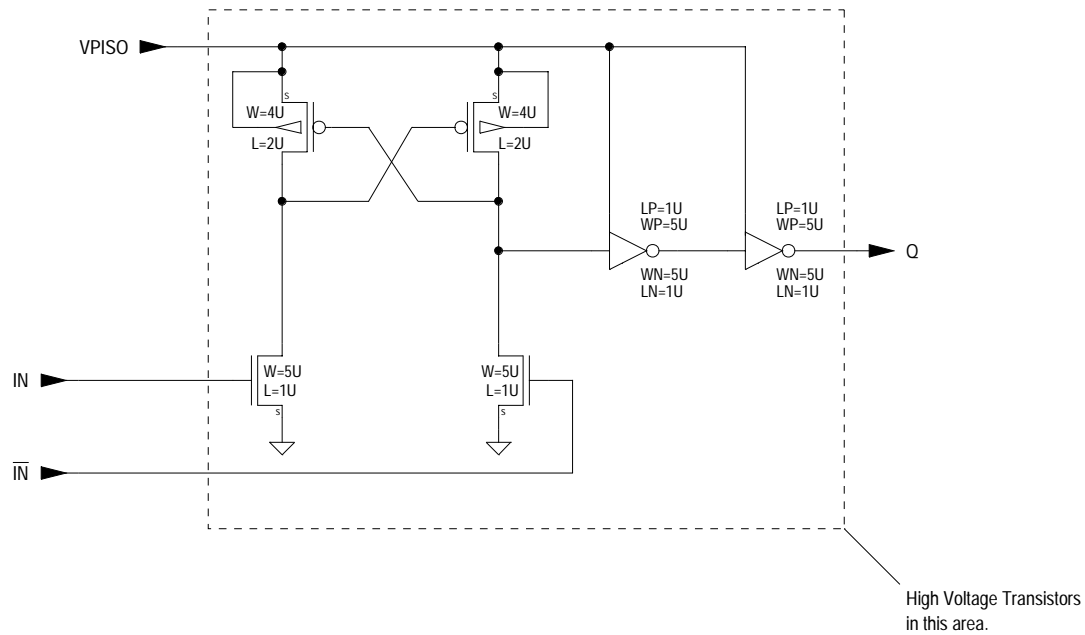


Figure 4.13.2 LEVEL SHIFTER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2Y-P01	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:01		
LOCATION:	BLOCK_NAME	INITIALS:	GM

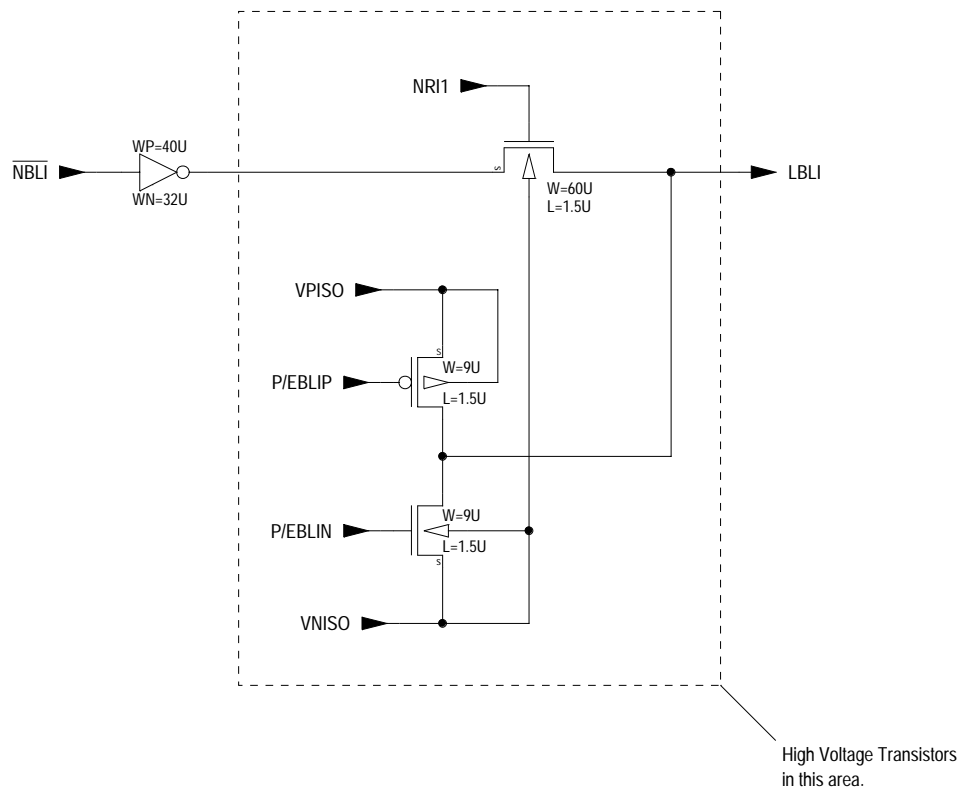


Figure 4.13.3 DRIVER ARRANGEMENTS FOR NORMAL READ, PROGRAM AND ERASE

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2Y-P02	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:01		
LOCATION:	BLOCK_NAME	INITIALS:	GM

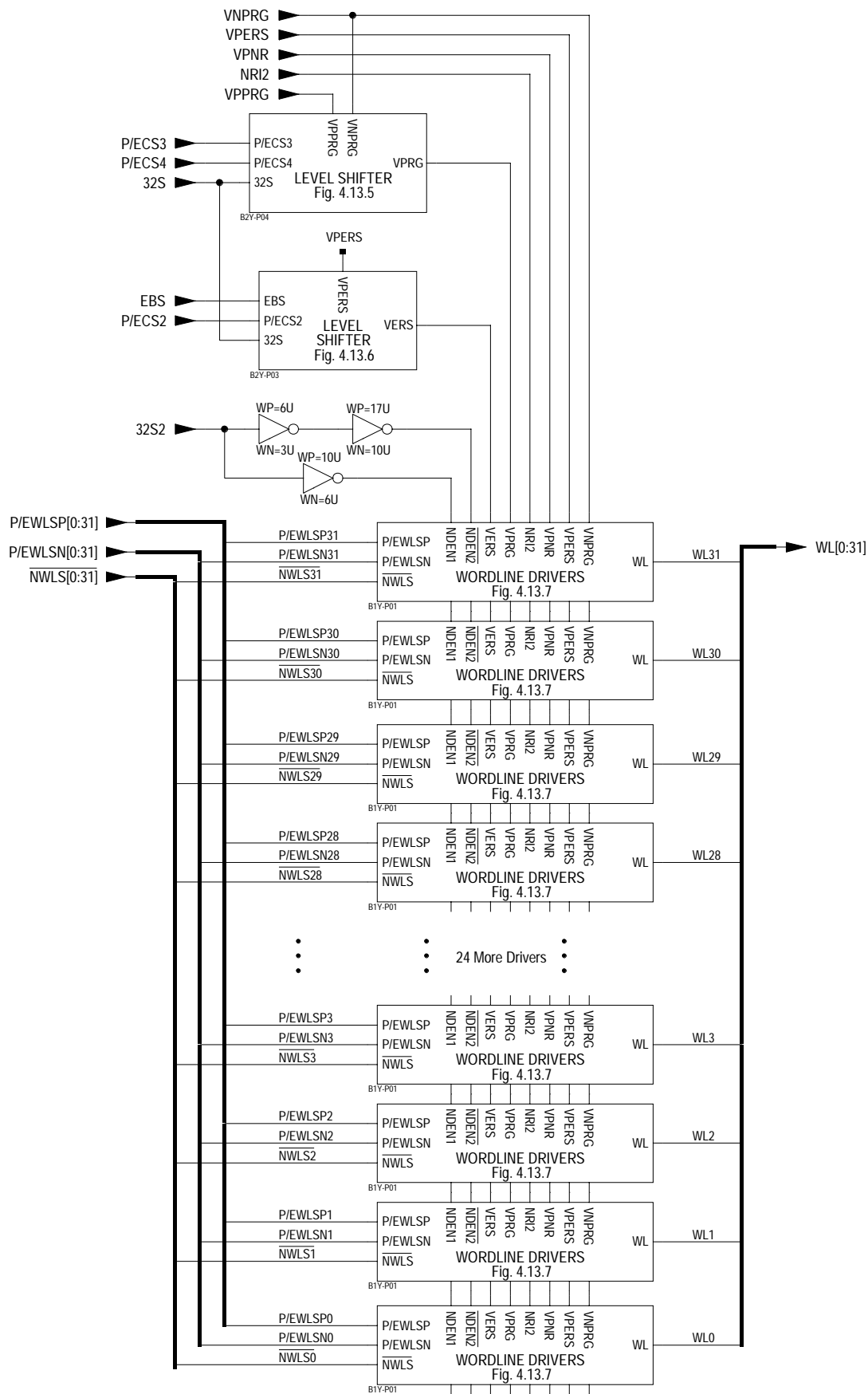


Figure 4.13.4 GROUP OF 32 WORDLINE DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B1Y-P02
SCH_NAME:	B1Y-P02	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:02	LOCATION:	BLOCK_NAME
LOCATION:	BLOCK_NAME	INITIALS:	GM

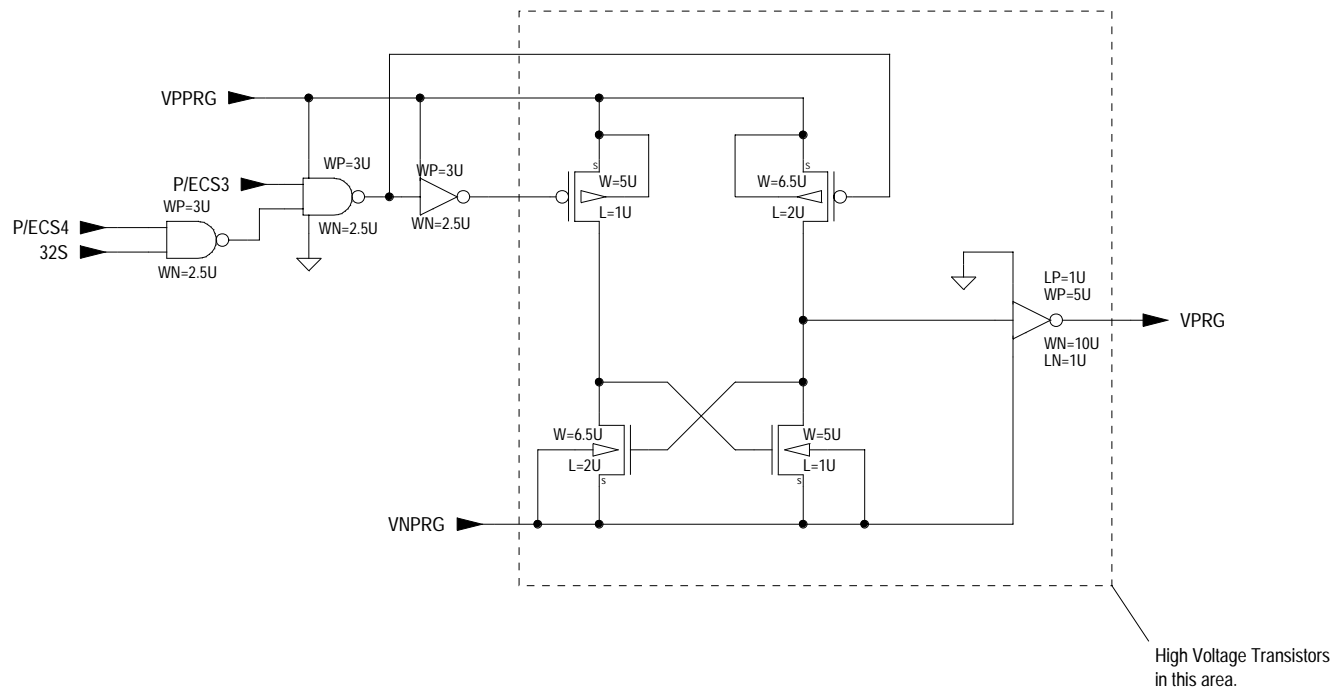


Figure 4.13.5 LEVEL SHIFTER FOR PROGRAMMING PURPOSES

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2Y-P04	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:02		
LOCATION:	BLOCK_NAME	INITIALS:	GM

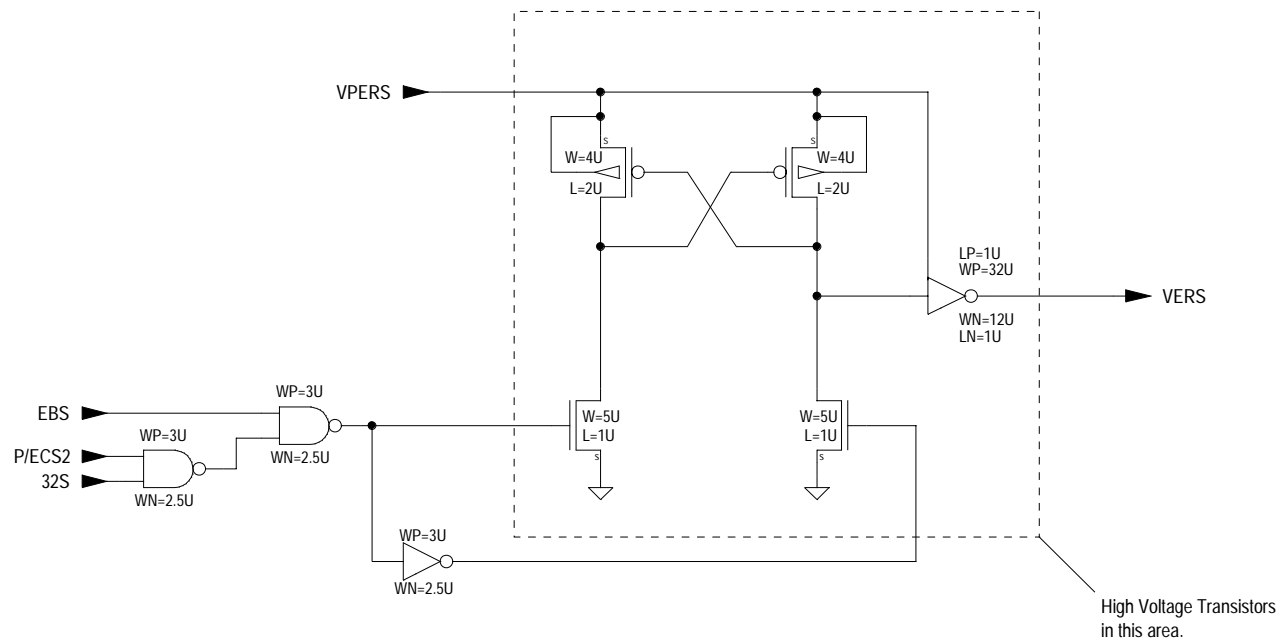


Figure 4.13.6 LEVEL SHIFTER FOR ERASE PURPOSES

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2Y-P03	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:02		
LOCATION:	BLOCK_NAME	INITIALS:	GM



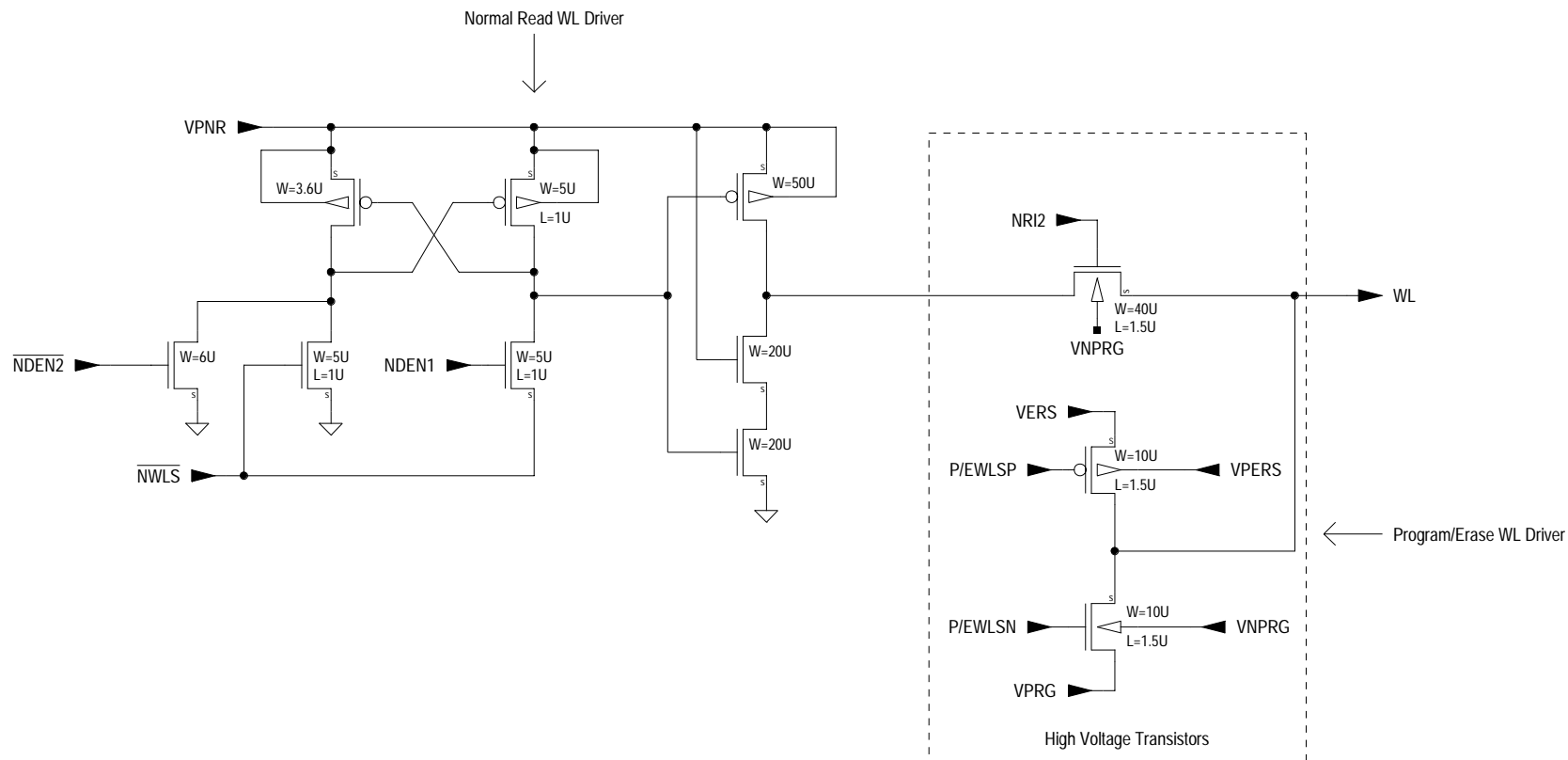


Figure 4.13.7 WORDLINE DRIVERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B1Y-P01	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:02		
LOCATION:	BLOCK_NAME	INITIALS:	GM

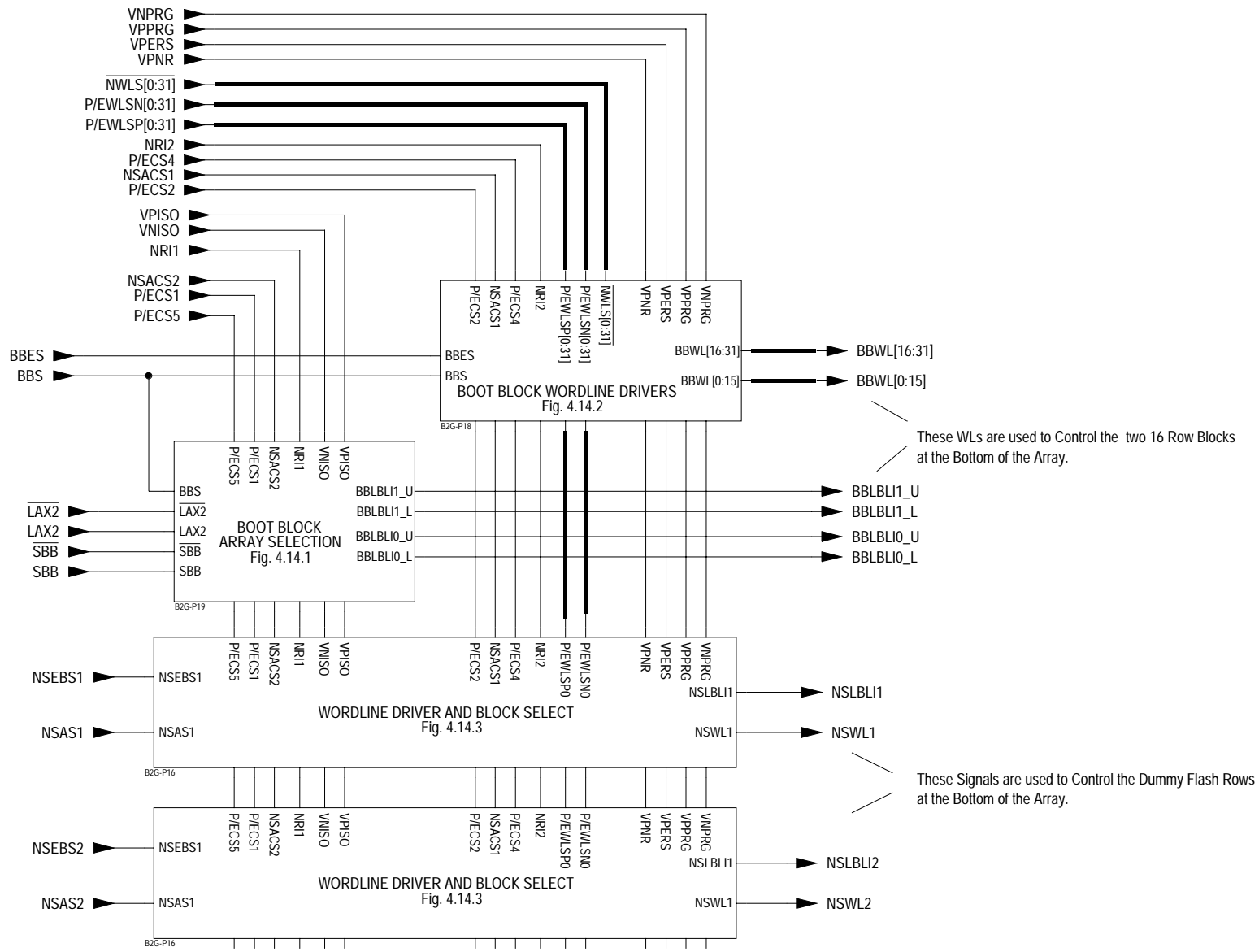


Figure 4.14 ROW ADDRESS CIRCUITRY FOR BOOT BLOCK AND NON STANDARD ARRAYS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SI NUMBER:	SI01
SCH_NAME:	B2G18-19	INITIALS:	GM
DATE_TIME:	6-18-2002_9:12		
LOCATION:	BLOCK_NAME		

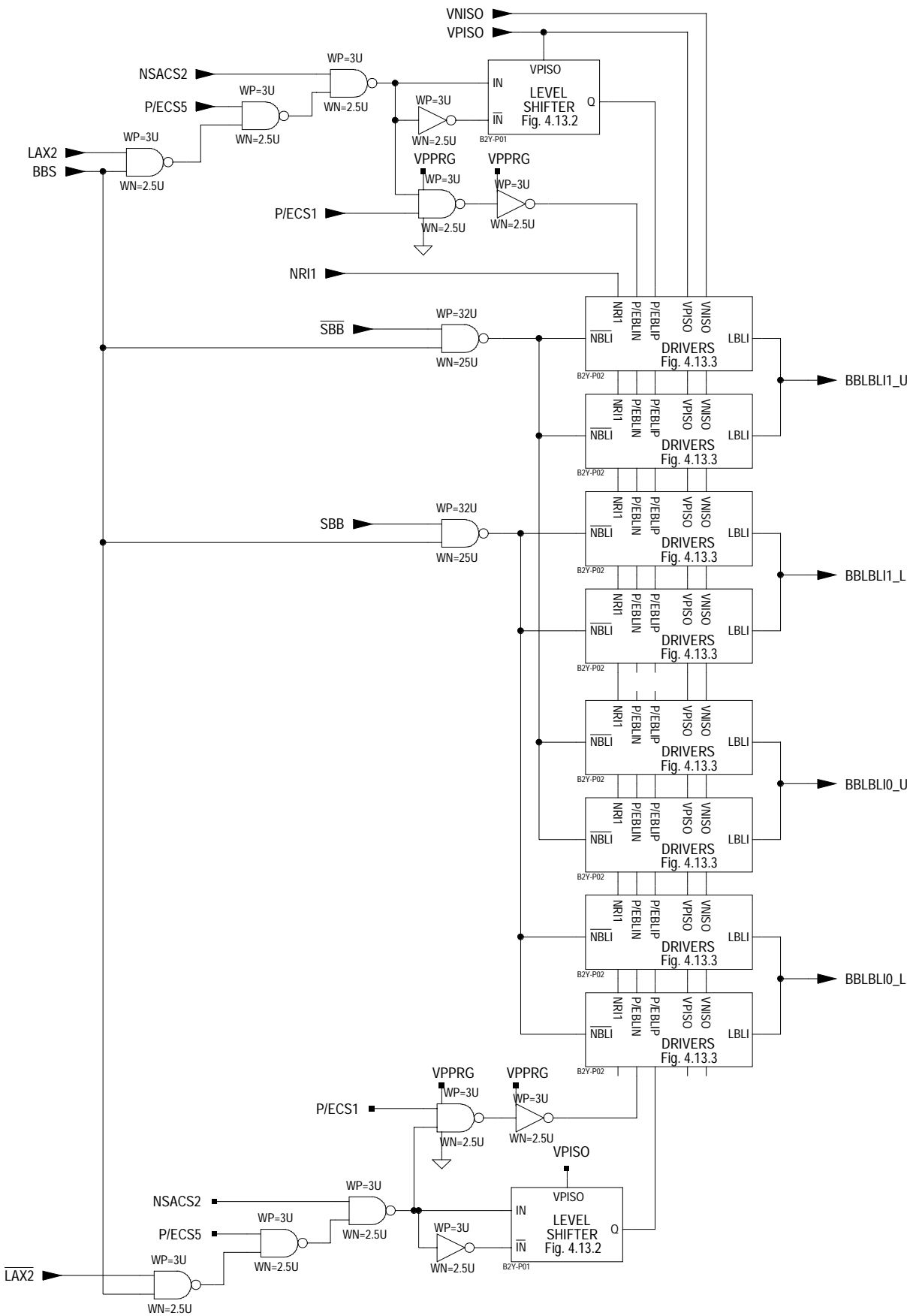


Figure 4.14.1 BLOCK SELECT SIGNAL GENERATORS FOR BOTTOM GROUP OF 32 WLS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2G-P19	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:03		
LOCATION:	BLOCK_NAME	INITIALS:	GM

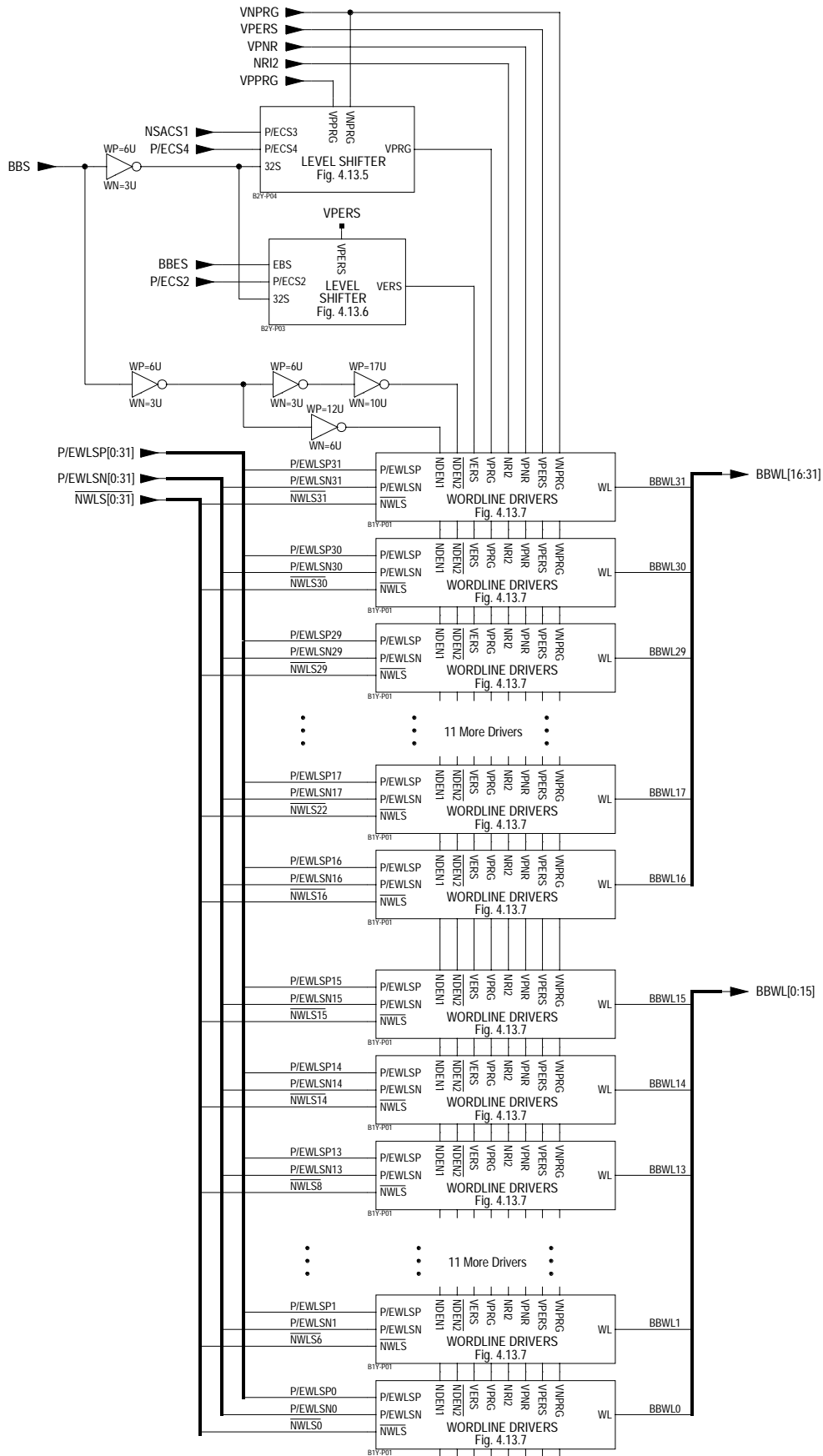


Figure 4.14.2 GROUP OF 32 WORDLINE DRIVERS FOR THE BOOT BLOCK

Part #: SI EXAMPLE REPORT

DATE CODE: 0230

SCH\_NAME: B2G-P18

SI NUMBER: SI01

DATE\_TIME: 6-20-2002\_13:03

LOCATION: BLOCK\_NAME

INITIALS: GM

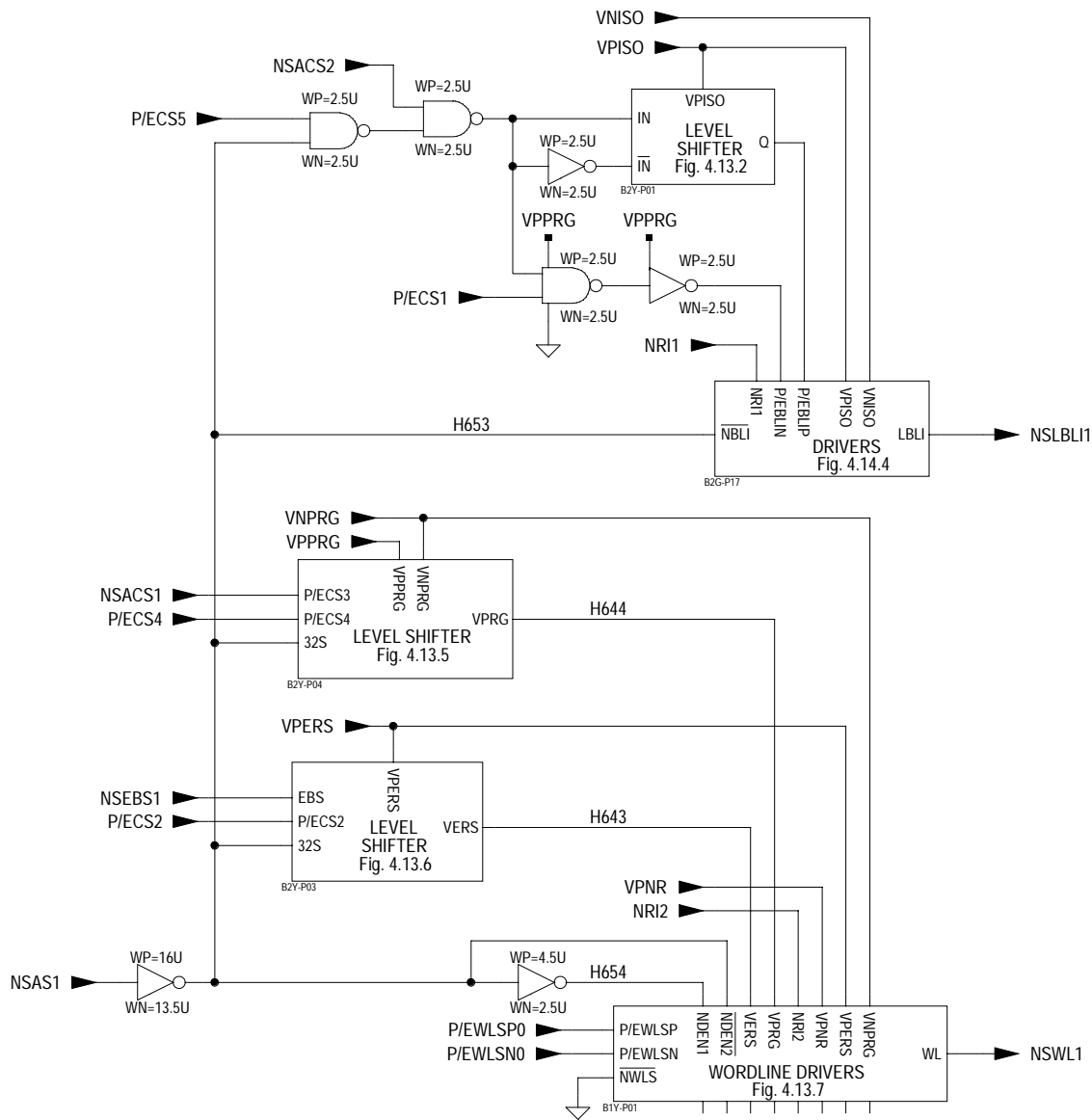


Figure 4.14.3 WORDLINE DRIVER AND BLOCK SELECT FOR BOTTOM SINGLE FLASH ARRAYS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	B2G-P16
SCH_NAME:	B2G-P16	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:04	LOCATION:	BLOCK_NAME
LOCATION:	BLOCK_NAME	INITIALS:	GM

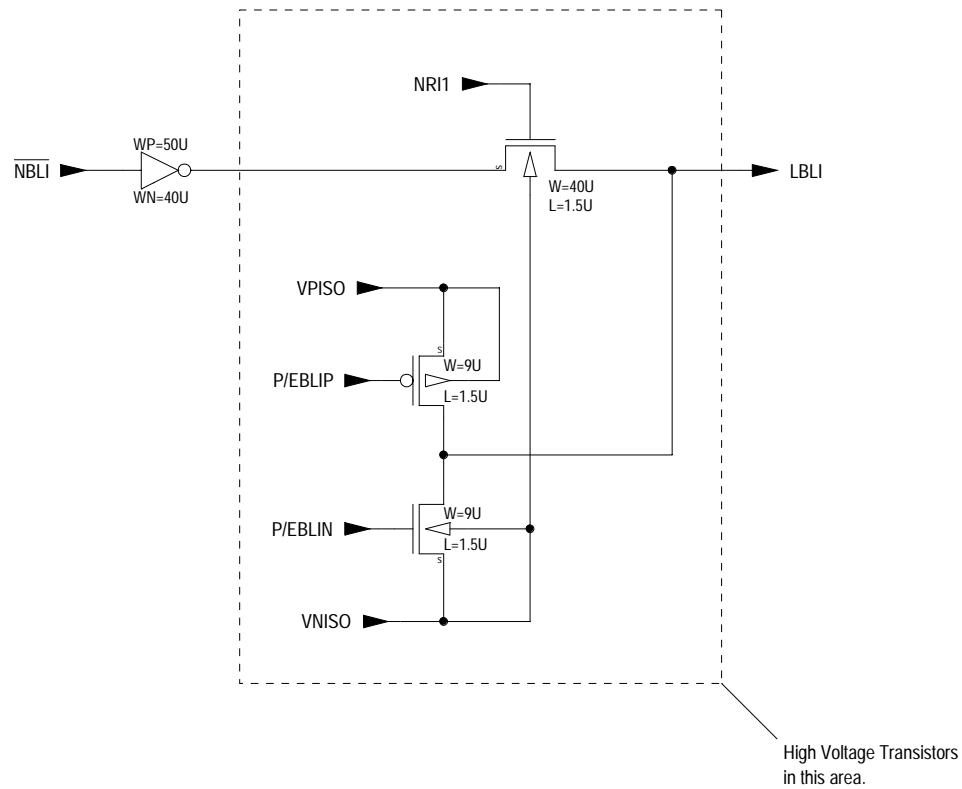


Figure 4.14.4 SWITCH AND PRECHARGE

<b>Part #:</b>	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	B2G-P17	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:05		
LOCATION:	BLOCK_NAME	INITIALS:	GM

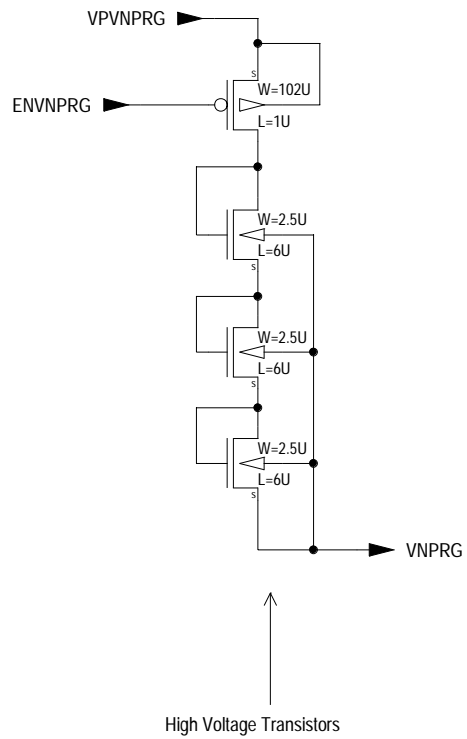


Figure 4.15 VOLTAGE GENERATOR

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	C1G-P02	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:13		
LOCATION:	BLOCK_NAME	INITIALS:	GM

## 5.0 RX Prescaler

*The following section was taken from a frequency synthesizer report. This particular device was manufactured with a BiCMOS process and the schematics therefore contain bipolar transistors.*

The RX Synthesizer Prescaler is a separate layout block that implements Emitter Coupled Logic (ECL) logic. ECL gates and flip-flops utilize only BiPolar NPN transistors. ECL Divider flip-flops are individually tuned, accordingly to operating frequency, to minimize power consumption. Individual tuning is achieved by selecting the appropriate length of polysilicon emitter and collector resistors. The Prescaler schematic is shown in Figure 5.

The input frequency FINRX goes through a differential pre-amplifier to form RXIN and ~RXIN complementary clocks. The divide ratio of the Prescaler (32/64) is set with the RX\_SW input. The RX\_SW signal controls the Toggle\_Pass (T\_P) input of the flip flop in Figure 3.6. The clock swallow is controlled with the SWEN input. When SWEN = 0, the divide ratio of the Prescaler is 32 or 64. When SWEN = 1, the Prescaler swallows one clock pulse, after an “all zeros” state, and the resulting divide ratio becomes 33 or 65.

The ECL to CMOS converter layout (Figure 5.10) is not located in the Prescaler block but in the RX Counters Standard Cells block. All Prescaler circuits are supplied from the upper VccRX(1) pad, except for the ECL\_CMOS converter and the entire RX Standard Cell block which are supplied from the bottom VccRX(2) pad. Both VccRX pads are bonded to a common package pin.

As seen on the Prescaler schematics the BiPolar NPN transistors have an attached AREA attribute. Only two types of BiPolar NPN transistors are used in the design. The smaller one (Type 1) has an AREA = 1 or is left without an AREA attribute on the schematics. The larger transistors (Type 2) have an AREA = 2. If an NPN transistor on a schematic has an attribute of AREA = 4 it is a parallel connection of two Type 2 transistors.





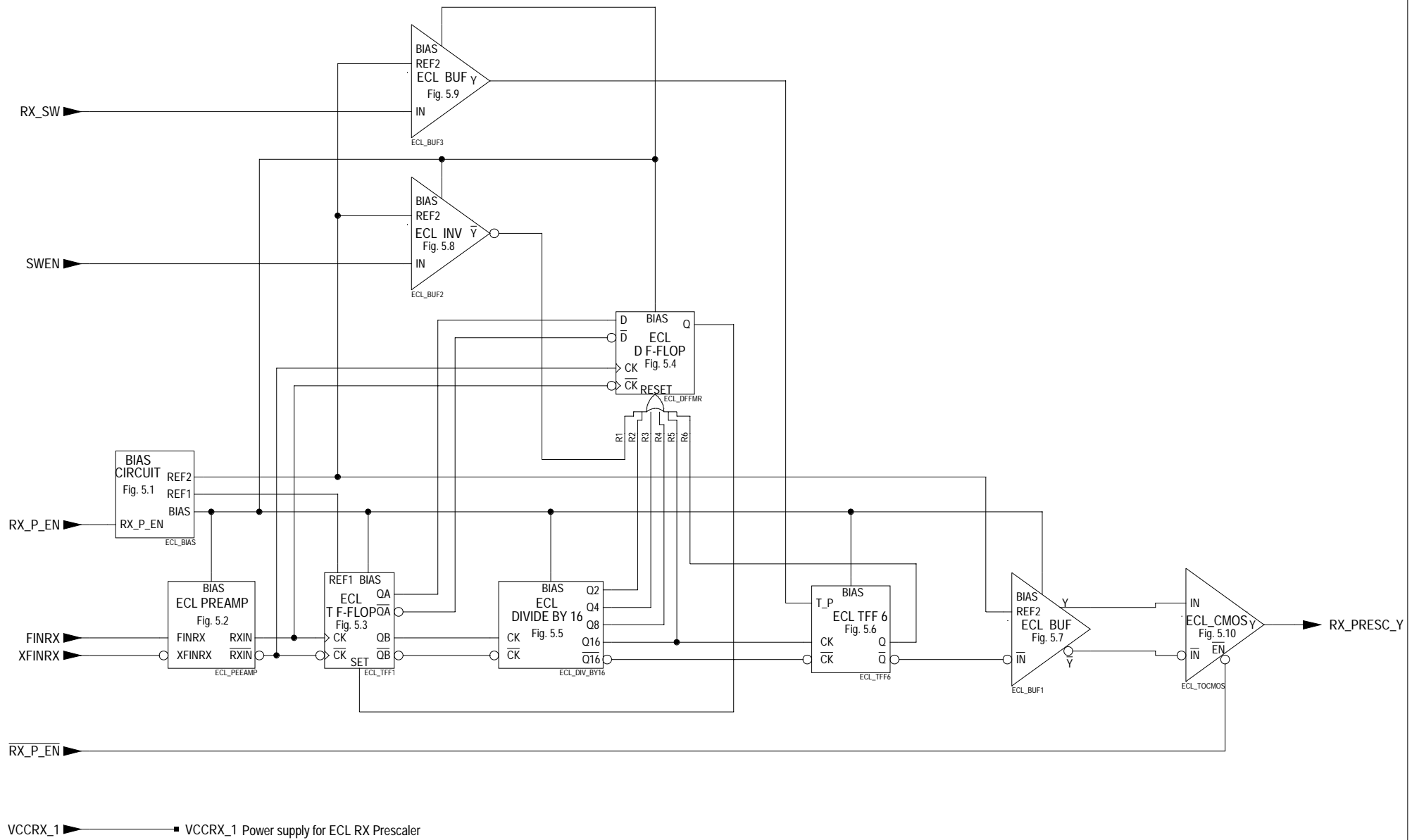


Figure 5.0 RX ECL DIVIDE BY 32/33 OR 62/63 PRESCALER

Part #:	SI EXAMPLE REPORT	
DATE CODE:	0230	
SCH_NAME:	RX_PRESCALER	SI NUMBER: SI01
DATE_TIME:	6-18-2002_9:13	
LOCATION:	XX	INITIALS: GY

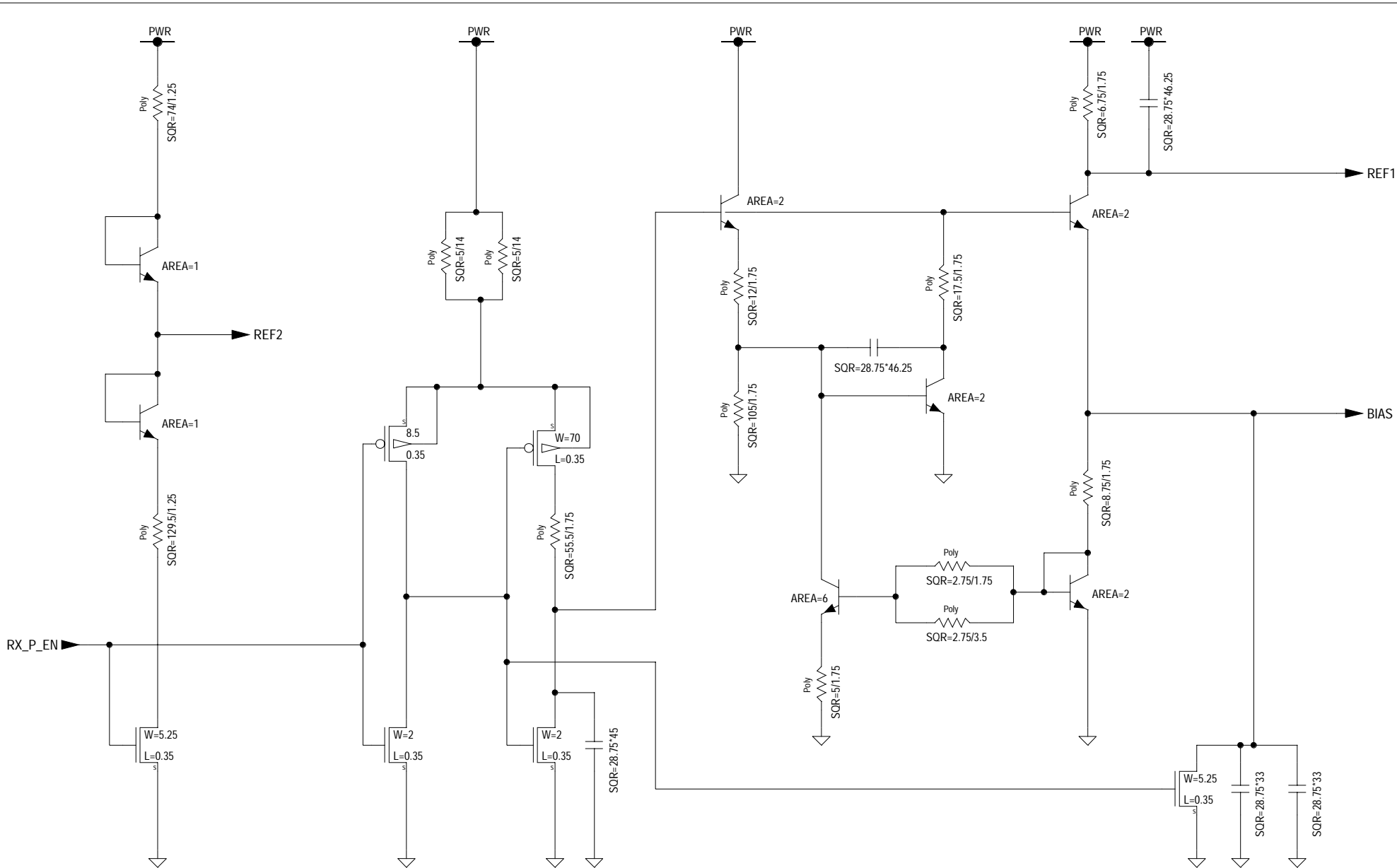


Figure 5.1 BIAS AND REFERENCE VOLTAGES FOR ECL PRESCALER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	ECL_BIAS
		SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:13	LOCATION:	XX
		INITIALS:	GY

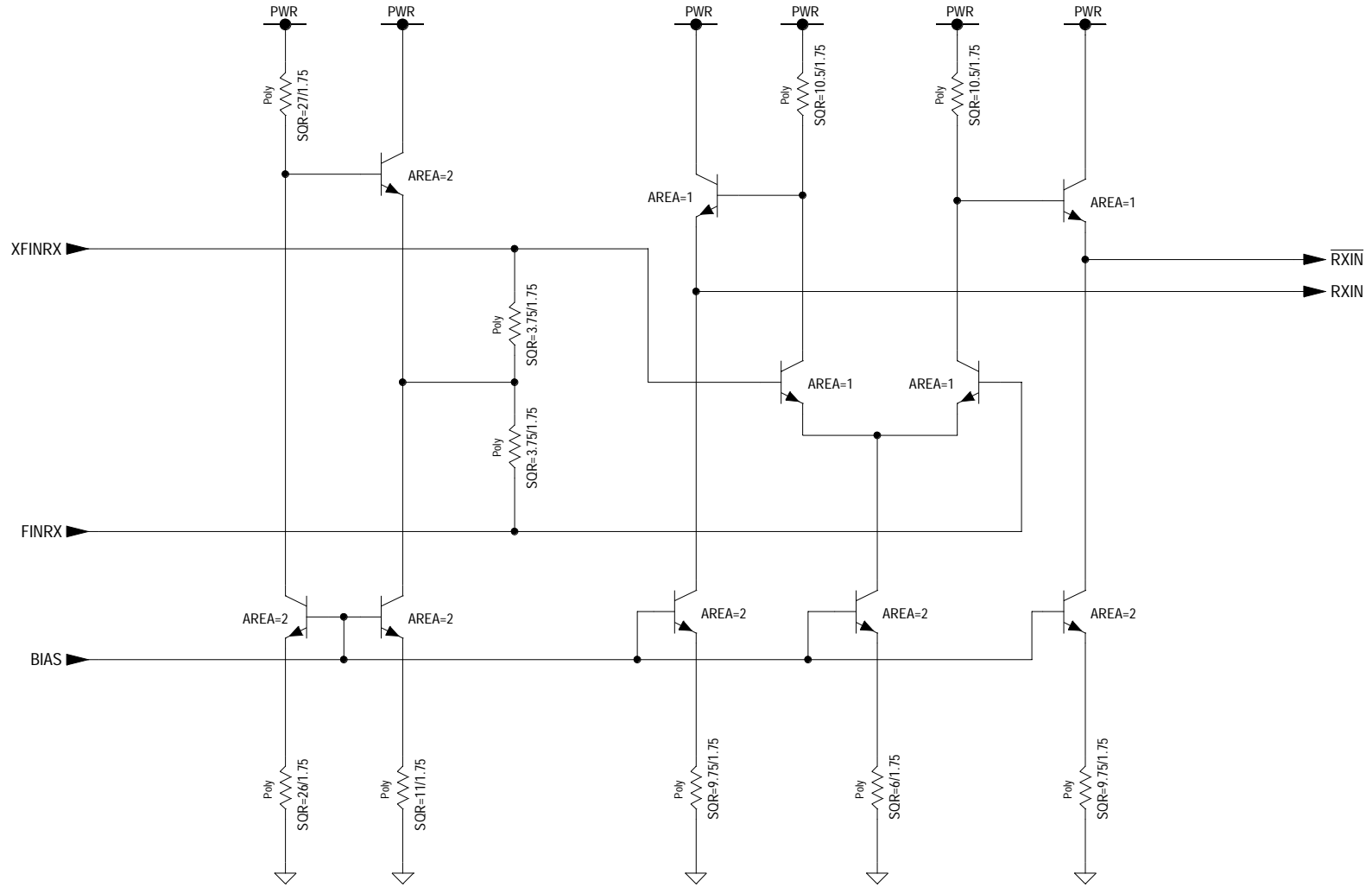


Figure 5.2 RX INPUT PRE-AMPLIFIER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ECL_PREAMP	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:14		
LOCATION:	XX	INITIALS:	GY

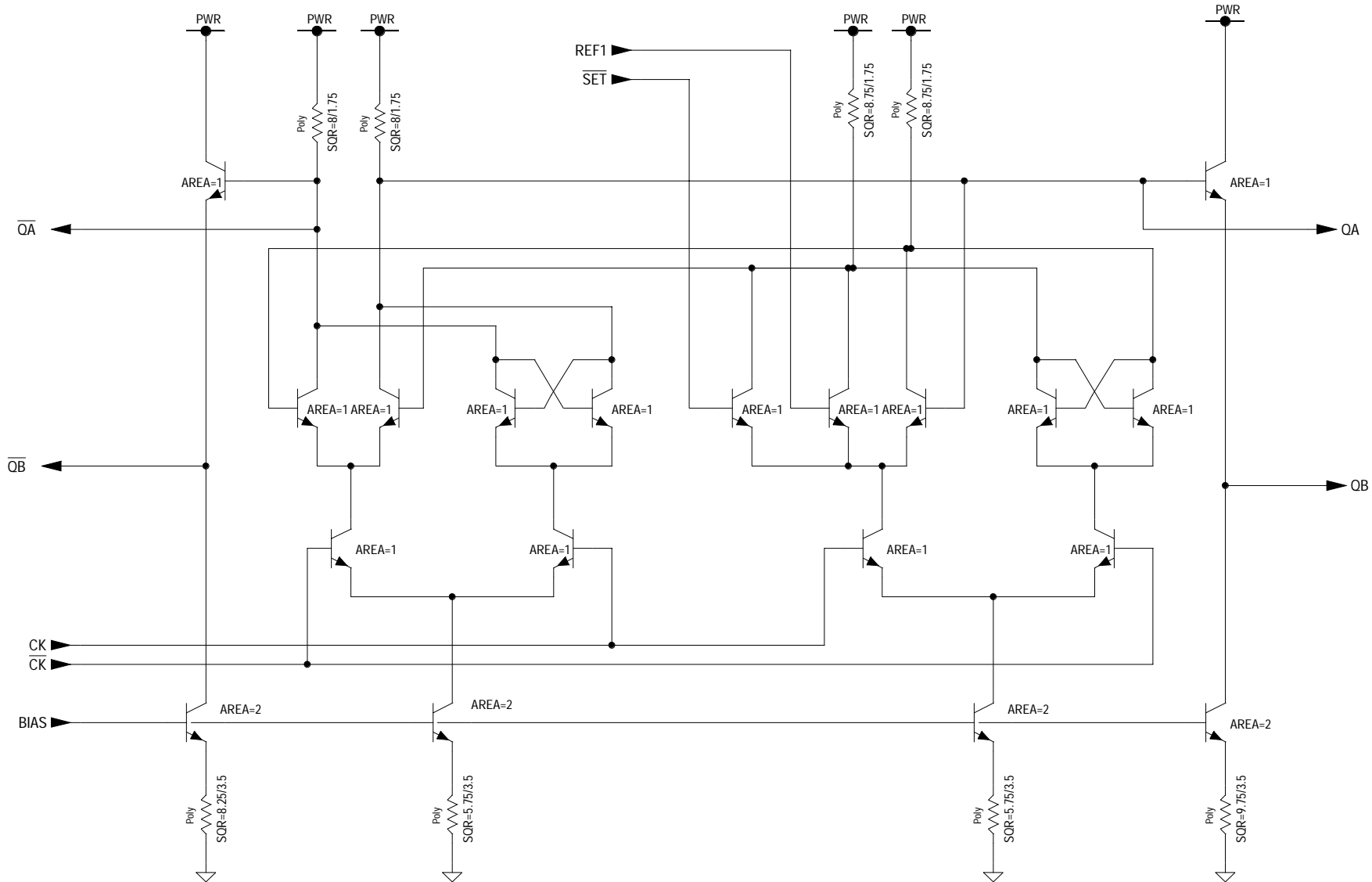


Figure 5.3 ECL - T FLIP-FLOP WITH RESET

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	ECL_TFF1
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:05	LOCATION:	XX
		INITIALS:	GY

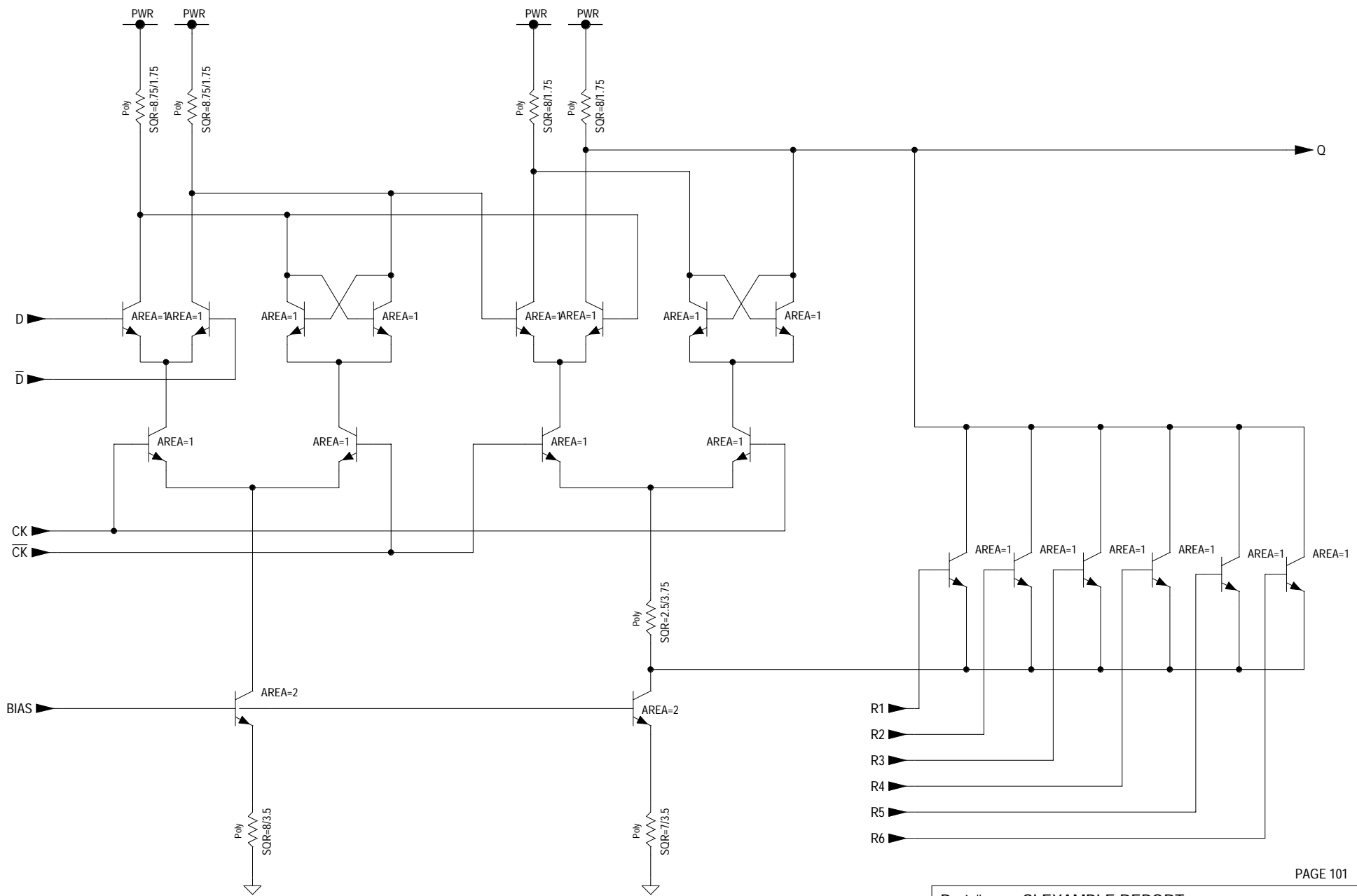


Figure 5.4 ECL - D FLIP-FLOP WITH MULTI-INPUT RESET

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ECL_DFFMR	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:14		
LOCATION:	XX	INITIALS:	GY

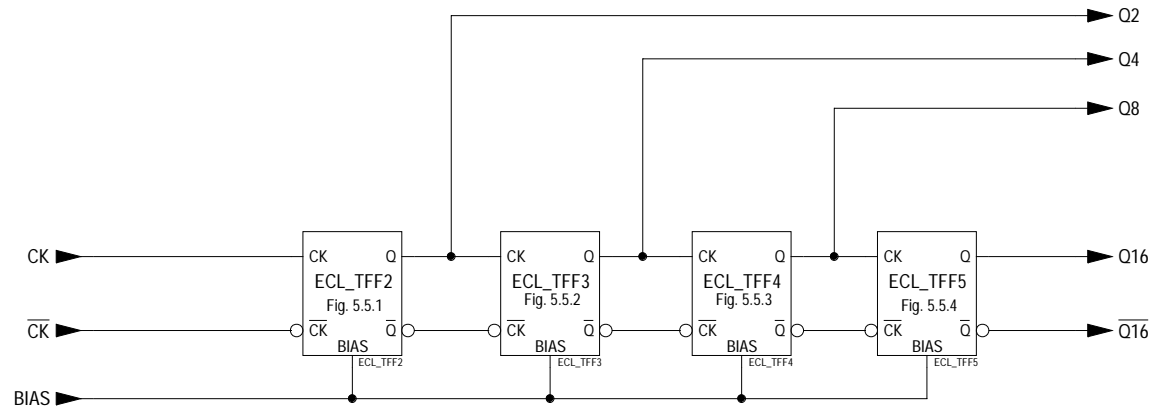


Figure 5.5 ECL PRESCALER DIVIDE BY 16 SECTION

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ECL_DIV_BY16	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:14		
LOCATION:	XX	INITIALS:	GY

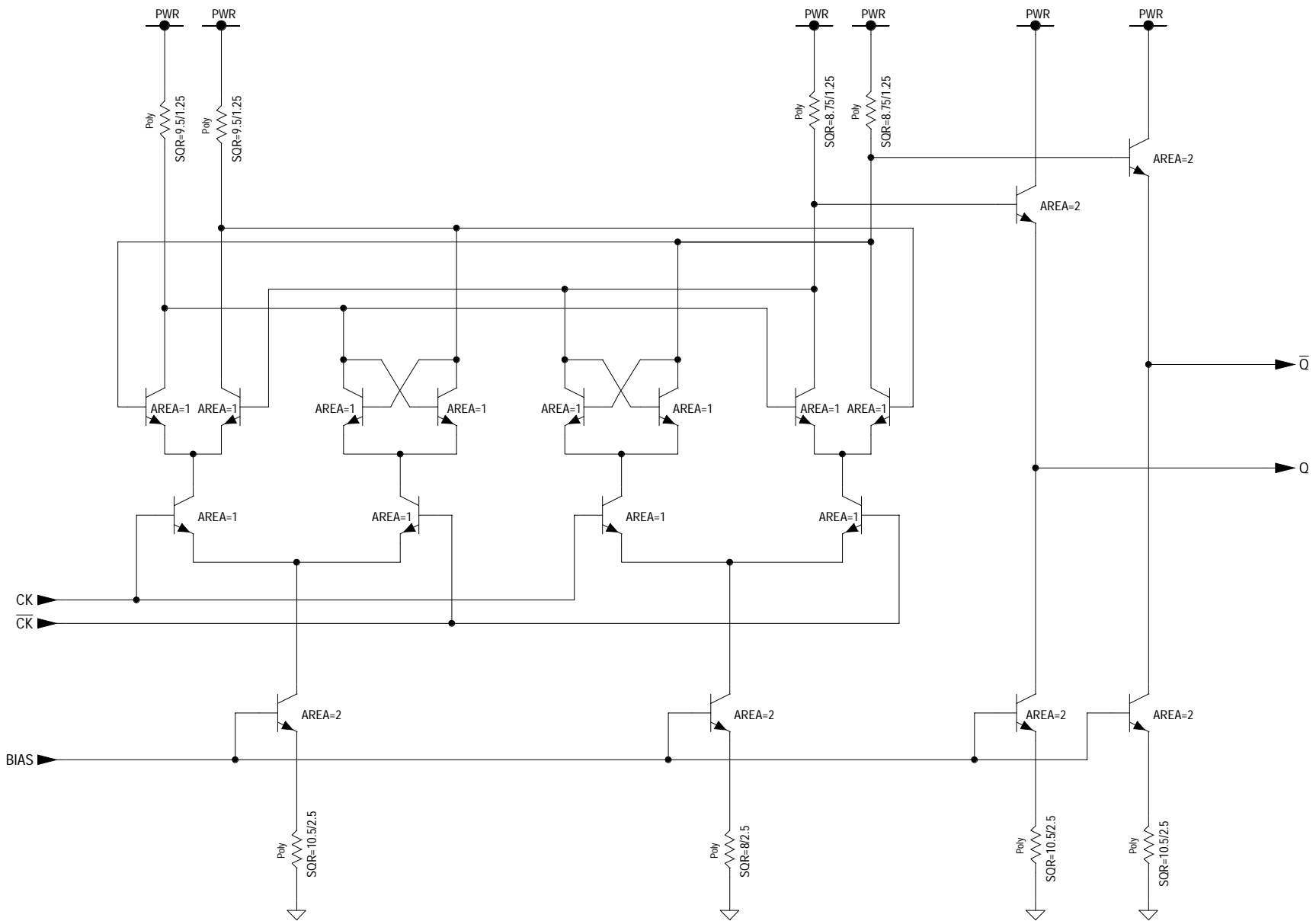


Figure 5.5.1 ECL - T FLIP-FLOP TYPE 2

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	ECL_TFF2
		SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:14	LOCATION:	XX
		INITIALS:	GY



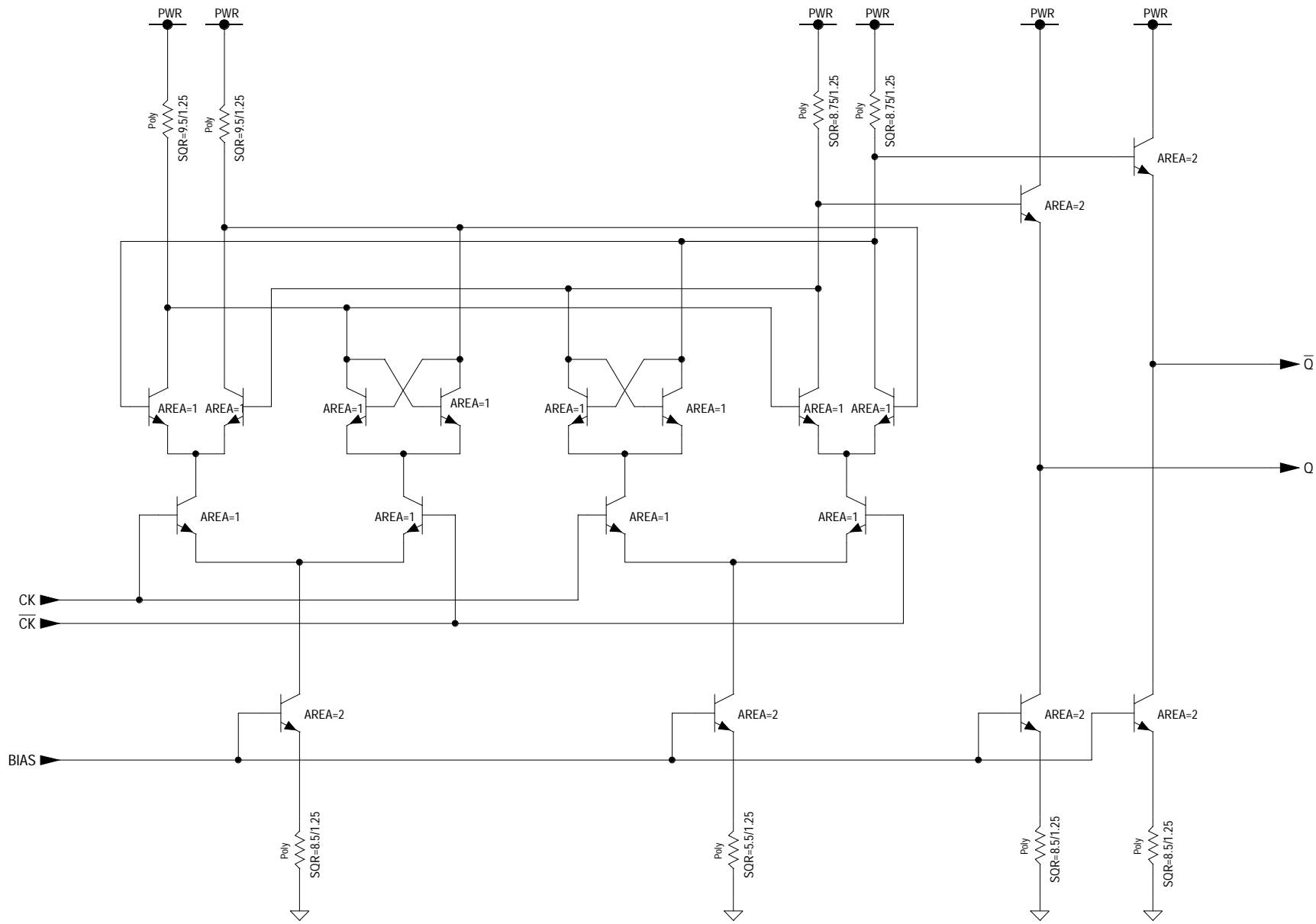


Figure 5.5.2 ECL - T FLIP-FLOP TYPE 3

Part #:	SI EXAMPLE REPORT	
DATE CODE:	0230	
SCH_NAME:	ECL_TFF3	SI NUMBER: SI01
DATE_TIME:	6-18-2002_9:14	
LOCATION:	XX	INITIALS: GY

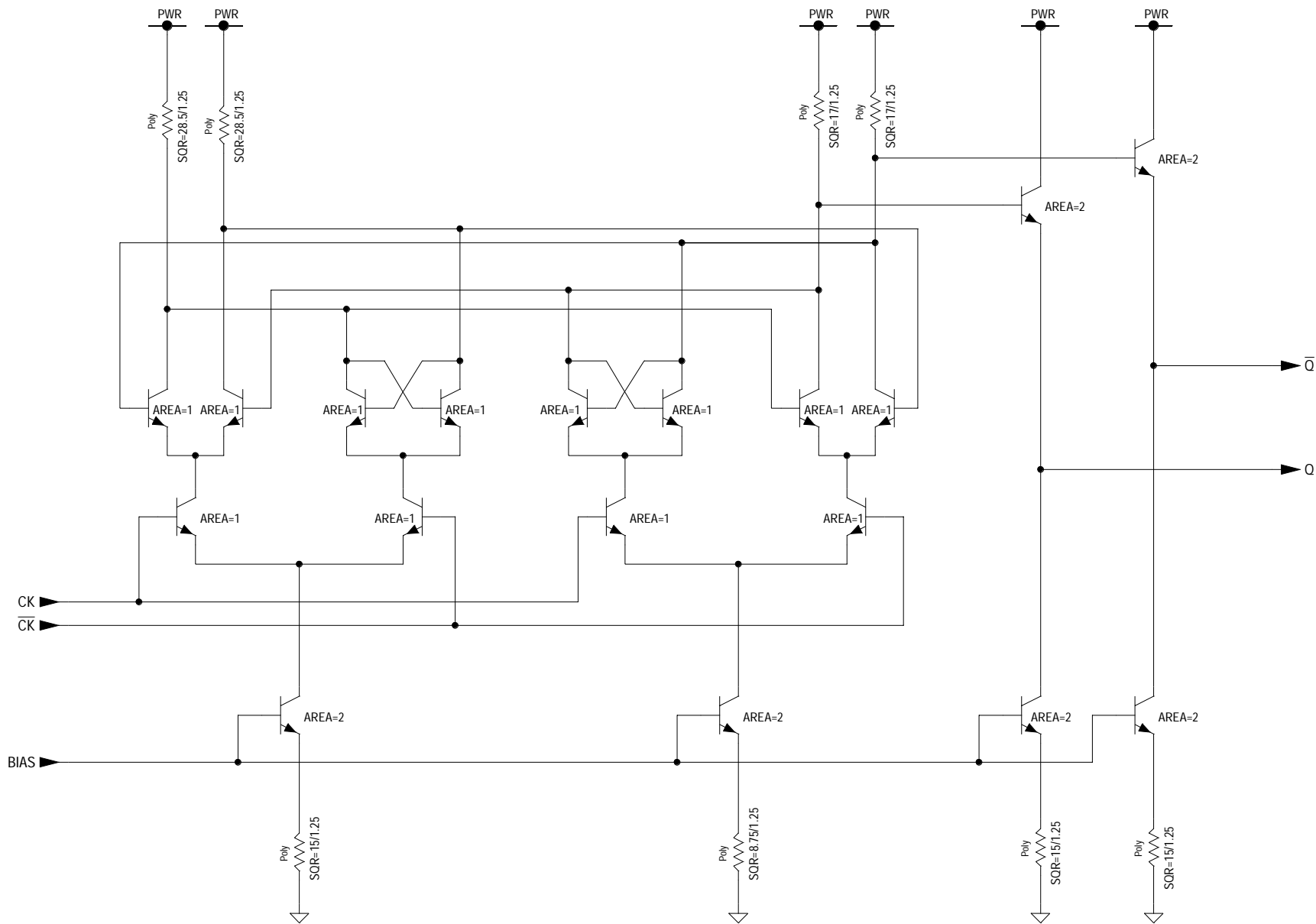


Figure 5.5.3 ECL T FLIP-FLOP TYPE 4

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ECL_TFF4	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:14		
LOCATION:	XX	INITIALS:	GY

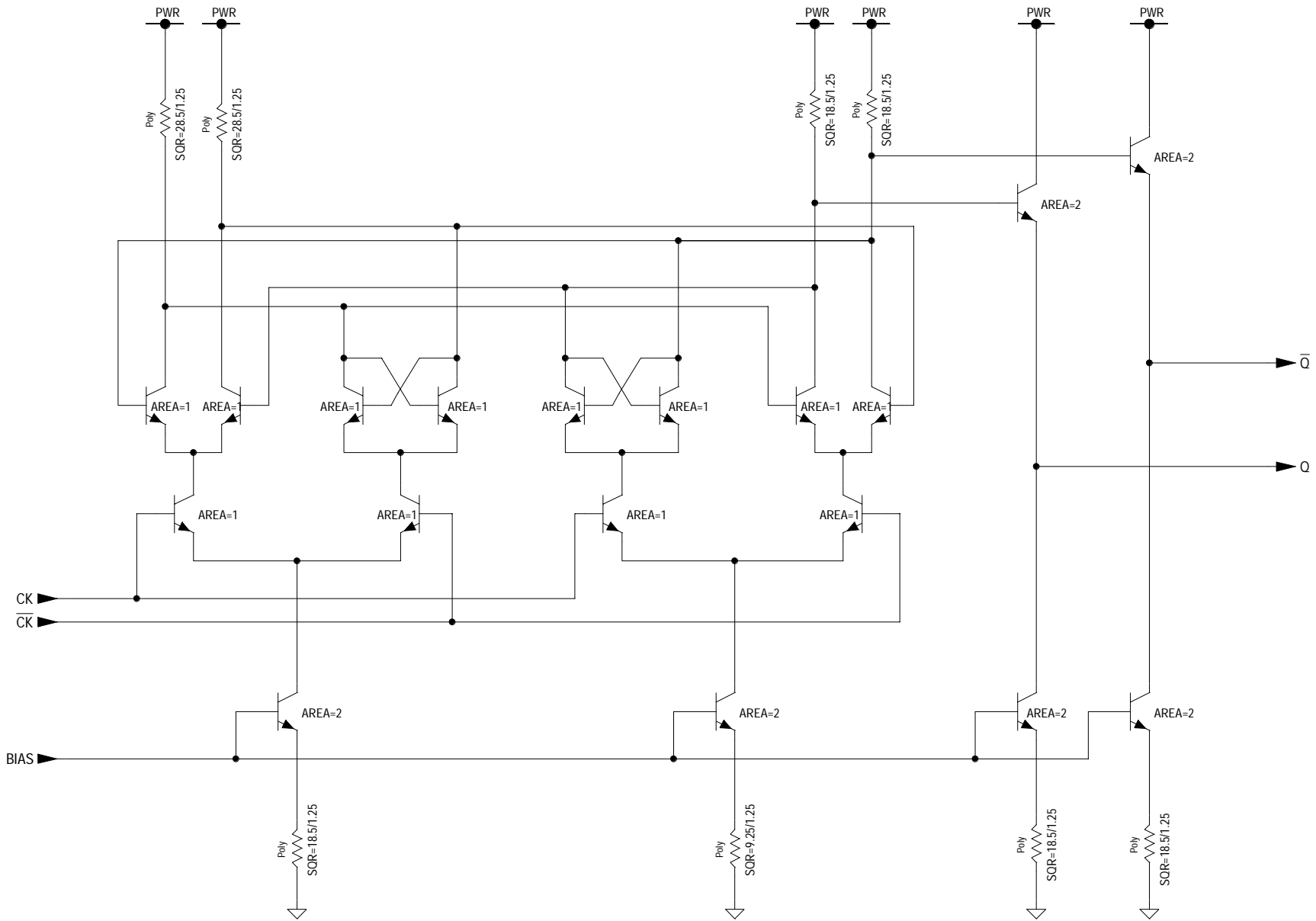


Figure 5.5.4 ECL - T FLIP-FLOP TYPE 5

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	ECL_TFF5
		SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:14	LOCATION:	XX
		INITIALS:	GY

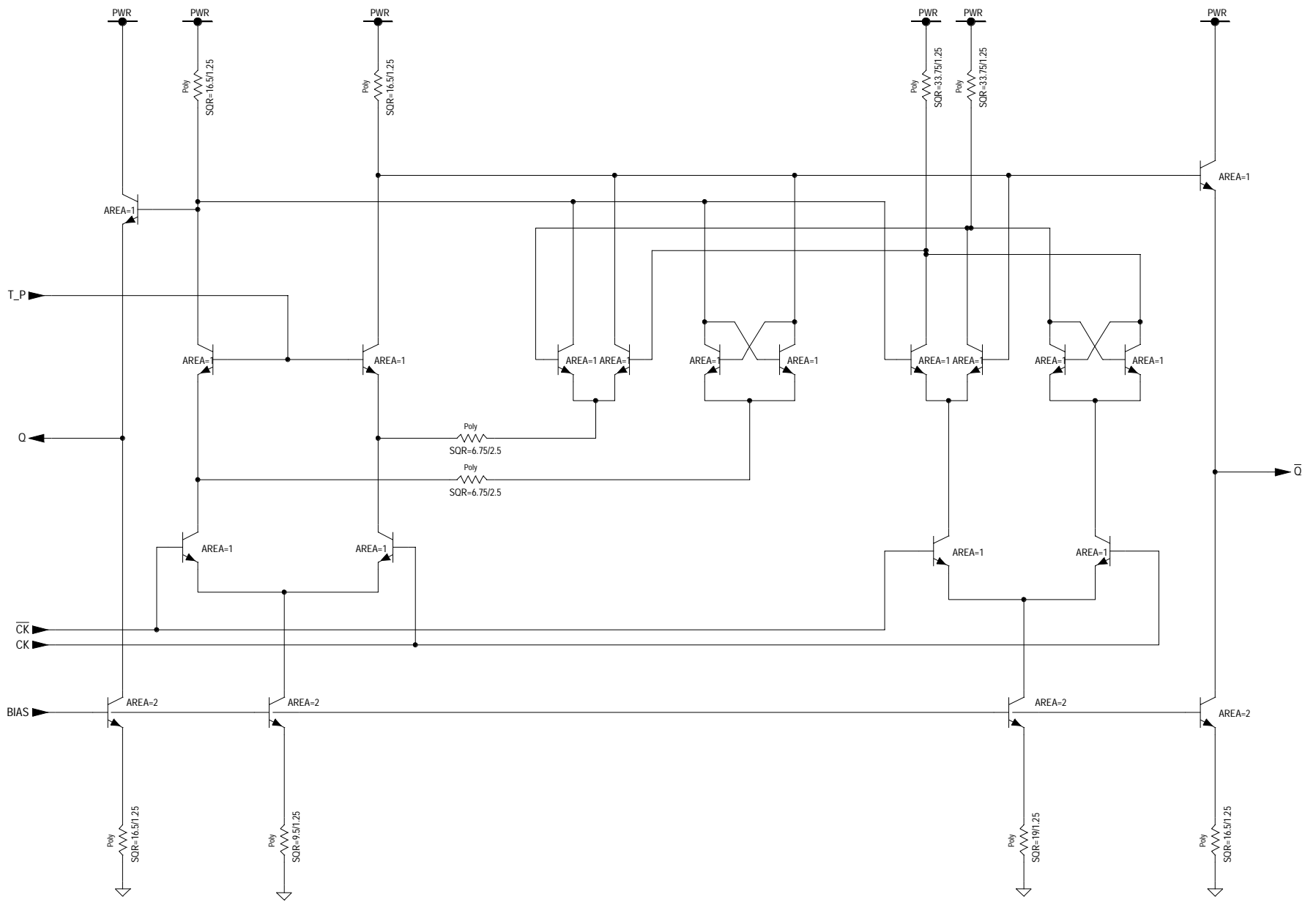


Figure 5.6 ECL T FLIP-FLOP TYPE 6

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	ECL_TFF6
		SI NUMBER:	SI01
		DATE_TIME:	6-18-2002_9:14
LOCATION:	XX	INITIALS:	GY

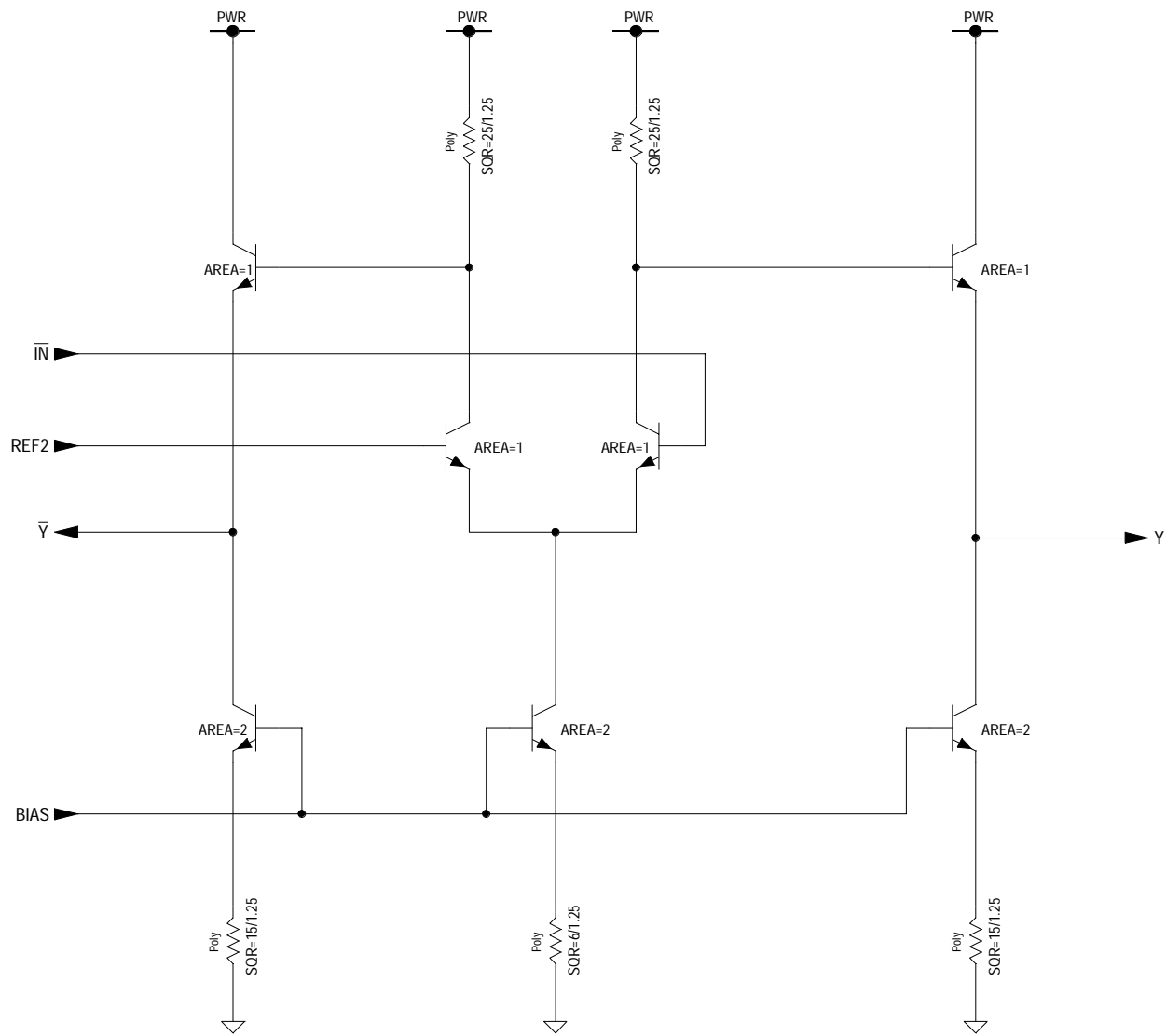


Figure 5.7 ECL BUFFER TYPE 1

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ECL_BUF1	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:14		
LOCATION:	XX	INITIALS:	GY

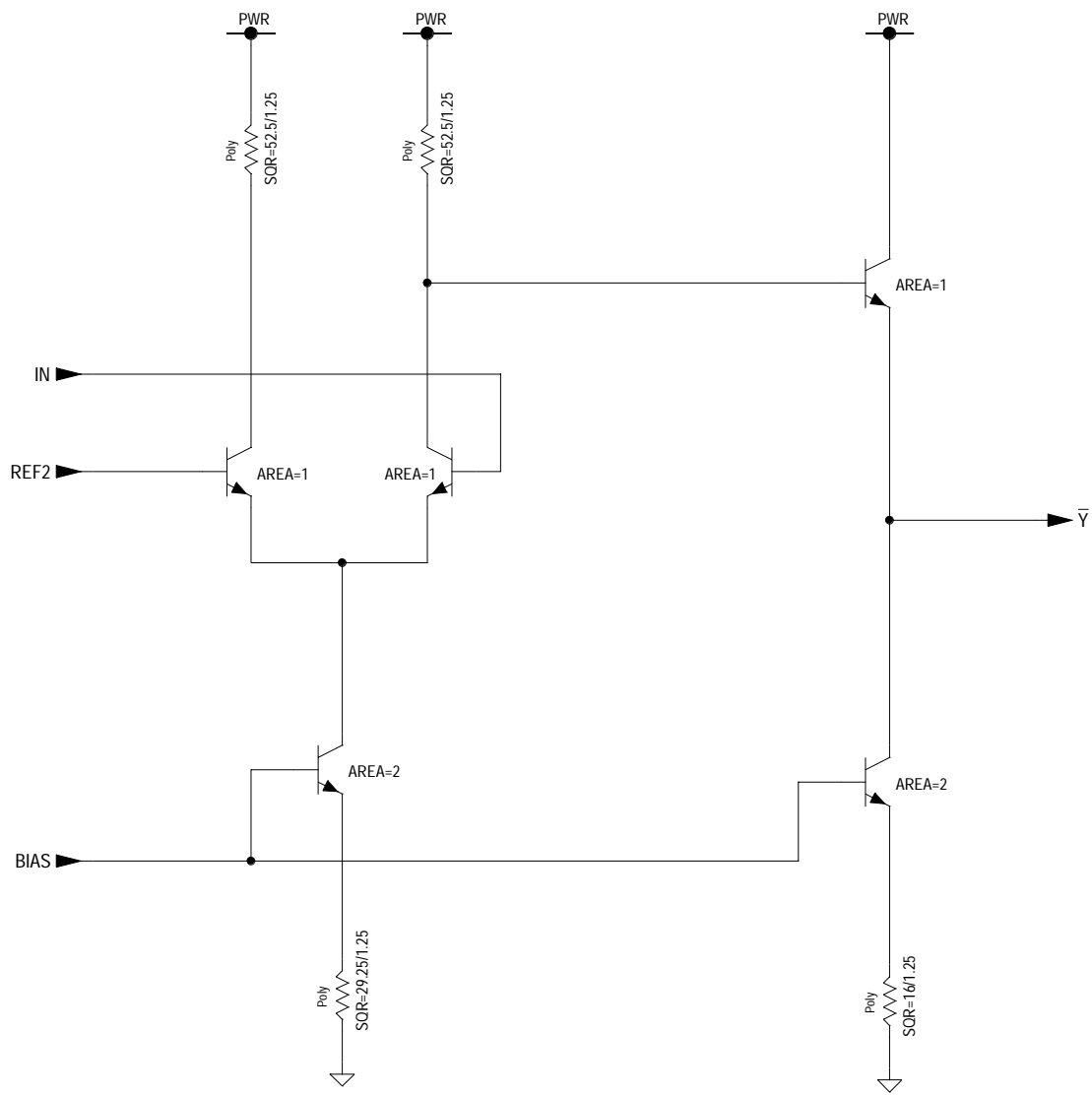


Figure 5.8 ECL INVERTER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ECL_BUF2B	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:05		
LOCATION:	XX	INITIALS:	GY

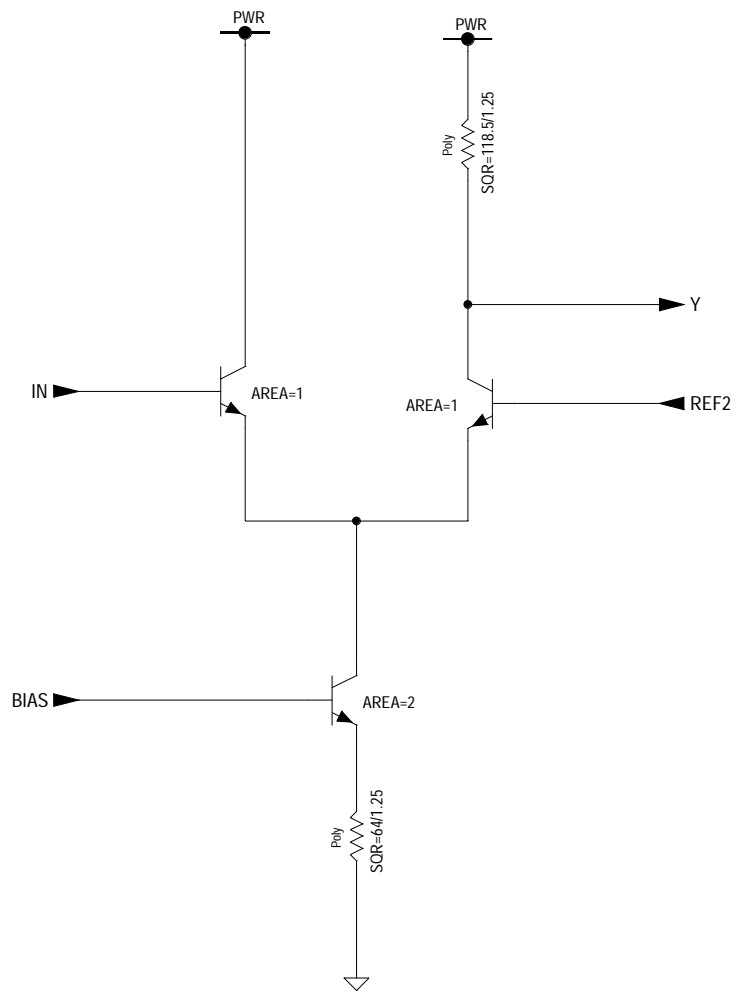


Figure 5.9 ECL BUFFER TYPE 3

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	ECL_BUF3	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:05		
LOCATION:	XX	INITIALS:	GY

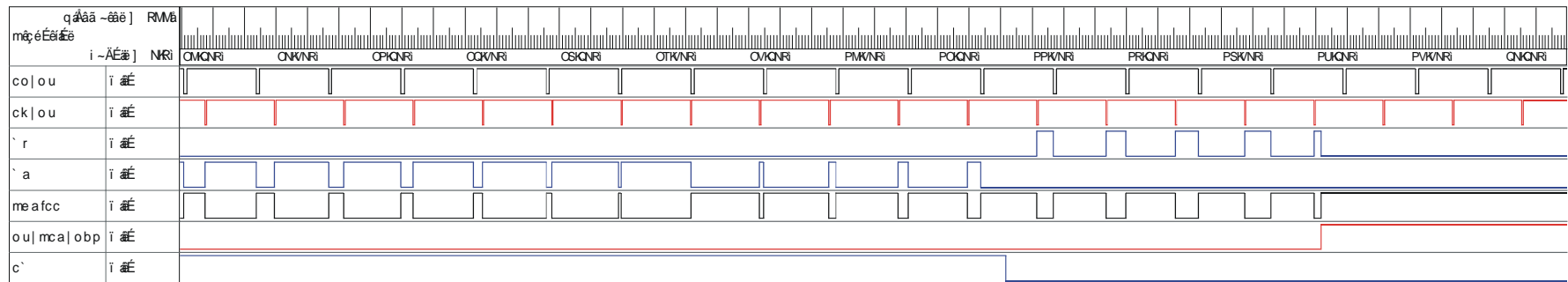
## 6.0 Phase Frequency Detector

*The following section was taken from a frequency synthesizer report. The analysis for this section included simulation results.*

The Phase Frequency Detector (PFD) shown in Figure 6 is of conventional design methodology. Except for the Charge\_Up (CU) and Charge\_Down (CD) outputs, it generates the Phase Difference (~PHDIFF) signal, which is used to drive the Lock detector and Charge Pump & Fast Lock logic. The RX\_FC input is used to control PFD operation, depending on external Voltage Controlled Oscillator (VCO) polarity. There are two types of VCOs. Type 1 increases output frequency with increasing control voltage and type 2 decreases output frequency with increasing control voltage. PFD timing is shown in Diagram 6.1.

The PFD logic includes a small delay in the CU and CD flip-flop Reset path. This delay ensures the generation of short compensating pulses that prevent the Phase Lock Loop (PLL) from entering the “dead zone” and eliminates crossover distortion. Diagram 6.2 shows the compensating pulses. For this simulation all gate delays were set to 0.3 ns.





**Diagram 6.1: Phase Frequency Detector timing.**

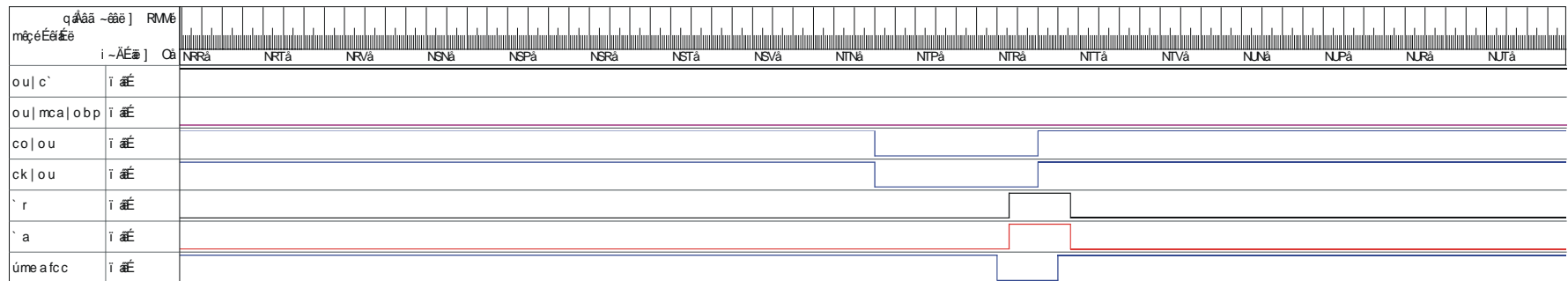
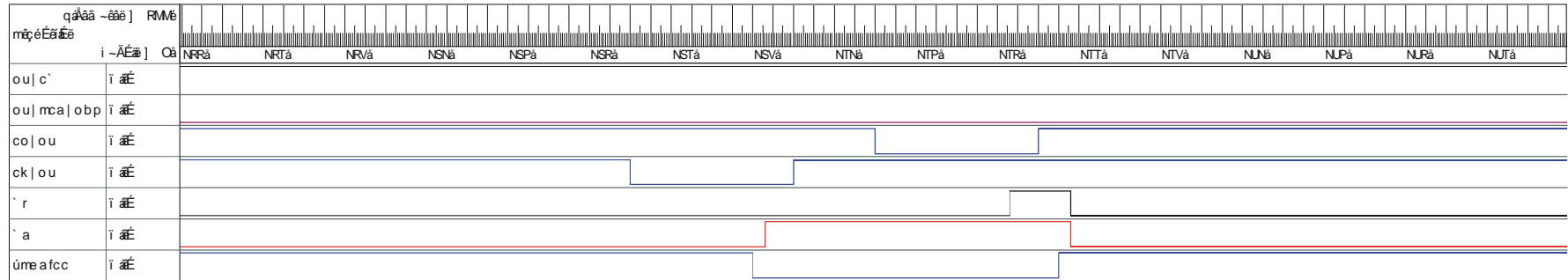


Diagram 6.2: PFD detailed timing.

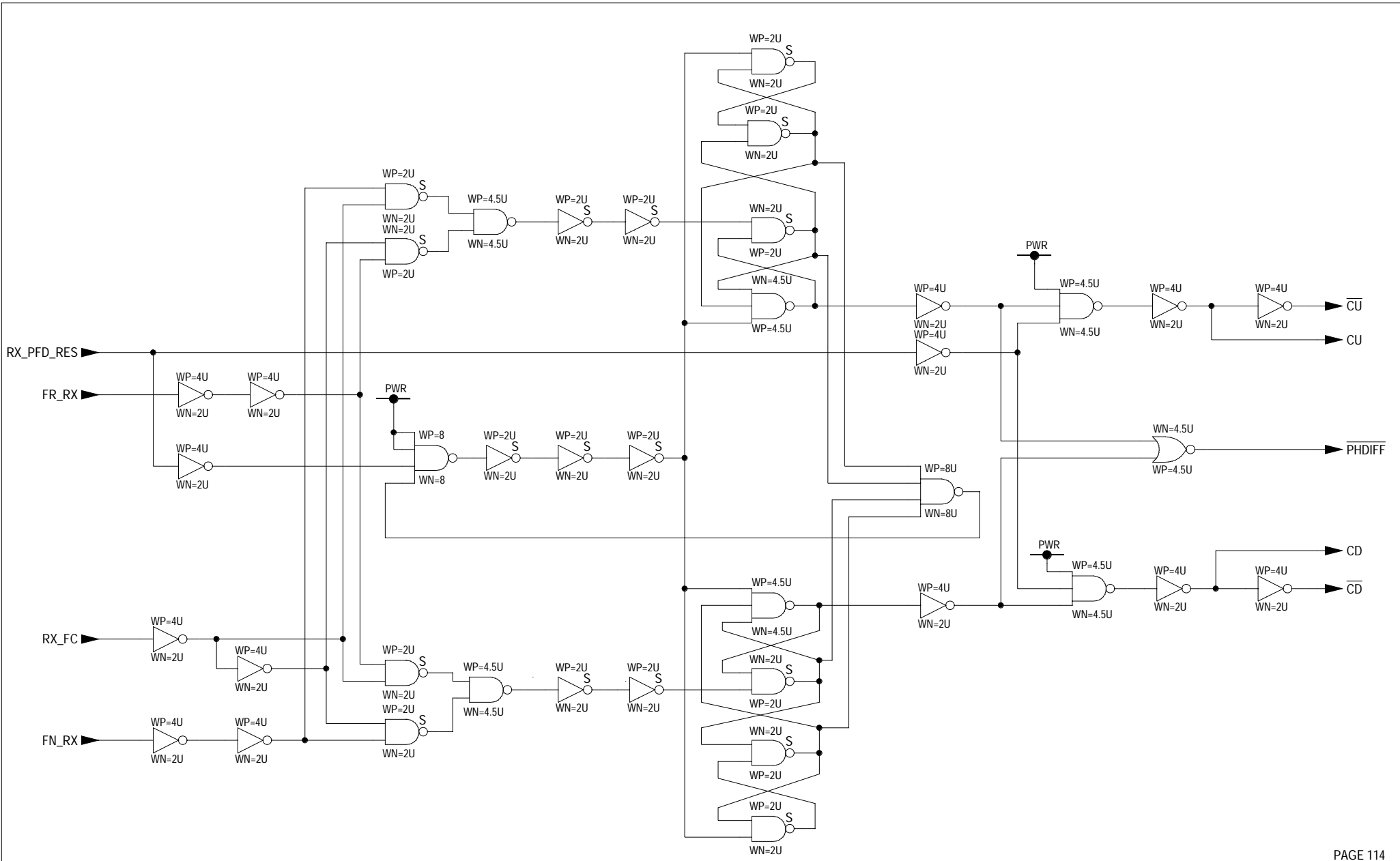


Figure 6.0 PHASE / FREQUENCY DETECTOR

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	PHDETECTOR
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:05	LOCATION:	XX
		INITIALS:	GY

## 7.0 ADC Converter

*The following section was taken from an mixed signal device and consists of a portion of the analog to digital converter.*

The SI Example IC ADC schematic is found in Figure 7.0 contained in Section 7. The ADC has a pipelined nine-stage architecture. The first stage comprises a 2½ bit flash converter and a residue amplifier. The end stage is also a two and half bit flash converter. The ADC can be configured as a 12bit converter, although it is specified as a 10 bit in the data sheet.

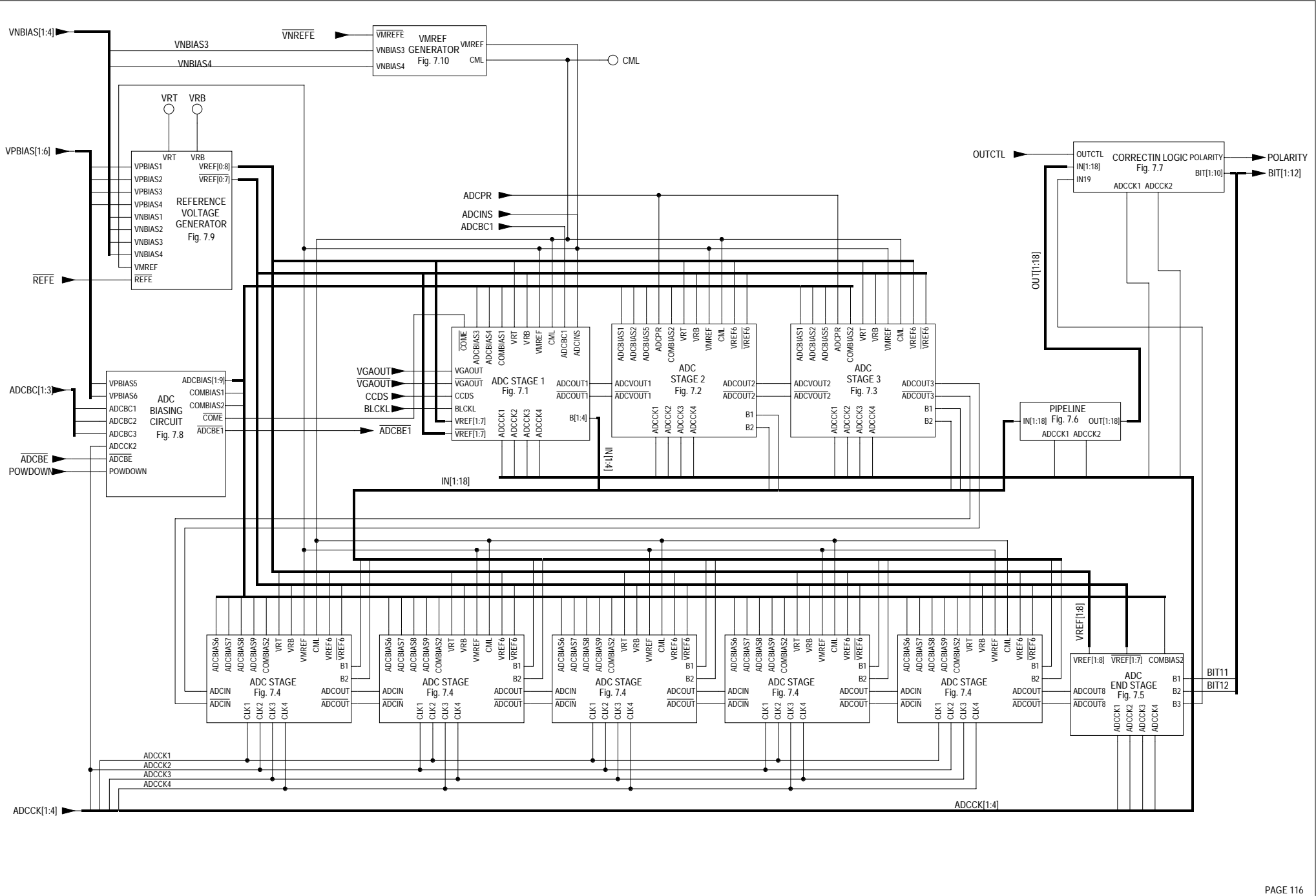


Figure 7.0 ADC

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	61	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:15		
LOCATION:	XX	INITIALS:	GY

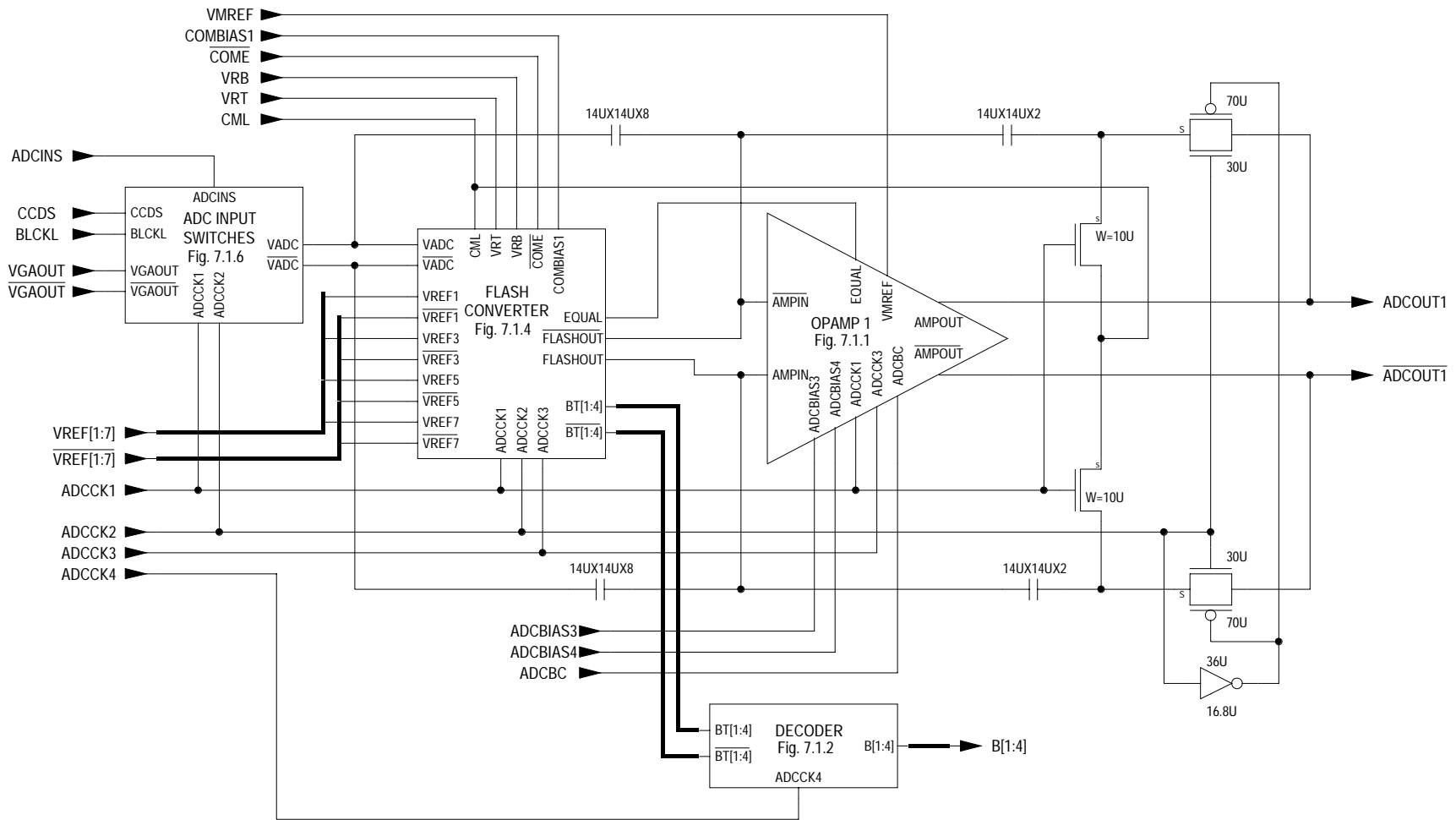


Figure 7.1 ADV STAGE 1

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	53	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:15		
LOCATION:	XX	INITIALS:	MH

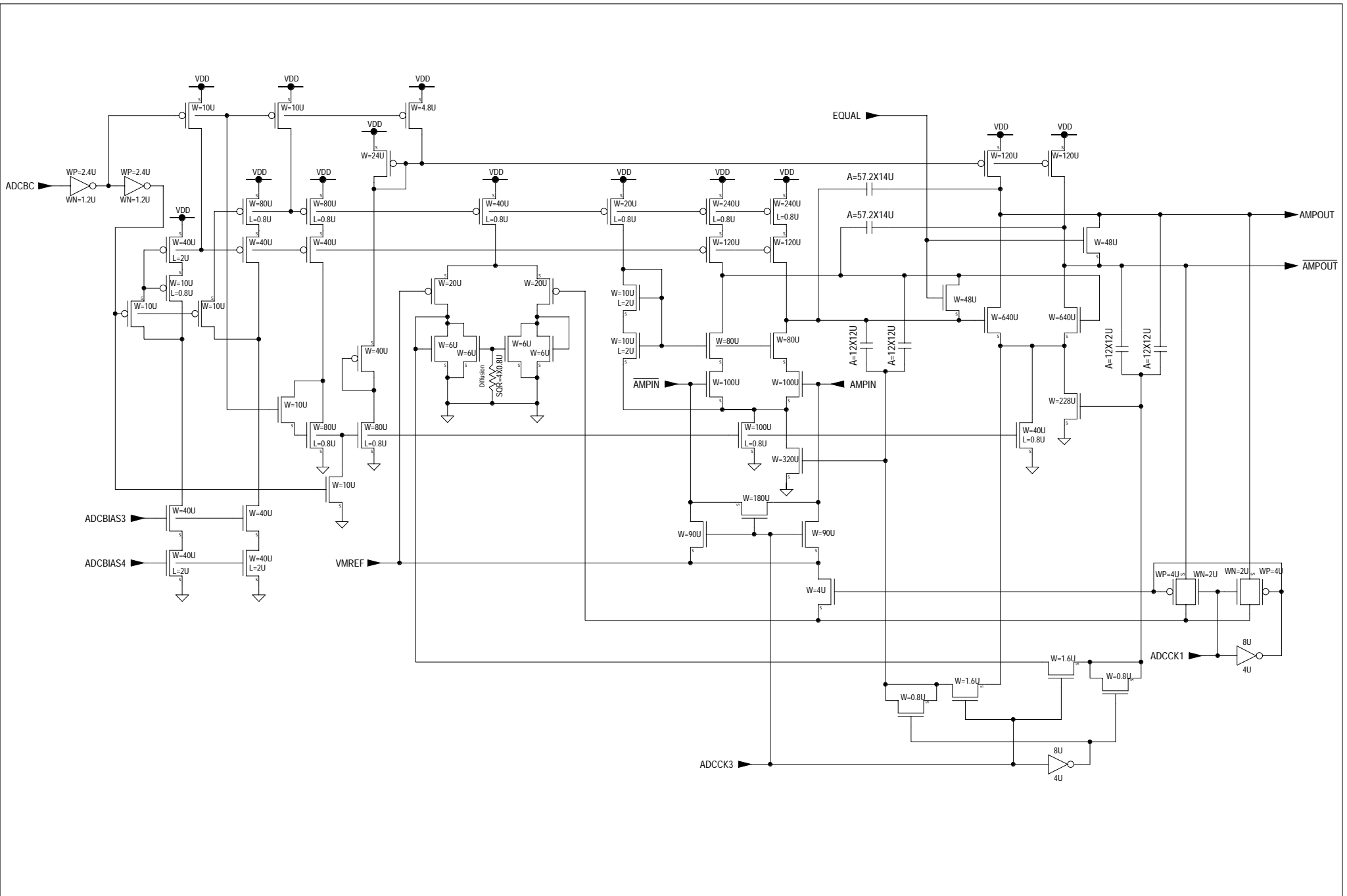


Figure 7.1.1 OPAMP1

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	52	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:15		
LOCATION:	XX	INITIALS:	MH

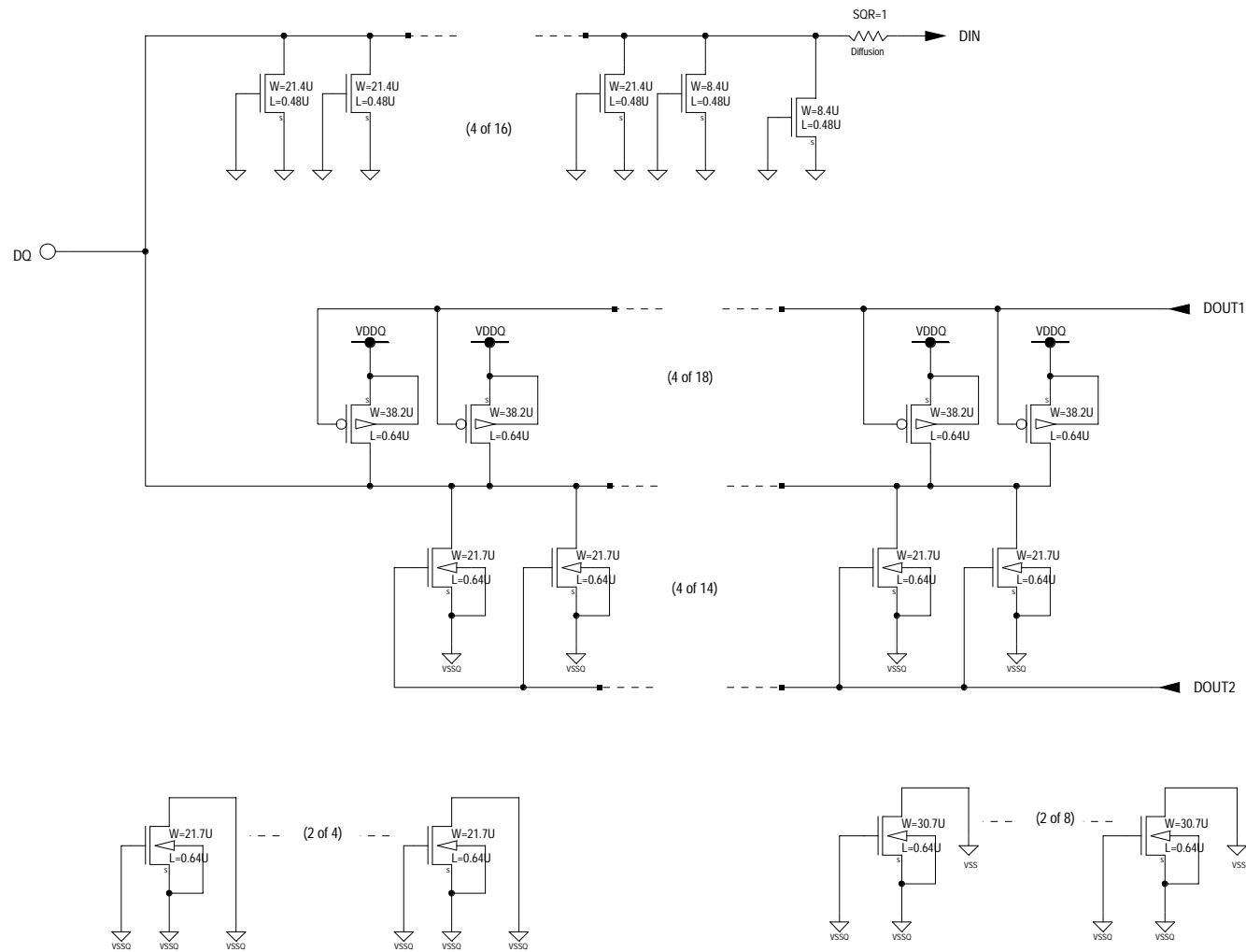


Figure 7.1.1.1 ESD PROTECTION - DQ PIN

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0031	SCH_NAME:	ESD_DO
		SI NUMBER:	4967
DATE_TIME:	6-18-2002_9:15	LOCATION:	XXX
		INITIALS:	AZ, LW



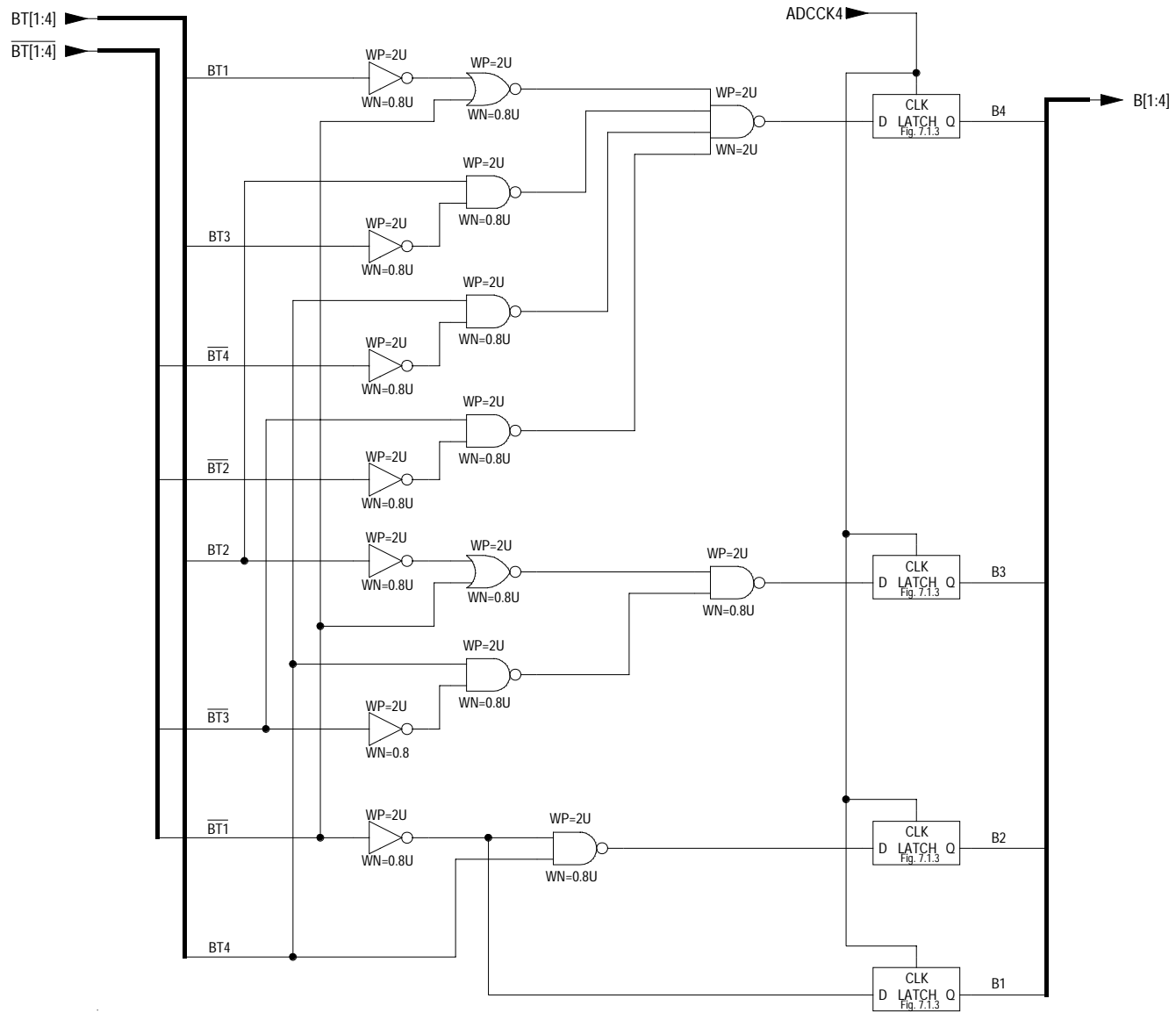


Figure 7.1.2 FLASH CONVERTER DECODER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	51	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:05		
LOCATION:	XX	INITIALS:	MH

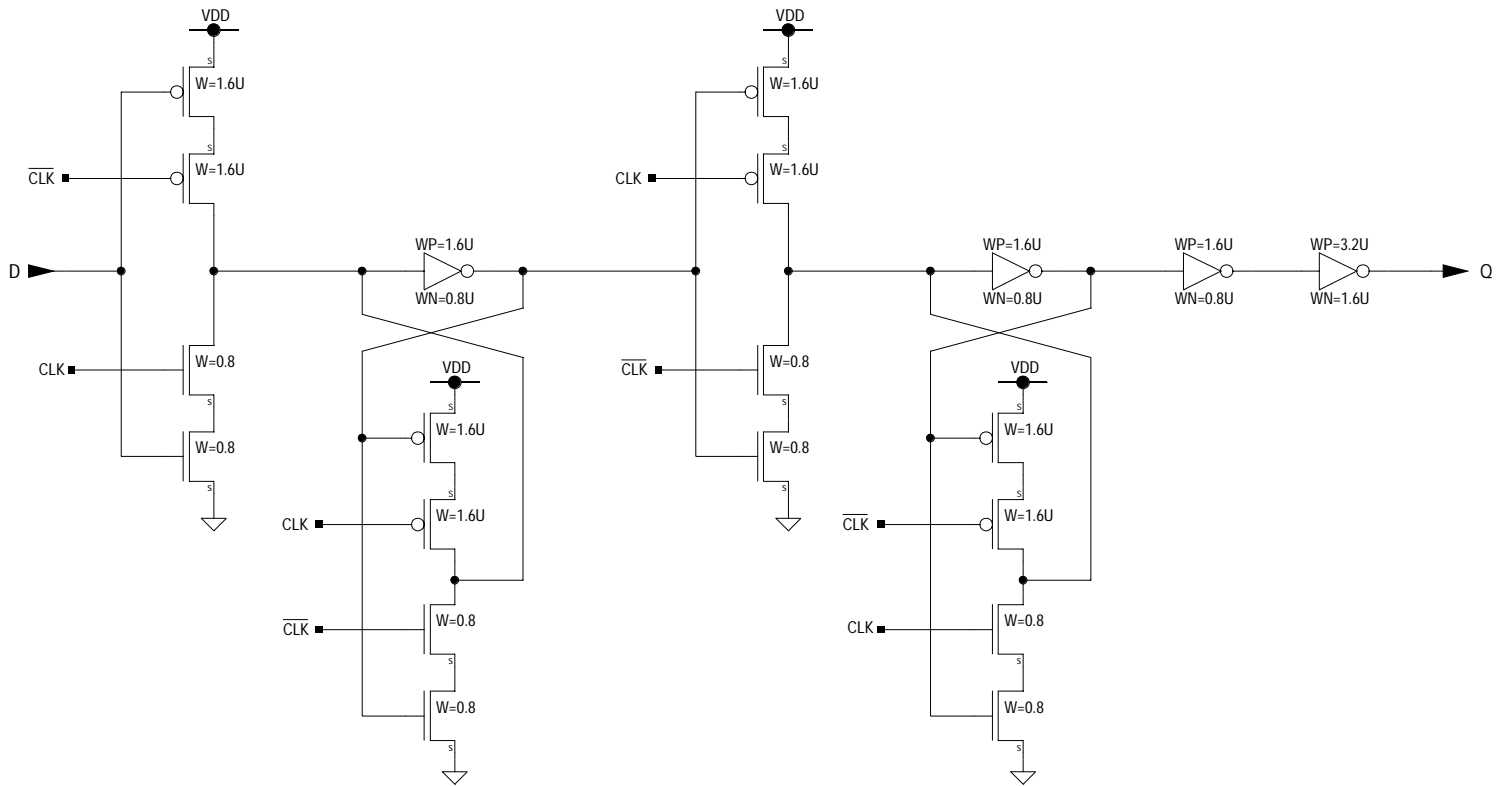
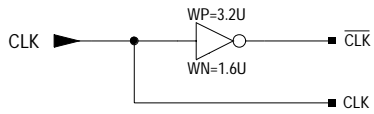
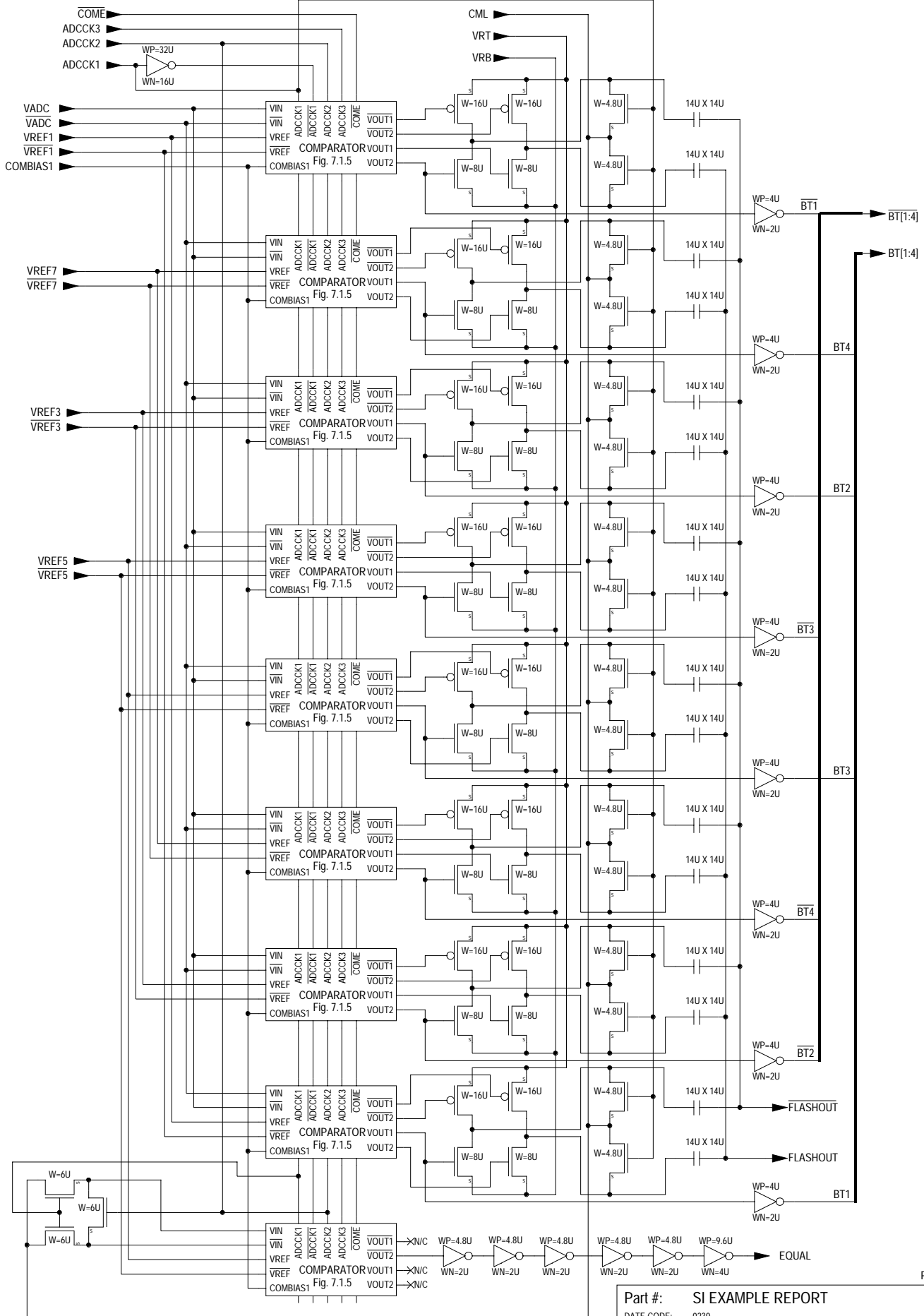


Figure 7.1.3 LATCH 1

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	50	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:05		
LOCATION:	XX	INITIALS:	MH



Part #: SI EXAMPLE REPORT

DATE CODE: 0230  
 SCH\_NAME: 49 SI NUMBER: SI01  
 DATE\_TIME: 6-20-2002\_13:05  
 LOCATION: XX INITIALS: MH

Figure 7.14 FLASH CONVERTER

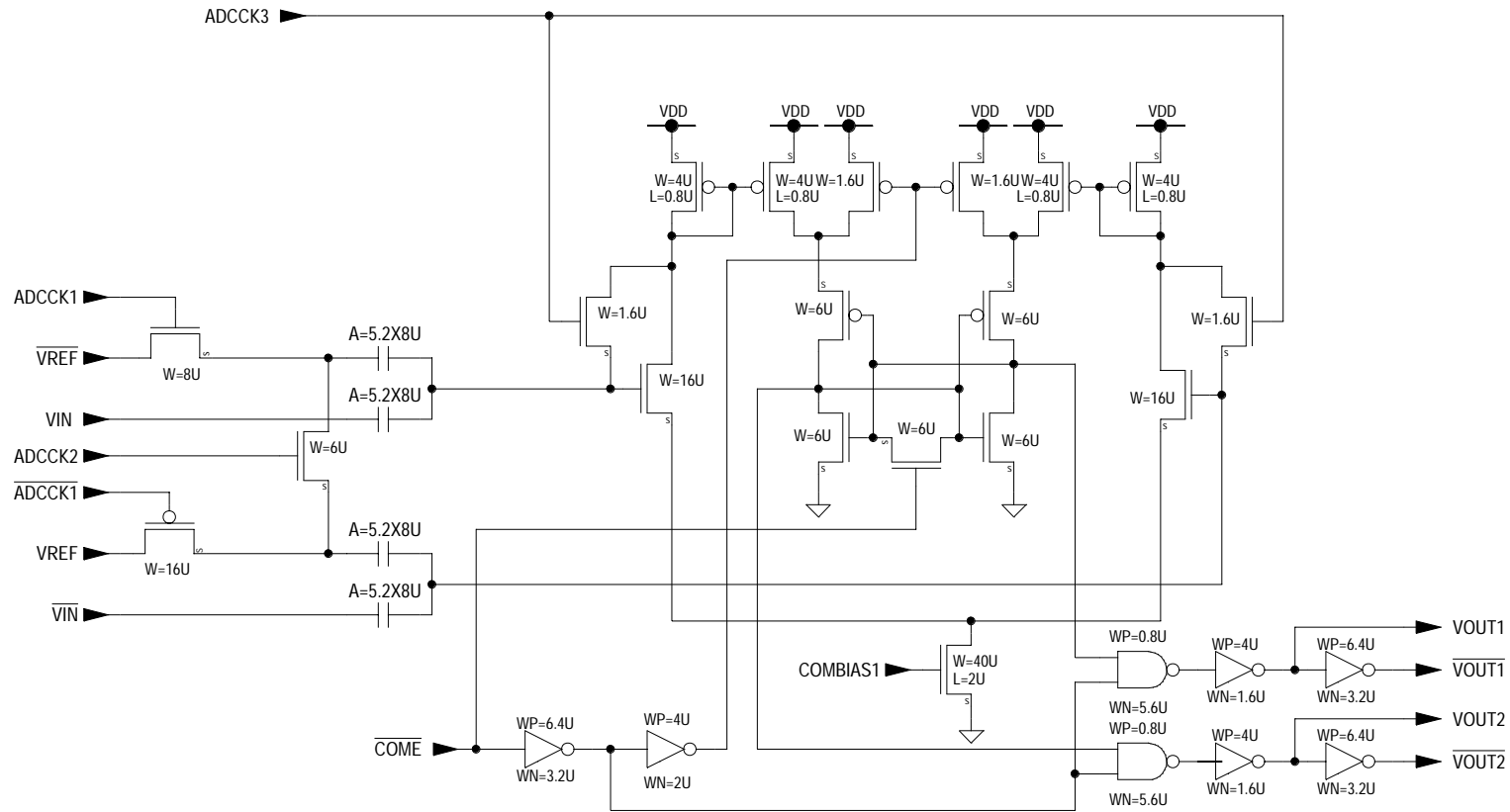


Figure 7.1.5 COMPARATOR 1

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	48	SII NUMBER:	SI01
DATE_TIME:	6-18-2002_9:22		
LOCATION:	XX	INITIALS:	MH

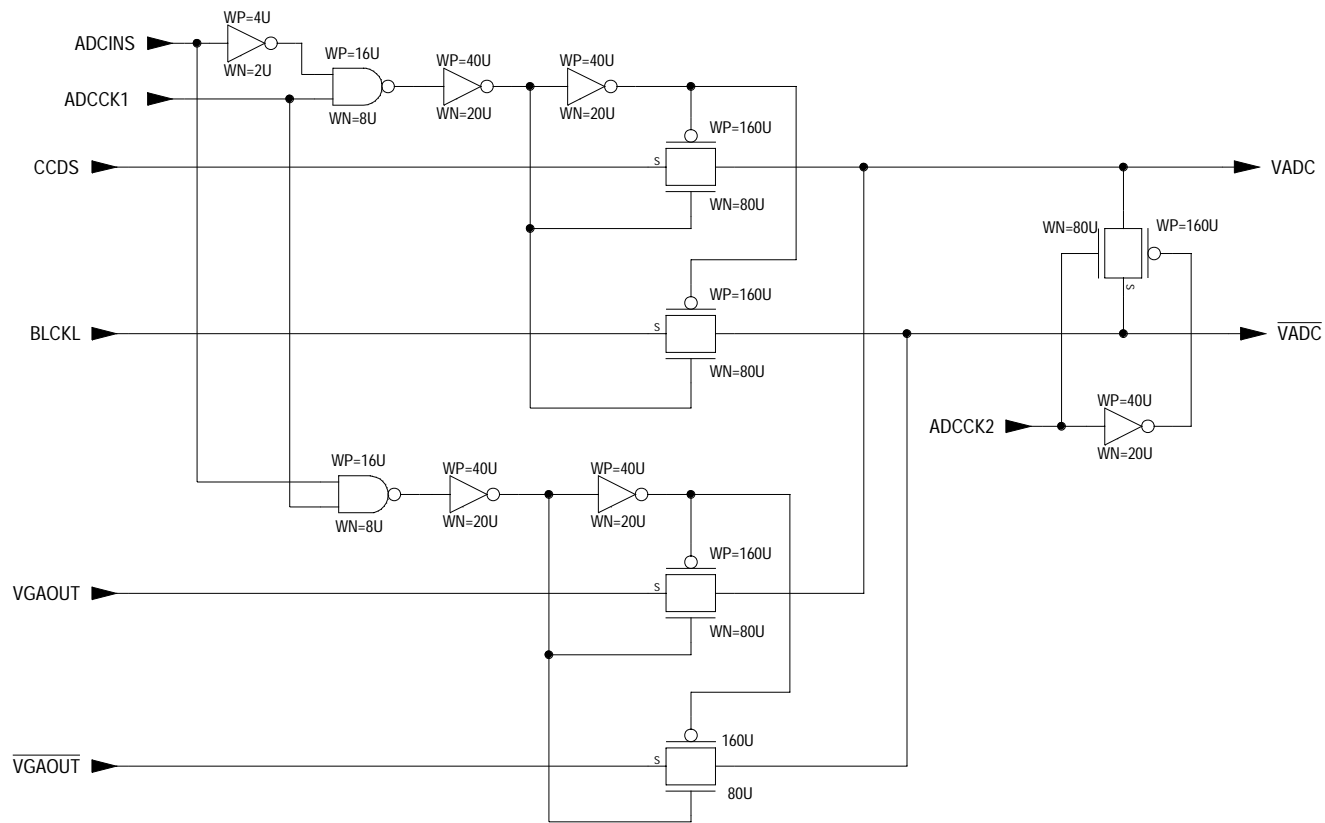


Figure 7.1.6 INPUT SWITCHES

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	47	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:07		
LOCATION:	XX	INITIALS:	MH

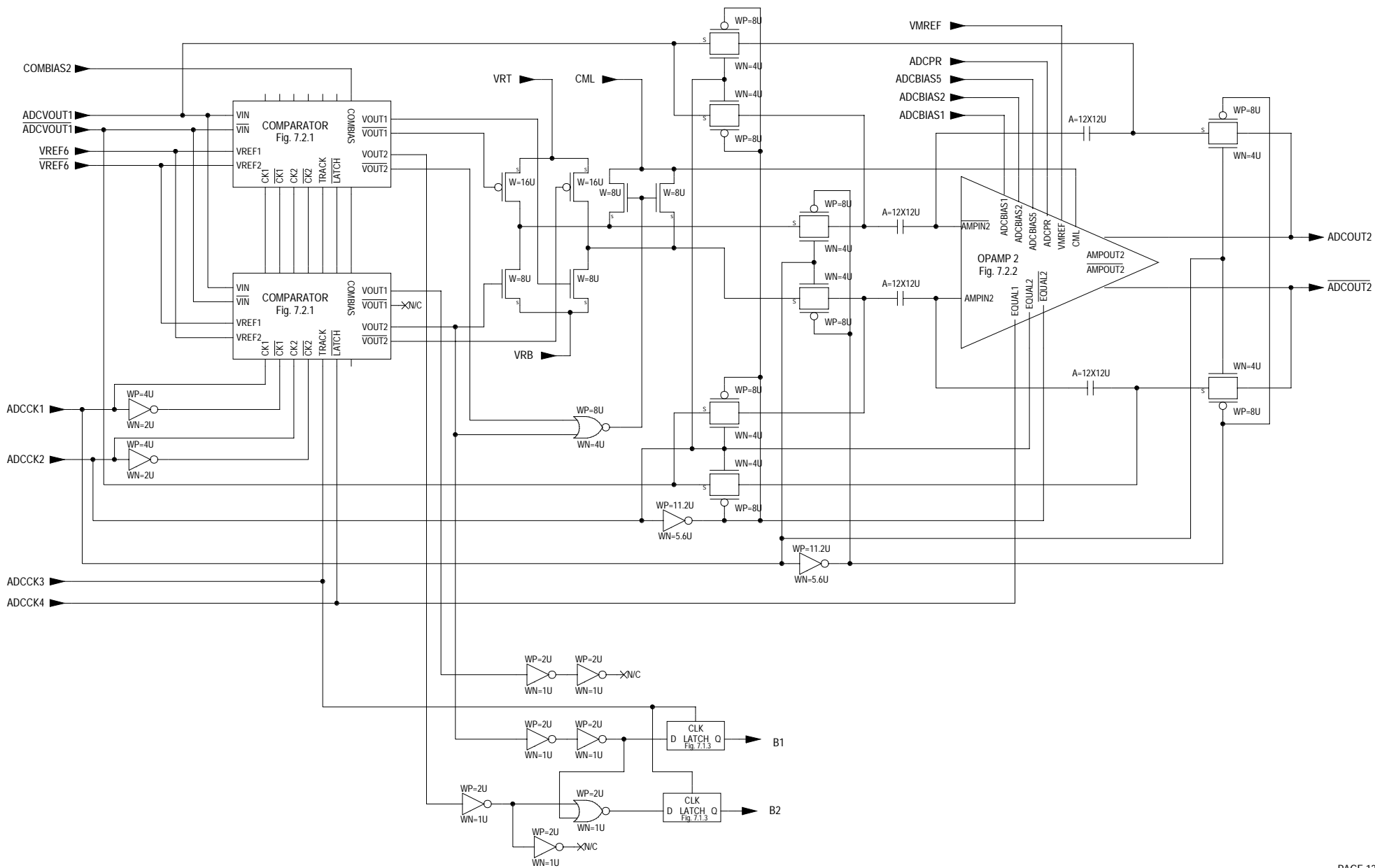


Figure 7.2 ADC STAGE 2

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	56
DATE_TIME:	6-18-2002_9:22
LOCATION:	XX
SI NUMBER:	SI01
INITIALS:	MH

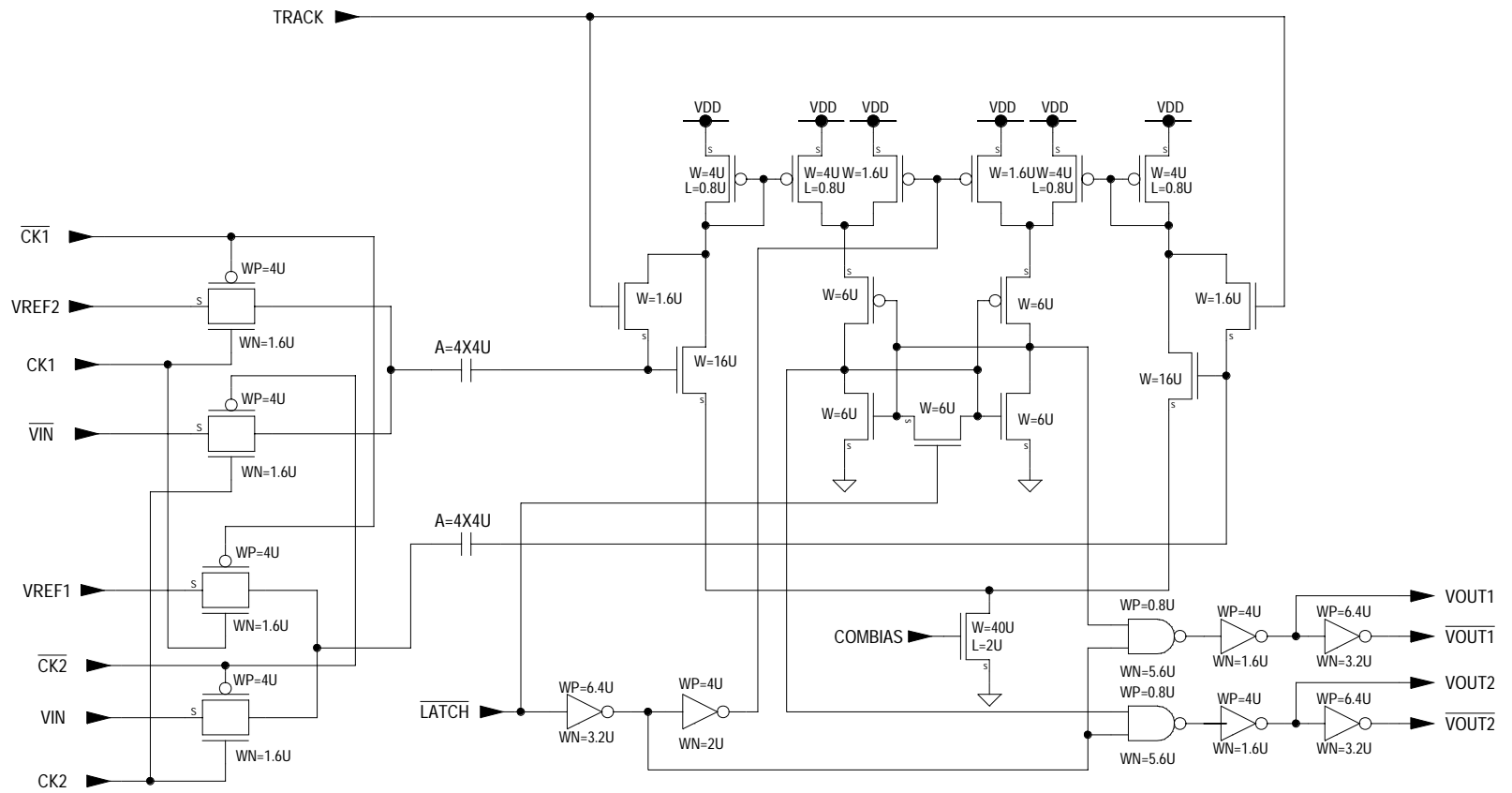


Figure 7.2.1 COMPARATOR 2

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	54	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:22		
LOCATION:	XX	INITIALS:	MH

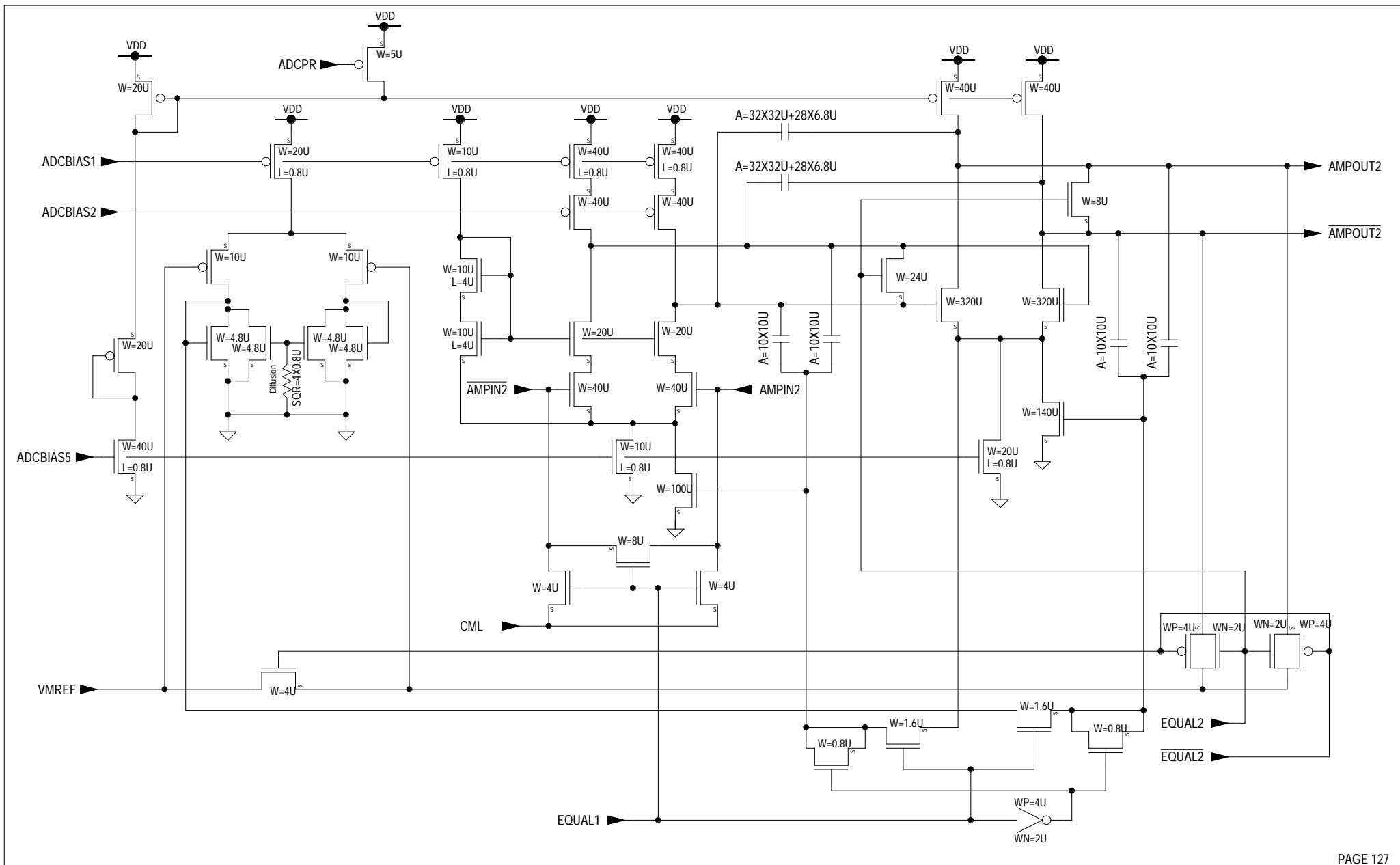


Figure 7.2.2 OPAMP 2

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	55
SCH_NAME:	55	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:07	LOCATION:	XX
LOCATION:	XX	INITIALS:	GY



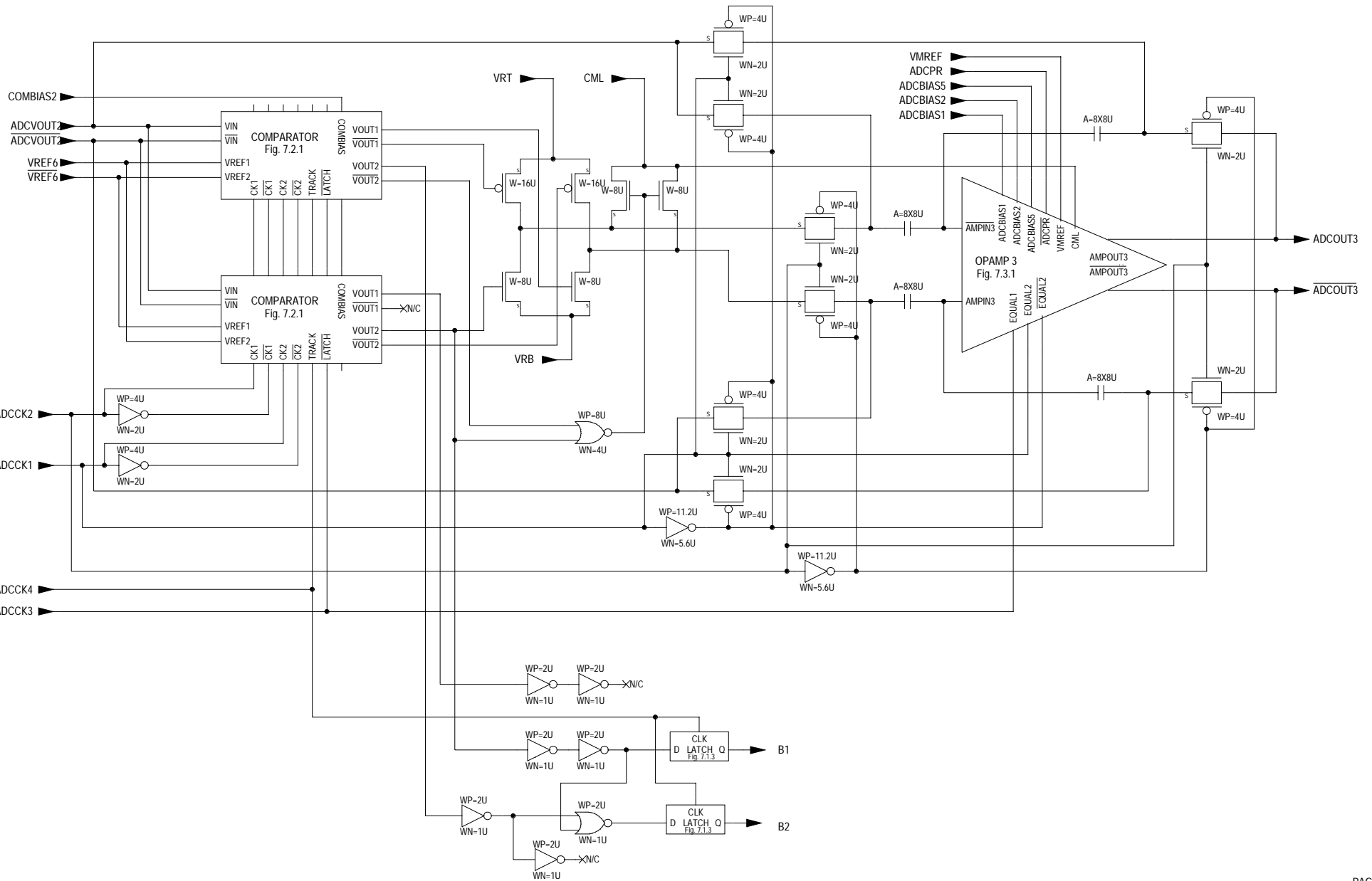


Figure 7.3 ADC STAGE 3

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	58
SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:22
LOCATION:	XX
INITIALS:	MH

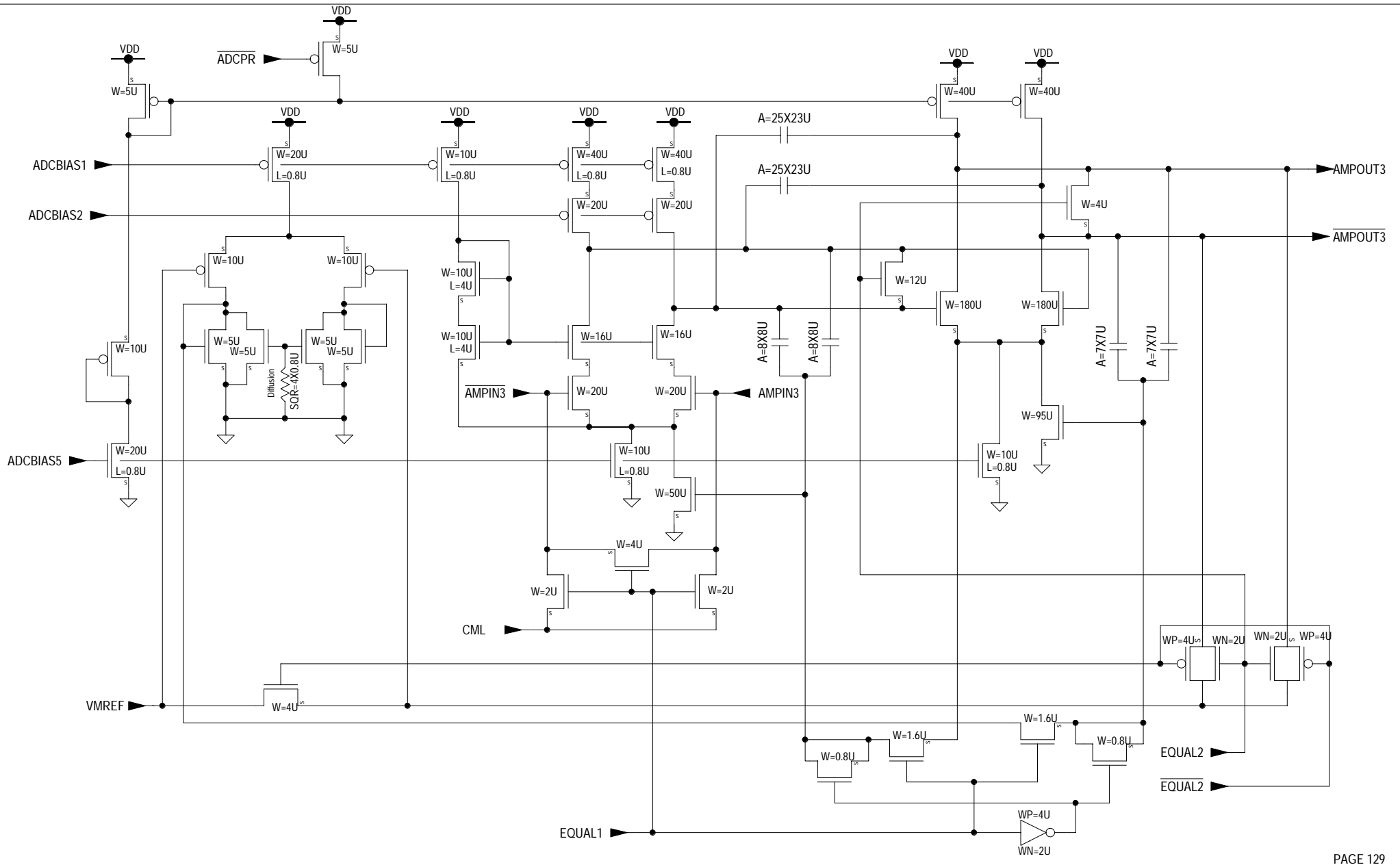


Figure 7.3.1 OPAMP 3

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	57
SCH_NAME:	57	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:07	LOCATION:	XX
LOCATION:	XX	INITIALS:	MH

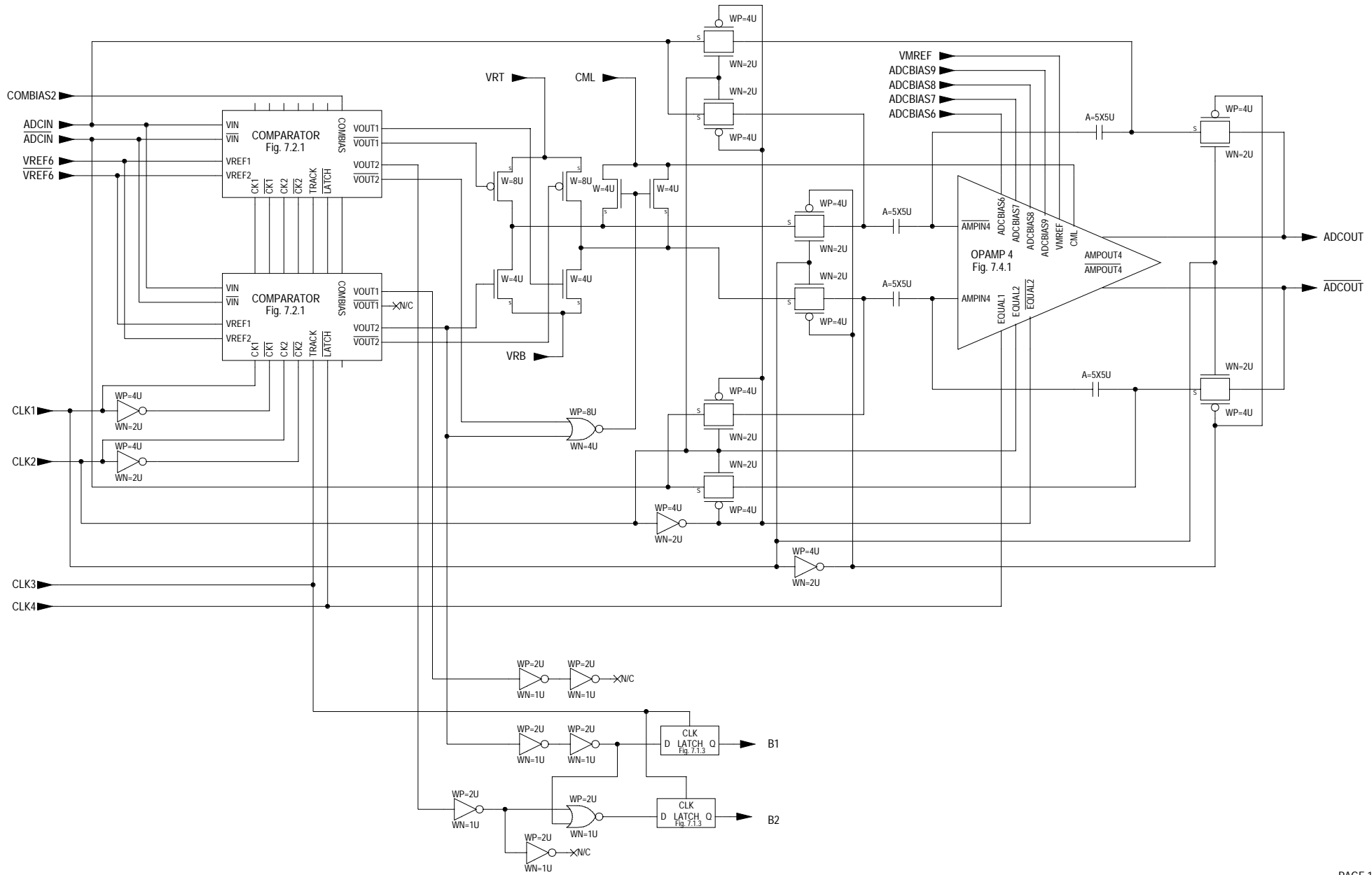


Figure 7.4 ADC STAGE 4

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	60
DATE_TIME:	6-26-2002_10:47
LOCATION:	XX
SI NUMBER:	SI01
INITIALS:	MH

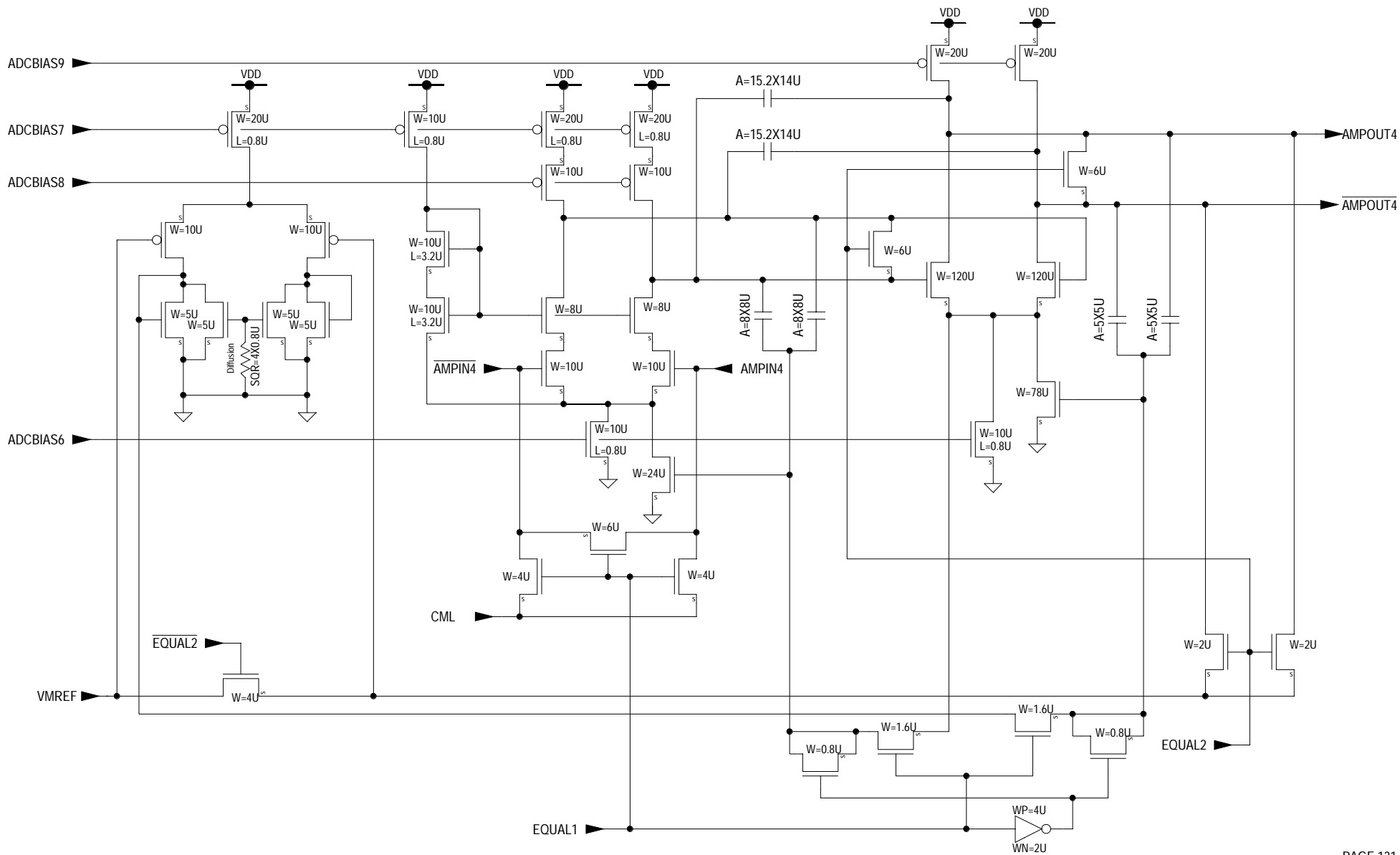


Figure 7.4.1 OPAMP 4

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	59
SCH_NAME:	59	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:07	LOCATION:	XX
LOCATION:	XX	INITIALS:	MH

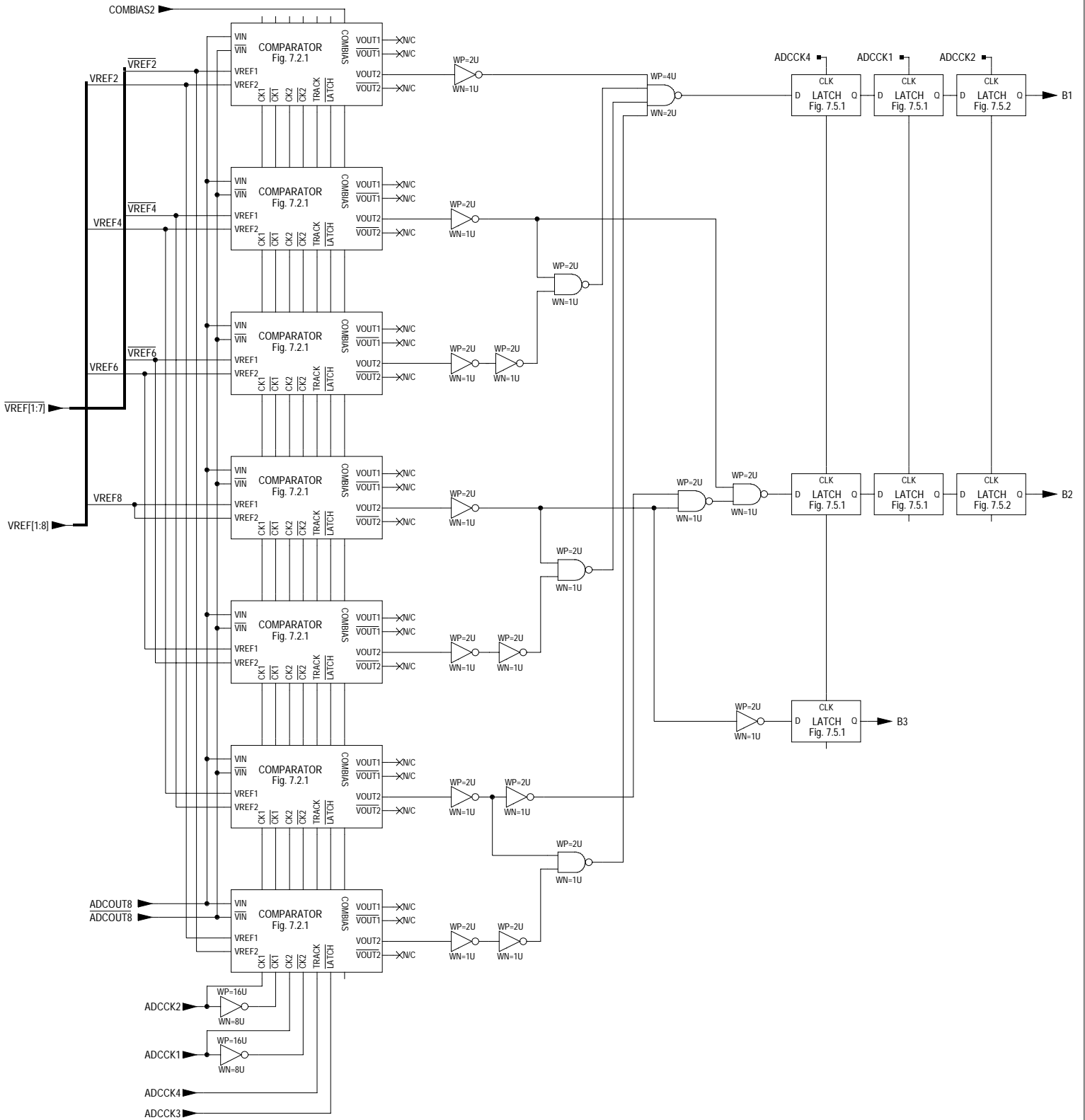


Figure 7.5 ADC END STAGE

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	68	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:23		
LOCATION:	XX	INITIALS:	GY

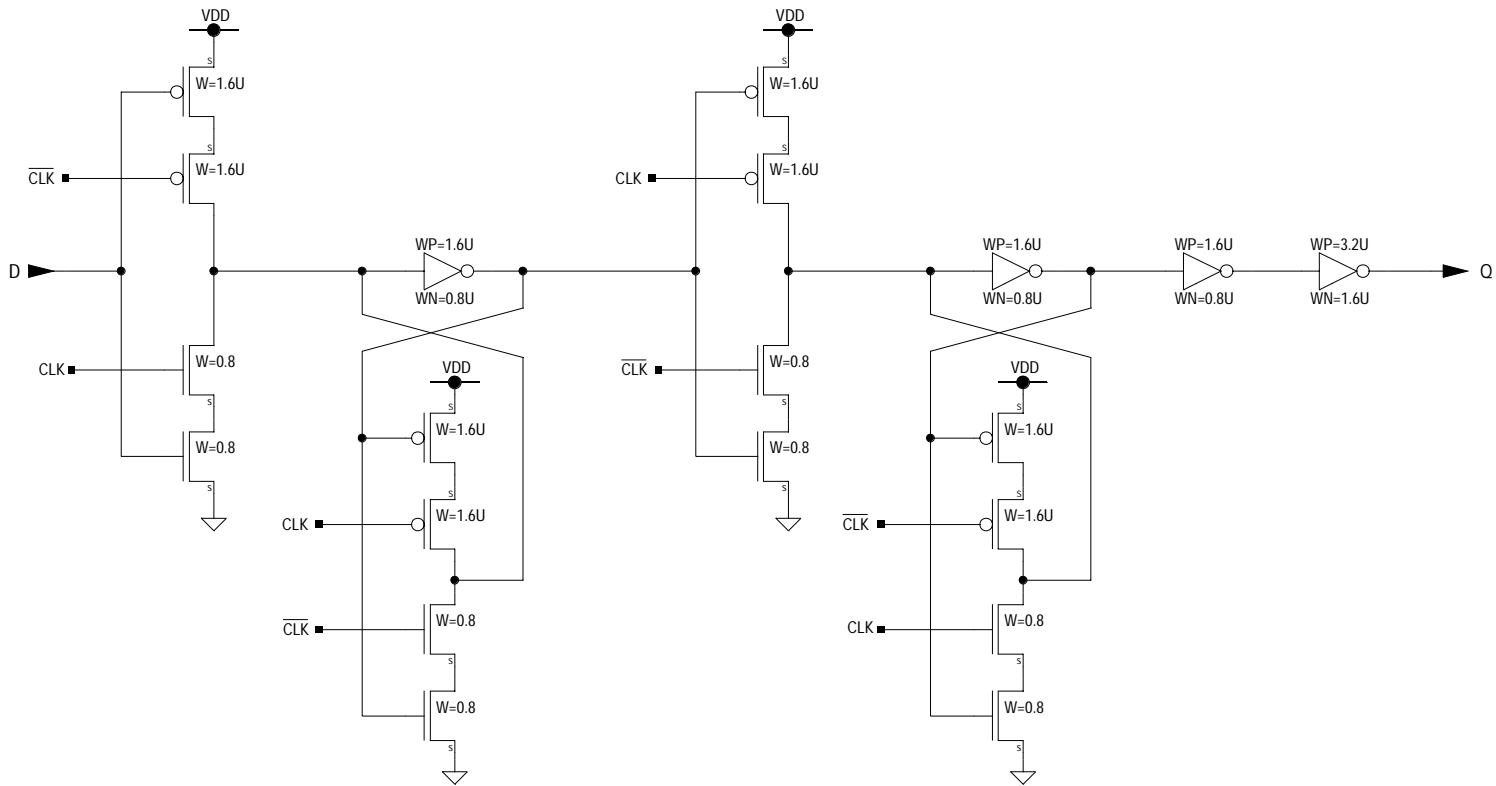
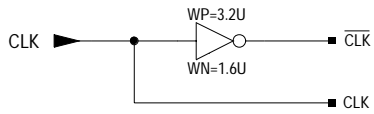


Figure 7.5.1 LATCH 2

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	62	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:08		
LOCATION:	XX	INITIALS:	MH

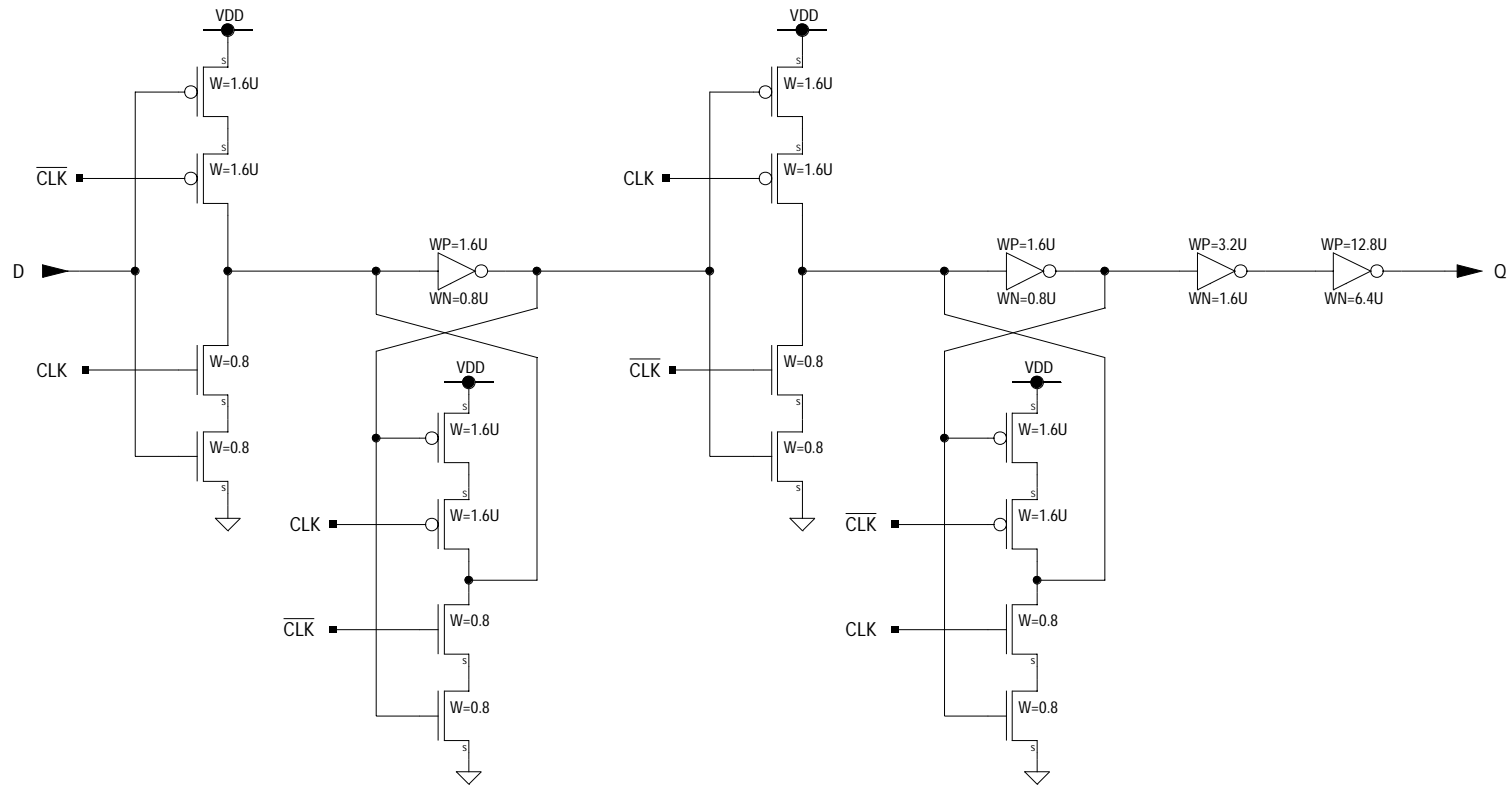
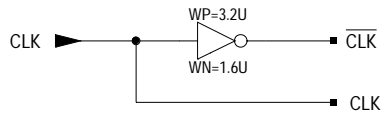


Figure 7.5.2 LATCH 3

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	66	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:08		
LOCATION:	XX	INITIALS:	MH

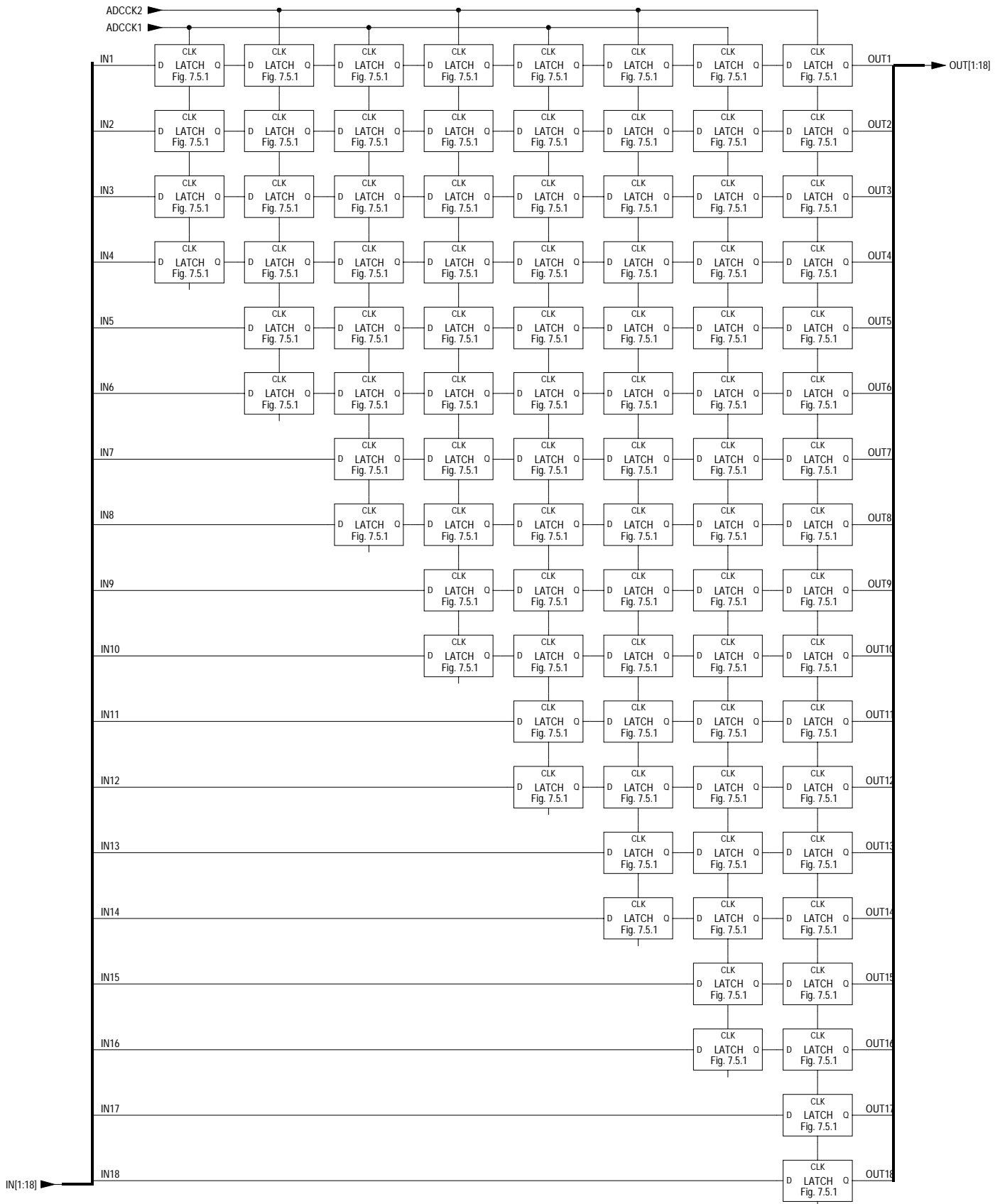


Figure 7.6 PIPELINE

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	63	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:23		
LOCATION:	XX	INITIALS:	MH



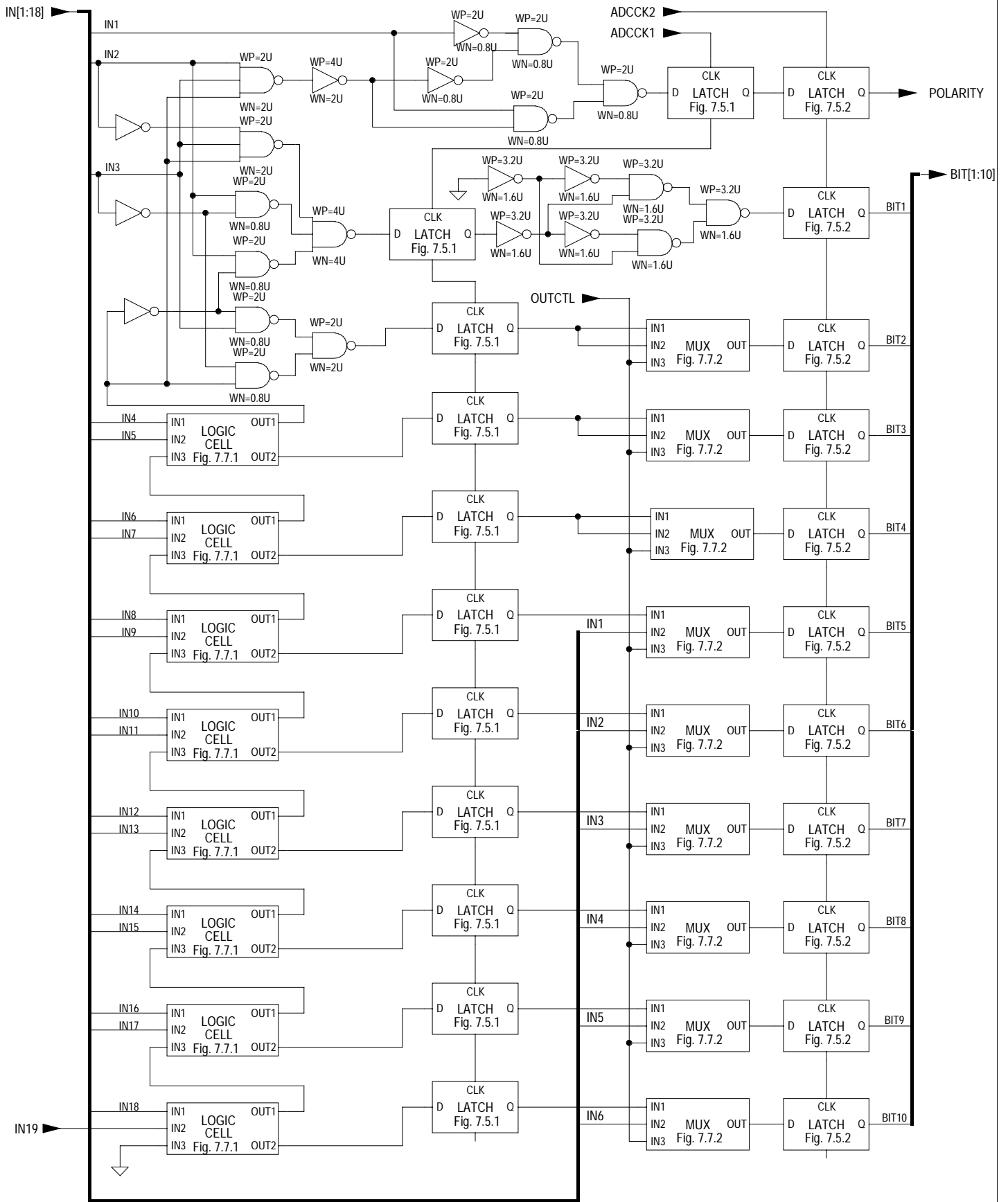


Figure 7.7 CORRECTION LOGIC

Part #:	SI EXAMPLE REPORT
DATE CODE:	0230
SCH_NAME:	67
SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:23
LOCATION:	XX
INITIALS:	MH

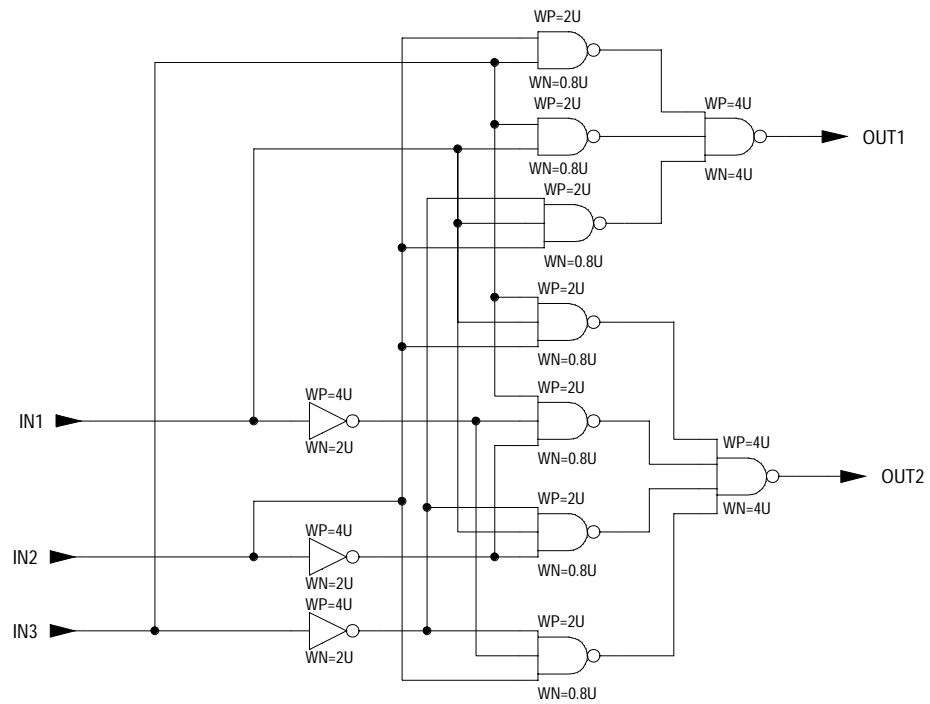


Figure 7.7.1 CORRECTION LOGIC CELL

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	64	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:24		
LOCATION:	XX	INITIALS:	MH

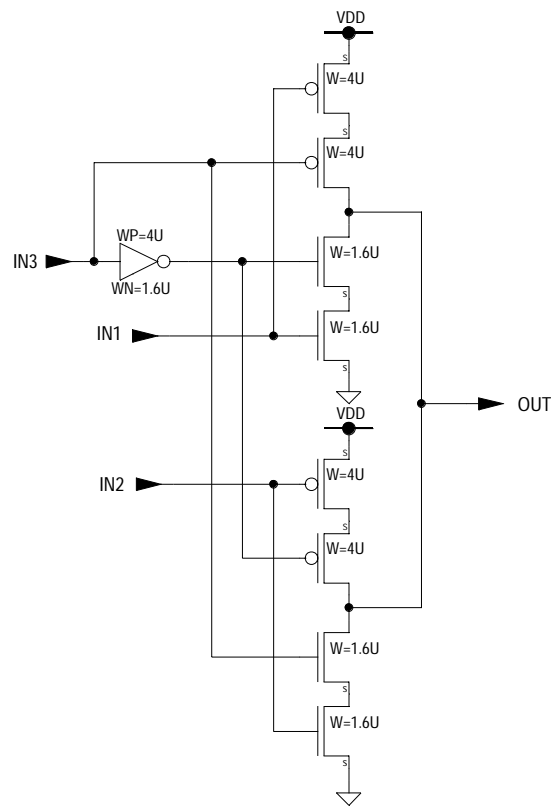


Figure 7.7.2 MULTIPLEXER

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	65	SI NUMBER:	SI01
DATE_TIME:	6-18-2002_9:24		
LOCATION:	XX	INITIALS:	MH

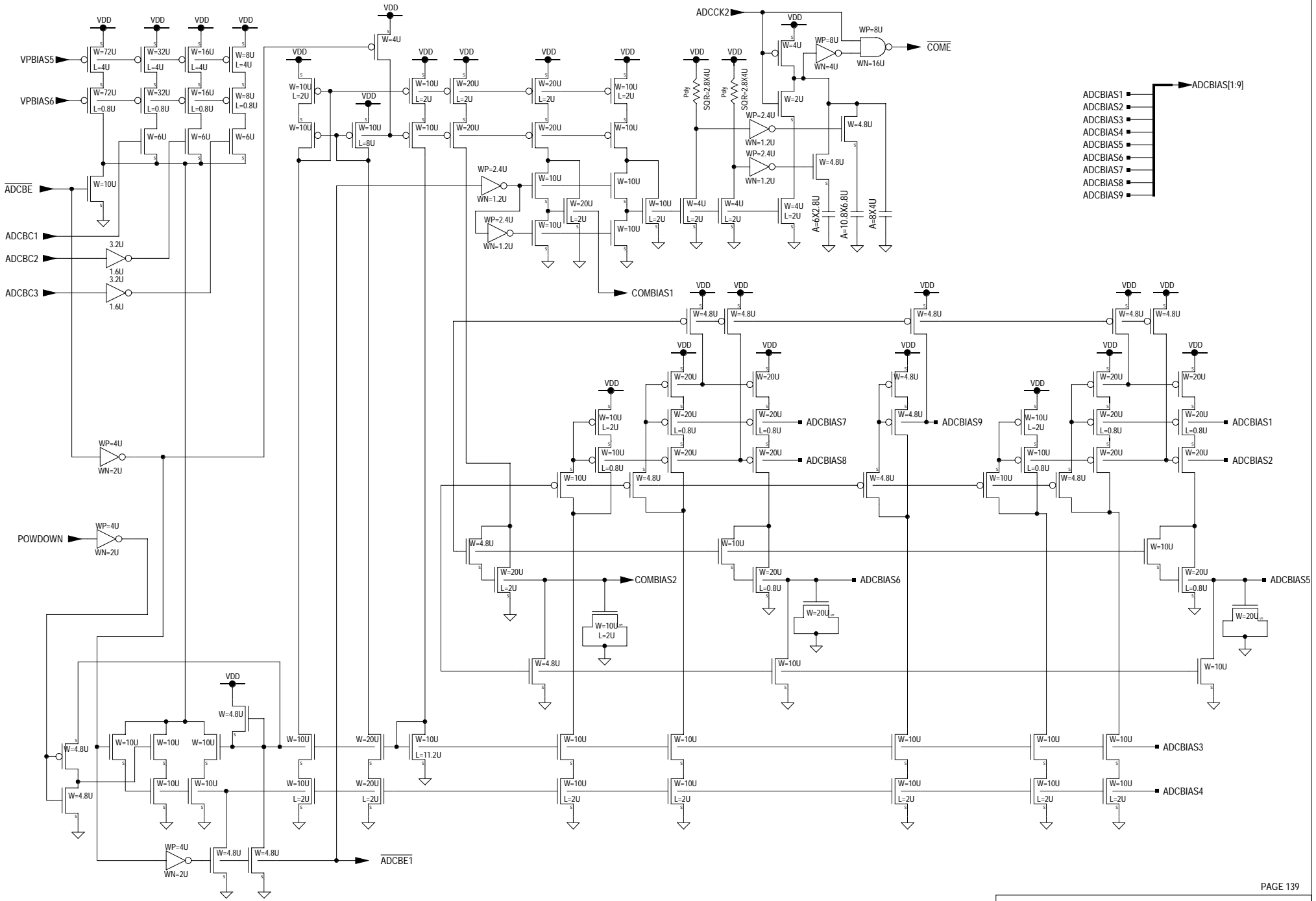


Figure 7.8 ADC BIASING VOLTAGE GENERATOR

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SI NUMBER:	SI01
SCH_NAME:	36	DATE_TIME:	6-18-2002_9:24
LOCATION:	XX	INITIALS:	GY

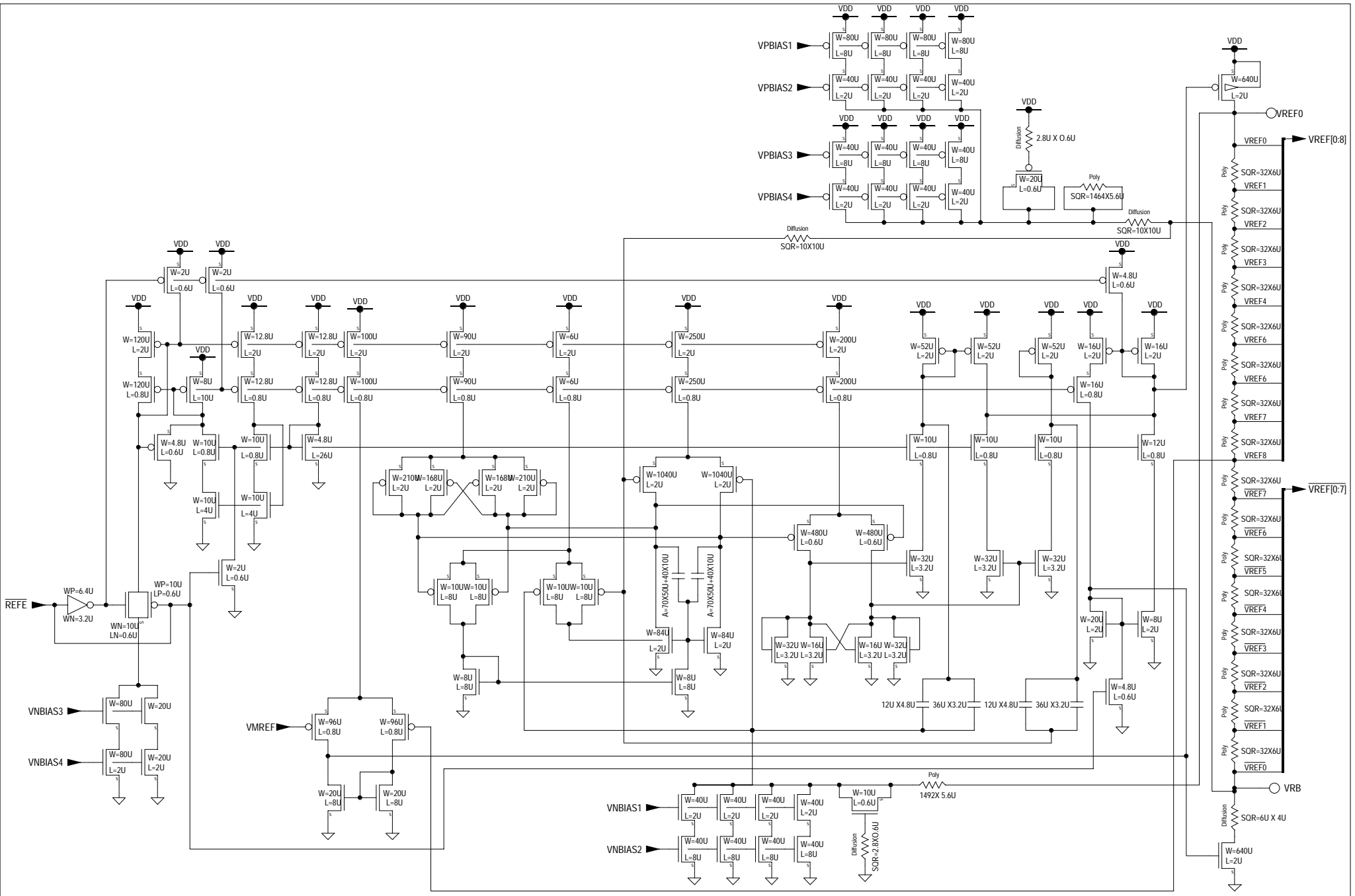


Figure 7.9 REFERENCE VOLTAGE GENERATOR

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SI NUMBER:	SI01
SCH_NAME:	15	DATE_TIME:	6-20-2002_13:08
LOCATION:	XX	INITIALS:	MH

## 8.0 SI Standard Cells

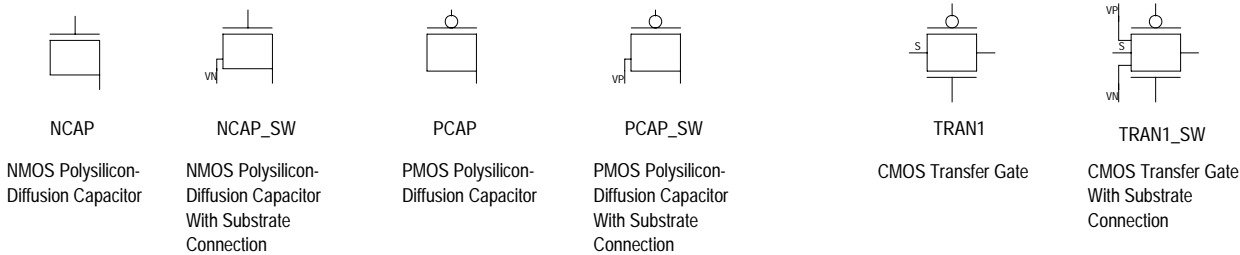
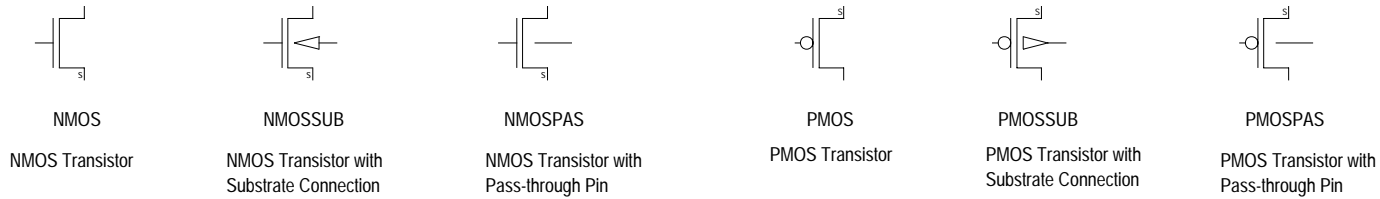
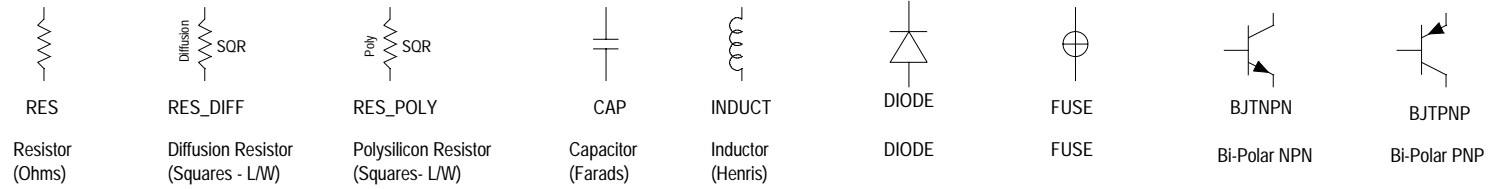
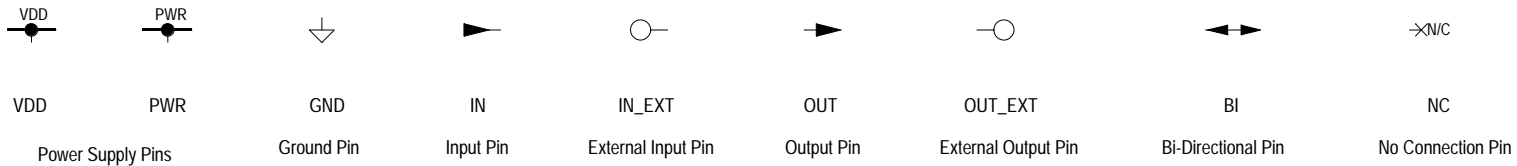


Figure 8.0 SI\_LIB SYMBOL DEFINITION PAGE 1

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	STCELL1	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:30		
LOCATION:	XX	INITIALS:	GY

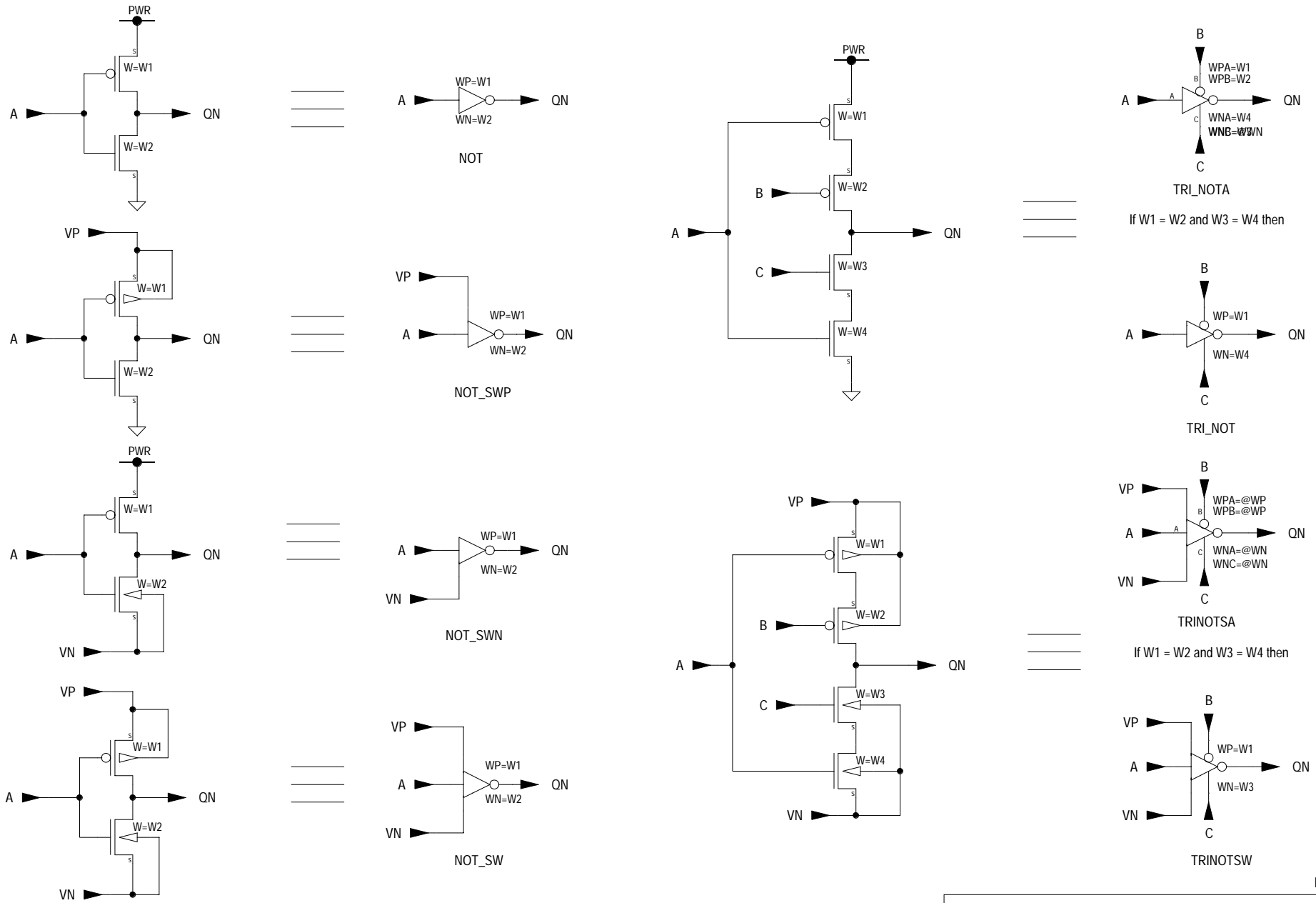


Figure 8.1 SI\_LIB SYMBOL DEFINITION PAGE 2 - INVERTERS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL2
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:31	LOCATION:	XX
		INITIALS:	GY



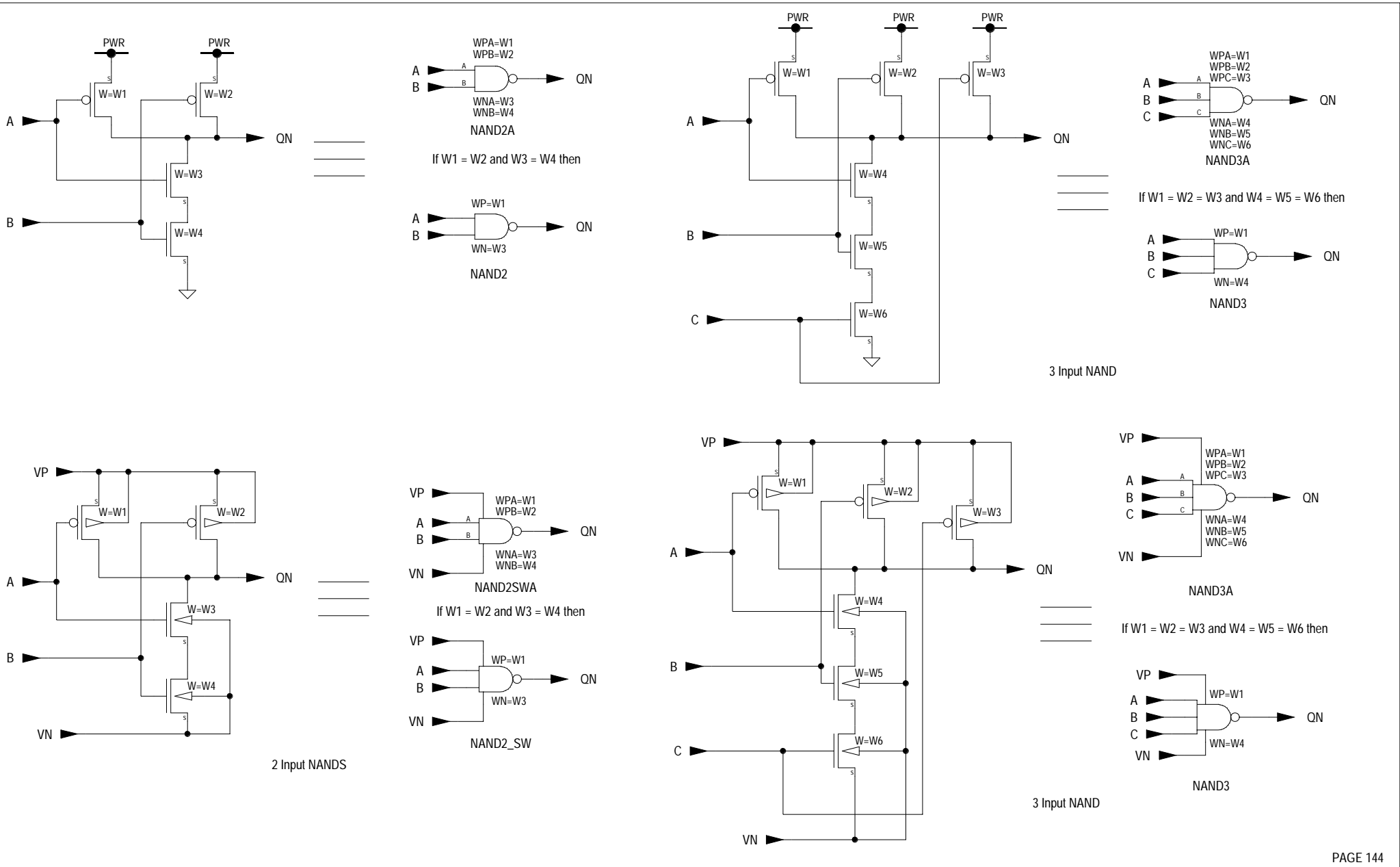


Figure 8.2 SI\_LIB SYMBOL DEFINITION PAGE 3 - NANDS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	STCELL3	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:31		
LOCATION:	XX	INITIALS:	GY

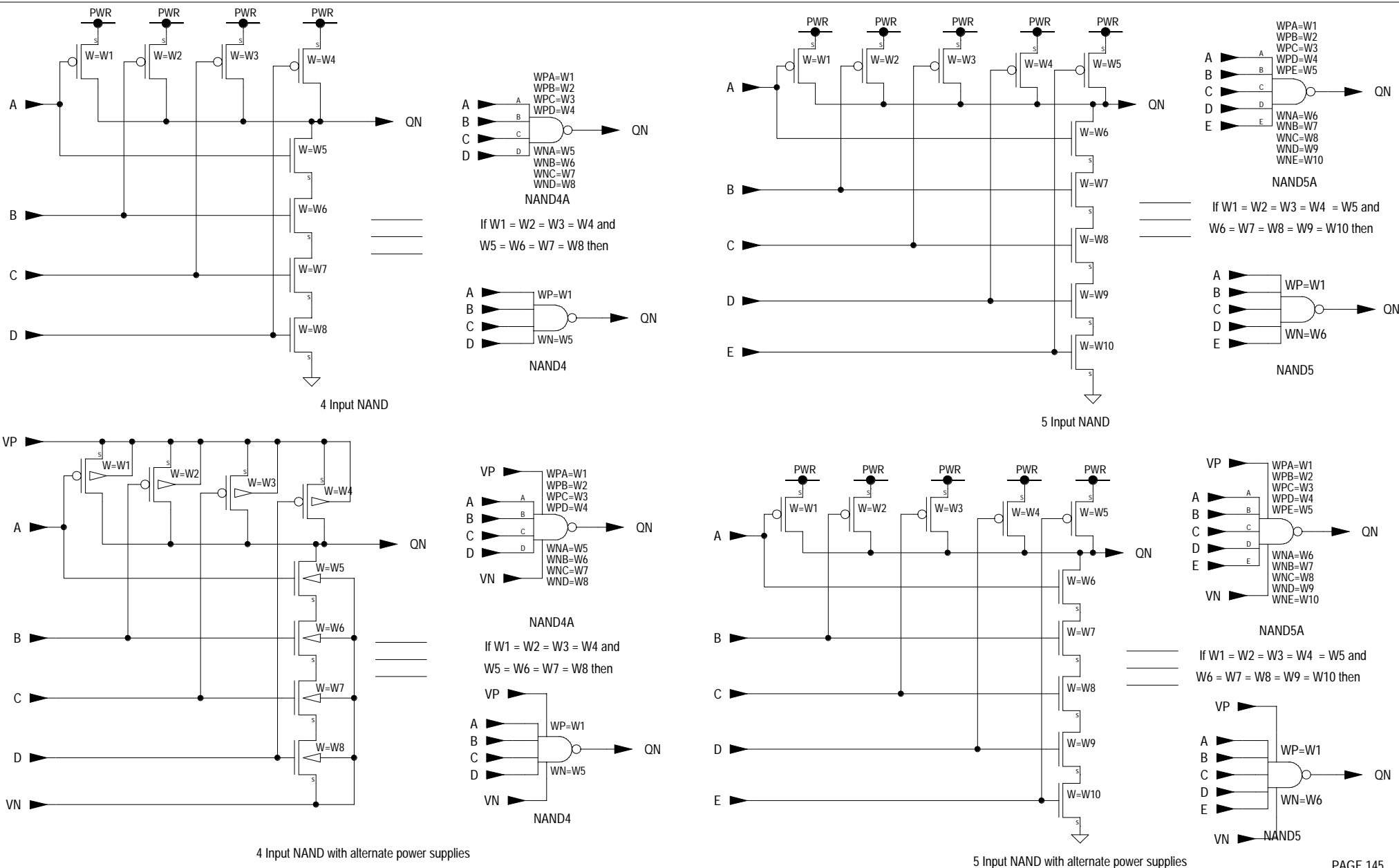
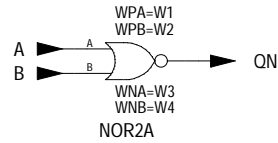
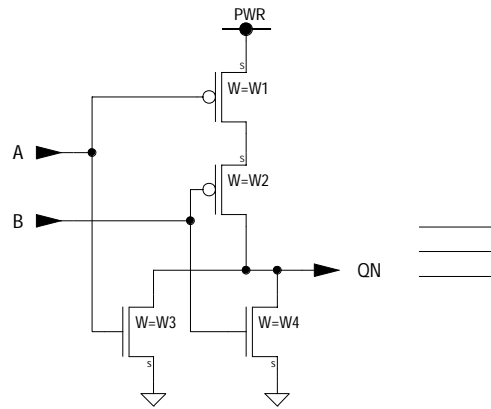
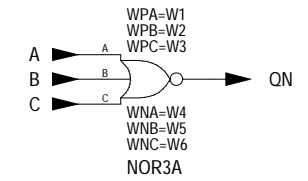
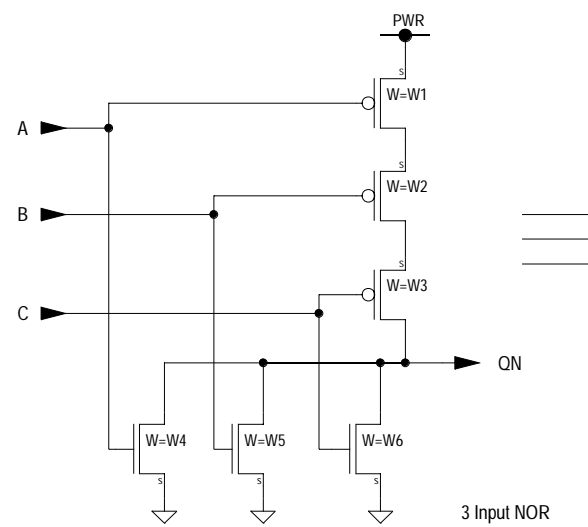
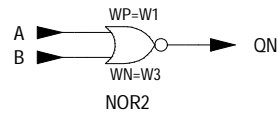


Figure 8.3 SI\_LIB SYMBOL DEFINITION PAGE 4 - NANDS

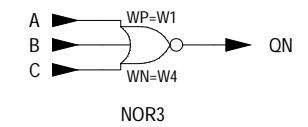
Part #:	SI EXAMPLE REPORT	
DATE CODE:	0230	
SCH_NAME:	STCELL4	SI NUMBER: SI01
DATE_TIME:	6-20-2002_13:31	
LOCATION:	XX	INITIALS: GY



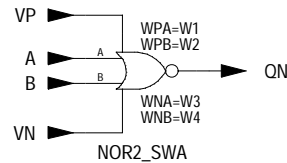
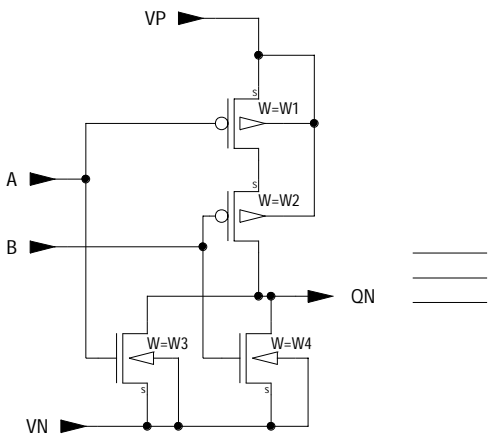
If  $W1 = W2$  and  $W3 = W4$  then



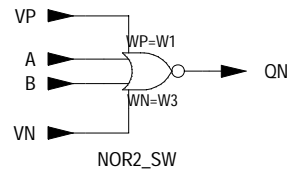
If  $W1 = W2 = W3$  and  $W4 = W5 = W6$  then



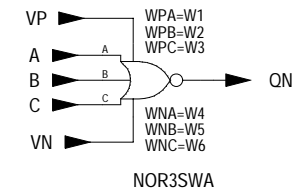
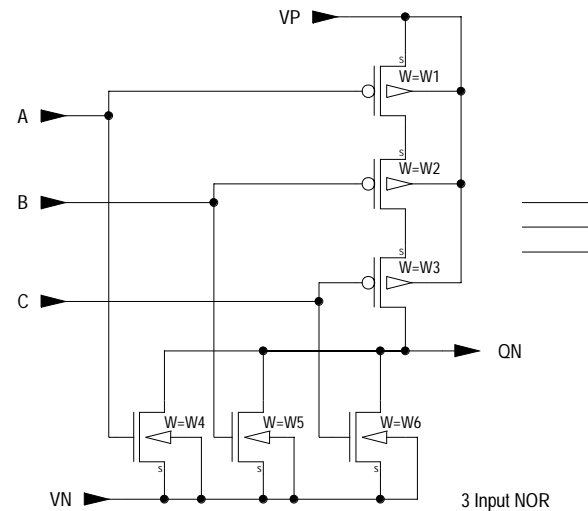
3 Input NOR



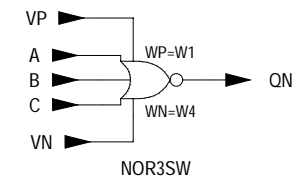
If  $W1 = W2$  and  $W3 = W4$  then



2 Input NOR



If  $W1 = W2 = W3$  and  $W4 = W5 = W6$  then



3 Input NOR

Figure 8.4 SI\_LIB SYMBOL DEFINITION PAGE 5 - NORs

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL5
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:31	LOCATION:	XX
		INITIALS:	GY

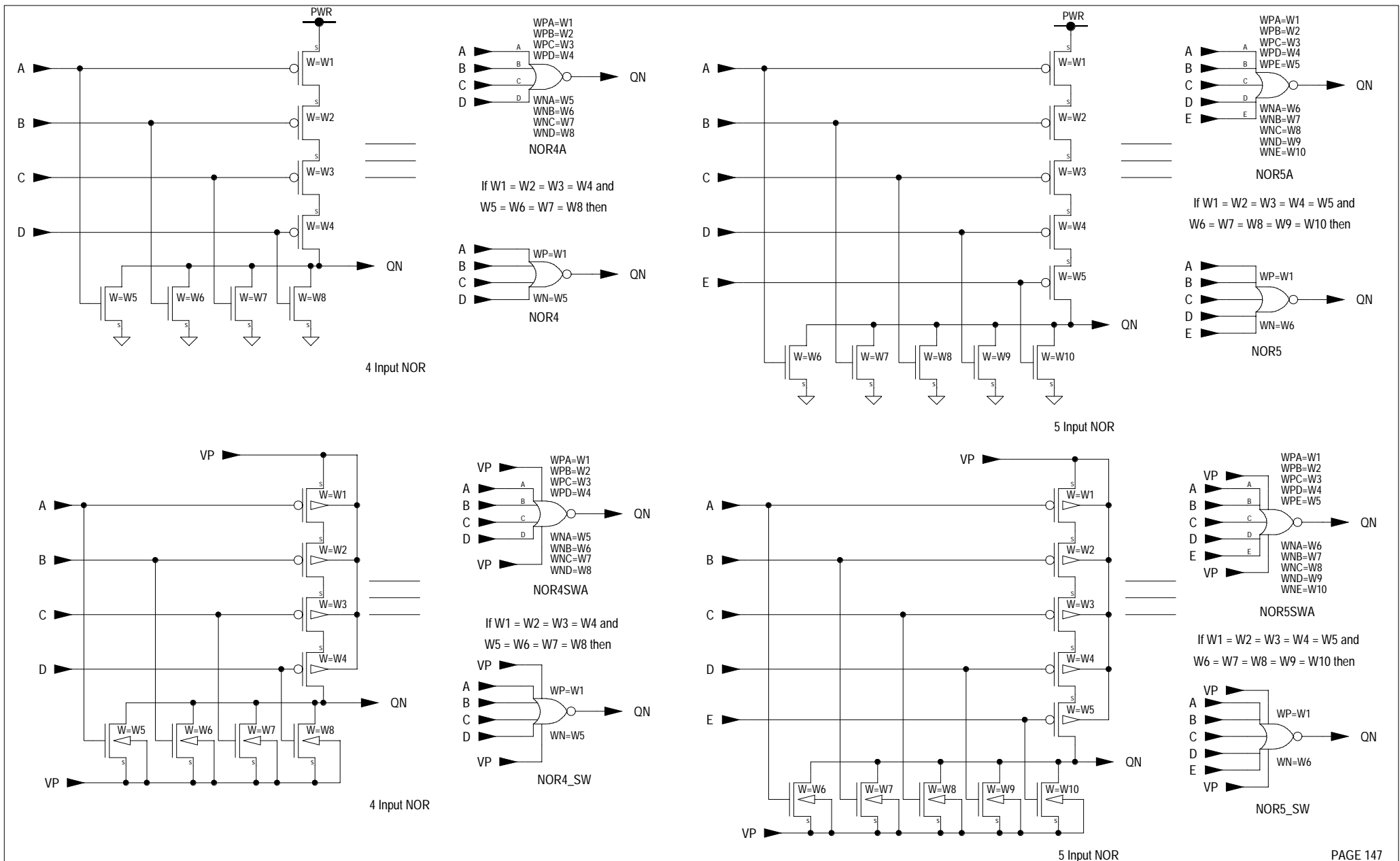


Figure 8.5 SI\_LIB SYMBOL DEFINITION PAGE 6 - NORs

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL6
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:35	LOCATION:	XX
		INITIALS:	GY

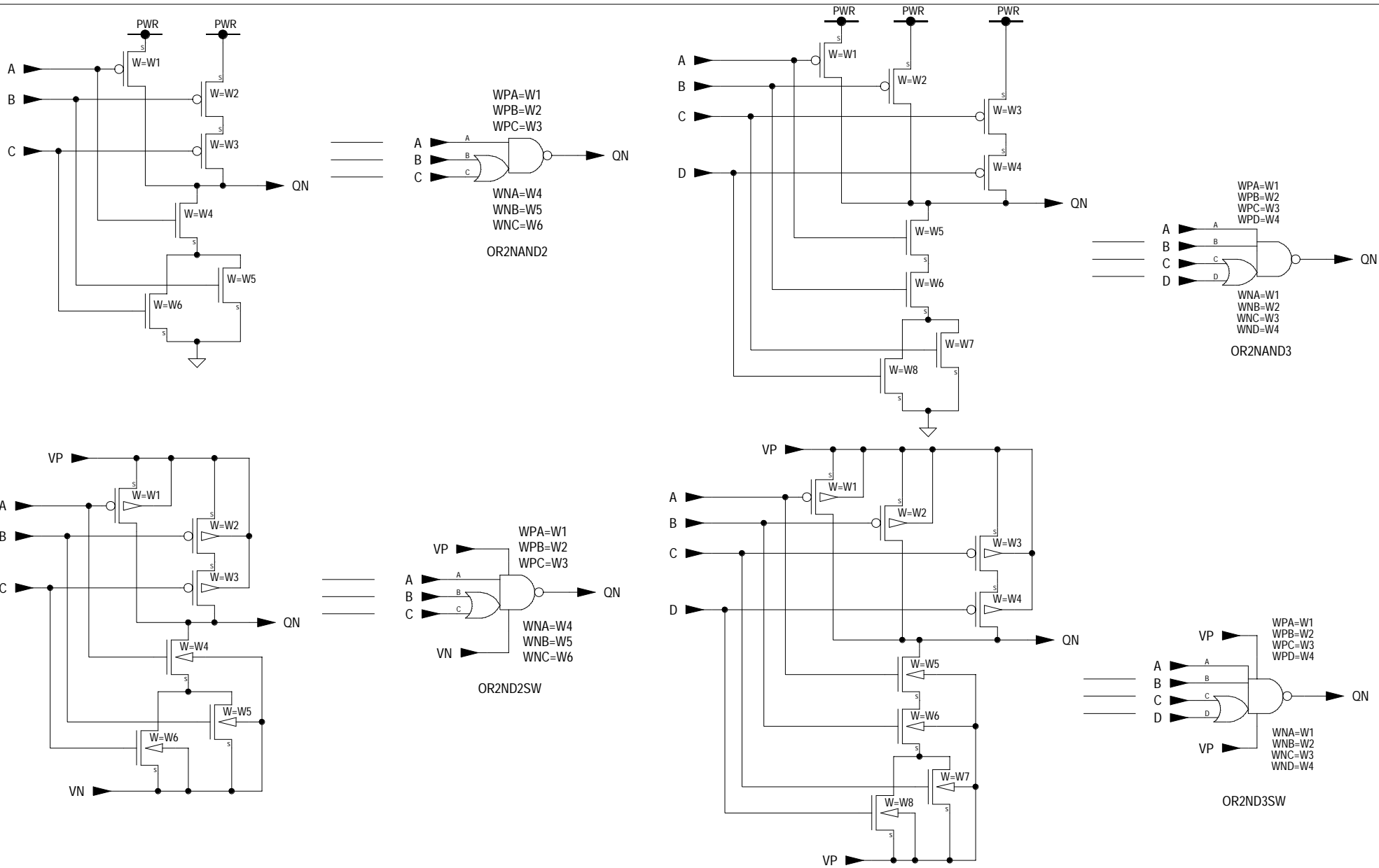


Figure 8.6 SI\_LIB SYMBOL DEFINITION PAGE 7

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL7
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:31	LOCATION:	XX
		INITIALS:	GY

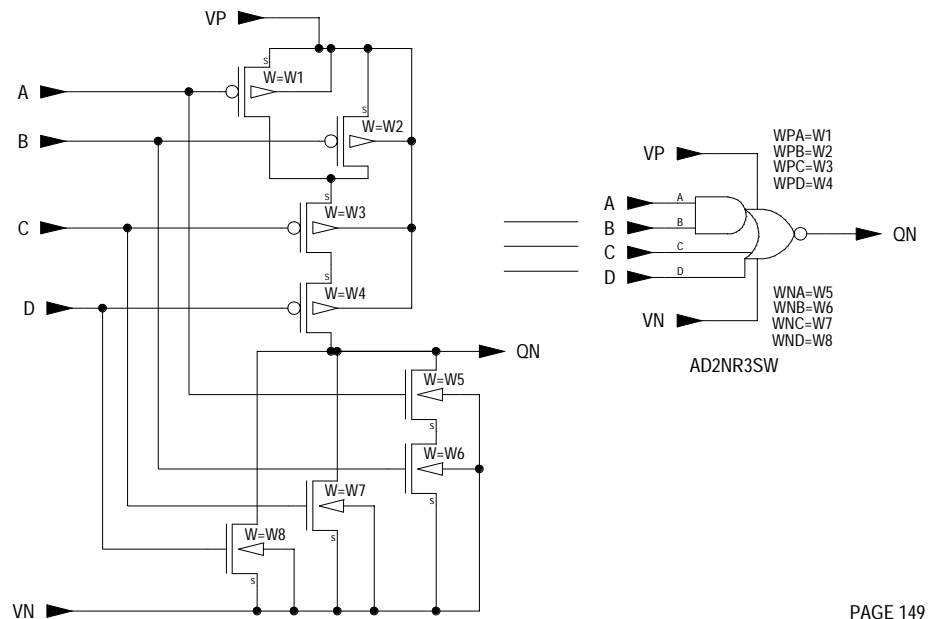
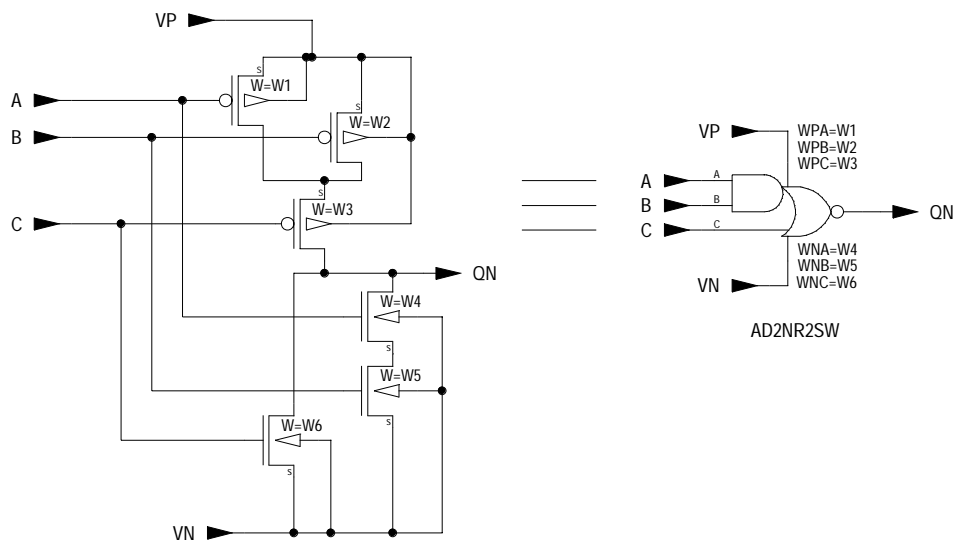
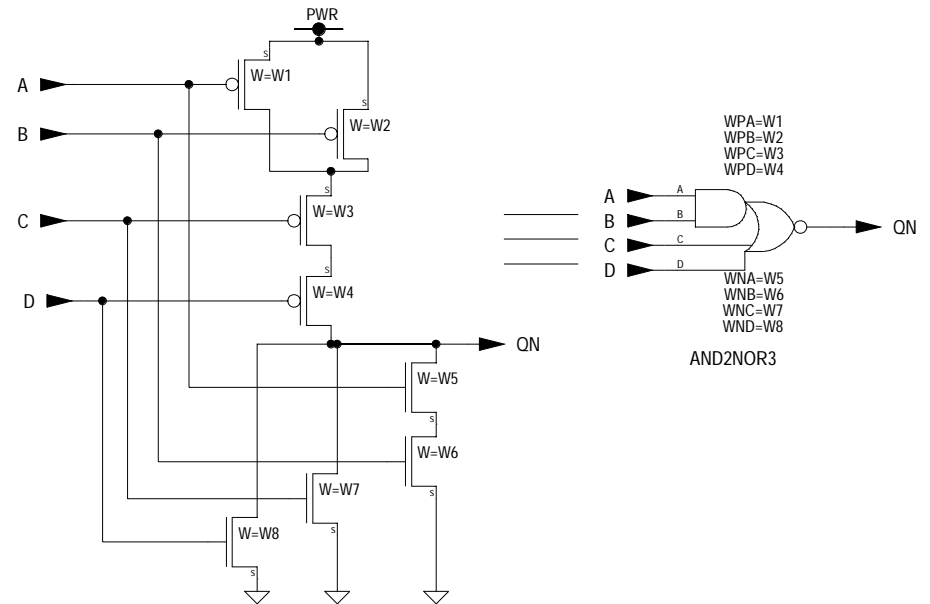
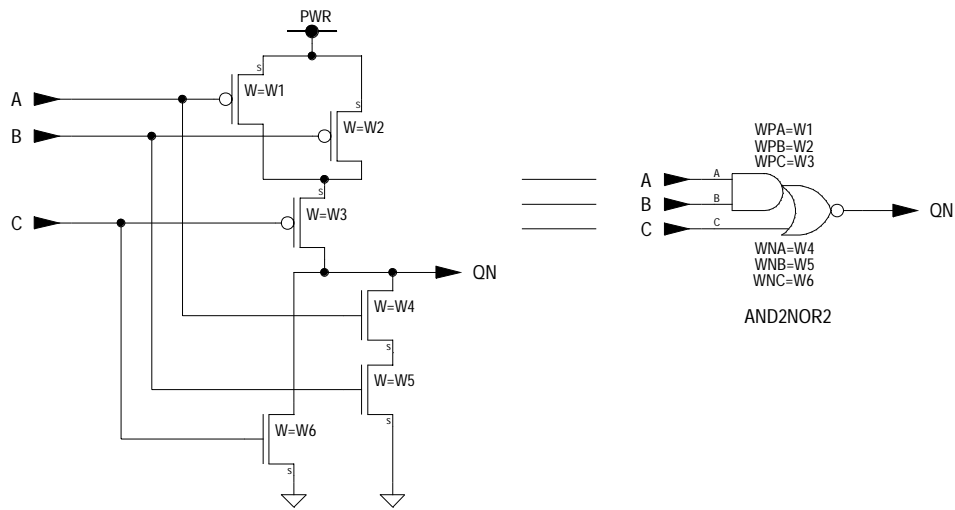


Figure 8.7 SI\_LIB SYMBOL DEFINITION PAGE 8

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL8
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:31	LOCATION:	XX
		INITIALS:	GY

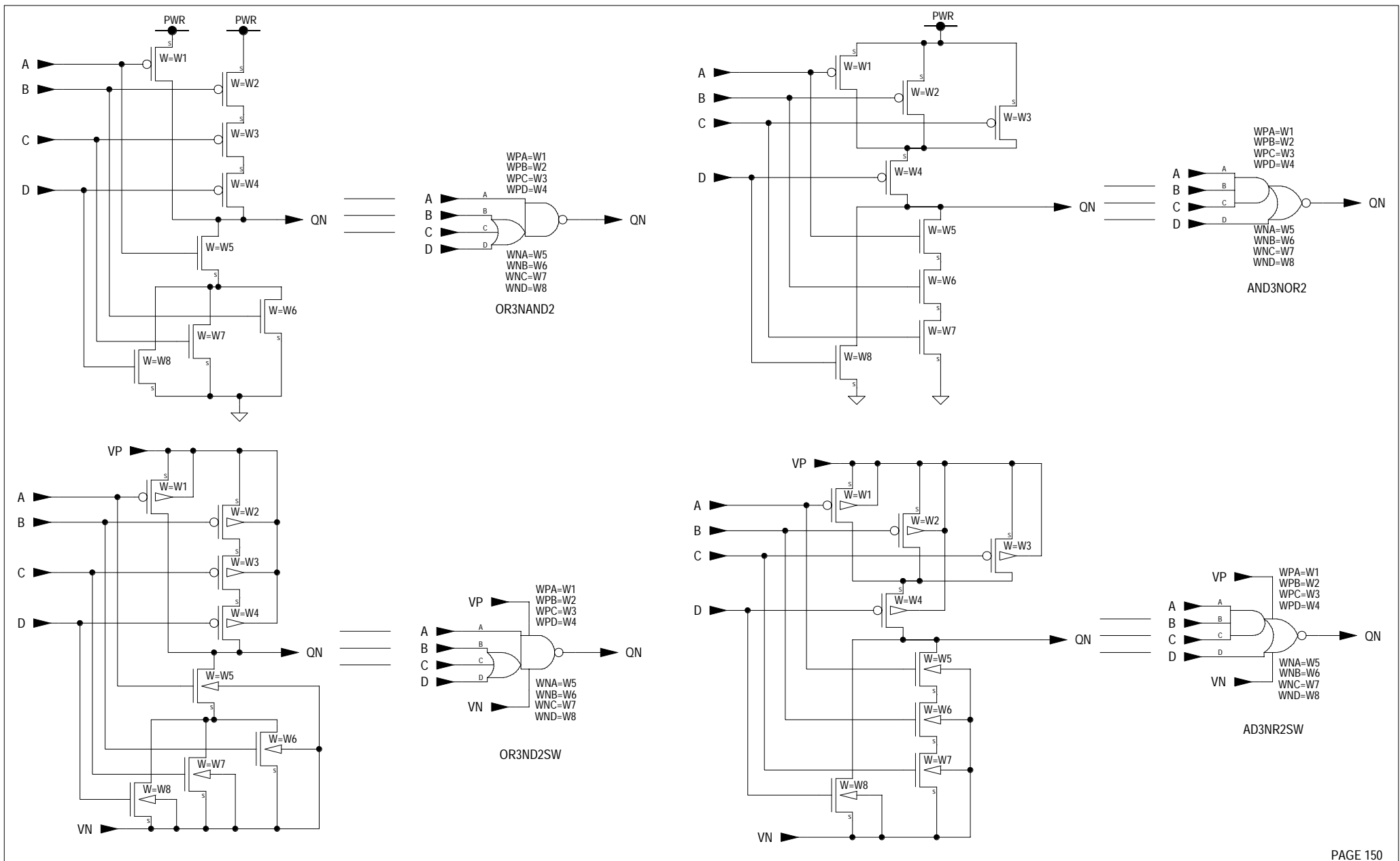
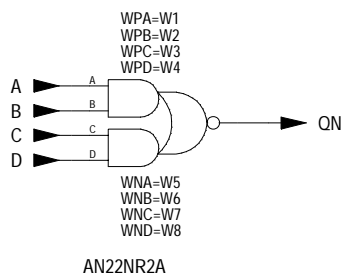
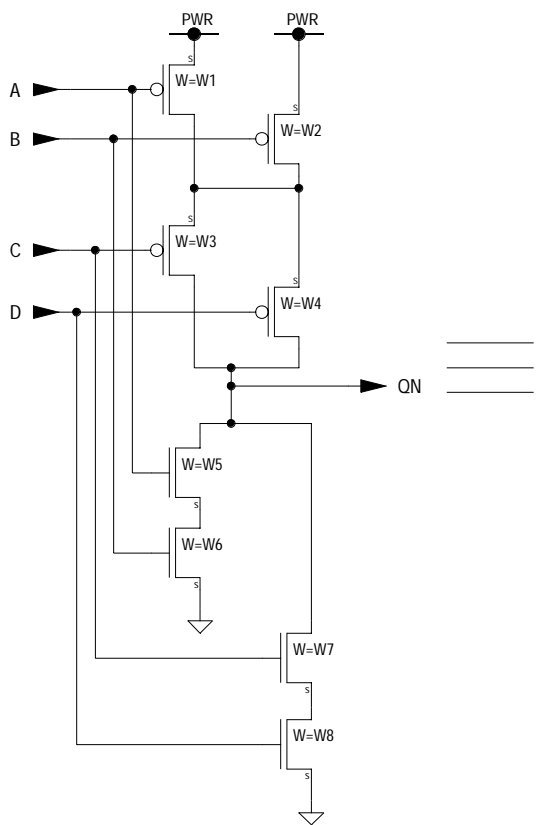
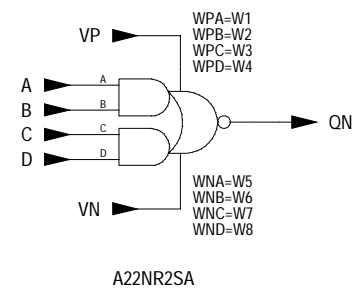
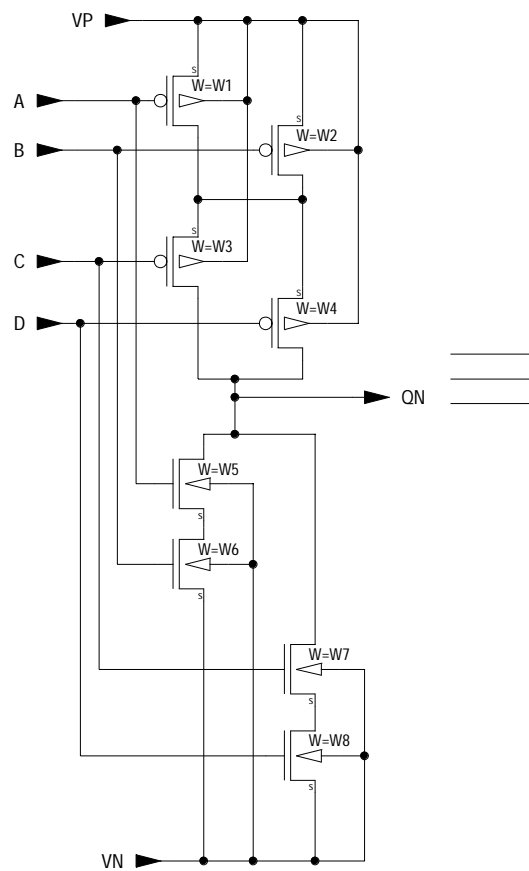
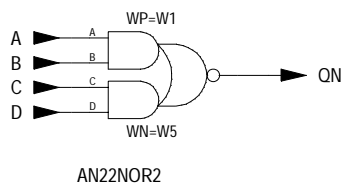


Figure 8.8 SI\_LIB SYMBOL DEFINITION PAGE 9

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL9
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:31	LOCATION:	XX
		INITIALS:	GY



If  $W1 = W2 = W3 = W4$  and  
 $W5 = W6 = W7 = W8$  then



If  $W1 = W2 = W3 = W4$  and  
 $W5 = W6 = W7 = W8$  then

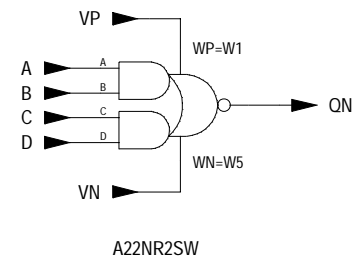


Figure 8.9 SI\_LIB SYMBOL DEFINITION PAGE 10

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	STCELL10	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:30		
LOCATION:	XX	INITIALS:	GY



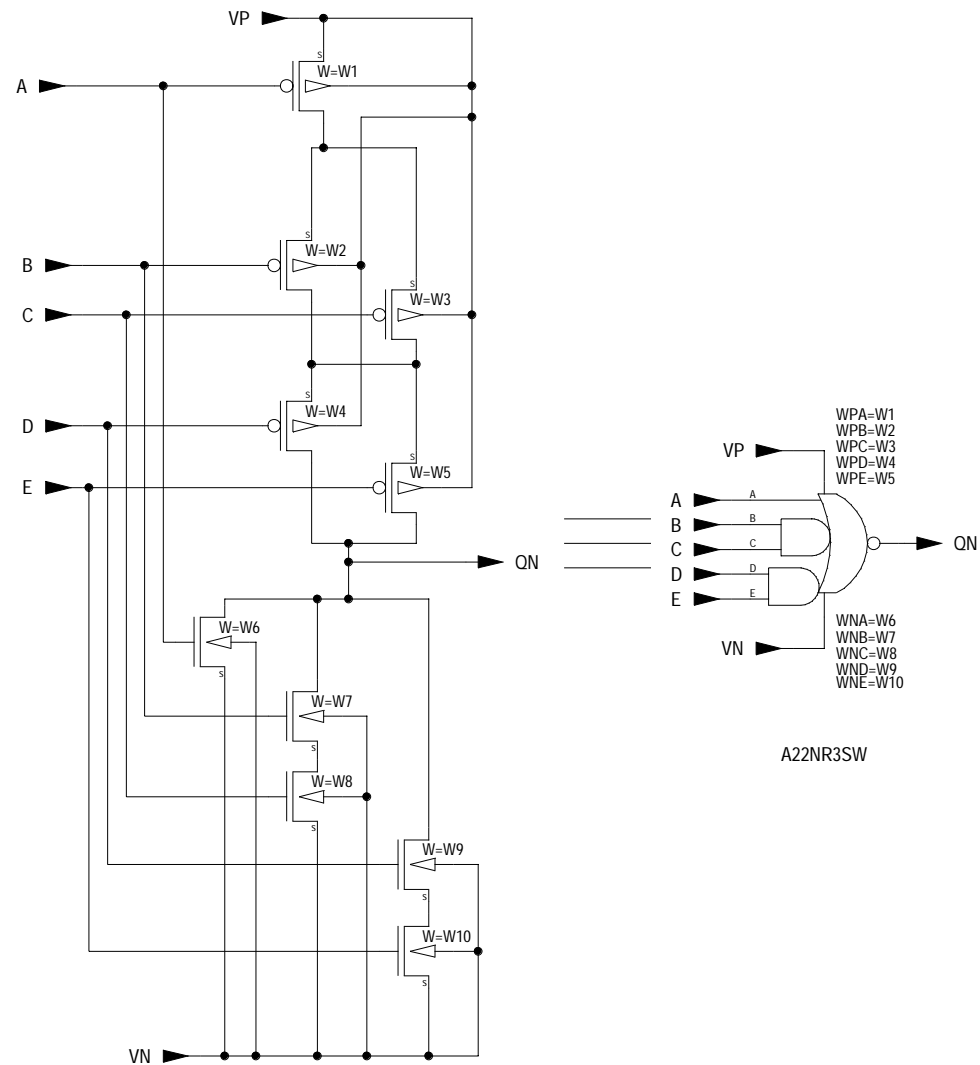
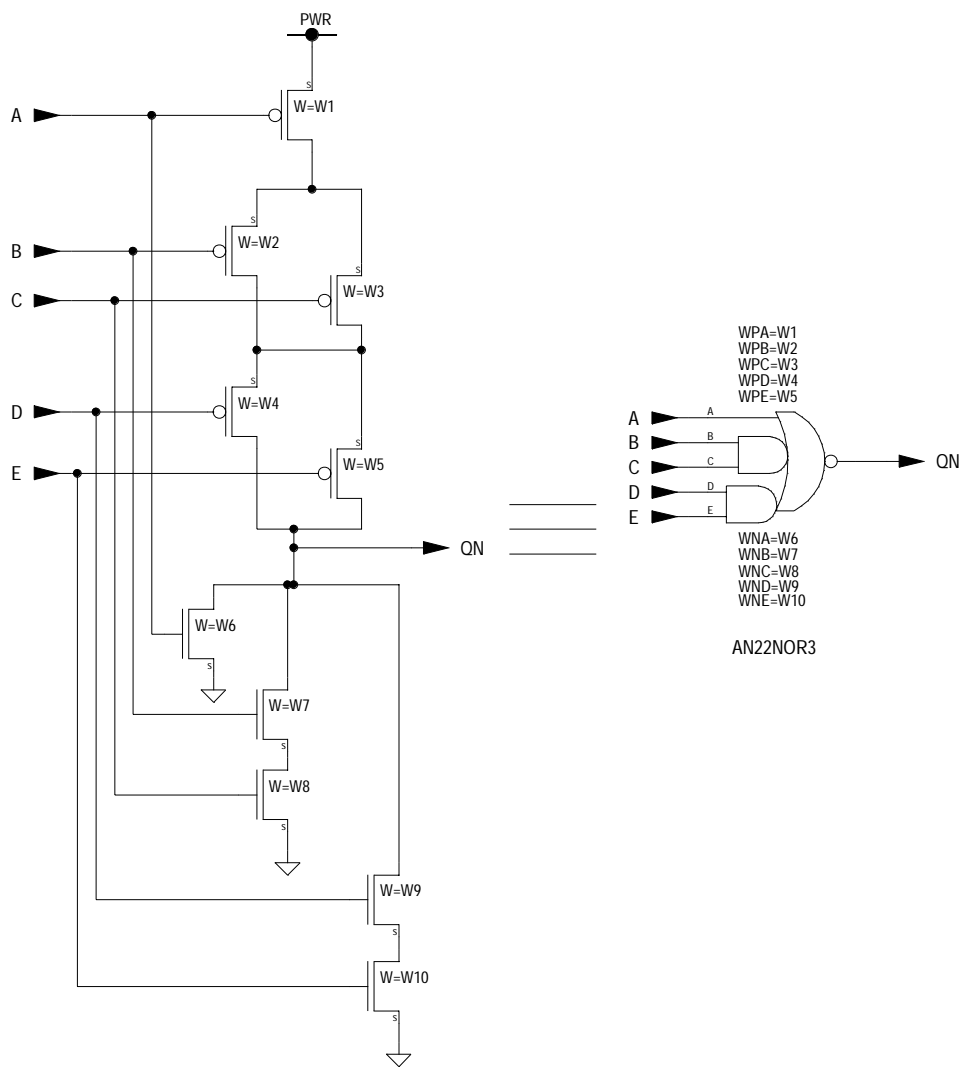


Figure 8.10 SI\_LIB SYMBOL DEFINITION PAGE 11

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL11
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:30	LOCATION:	XX
		INITIALS:	GY

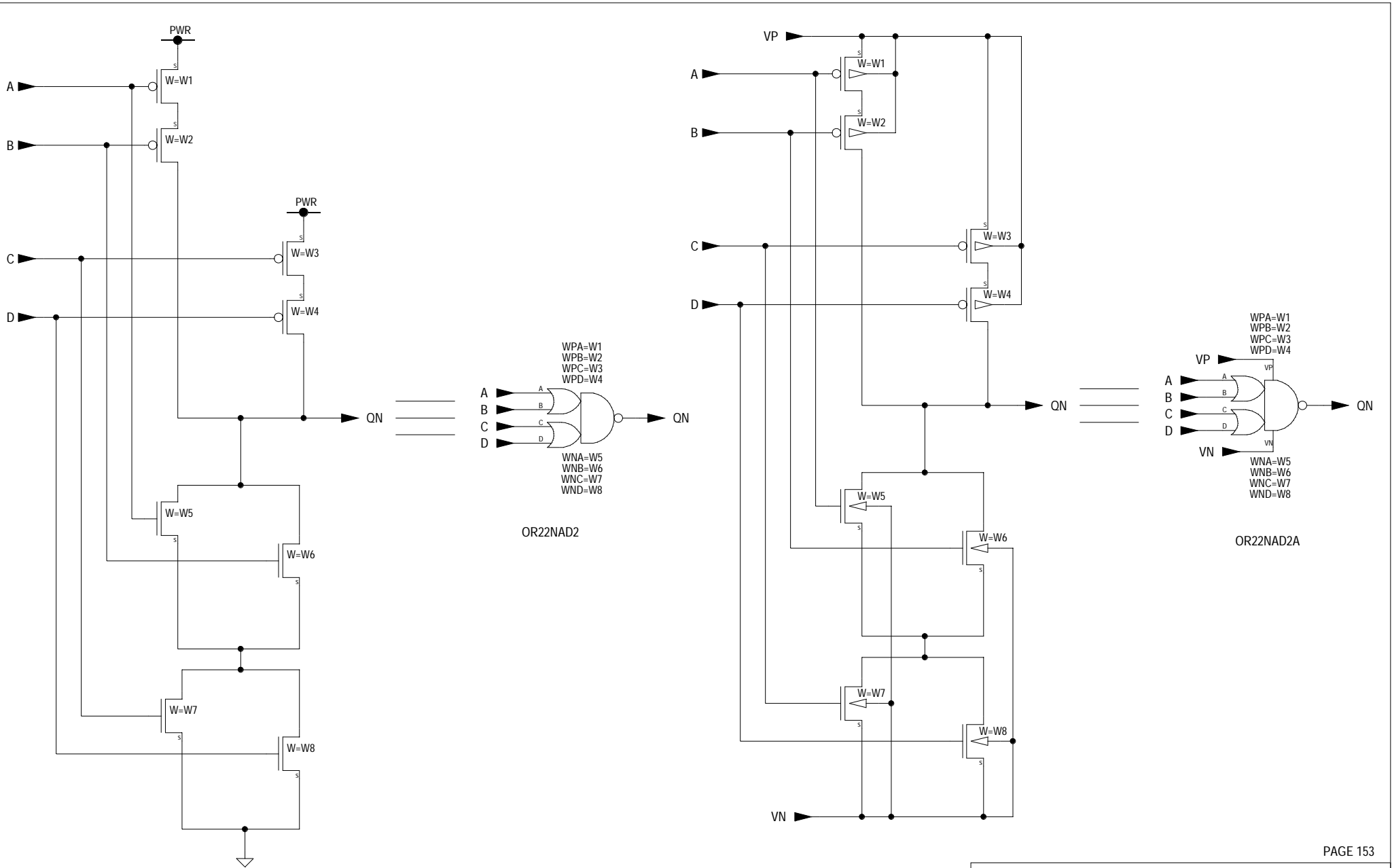


Figure 8.11 SI\_LIB SYMBOL DEFINITION PAGE 12 - SIGNAL GENERATORS

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230		
SCH_NAME:	STCELL12	SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:30		
LOCATION:	XX	INITIALS:	GY

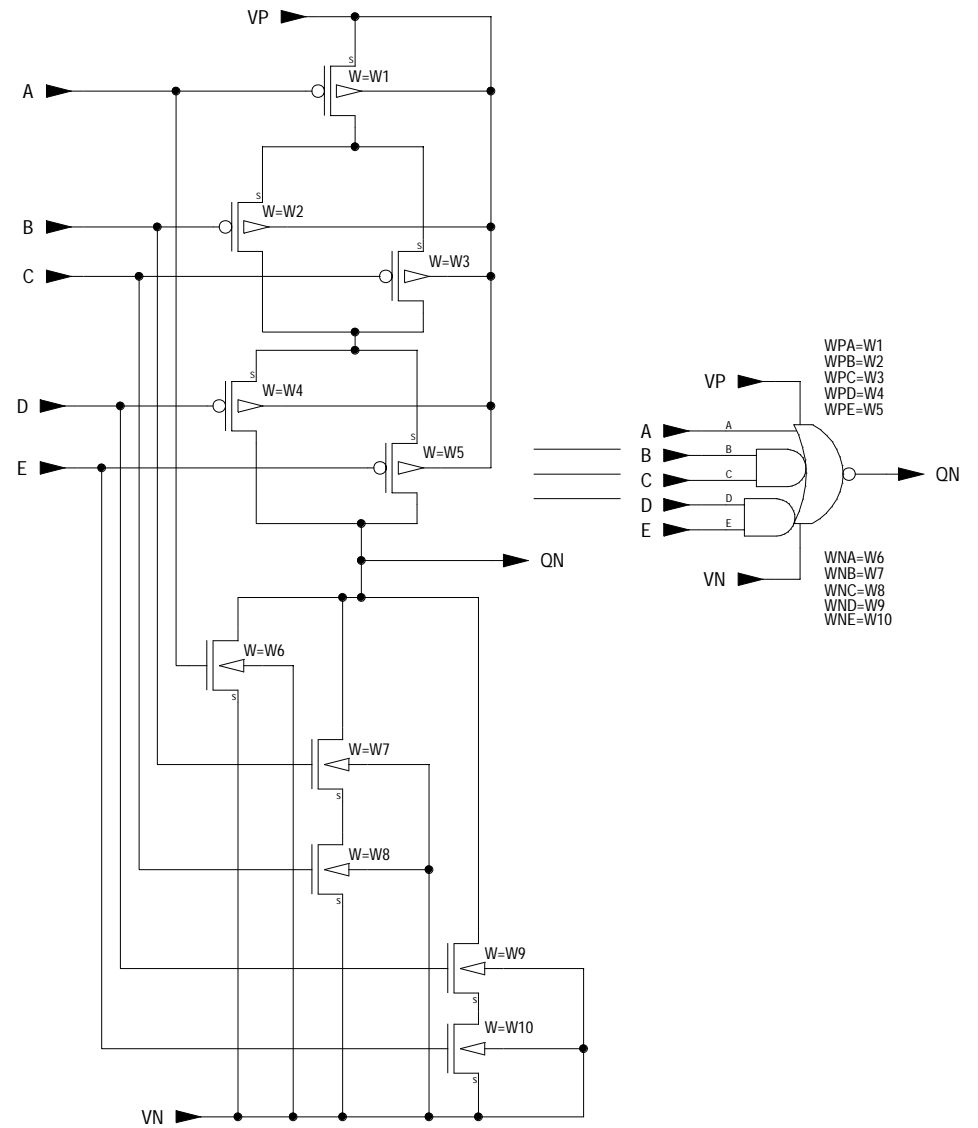
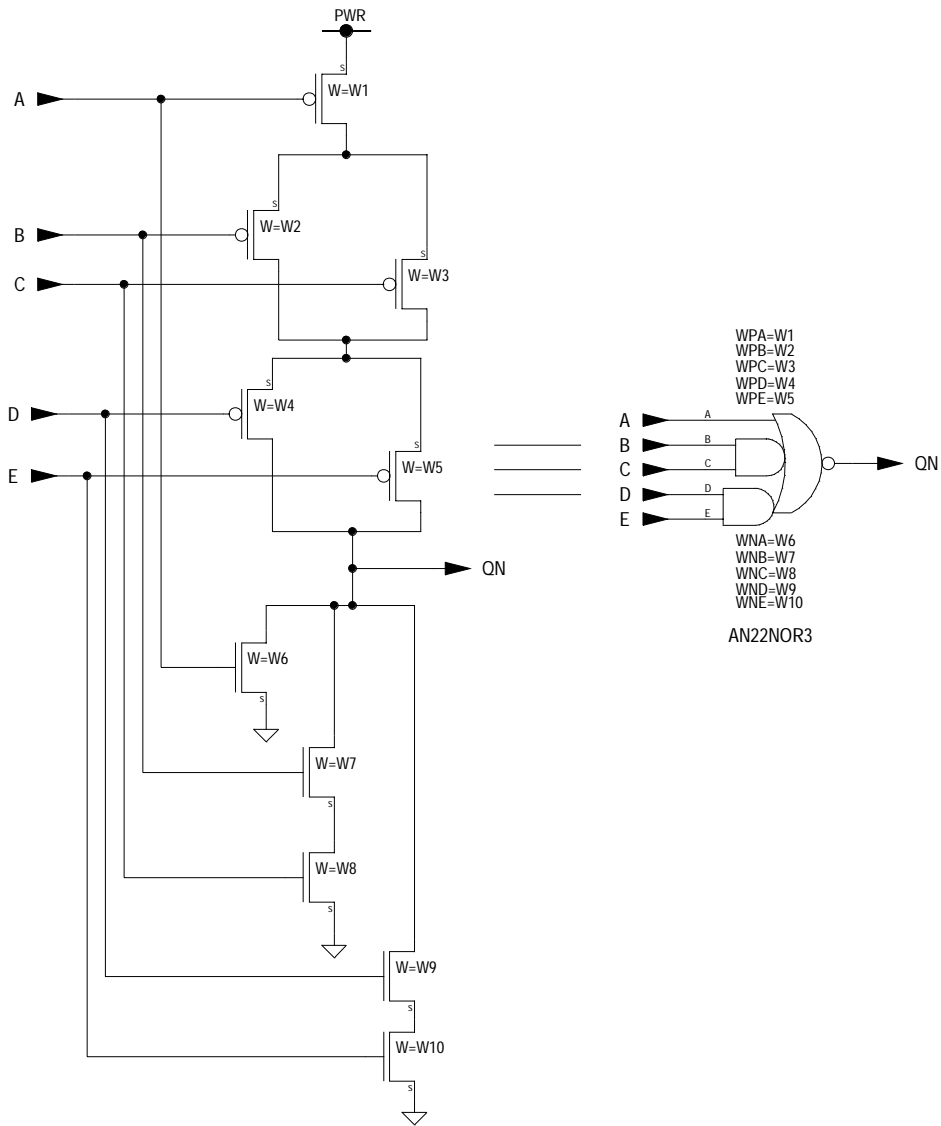


Figure 8.12 SI\_LIB SYMBOL DEFINITION PAGE 13

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL13
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:30	LOCATION:	XX
		INITIALS:	GY

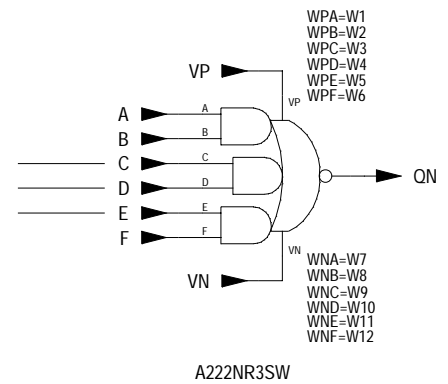
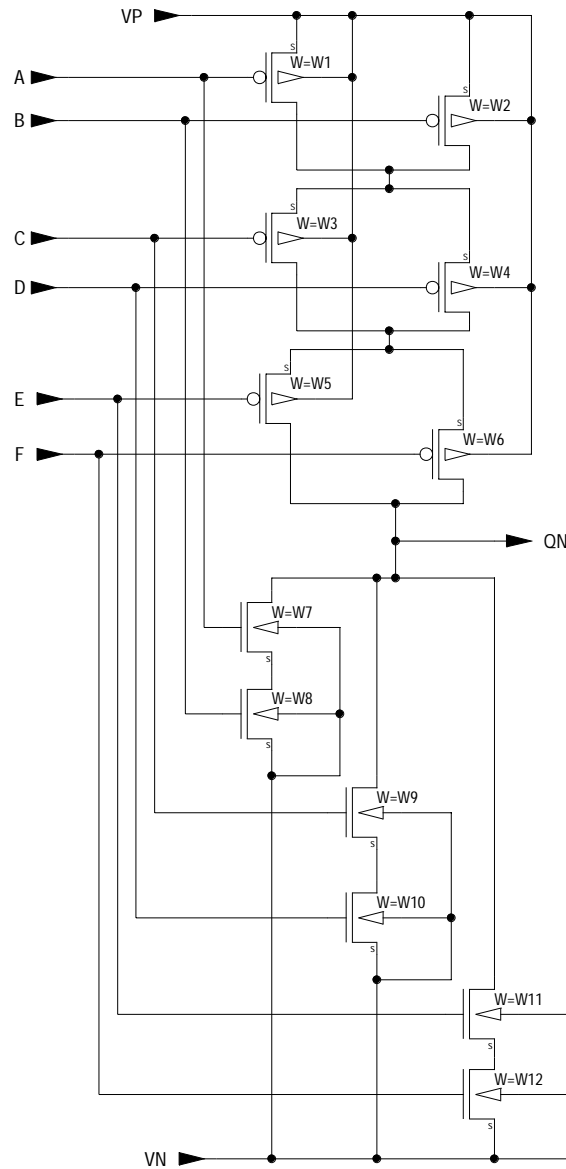
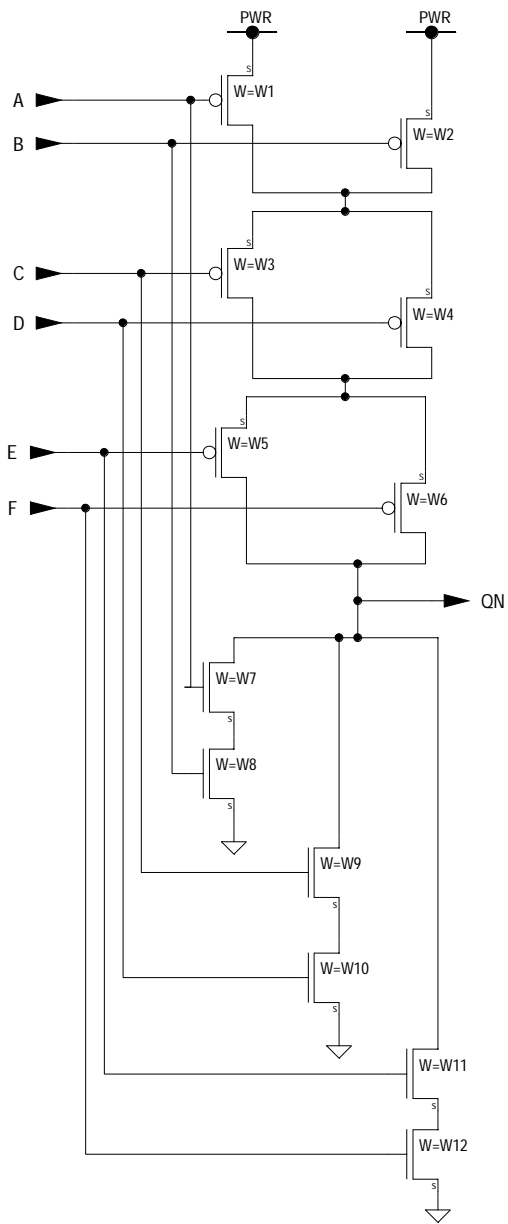


Figure 8.13 SI\_LIB SYMBOL DEFINITION PAGE 14

Part #:	SI EXAMPLE REPORT		
DATE CODE:	0230	SCH_NAME:	STCELL14
		SI NUMBER:	SI01
DATE_TIME:	6-20-2002_13:30	LOCATION:	XX
		INITIALS:	GY

## Appendix A – List of Signals

The following section contains a list of signals and there descriptions. The signal list is intended to aid navigation in this report by providing source and destination schematics for all signals.

*Note: This signal list is an example and the figure numbers do not necessarily match with the schematics found in this report.*

Signal Name	I/O	Fig. #	Signal Description
BIAS	IN	3.5	ECL Dividers Bias Voltage
BIAS	IN	3.4	ECL Dividers Bias Voltage
BIAS	IN	3.8	ECL Dividers Bias Voltage
BIAS	IN	3.2	ECL Dividers Bias Voltage
BIAS	IN	3.5.3	ECL Dividers Bias Voltage
BIAS	IN	3.6	ECL Dividers Bias Voltage
BIAS	OUT	3.1	ECL Dividers Bias Voltage
BIAS	IN	3.3	ECL Dividers Bias Voltage
BIAS	IN	3.5.4	ECL Dividers Bias Voltage
BIAS	IN	3.5.1	ECL Dividers Bias Voltage
BIAS	IN	3.7	ECL Dividers Bias Voltage
BIAS	IN	3.9	ECL Dividers Bias Voltage
BIAS	IN	3.5.2	ECL Dividers Bias Voltage
CD	OUT	6	PFD Charge Down
CD	IN	7.1	PFD Charge Down
CD	IN	7	PFD Charge Down
CD~	IN	5	Inverted CD
CD~	IN	7	Inverted CD
CD~	OUT	6	Inverted CD
CD~	IN	7.1	Inverted CD
CHP_EN	IN	7.2	Charge Pump Enable
CHP_EN	OUT	5	Charge Pump Enable
CHP_EN	IN	7	Charge Pump Enable
CHP_EN	IN	7.1	Charge Pump Enable
CHP_EN~	OUT	5	Charge Pump Enable Inverted
CHP_EN~	IN	7.1	Charge Pump Enable Inverted
CHP_EN~	IN	7.2	Charge Pump Enable Inverted
CHP_EN~	IN	7	Charge Pump Enable Inverted
CHP_VREF	IN	7.1	Charge Pump Reference Voltage
CHP_VREF	OUT	7.2	Charge Pump Reference Voltage

Signal Name	I/O	Fig. #	Signal Description
CLOCK_S	IN	9	Serial Interface Clock, Buffered
CU	OUT	6	PFD Charge Up
CU	IN	7	PFD Charge Up
CU	IN	7.1	PFD Charge Up
CU~	OUT	6	Inverted CU
CU~	IN	5	Inverted CU
CU~	IN	7.1	Inverted CU
CU~	IN	7	Inverted CU
DATA_S	IN	9	Serial Register Data Input, Buffered
DATA_S	IN	9.1	Serial Register Data Input, Buffered
DORX	OUT	7.1	RX Charge Pump Output
DORX	OUT	7	RX Charge Pump Output
FINRX	IN	3	RX Prescaler Input
FINRX	IN	3.2	RX Prescaler Input
FLC1	IN	7.1	Fast Lock Control 1
FLC1	OUT	7.3	Fast Lock Control 1
FLC1~	OUT	7.3	FLC1 Inverted
FLC1~	IN	7.1	FLC1 Inverted
FLC2	OUT	7.3	Fast Lock Control 2
FLC2	IN	7.1	Fast Lock Control 2
FLC2~	OUT	7.3	FLC2 Inverted
FLC2~	IN	7.1	FLC2 Inverted
FL_ENAB	OUT	9	Fast Lock Enable
FL_ENAB	IN	5	Fast Lock Enable
FL_ENAB~	IN	7.3	Fast Lock Enable, LOW Active
FL_ENAB~	IN	7	Fast Lock Enable, LOW Active
FL_ENAB~	OUT	5	Fast Lock Enable, LOW Active
FN_RX	IN	6	RX N Counter Frequency
FN_RX	OUT	5	RX N Counter Frequency
FN_RX~	IN	8.2	Inverted RX N Counter Frequency
FN_RX~	OUT	5	Inverted RX N Counter Frequency
FN_TX	IN	8.2	TX N Counter frequency
FR_RX	IN	6	RX Reference counter Frequency
FR_RX	OUT	5	RX Reference counter Frequency
FR_RX~	IN	8.2	Inverted RX Reference Counter Frequency
FR_RX~	OUT	5	Inverted RX Reference Counter Frequency
FR_TX	IN	8.2	TX Reference Counter Frequency
LDS	IN	8.2	LDS BIT (Common for RX and TX)
LDS	OUT	9	LDS BIT (Common for RX and TX)
LDS_LD	OUT	9.2	LDS BIT LOAD

Signal Name	I/O	Fig. #	Signal Description
LD_F_Y	IN	11.5	LD/Fout Selector Output
LD_F_Y	OUT	8.2	LD/Fout Selector Output
LE_S	IN	9	Serial Interface Latch Enable, Buffered
LE_SB	IN	9.2	Serial Interface Latch Enable, Buffered
NCT_8H	OUT	4.5	RX N Counter value less than 08/h
NCT_8H	IN	5	RX N Counter value less than 08/h
NCT_Q	IN	4.6	RX N Counter Output
NCT_Q	OUT	4.5	RX N Counter Output
NCT_Q	IN	5	RX N Counter Output
NCT_Q	IN	4.3	RX N Counter Output
NCT_RES	OUT	5	RX N Counter output FF Reset
NCT_RES	IN	4.5	RX N Counter output FF Reset
NCT_RES	IN	4.3	RX N Counter output FF Reset
N_R[11:1]~	BUS	2	N Counter Reset BUS
N_R[11:1]~	BUS	4.6	N Counter Reset BUS
N_R[11:1]~	OUT	4.6	N Counter Reset BUS
N_R[11:1]~	BUS	4.5	N Counter Reset BUS
N_R[11:1]~	IN	4.5	N Counter Reset BUS
N_S[11:1]~	BUS	4.6	N Counter SET BUS
N_S[11:1]~	BUS	2	N Counter SET BUS
N_S[11:1]~	OUT	4.6	N Counter SET BUS
N_S[11:1]~	IN	4.5	N Counter SET BUS
N_S[11:1]~	BUS	4.5	N Counter SET BUS
OSCIN	IN	10	Reference Frequency from OSCin Pad
PHDIFF~	OUT	6	Phase Difference, Active Low
PHDIFF~	IN	7	Phase Difference, Active Low
PHDIFF~	IN	7.3	Phase Difference, Active Low
PHDIFF~	IN	8.1	Phase Difference, Active Low
PSRX_B	OUT	11.4	PSRX from Input Buffer
PSRX_B	IN	5	PSRX from Input Buffer
PSRX_BB	IN	8.1	Logic Equivalent of PSRX_B
PSRX_BB	OUT	5	Logic Equivalent of PSRX_B
RCT_8H	IN	5	RX Reference Counter value less than 08/h
RCT_8H	OUT	4.1	RX Reference Counter value less than 08/h
RCT_Q	IN	5	RX Reference Counter Underflow (=0001/h)
RCT_Q	IN	4.2	RX Reference Counter Underflow (=0001/h)
RCT_Q	OUT	4.1	RX Reference Counter Underflow (=0001/h)
RCT_RES	IN	4.1	RX Reference Counter output FF Reset
RCT_RES	OUT	5	RX Reference Counter output FF Reset
REF1	OUT	3.1	ECL FFLOP Reference Voltage

Signal Name	I/O	Fig. #	Signal Description
REF1	IN	3.3	ECL FFLOP Reference Voltage
REF2	IN	3.7	ECL Buffers Reference Voltage
REF2	IN	3.8	ECL Buffers Reference Voltage
REF2	OUT	3.1	ECL Buffers Reference Voltage
REF2	IN	3.9	ECL Buffers Reference Voltage
REF_R[14:1]~	IN	4.1	REF Counter RESET BUS
REF_R[14:1]~	BUS	2	REF Counter RESET BUS
REF_R[14:1]~	BUS	4.2	REF Counter RESET BUS
REF_R[14:1]~	BUS	4.1	REF Counter RESET BUS
REF_R[14:1]~	OUT	4.2	REF Counter RESET BUS
REF_S[14:1]~	OUT	4.2	REF Counter SET BUS
REF_S[14:1]~	BUS	4.2	REF Counter SET BUS
REF_S[14:1]~	BUS	2	REF Counter SET BUS
REF_S[14:1]~	BUS	4.1	REF Counter SET BUS
REF_S[14:1]~	IN	4.1	REF Counter SET BUS
RXIN	OUT	3.2	RX Preamplifier Output
RXIN~	OUT	3.2	Complementary RX Preamplifier Output
RX_CS	IN	7	RX Charge Pump Current Setting
RX_CS	IN	7.1	RX Charge Pump Current Setting
RX_CS	OUT	9	RX Charge Pump Current Setting
RX_CS~	IN	7	RX_CS Inverted
RX_CS~	OUT	9	RX_CS Inverted
RX_CS~	IN	7.1	RX_CS Inverted
RX_FC	OUT	9	RX FC BIT
RX_FC	IN	6	RX FC BIT
RX_LDET	IN	8.2	RX Lock Detect Bit
RX_LDET	OUT	8.1	RX Lock Detect Bit
RX_LD_RES	IN	8.1	RX Lock Detector Reset
RX_LD_RES	OUT	5	RX Lock Detector Reset
RX_OSC	OUT	10	OSCIn Input for RX Synthesizer
RX_OSCB	IN	4.1	Buffered RX_OSC
RX_OSCB	IN	5	Buffered RX_OSC
RX_OSCB_D2	OUT	4.1	RX_OSCB Clock divided by 2
RX_OSCB_D2	IN	8.1	RX_OSCB Clock divided by 2
RX_OSCB~	IN	5	Inverted RX_OSC
RX_OSCB~	IN	4.1	Inverted RX_OSC
RX_PFD_RES	IN	6	RX Phase Frequency Detector Reset
RX_PFD_RES	OUT	5	RX Phase Frequency Detector Reset
RX_PRESC_Y	OUT	3	RX Prescaler Output
RX_PRESC_YA	IN	4.5	RX_PRESC_Y Buffered



Signal Name	I/O	Fig. #	Signal Description
RX_PRESC_YA	IN	5	RX_PRESC_Y Buffered
RX_PRESC_YA~	IN	4.5	RX_PRESC_Y Inverted
RX_PRESC_YA~	IN	5	RX_PRESC_Y Inverted
RX_PRESC_YB	IN	4.3	RX_PRESC_Y Buffered
RX_PRESC_YB~	IN	4.3	RX_PRESC_Y Inverted
RX_P_EN	IN	3	RX Prescaler Enable
RX_P_EN	IN	10	RX Prescaler Enable
RX_P_EN	IN	3.1	RX Prescaler Enable
RX_P_EN~	OUT	5	RX Prescaler Enable. LOW Active
RX_P_EN~	IN	3	RX Prescaler Enable. LOW Active
RX_REF_LD	OUT	9	RX Reference Counter Ratio Load
RX_REF_LD	IN	4.2	RX Reference Counter Ratio Load
RX_REF_LD	OUT	9.2	RX Reference Counter Ratio Load
RX_SN_LD	IN	4.6	RX Swallow/N-Counter Ratios Load
RX_SN_LD	IN	4.4	RX Swallow/N-Counter Ratios Load
RX_SN_LD	OUT	9.2	RX Swallow/N-Counter Ratios Load
RX_SN_LD	OUT	9	RX Swallow/N-Counter Ratios Load
RX_SW	IN	3	RX Prescaler Divide Ratio setting
RX_SW_B	OUT	9	RX SW Bit (RX Prescaler Ratio Setting)
SR_CK	IN	9.1	Serial Register Clock
SR_OUT1	IN	9.2	CN1 Bit
SR_OUT1~	IN	9.2	CN1 Bit, Inverted
SR_OUT1~	OUT	9.1	CN1 Bit, Inverted
SR_OUT2	IN	9.2	CN2 Bit
SR_OUT2~	IN	9.2	CN2 Bit, Inverted
SR_OUT2~	OUT	9.1	CN2 Bit, Inverted
SR_OUT[12:6]	BUS	4.4	Serial Register Output BUS
SR_OUT[12:6]	IN	4.4	Serial Register Output BUS
SR_OUT[12:6]	BUS	2	Serial Register Output BUS
SR_OUT[18:5]	IN	4.2	Serial Register Output BUS
SR_OUT[18:5]	BUS	2	Serial Register Output BUS
SR_OUT[18:5]	BUS	4.2	Serial Register Output BUS
SR_OUT[23:13]	BUS	2	Serial Register Output BUS
SR_OUT[23:13]	BUS	4.6	Serial Register Output BUS
SR_OUT[23:13]	IN	4.6	Serial Register Output BUS
SR_OUT[23:1]	OUT	9.1	Serial Interface Register Output BUS
SR_OUT[23:1]	BUS	9.1	Serial Interface Register Output BUS
SR_OUT[23:1]	BUS	9	Serial Interface Register Output BUS
SR_OUT[23:5]	OUT	9	Serial Register Output BUS
SR_OUT[23:5]	BUS	2	Serial Register Output BUS

Signal Name	I/O	Fig. #	Signal Description
SR_OUT[23:5]	BUS	9	Serial Register Output BUS
SWCT_Q	IN	4.4	Swallow Counter Output
SWCT_Q	OUT	4.3	Swallow Counter Output
SWEN	OUT	4.3	Swallow Enable (RX Prescaler)
SWEN	IN	3	Swallow Enable (RX Prescaler)
SW_R[7:1]~	OUT	4.4	Swallow Counter Reset BUS
SW_R[7:1]~	BUS	4.3	Swallow Counter Reset BUS
SW_R[7:1]~	BUS	2	Swallow Counter Reset BUS
SW_R[7:1]~	IN	4.3	Swallow Counter Reset BUS
SW_R[7:1]~	BUS	4.4	Swallow Counter Reset BUS
SW_S[7:1]~	IN	4.3	Swallow Counter SET BUS
SW_S[7:1]~	OUT	4.4	Swallow Counter SET BUS
SW_S[7:1]~	BUS	2	Swallow Counter SET BUS
SW_S[7:1]~	BUS	4.3	Swallow Counter SET BUS
SW_S[7:1]~	BUS	4.4	Swallow Counter SET BUS
T1	OUT	9	T1 BIT (Common for RX and TX)
T1	IN	8.2	T1 BIT (Common for RX and TX)
T1_T2_LD	OUT	9.2	T1 and T2 Bits Load
T2	OUT	9	T2 BIT (Common for RX and TX)
T2	IN	8.2	T2 BIT (Common for RX and TX)
TX_CS	OUT	9	TX CS BIT
TX_CS~	OUT	9	Inverted TX_CS
TX_FC	OUT	9	TX FC Bit
TX_LDET	IN	8.2	TX Lock Detect Bit
TX_OSC	OUT	10	OSCin Input to TX Synthesizer
TX_P_EN	IN	10	From TX Synthesizer Logic
TX_REF_LD	OUT	9	TX Reference Counter Ratio Load
TX_REF_LD	OUT	9.2	TX Reference Counter Ratio Load
TX_SN_LD	OUT	9.2	TX Swallow/N-Counter Ratios Load
TX_SN_LD	OUT	9	TX Swallow/N-Counter Ratios Load
TX_SW	OUT	9	TX SW Bit
VCCR_X_1	IN	3	RX Section Power Supply
VCCR_X_2	IN	7	RX Section Power Supply
VCCR_X_2	IN	11.4	RX Section Power Supply
VCCR_X_2R	IN	7.3	RX Charge Pump logic Power Supply
VCCR_X_2R	IN	7.1	RX Charge Pump logic Power Supply
VCCTX_2	IN	10	TX Section and Serial Interface Power Supply
VCCTX_2	IN	11.5	TX Section and Serial Interface Power Supply
VPRX	IN	7.1	RX Charge Pump Power Supply
VPRX	IN	7	RX Charge Pump Power Supply

<b>Signal Name</b>	<b>I/O</b>	<b>Fig. #</b>	<b>Signal Description</b>
XFINRX	IN	3	Complementary RX Prescaler Input
XFINRX	IN	3.2	Complementary RX Prescaler Input
[CLOCK]	IN	2	Serial Interface Clock Input PAD
[DATA]	IN	2	Serial Interface Data Input PAD
[DORX]	OUT	2	RX Charge Pump Output PAD
[FINRX]	IN	2	RX Prescaler Input PAD
[LD/FOUT]	OUT	2	RX/TX Lock Detect Output PAD
[LE]	IN	2	Load Enable, Serial Interface Input PAD
[OSCIN]	IN	2	Reference Frequency Input PAD
[PSRX]	IN	2	RX Power Saving Mode Control Input PAD
[VCCR_X_1]	IN	2	RX Section Power Supply PAD 1
[VCCR_X_2]	IN	2	RX Section Power Supply PAD 2
[VCCTX_2]	IN	2	TX Section and Serial Interface Power Supply PAD 2
[VPRX]	IN	2	RX Charge Pump Power Supply PAD
[XFINRX]	IN	2	Complementary RX Prescaler Input PAD

